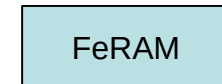
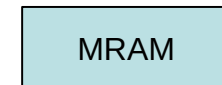
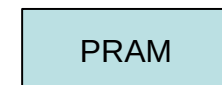
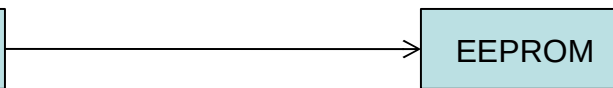
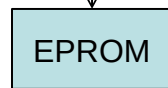
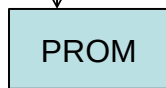
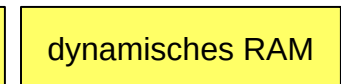
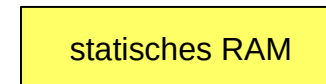
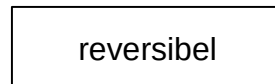
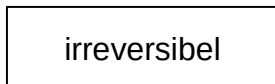
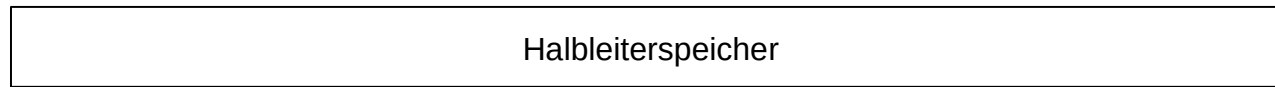


Design digitaler Schaltkreise



Basiert auf rückgekoppelten Invertern

Basiert auf Kondensatoren

Löschbar mit UV-Licht

Elektrisch löschar
und programmierbar

RAM-Erweiterungen

ROM - read only memory
RAM - random access memory
PROM - programmable ROM
EPROM - electrically programmable ROM
FeRAM - Ferroelectric RAM
MRAM - Magnetoresistive RAM
PRAM - Phase-change RAM

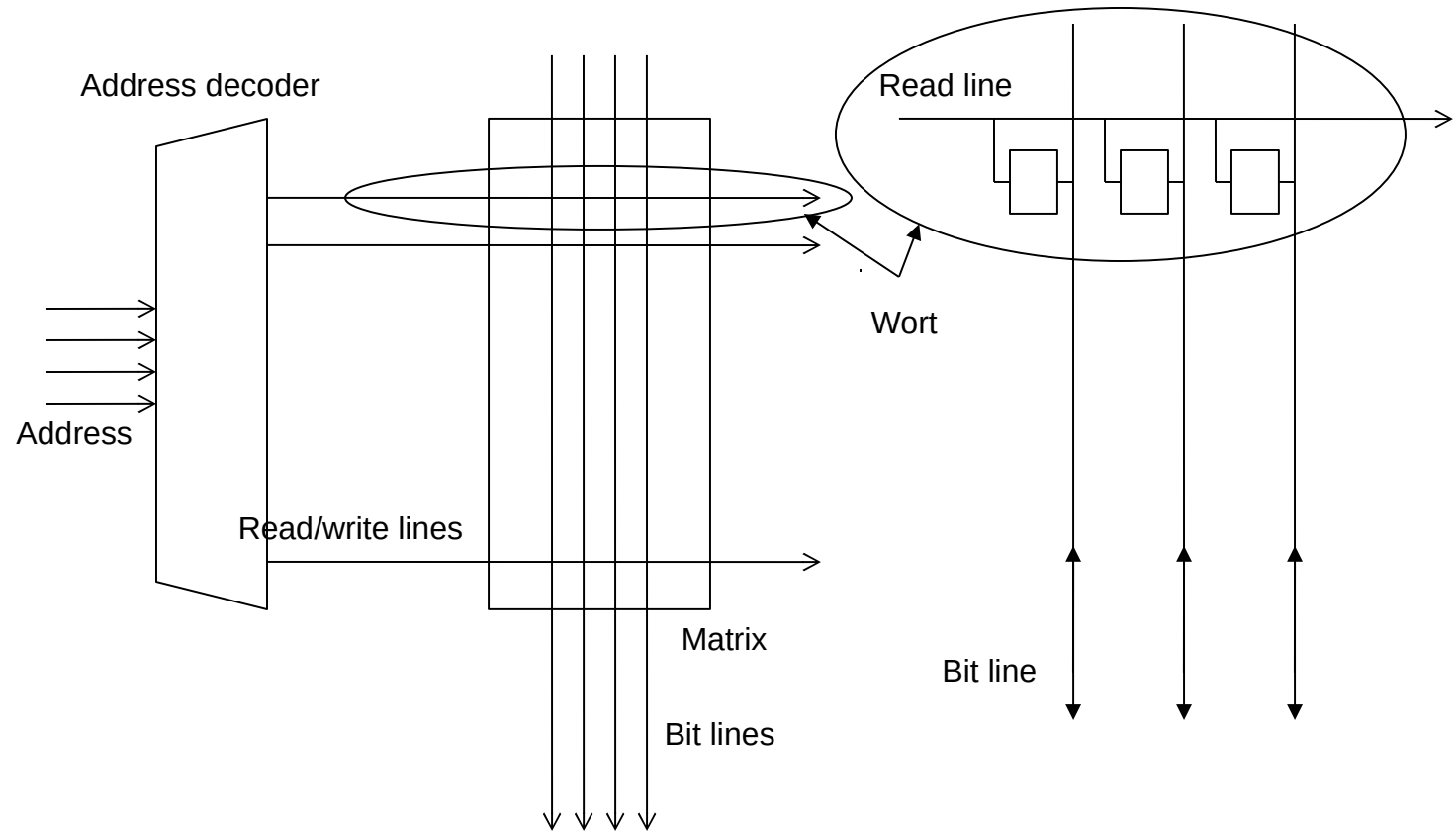
Flüchtig (volatile)

Permanent (non-volatile)

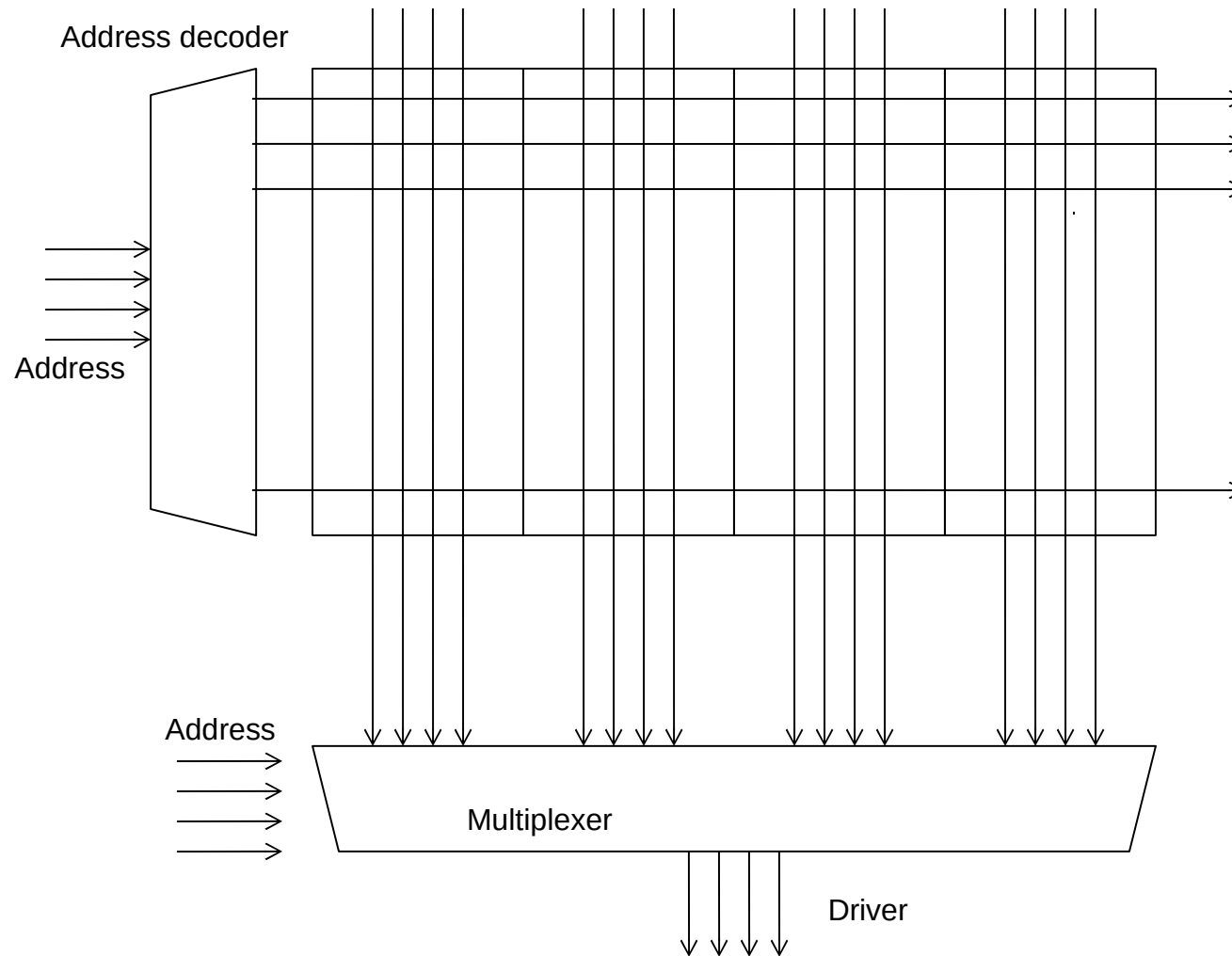


Programmierung bei
Herstellung

P. mit spez. Geräten

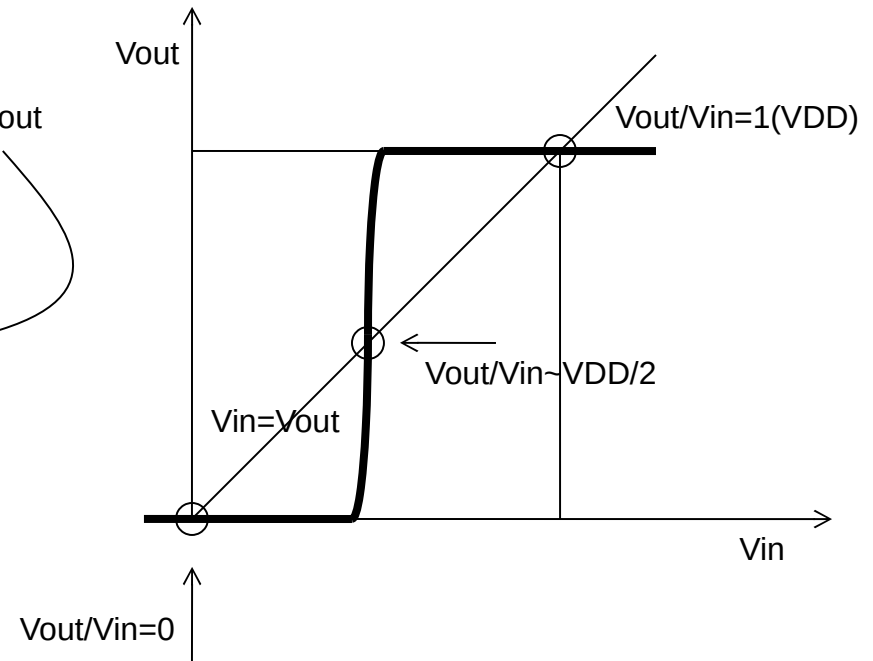
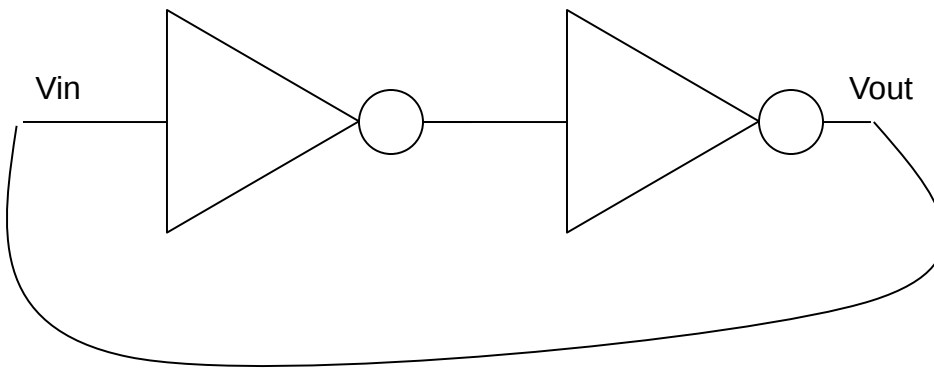


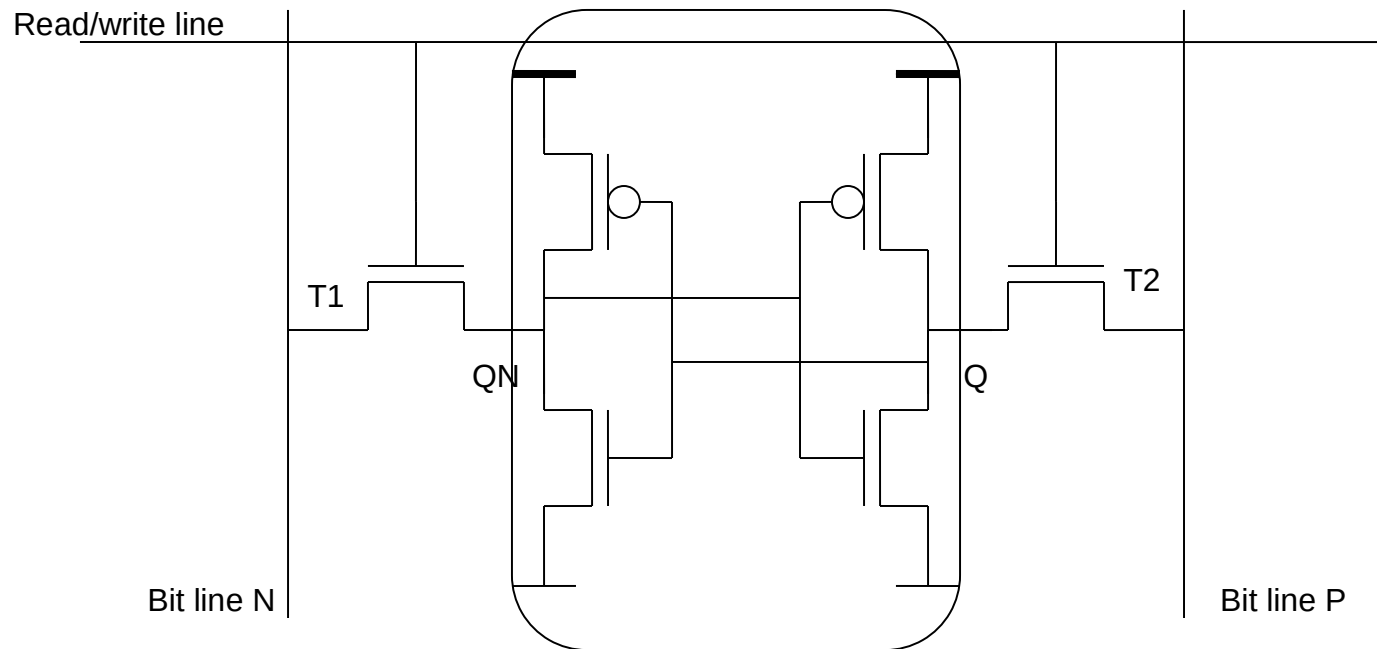
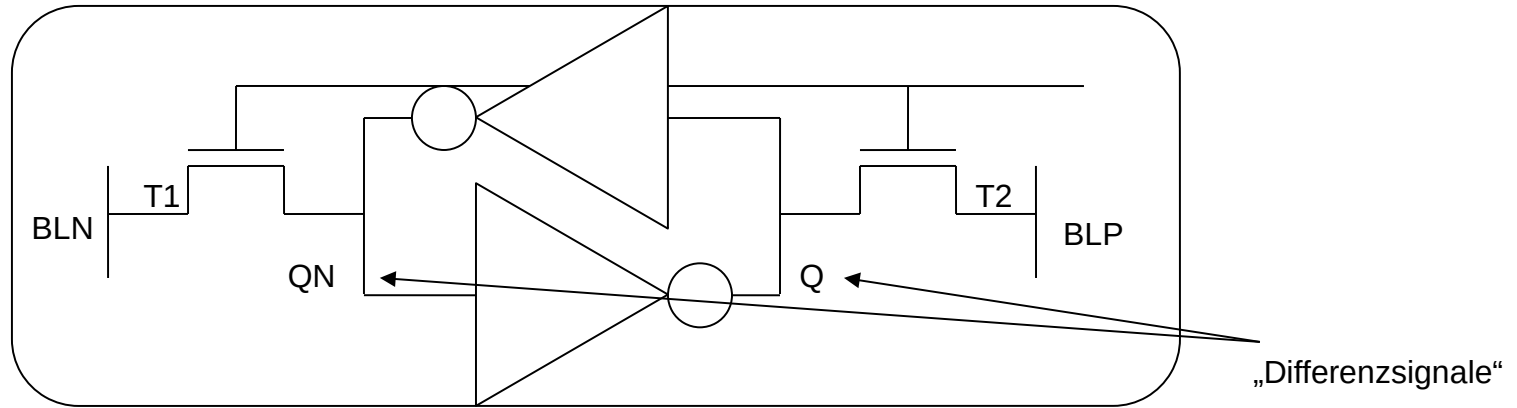
Aspect ratio (too high and too narrow layout) may be a problem!



SRAM

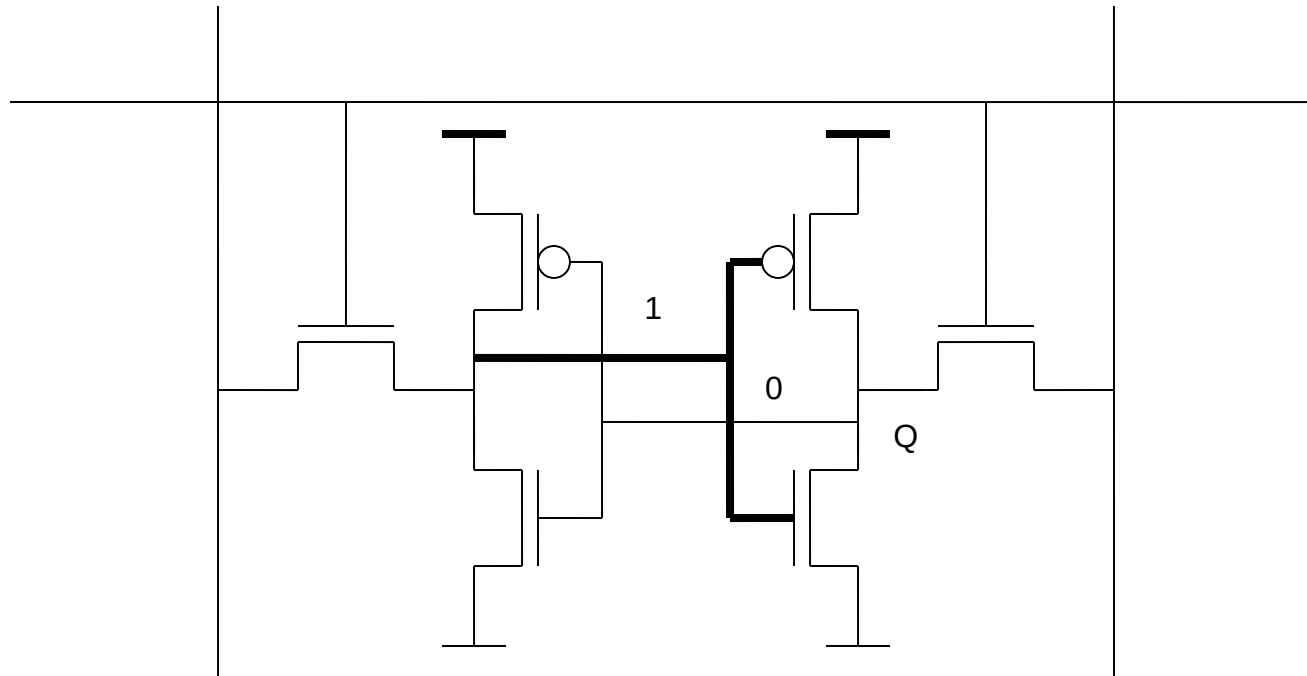
- Statische Speicherzellen
- Wenn wir den Ausgang des zweiten Inverters mit dem Eingang des ersten verbinden, gilt $V_{in} = V_{out}$.
- Der Zustand der Schaltung liegt im Schnittpunkt der Kennlinie $V_{out} = f(V_{in})$ und der Geraden $V_{out} = V_{in}$.



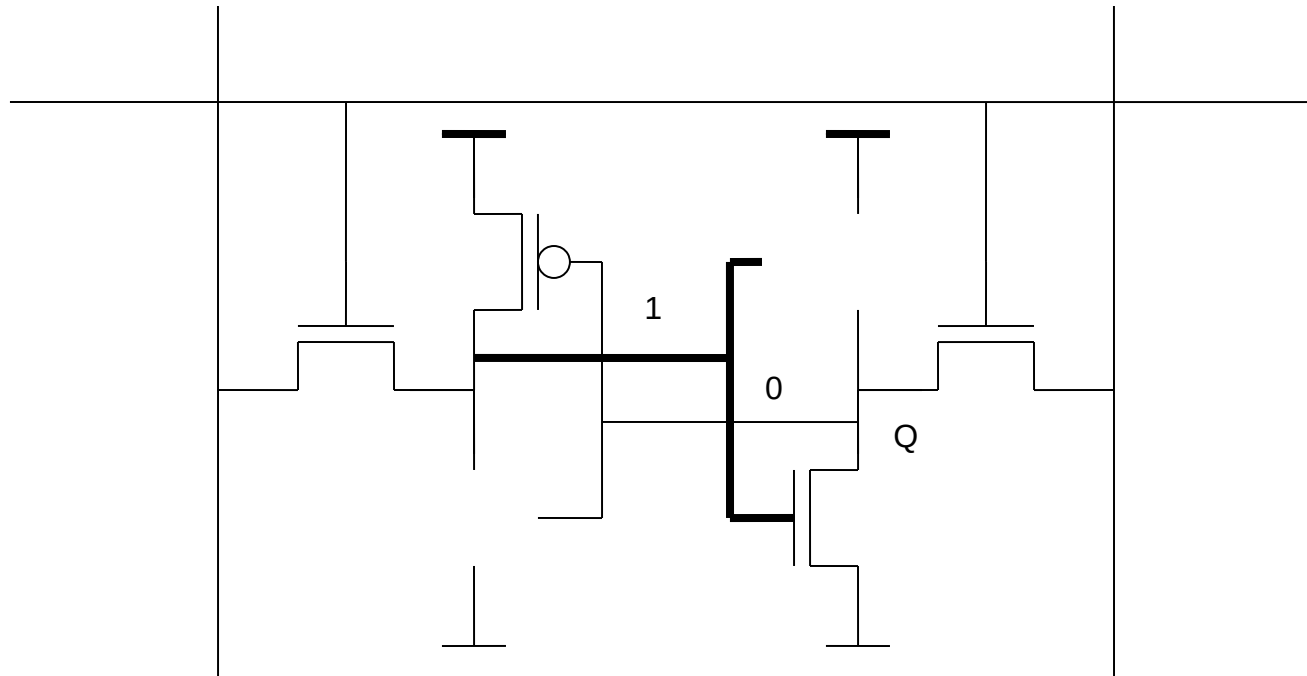


Diese 4 Transistoren speichern den Zustand

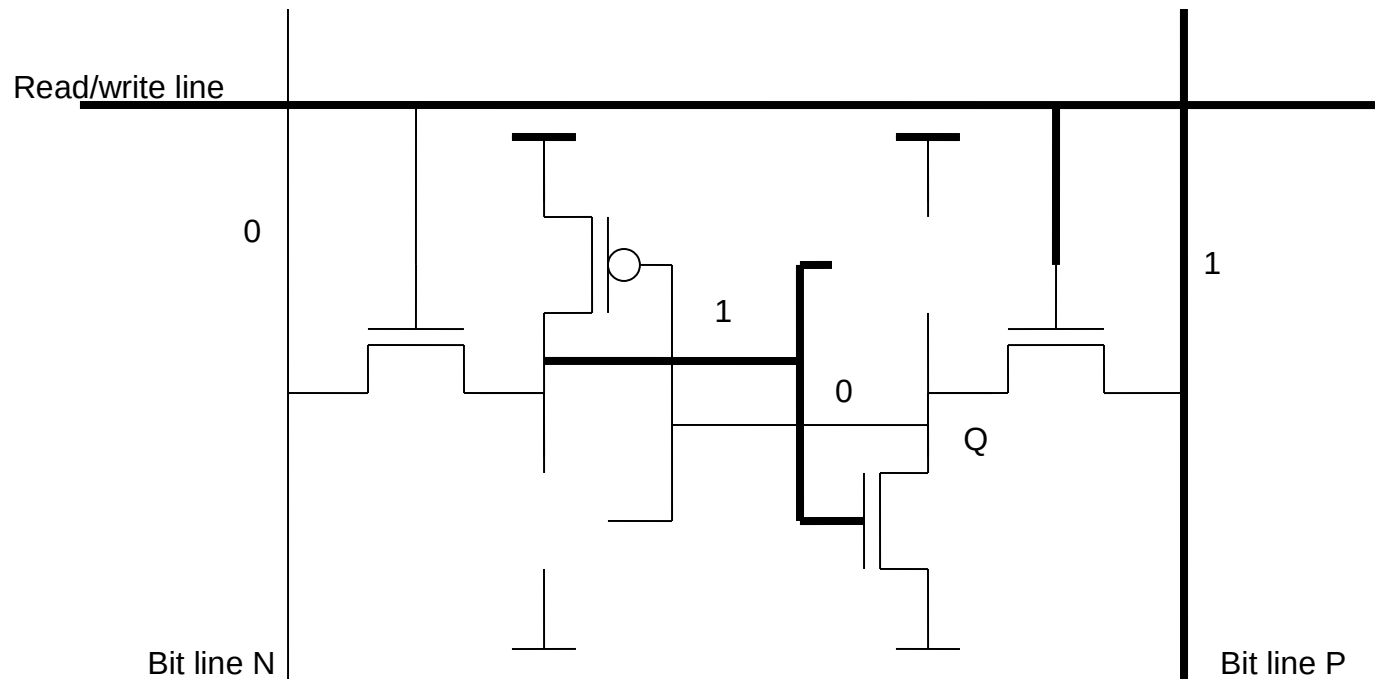
- SRAM befindet sich im Zustand $Q=0$



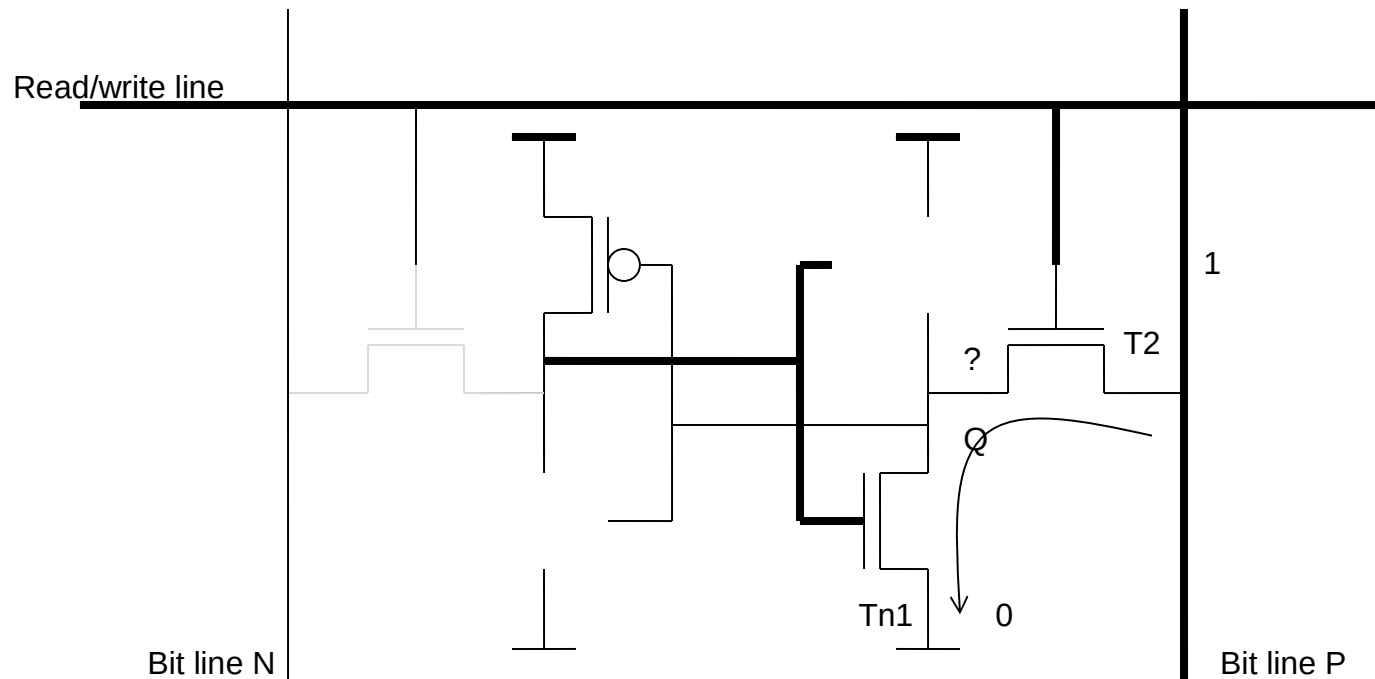
- SRAM befindet sich im Zustand $Q=0$



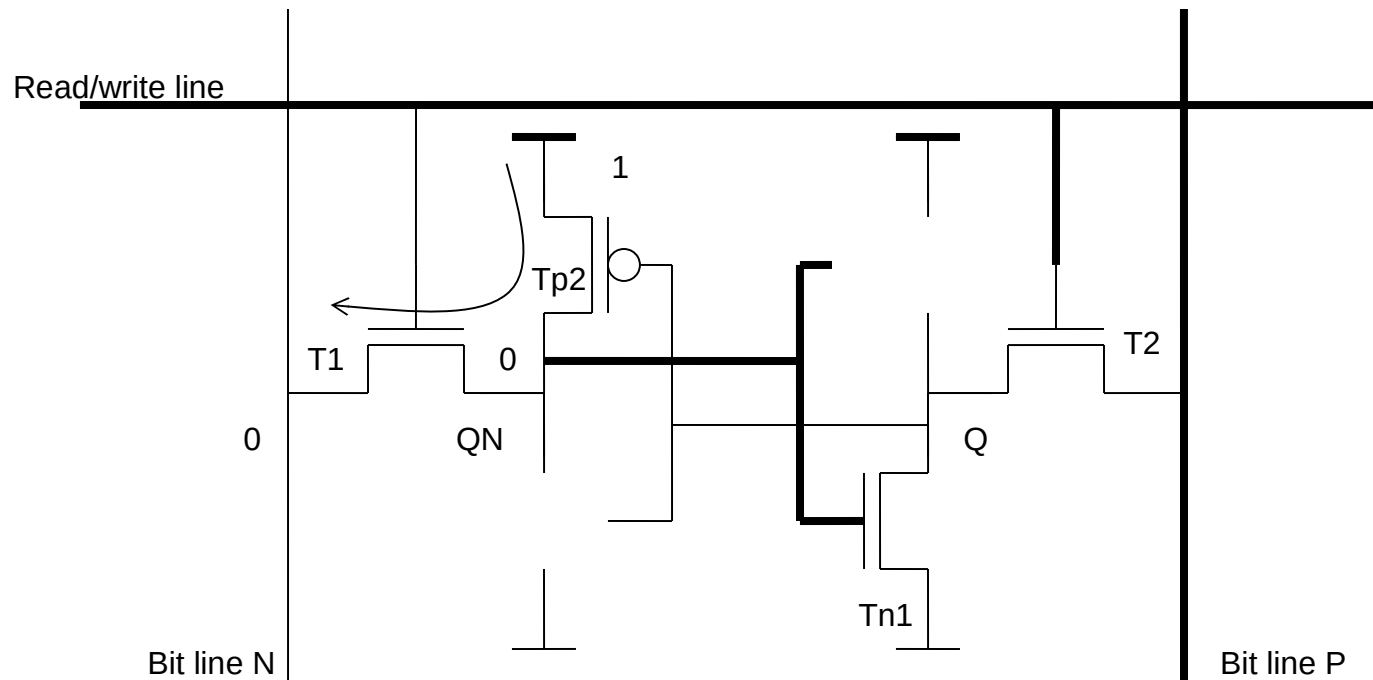
- Versuchen wir die RAM Zelle zu überschreiben...
- Annahme: NMOS leitet starker als PMOS
- Bit line P wird auf 1 aufgeladen, bit line N auf 0 entladen
- Word line (read/write line) wird geschaltet



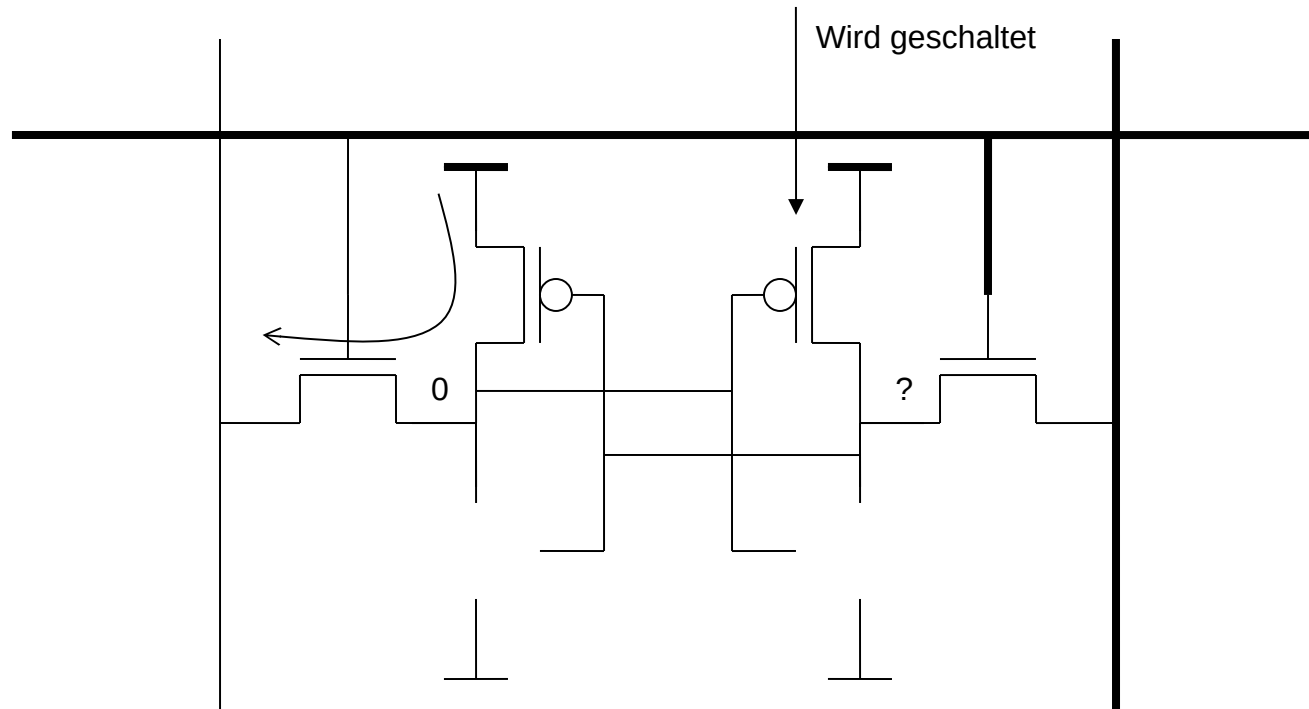
- Frage: Warum gibt es zwei Schalter-Transistoren und zwei bit lines?
- In unserem Fall ist es schwer nur mit der bit line P, RAM zu überschreiben. Transistor T2 leitet zu schwach wegen kleiner V_{gs}



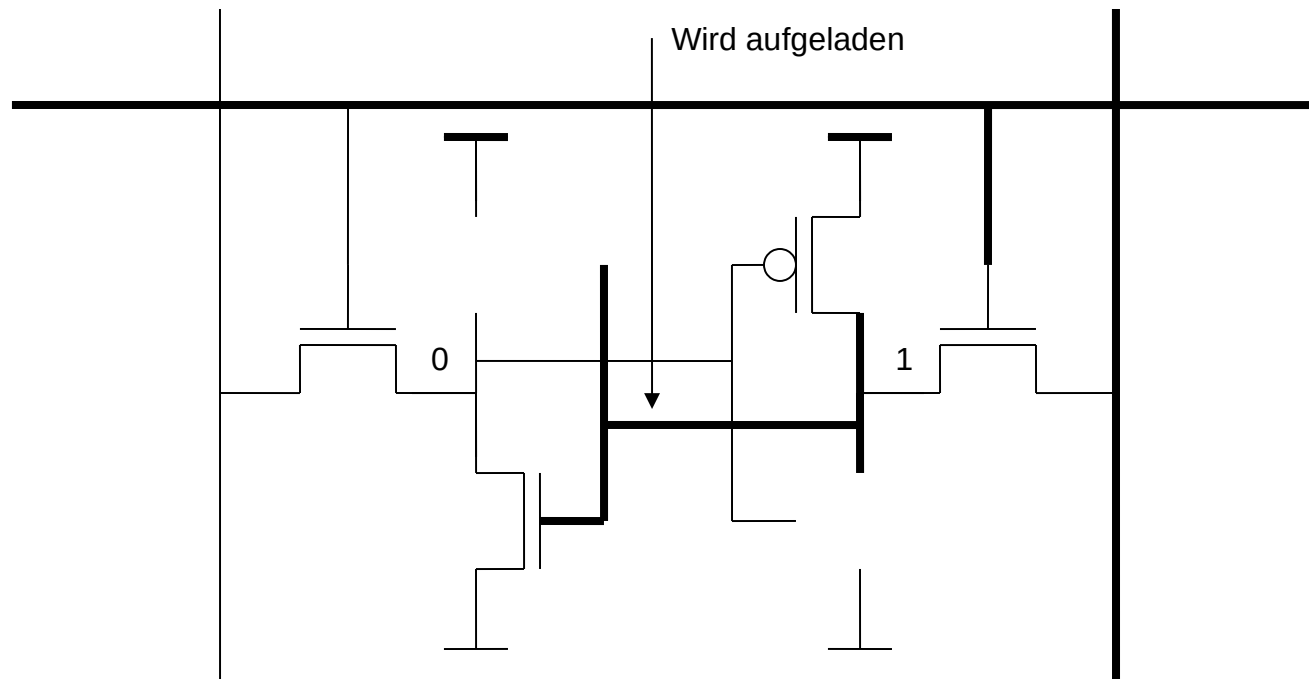
- Transistor T1 leitet gut und entlädt QN gegen 0



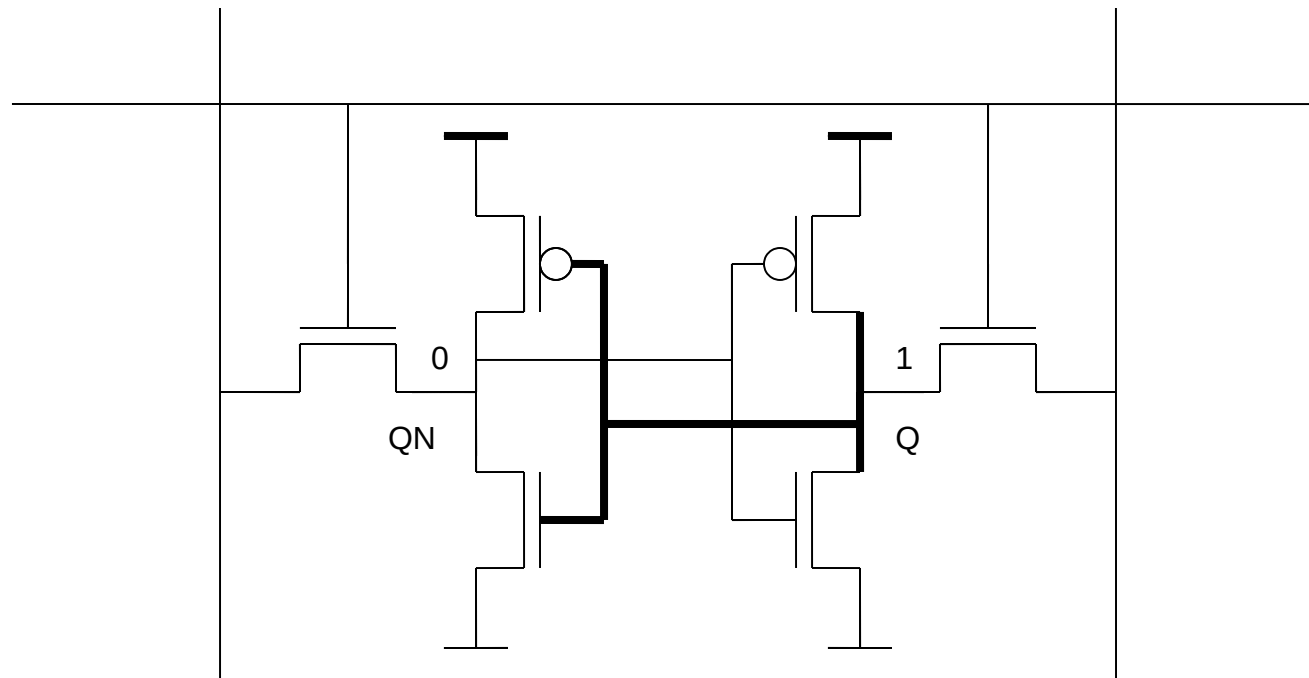
- Das führt zum “Umkippen” von RAM Zelle



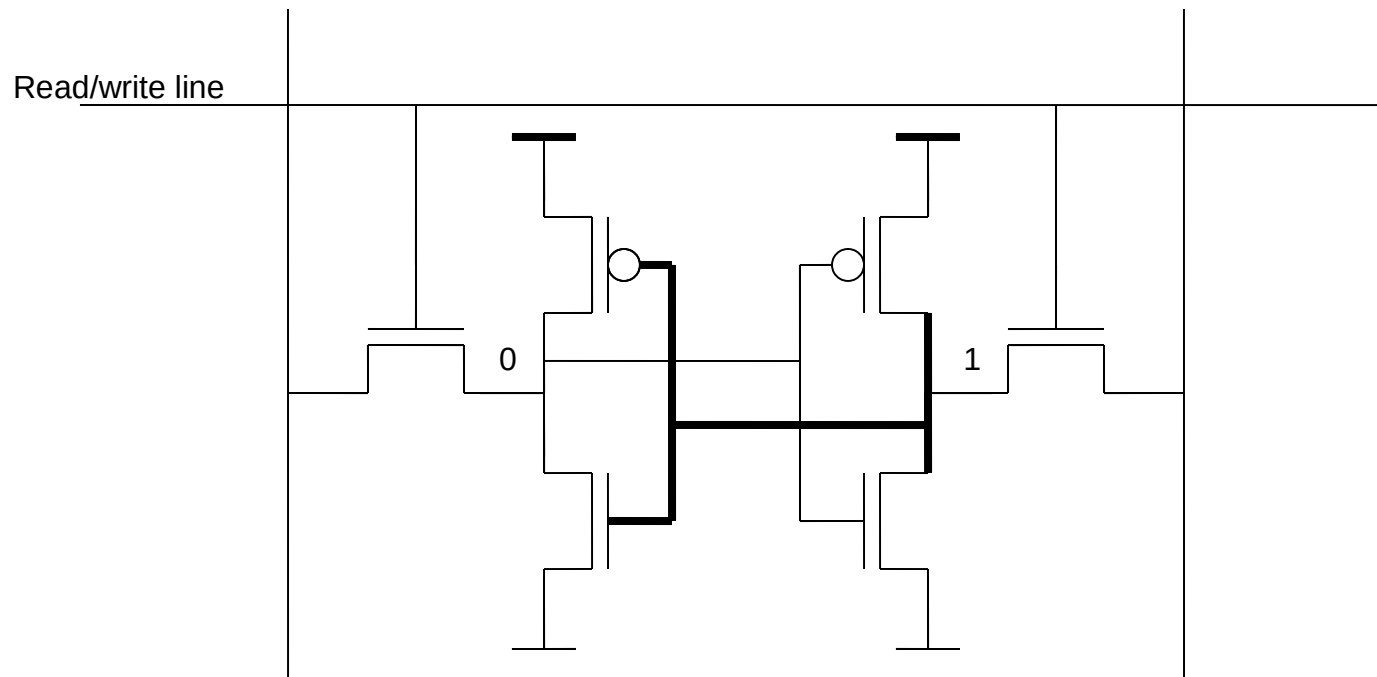
- Das führt zum “Umkippen” von RAM Zelle



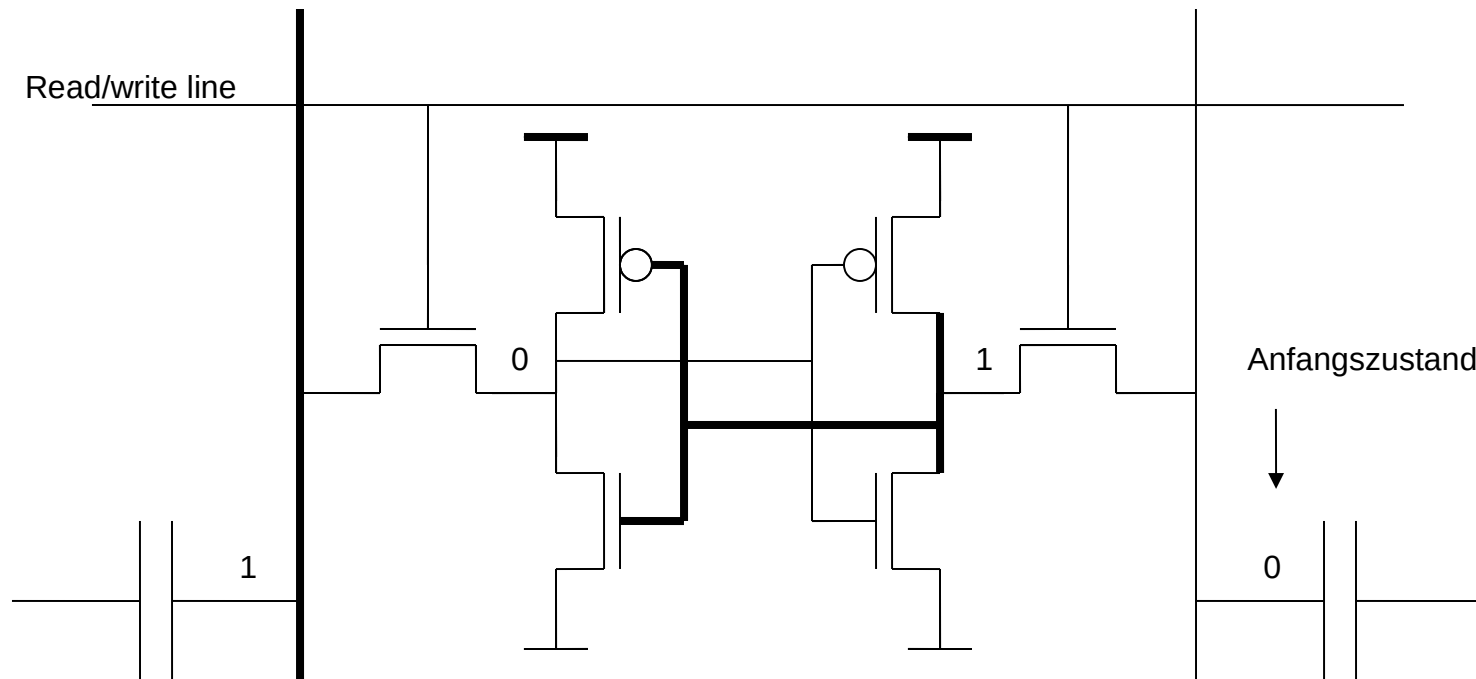
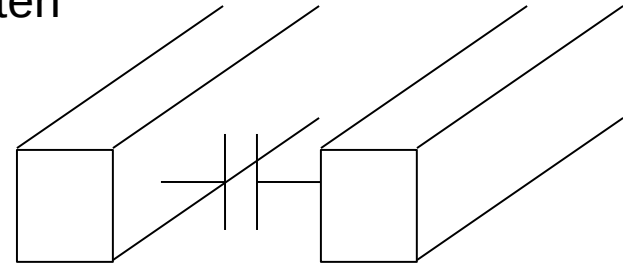
- Zustand $Q = 1/QN = 0$ wird hergestellt



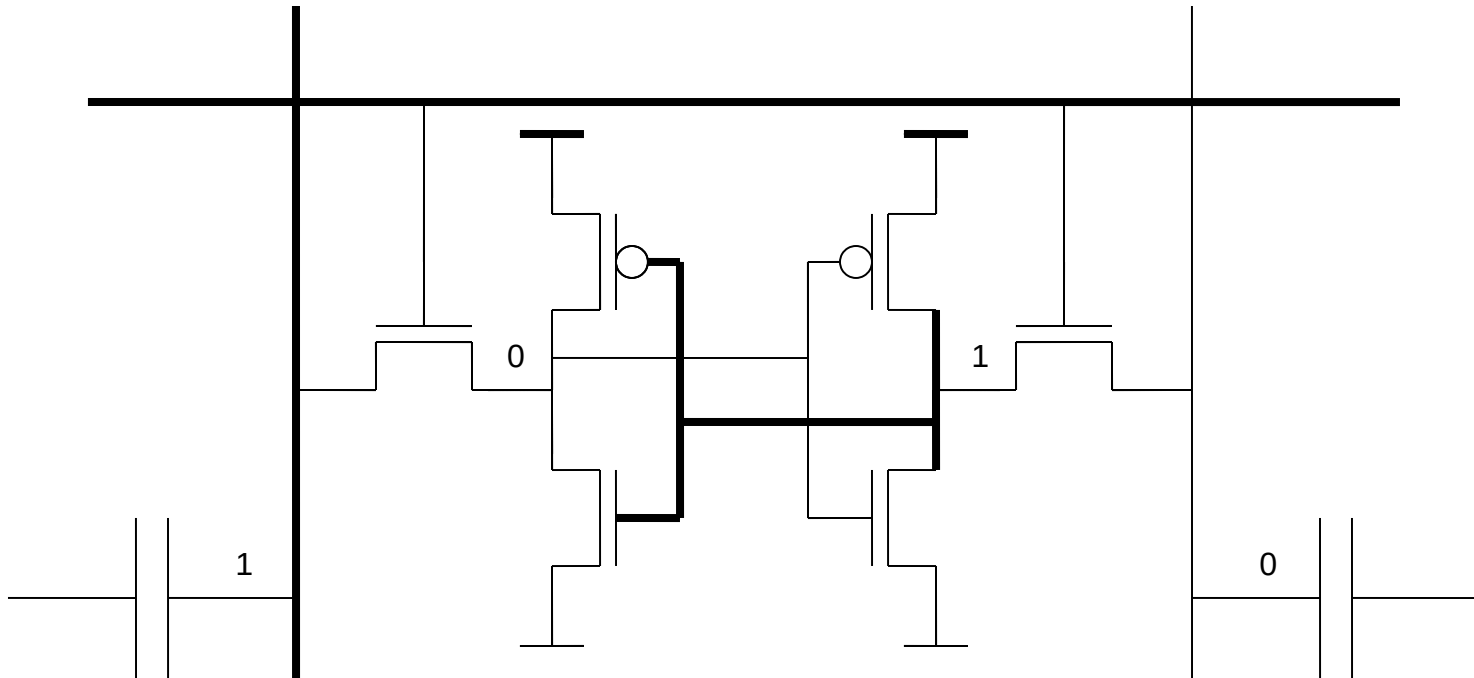
- Lesen von SRAM-Zellen



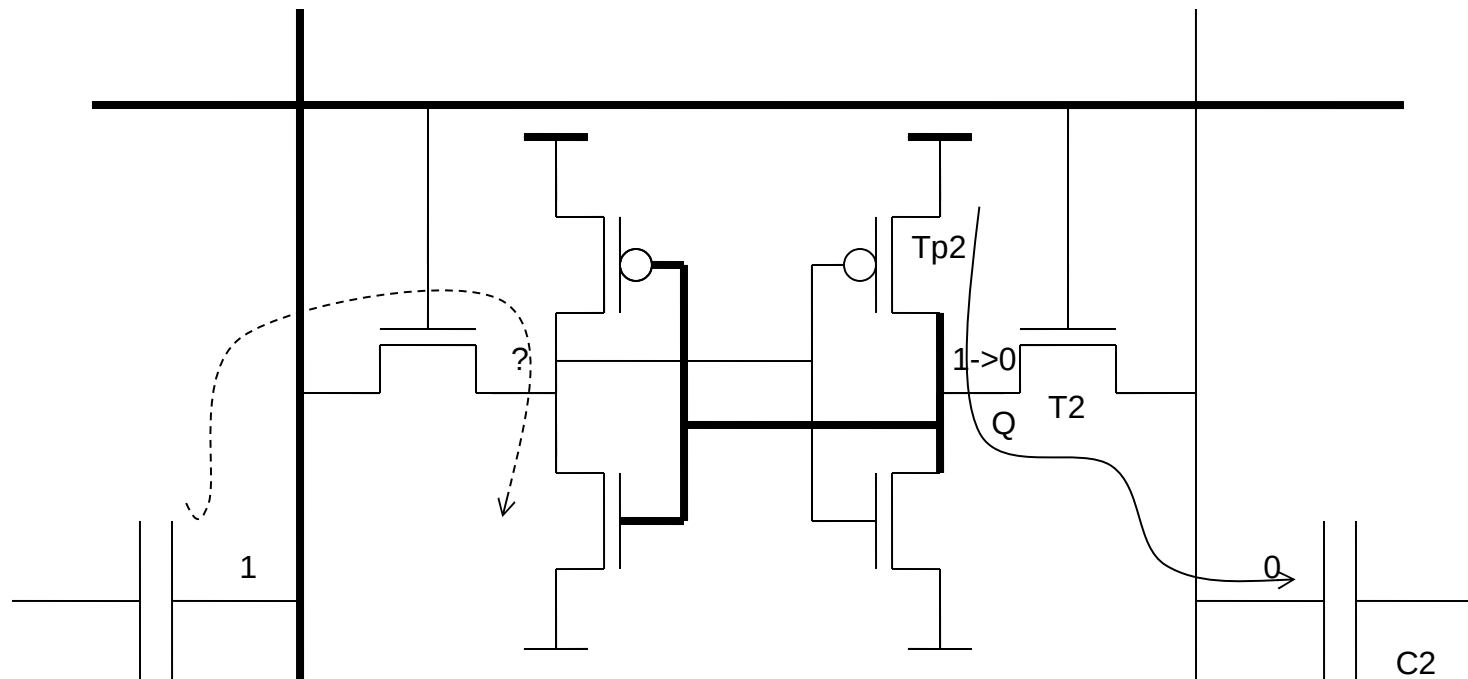
- Annahme: bit-Linien haben große Kapazitäten
- Die Bitlinien sind ungünstig aufgeladen



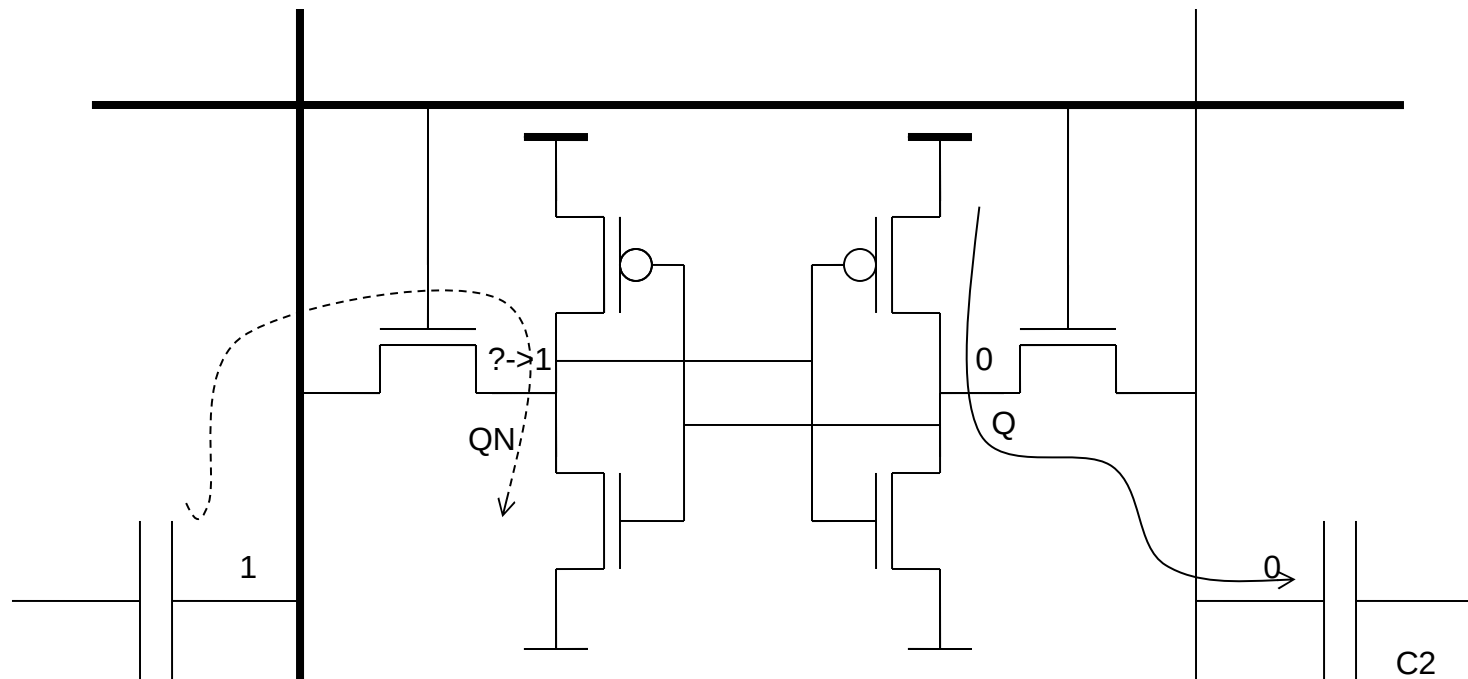
- Read line wird geschaltet



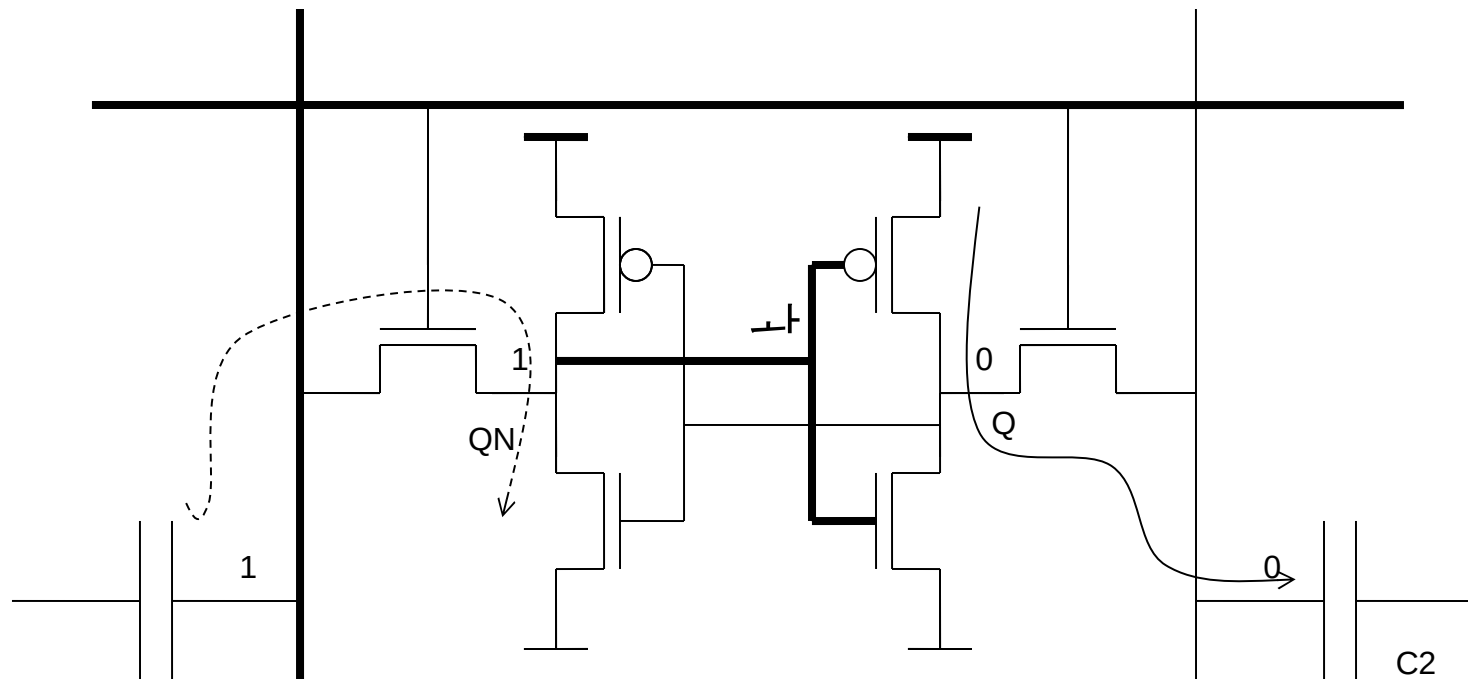
- Problem
- Tp2 leitet schwächer als T2
- Tp2 muss C2 aufladen, wegen großer Kapazität C2 fließt viel Strom



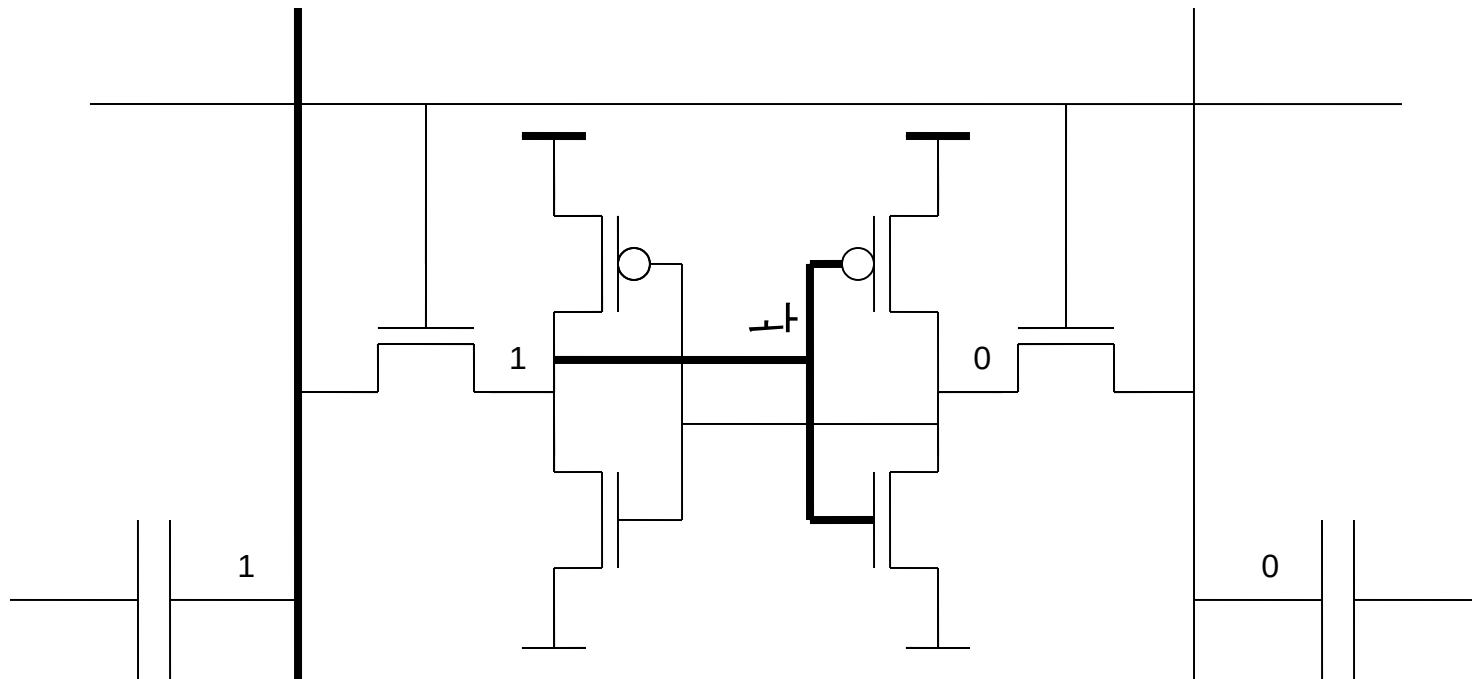
- Problem
- Tp2 leitet schwächer als T2
- Tp2 muss C2 aufladen, wegen großer Kapazität C2 fließt viel Strom -> Potential Q fällt



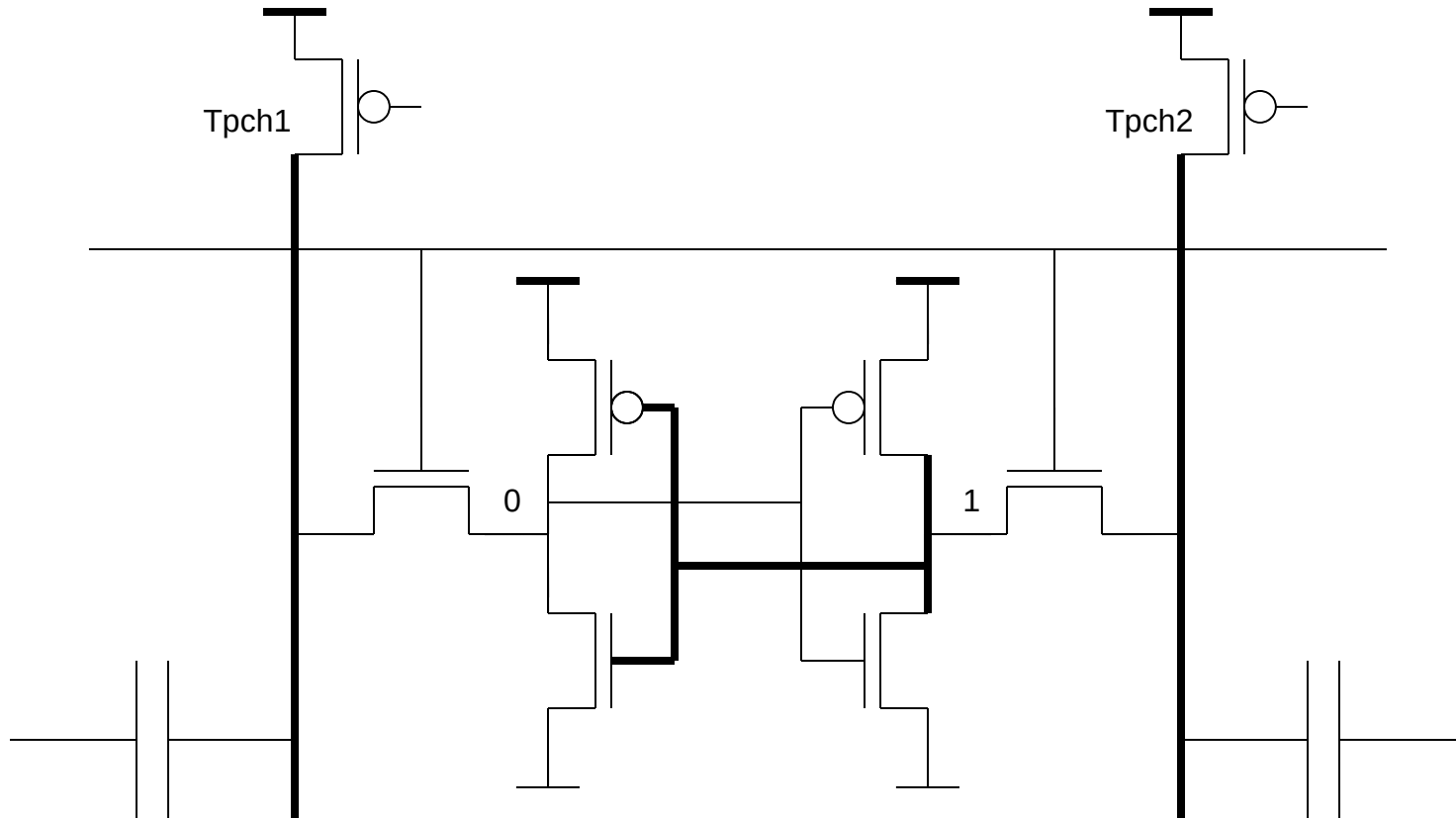
- Problem
- Tp2 leitet schwächer als T2
- Tp2 muss C2 aufladen, wegen großer Kapazität C2 fließt viel Strom -> Potential Q fällt -> QN wird aufgeladen, RAM Zelle kippt um



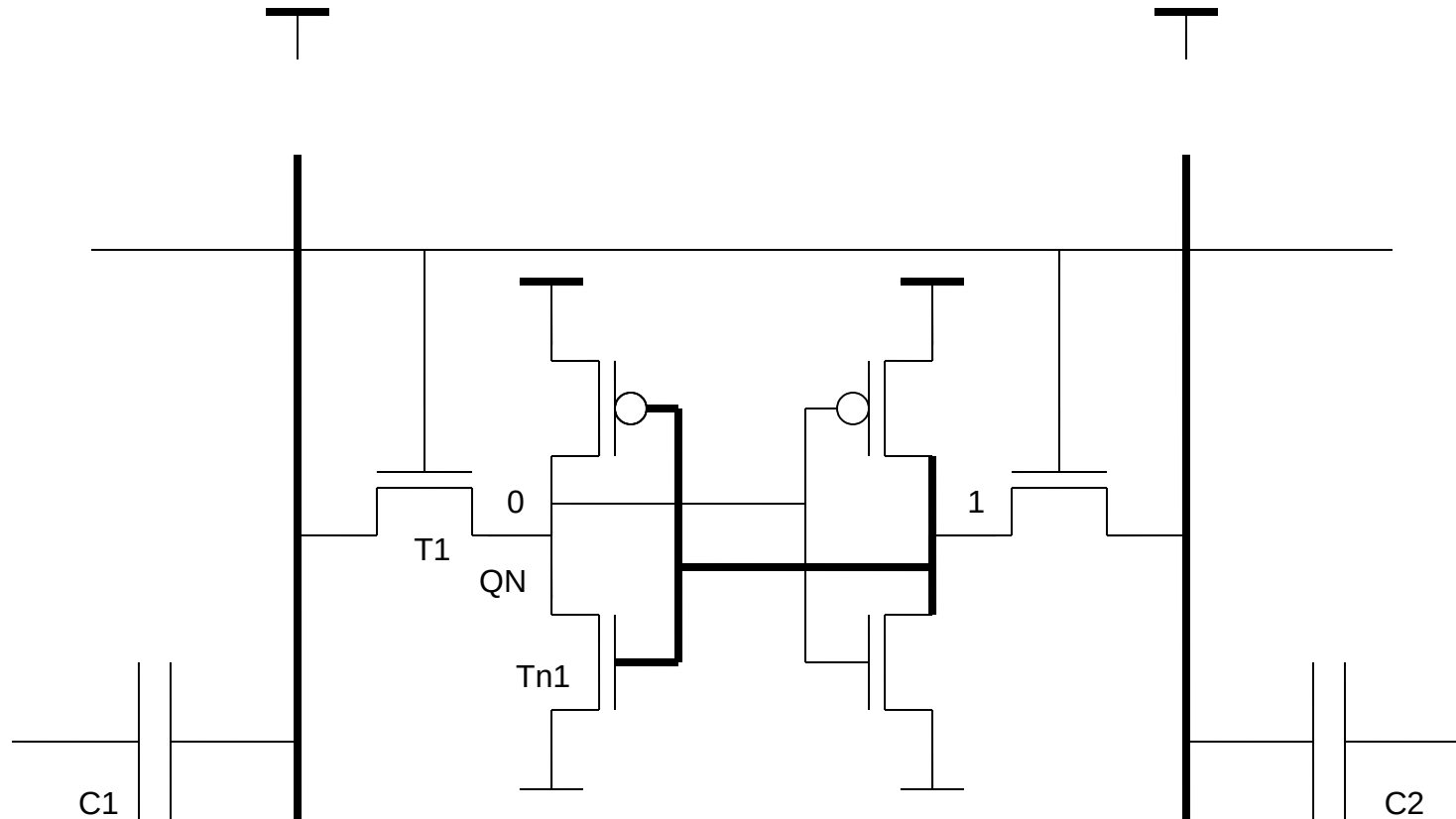
- RAM Zelle bleibt überschrieben



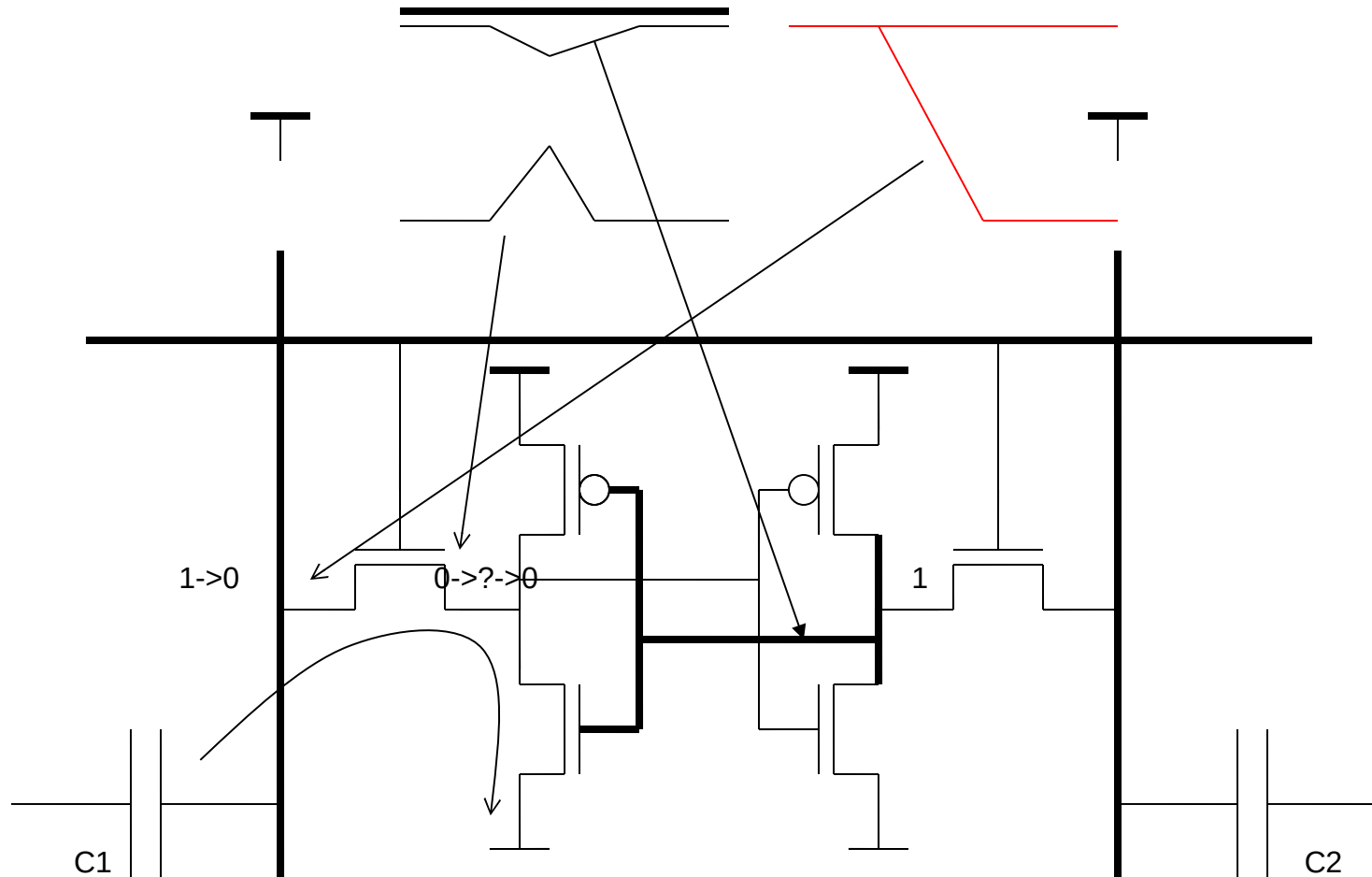
- Lösung des Problems: Precharge
- Bitlinien werden auf 1 aufgeladen (mithilfe von Transistoren Tpch1 und Tpch2)



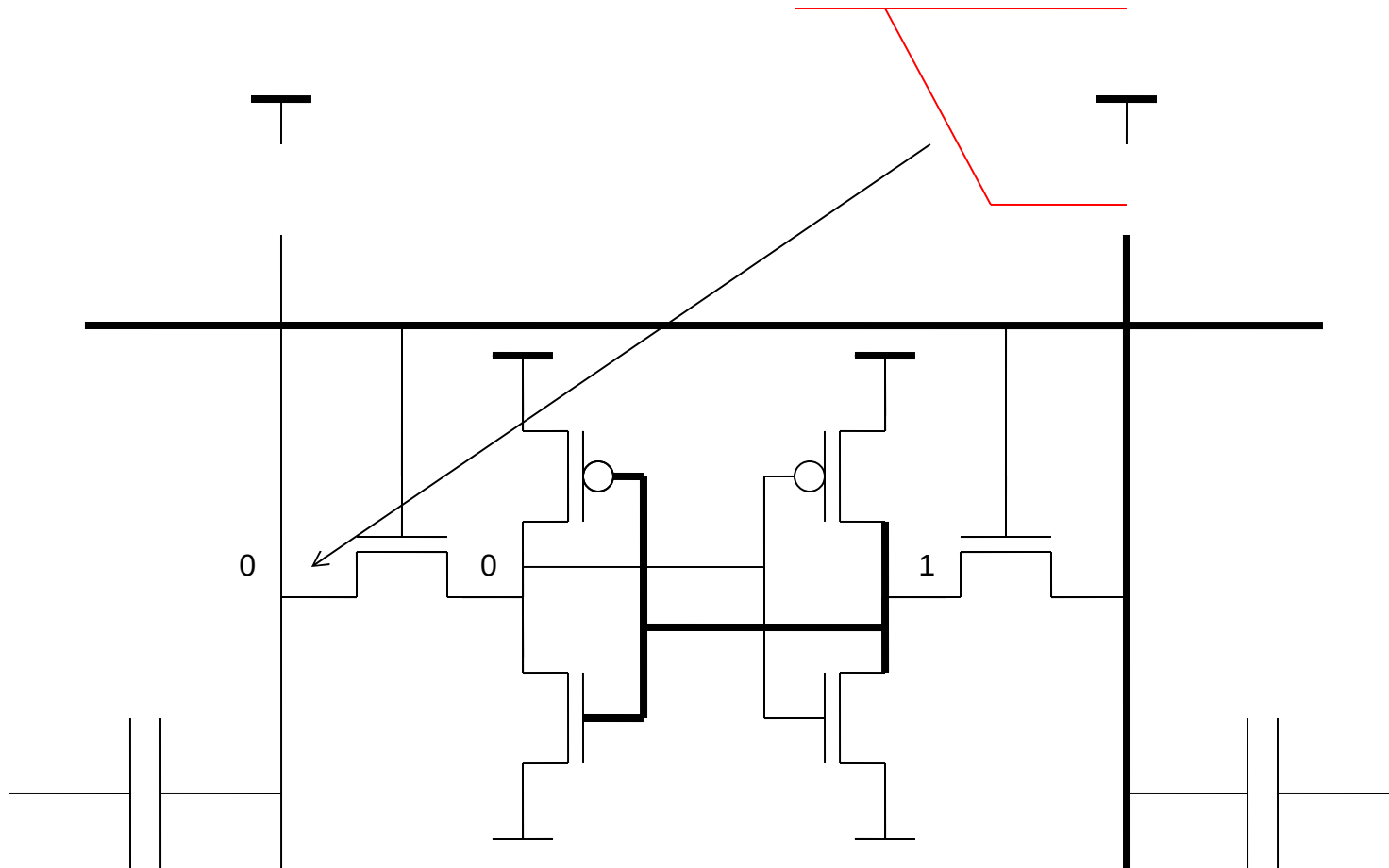
- C2 ist „richtig“ aufgeladen und verursacht kein Problem beim Lesen
- C1 muss entladen werden
- Das gelingt weil Tn1 stärker leitet (R kleiner) als T1 -> QN bleibt 0



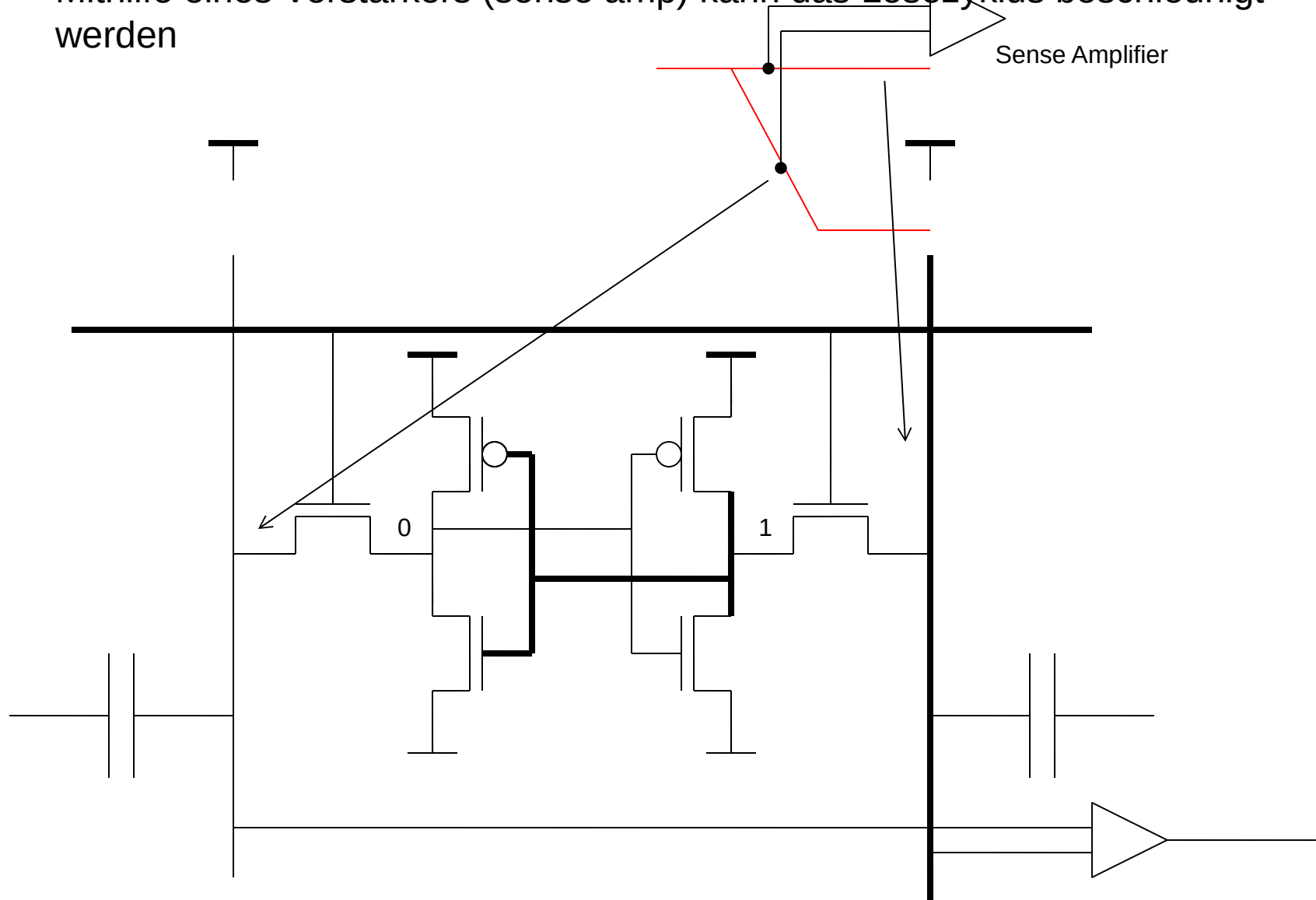
- C1 wird entladen, RAM Zelle kippt nicht um und wird richtig geschrieben



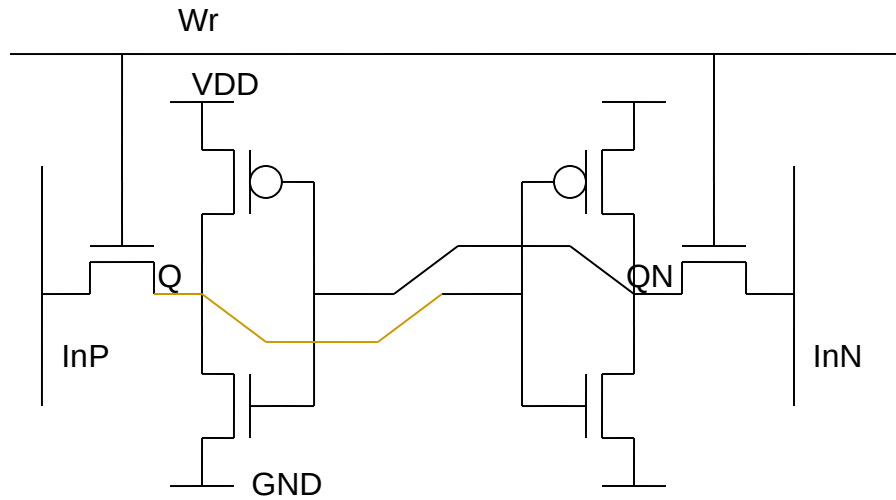
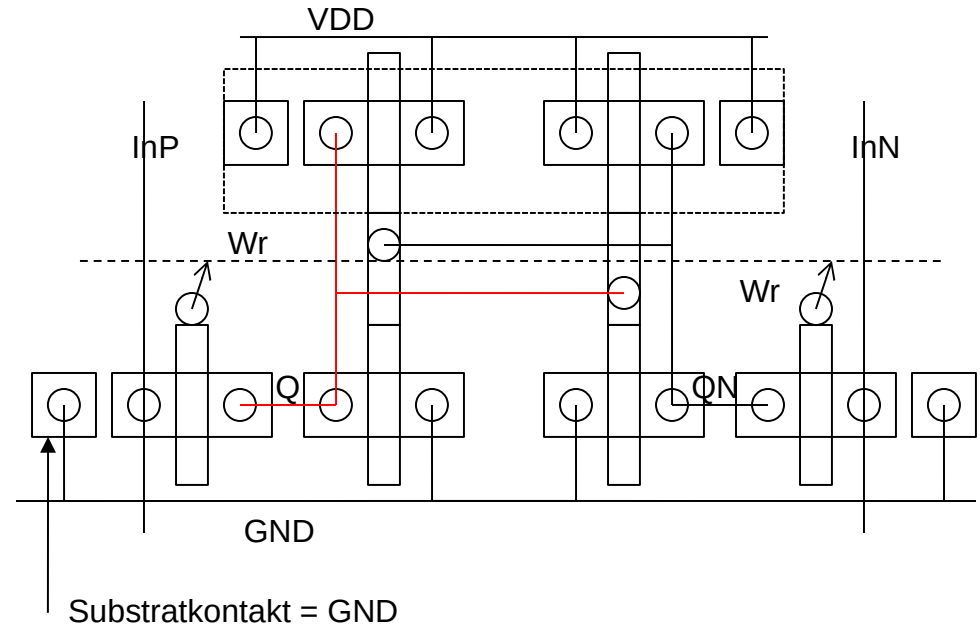
- C1 wird entladen, RAM Zelle kippt nicht um und wird richtig geschrieben



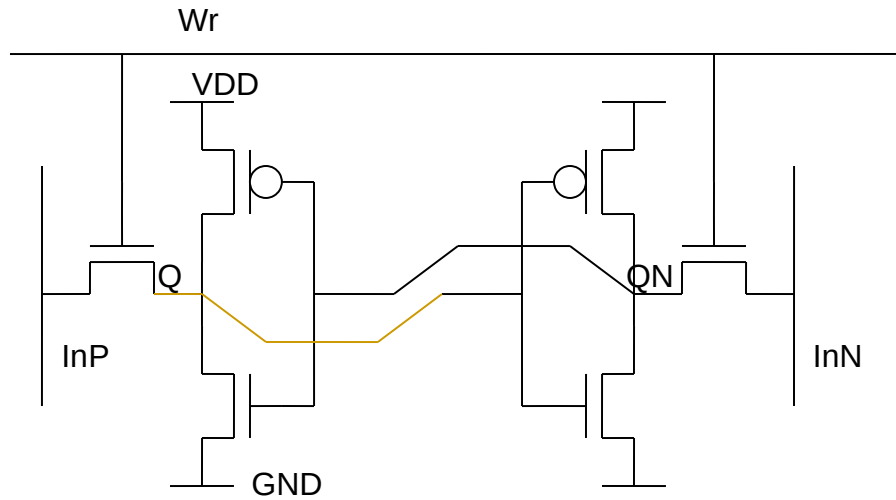
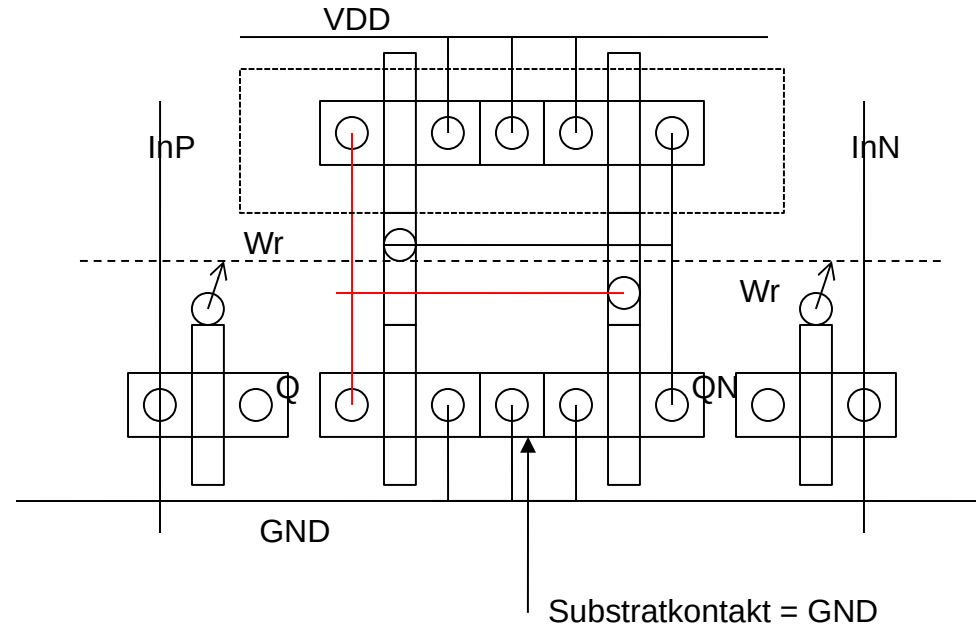
- Mithilfe eines Verstärkers (sense amp) kann das Lesezyklus beschleunigt werden



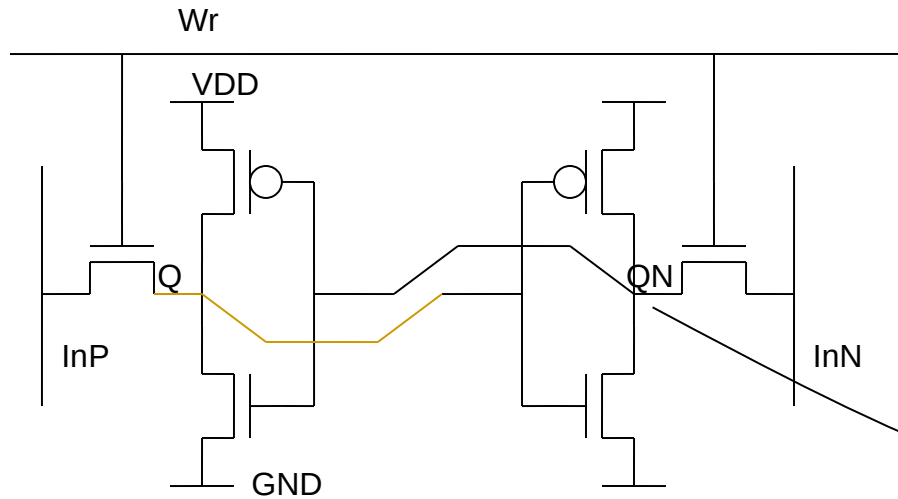
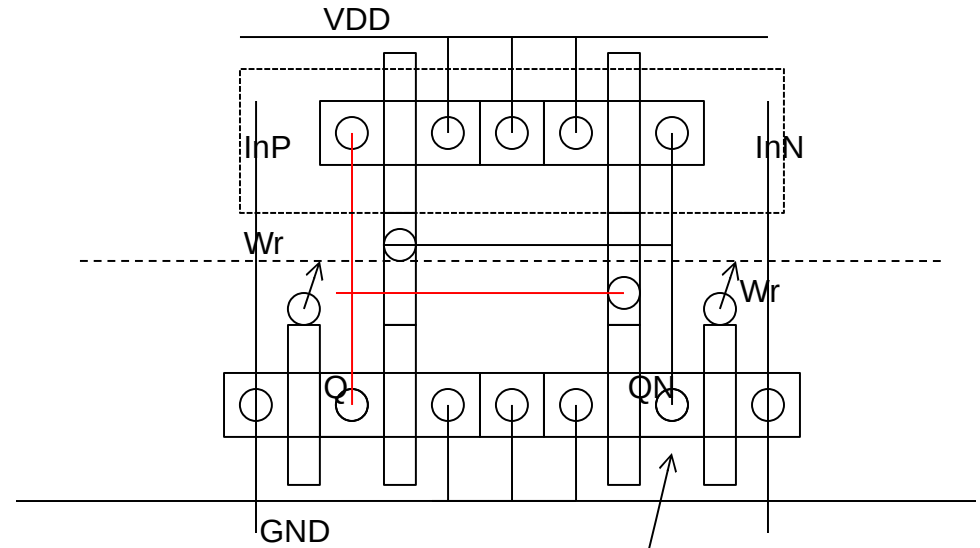
• ...



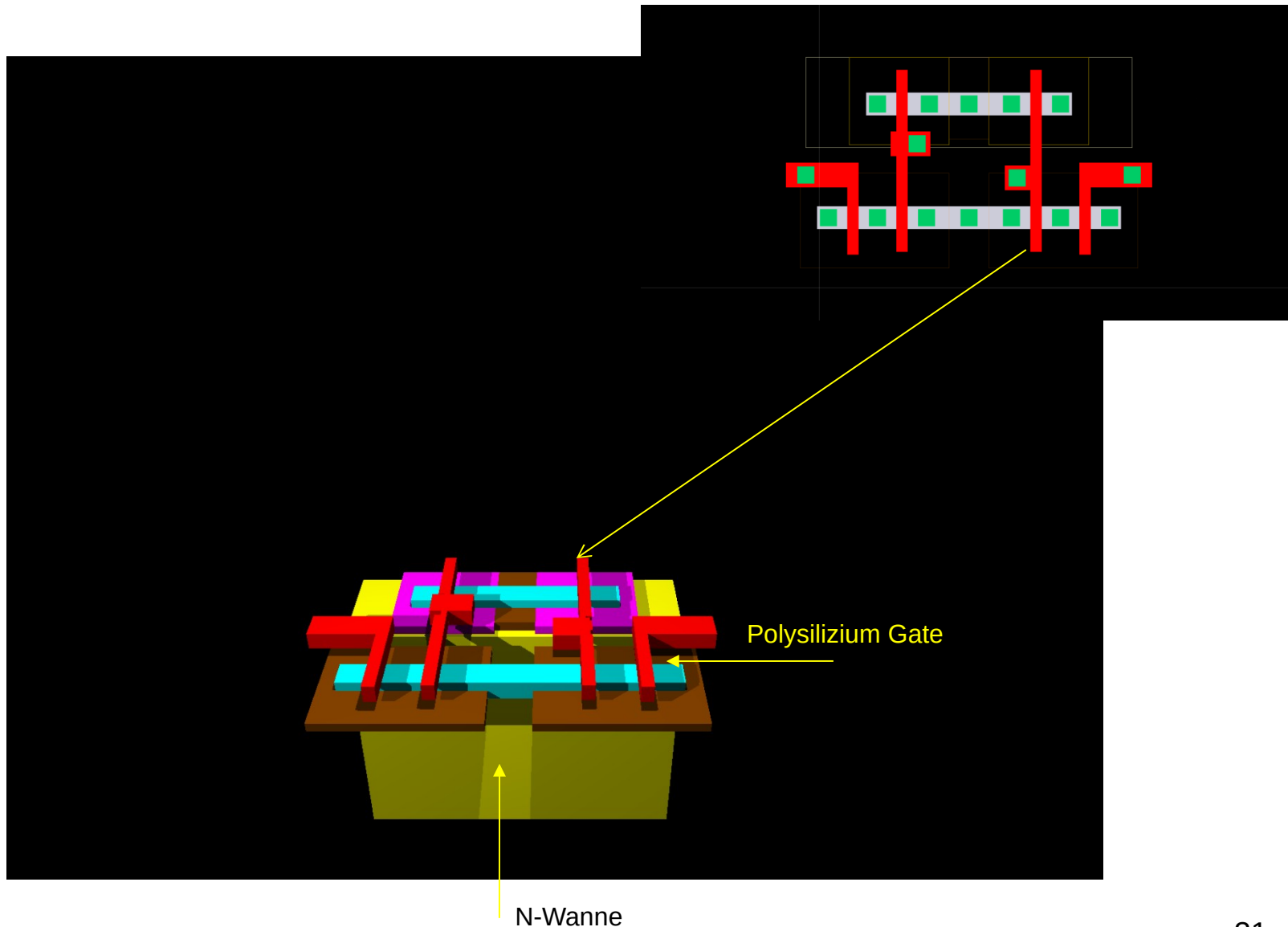
• ...



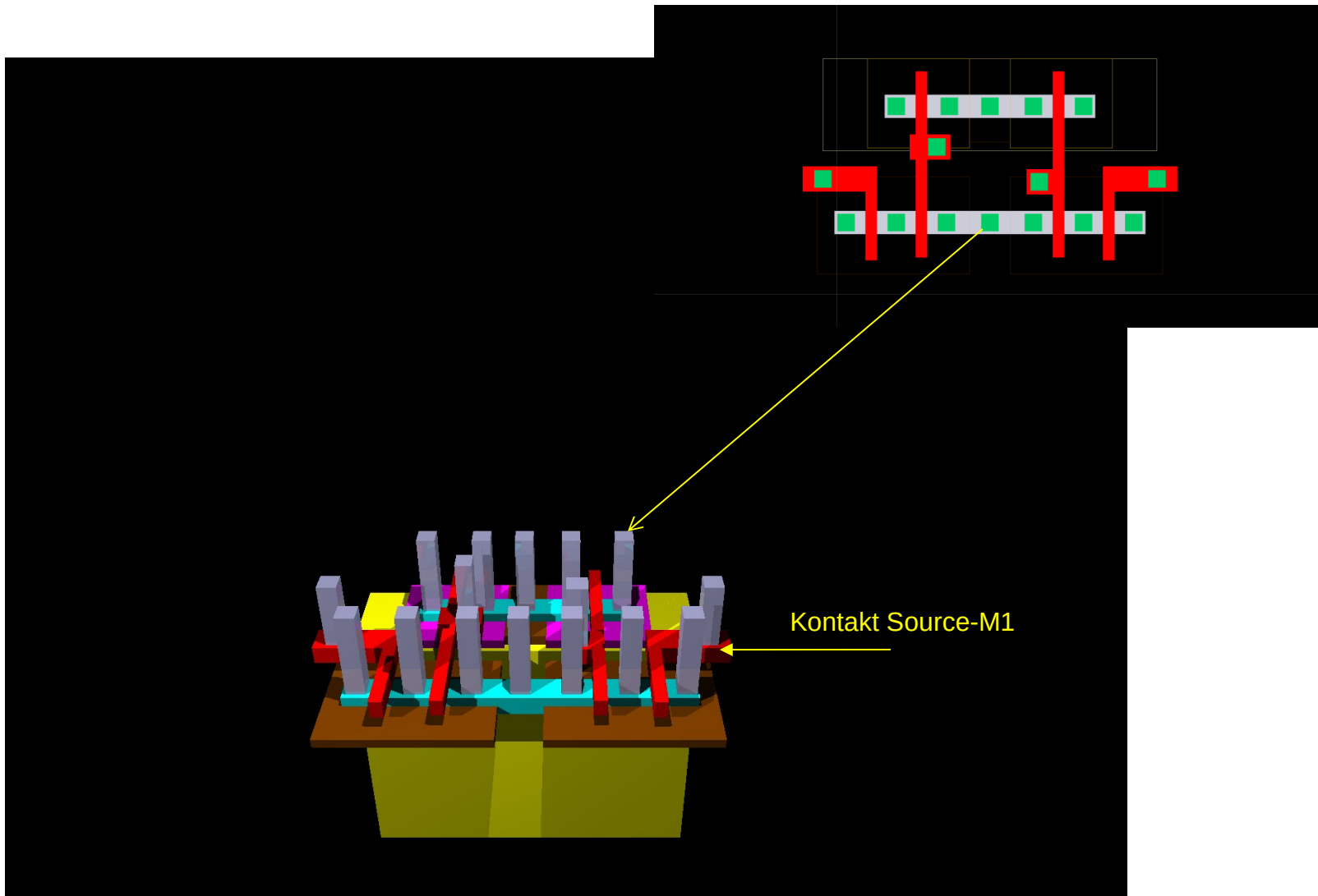
• ...



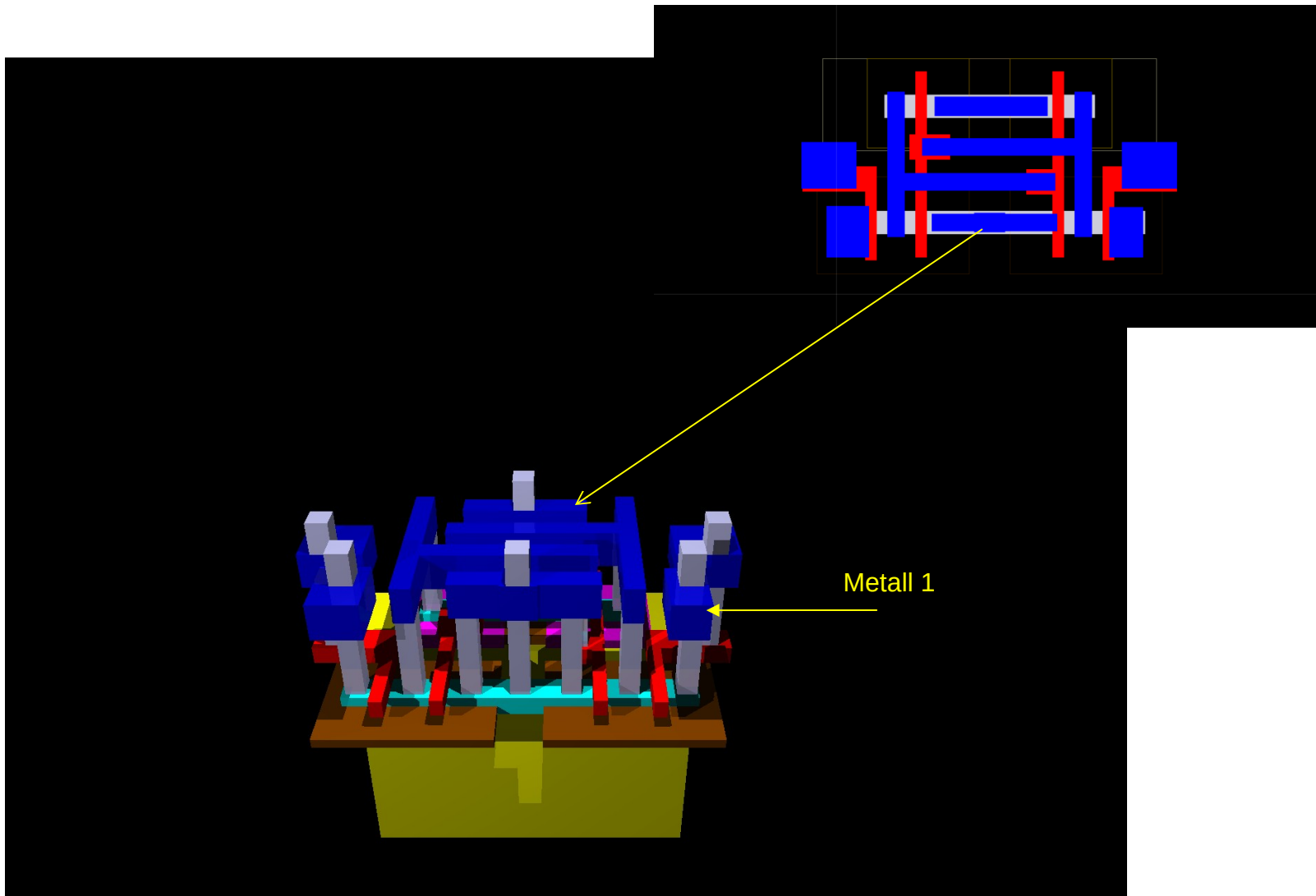
- ...



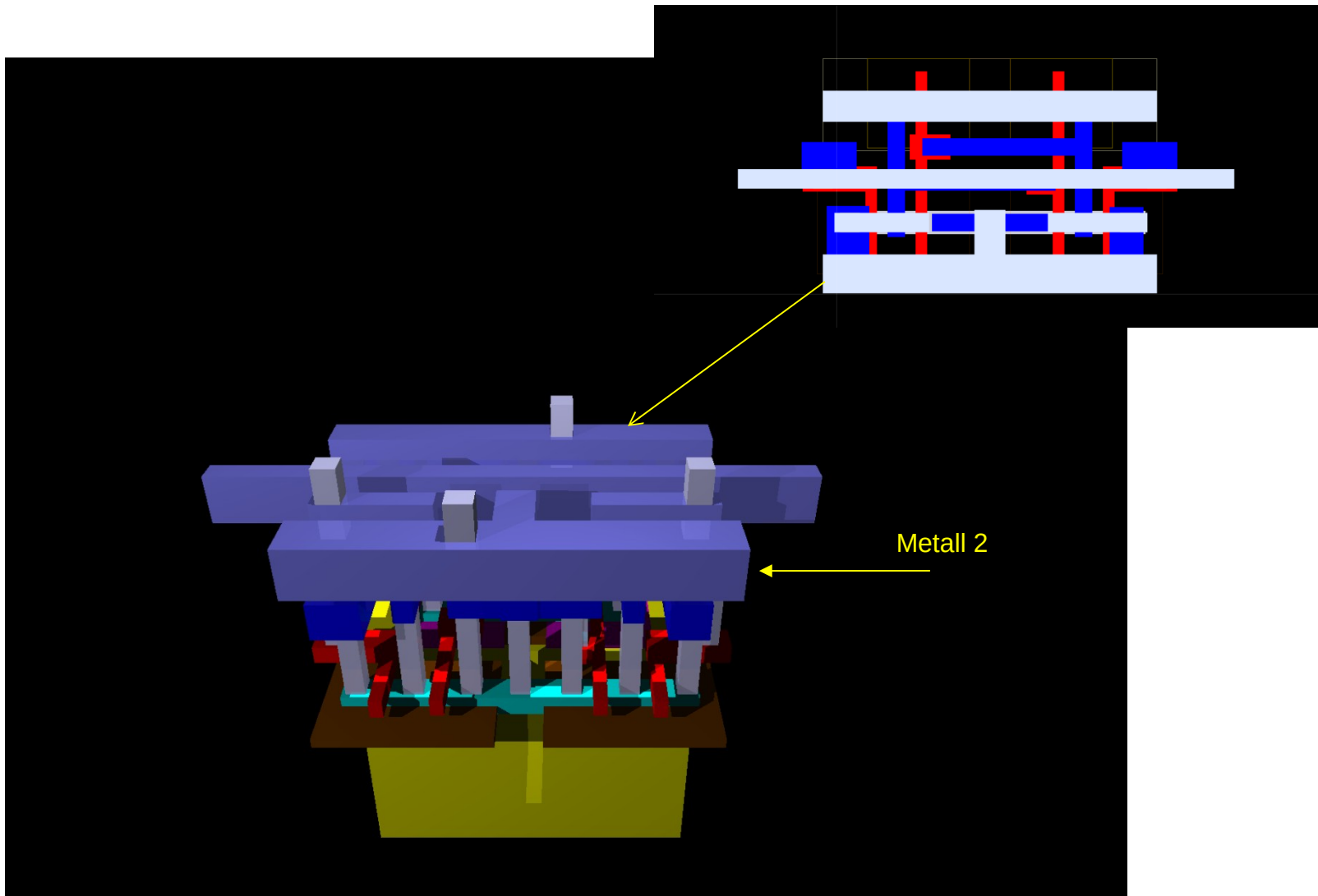
- ...



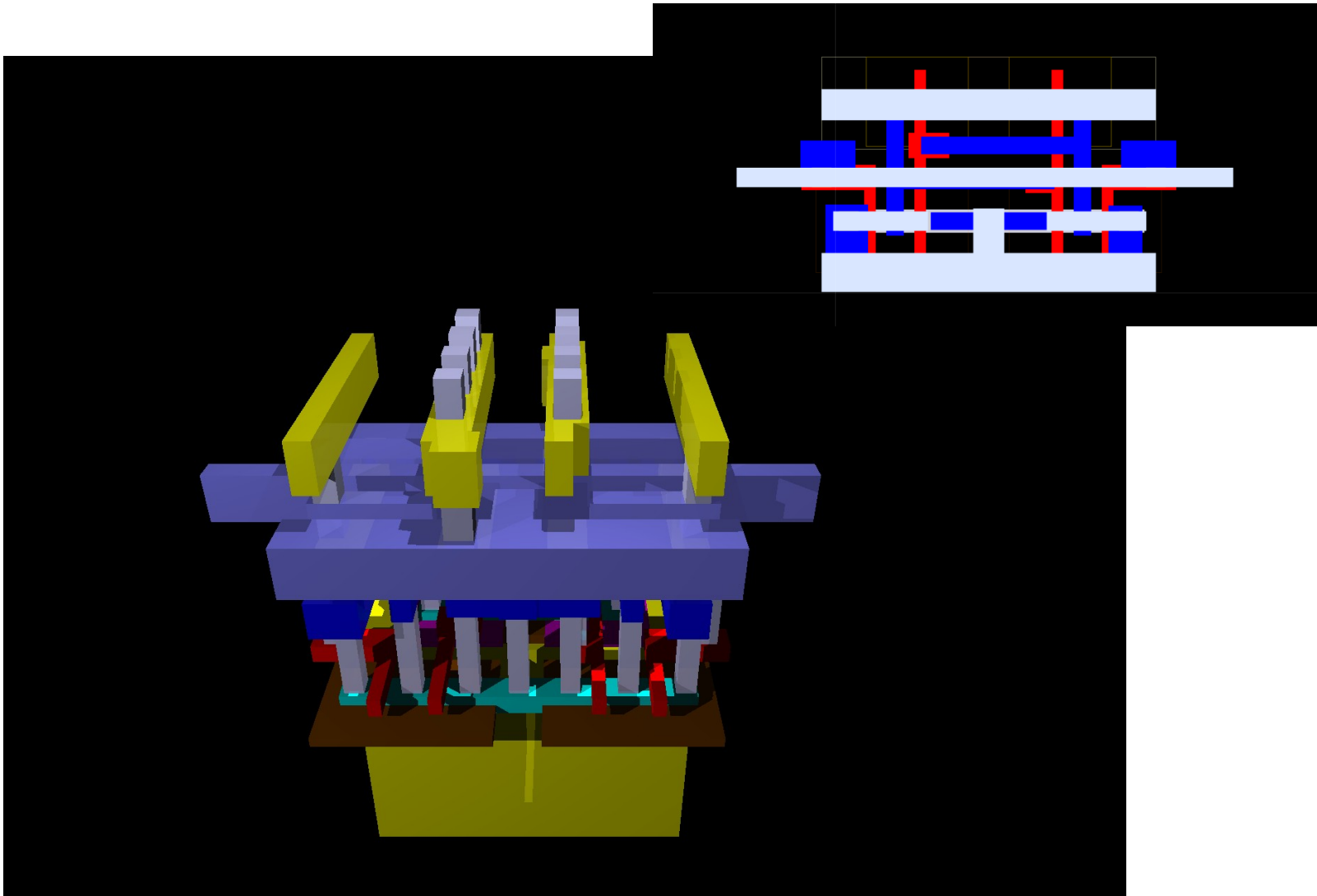
- ...



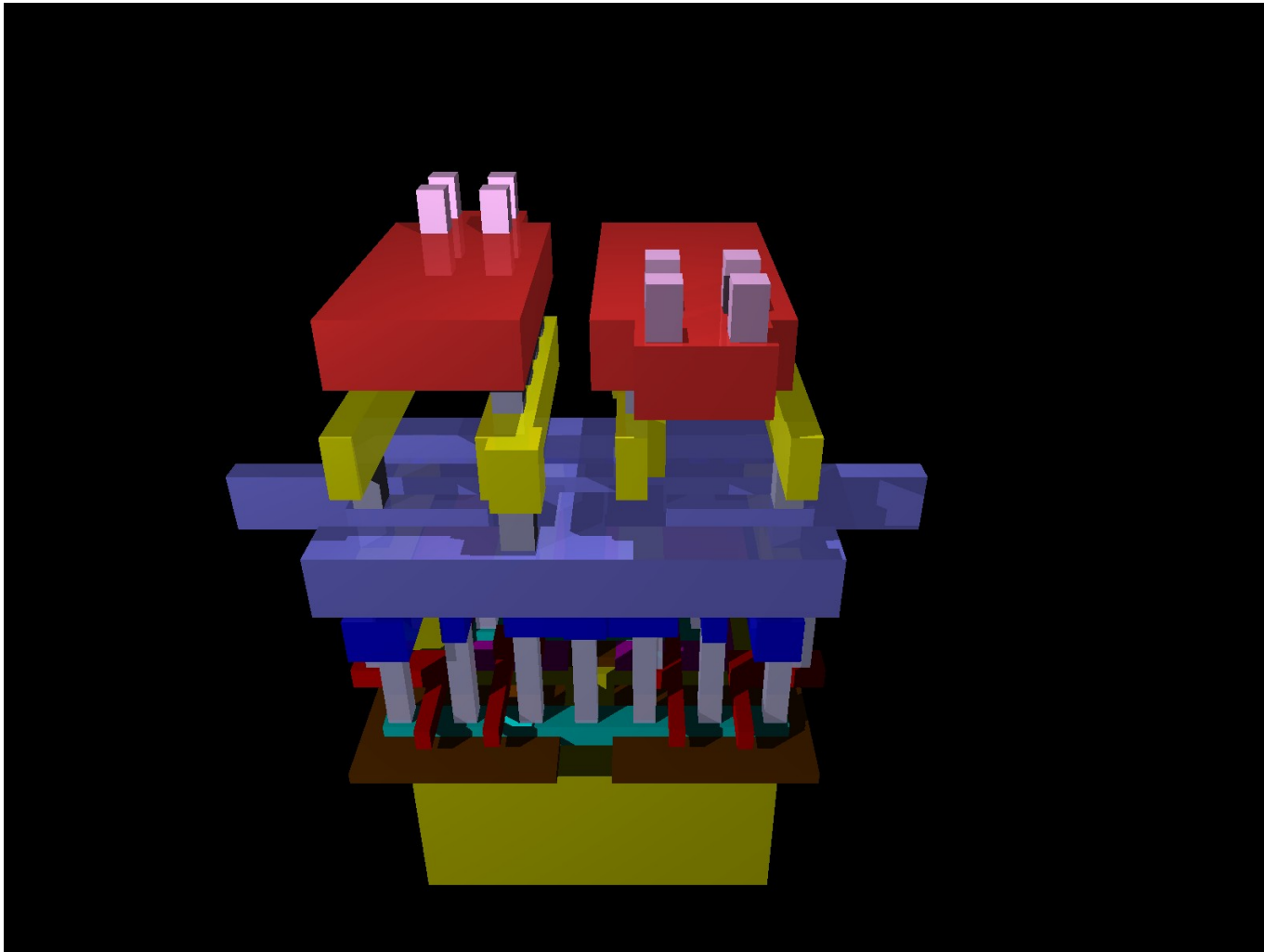
- ...



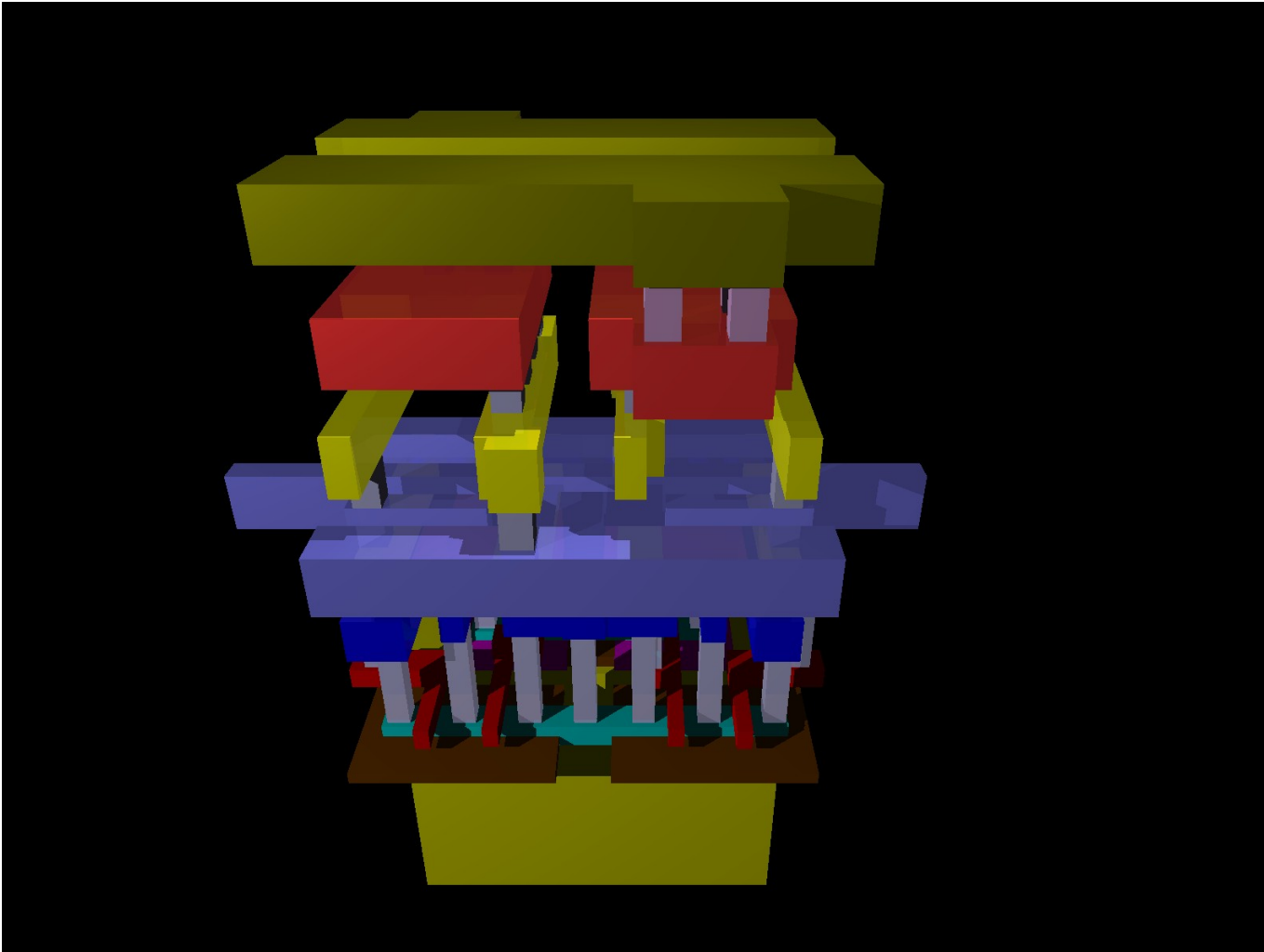
- ...



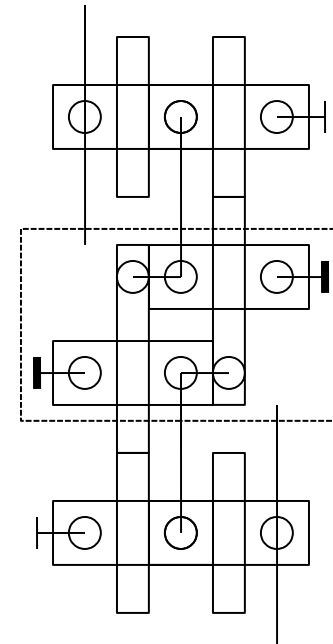
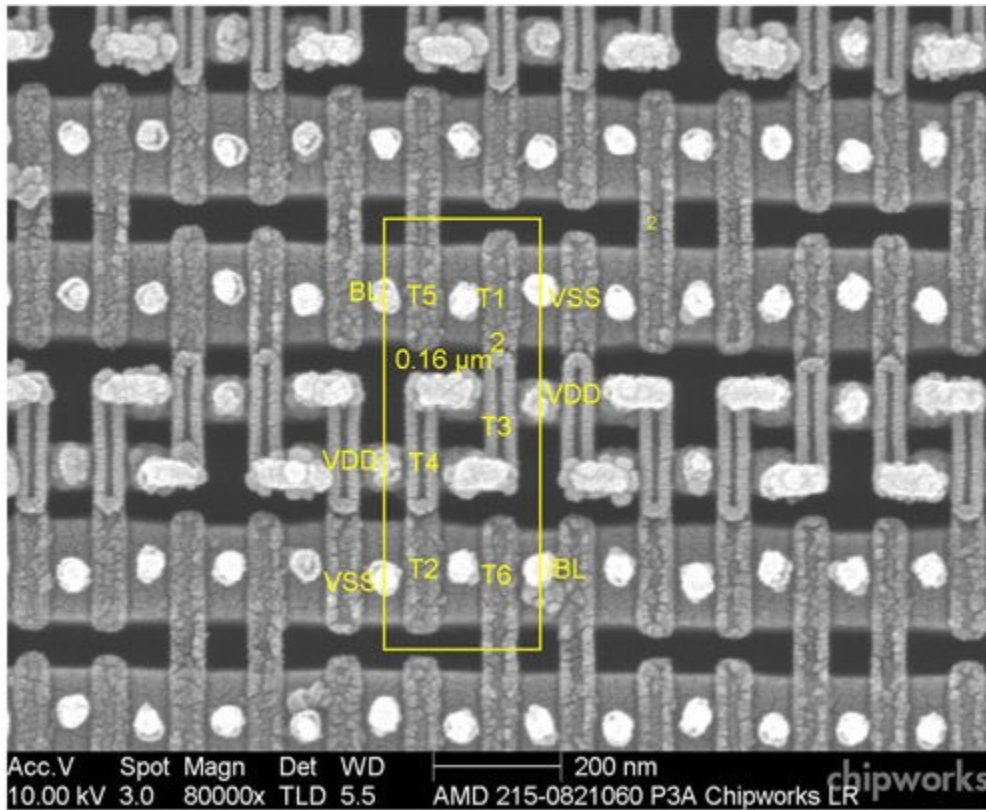
- ...



- ...

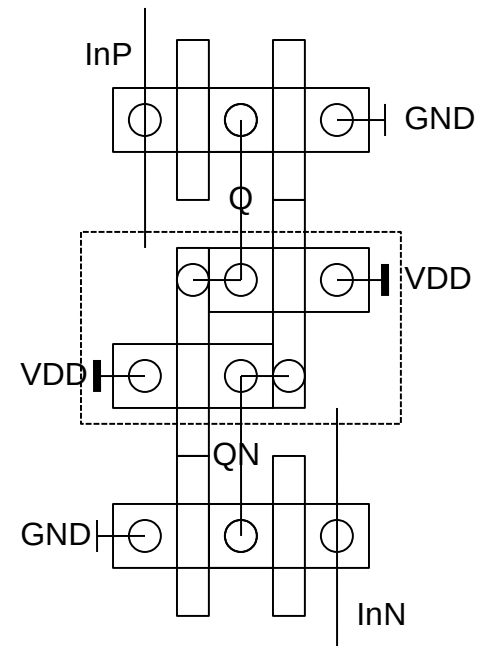
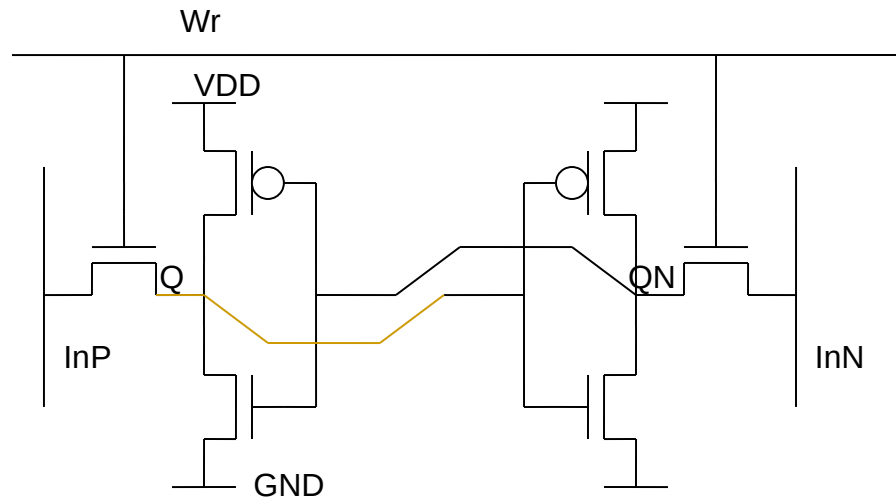


- SRAM



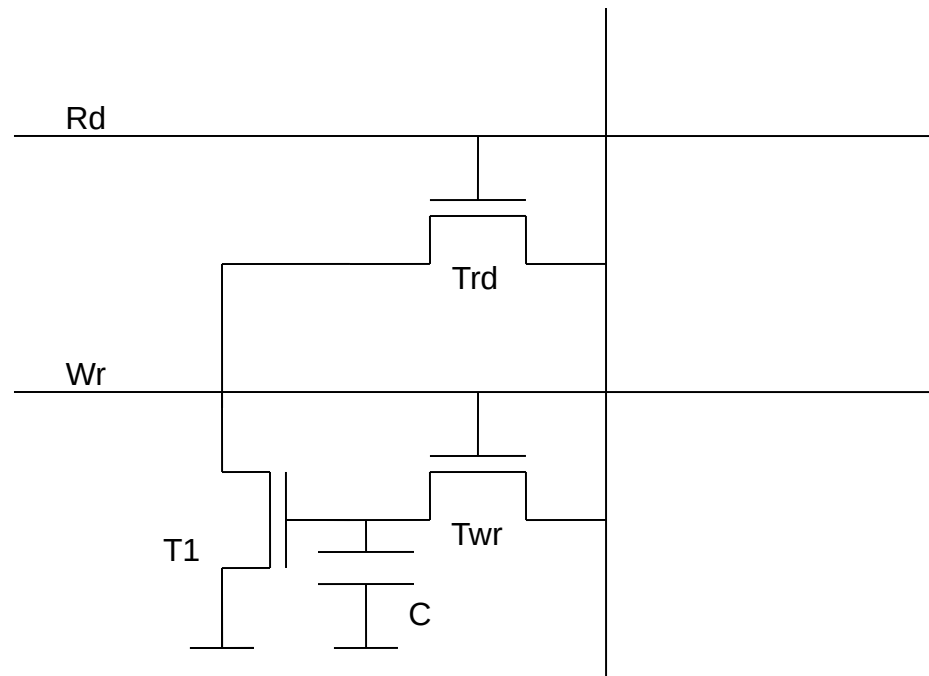
AMD 215-0821060 28 nm HP 6T-SRAM at Poly - Plan View SEM

- SRAM

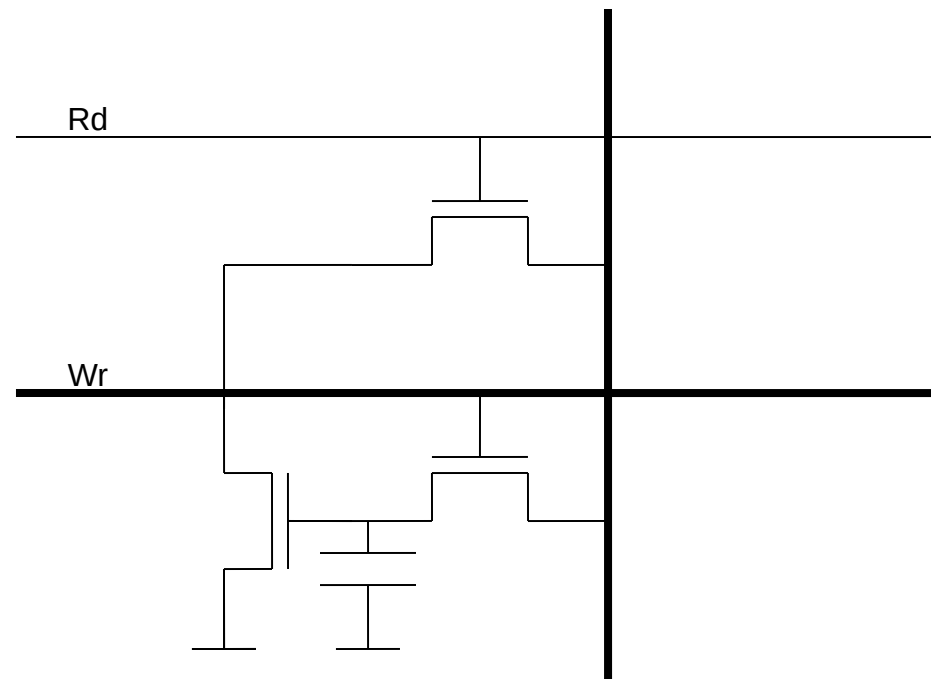


DRAM

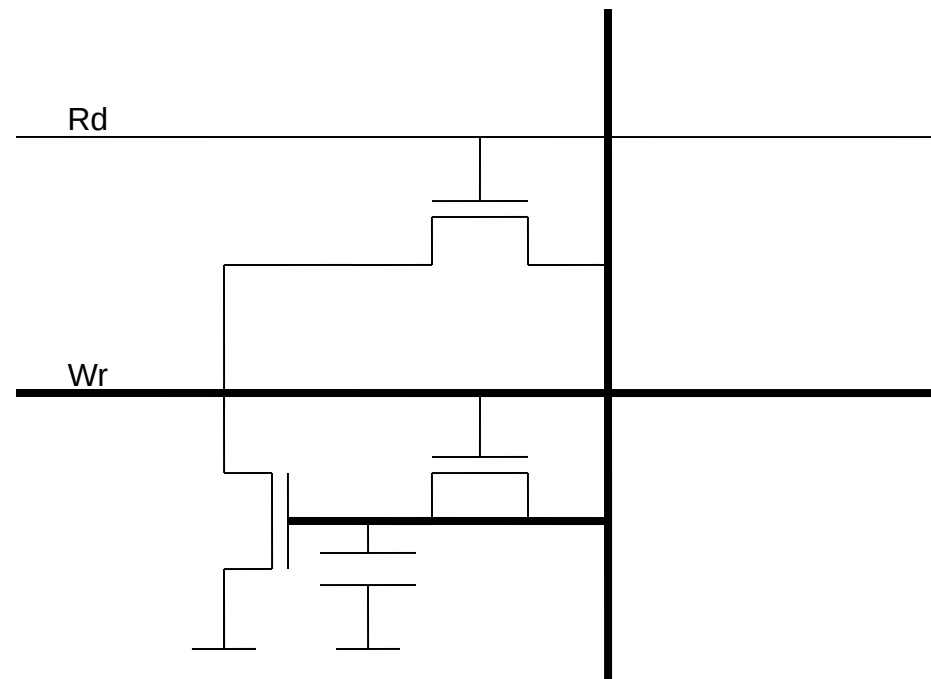
- DRAM basiert auf Kondensatoren (C) als Speicherelementen
- Realisierung 1
- Transistor T1 dient als Verstärker
- Getrennte Rd und Wr Schalter T_{wr} und T_{rd}



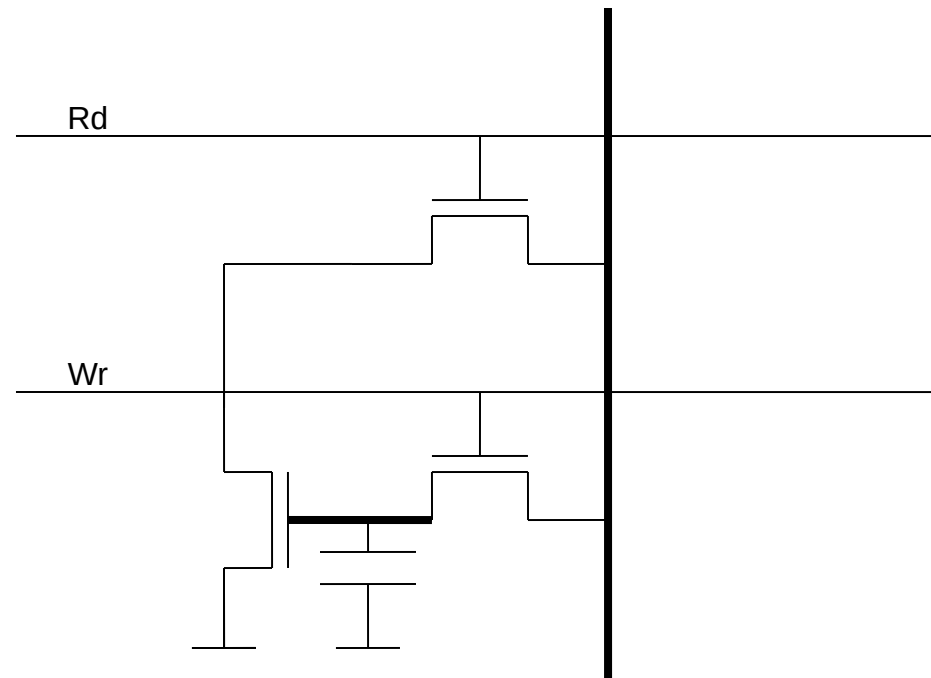
- DRAM



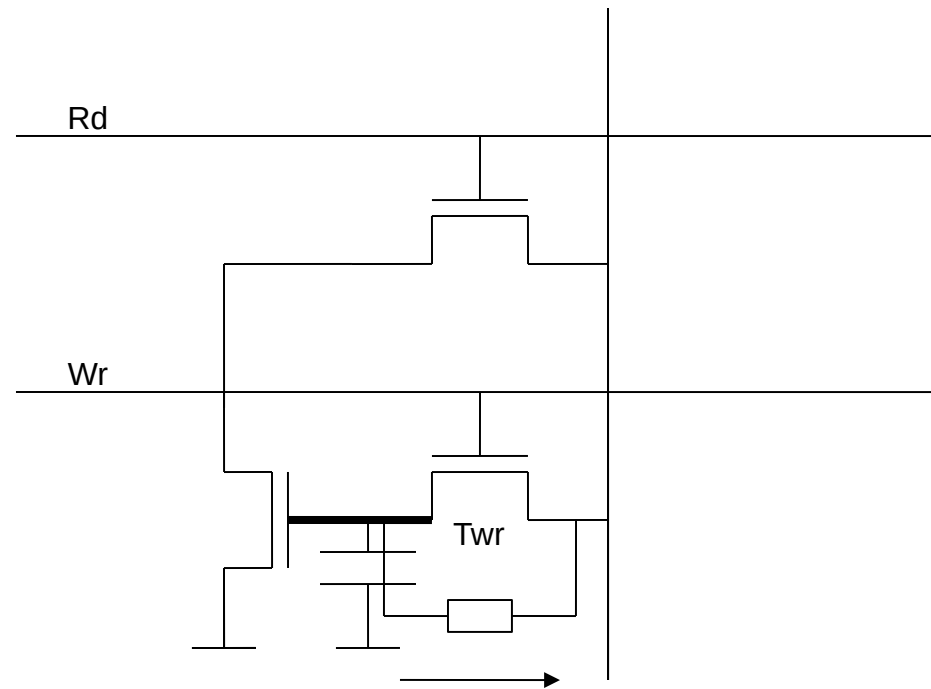
- DRAM



- DRAM

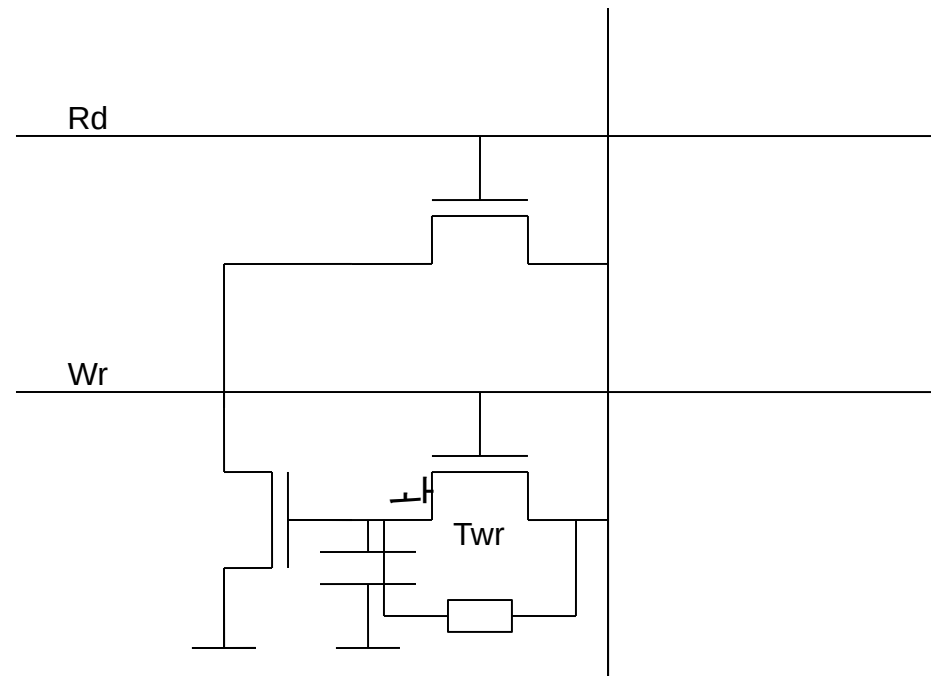


- DRAM



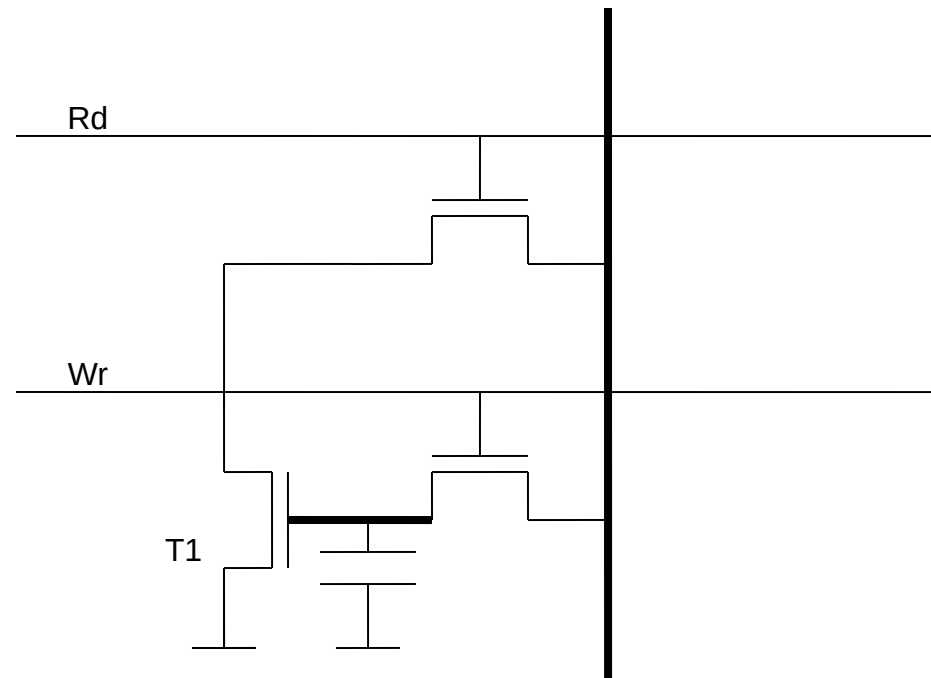
Leckstrom ist Problem, Ladung fließt ab

- DRAM

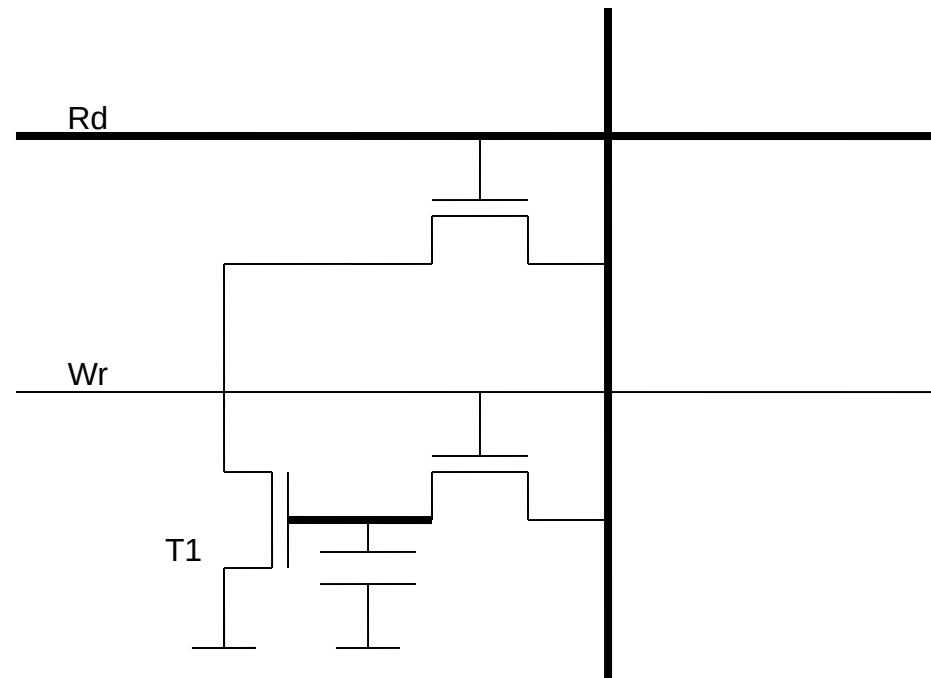


Leckstrom ist Problem, Ladung fließt ab

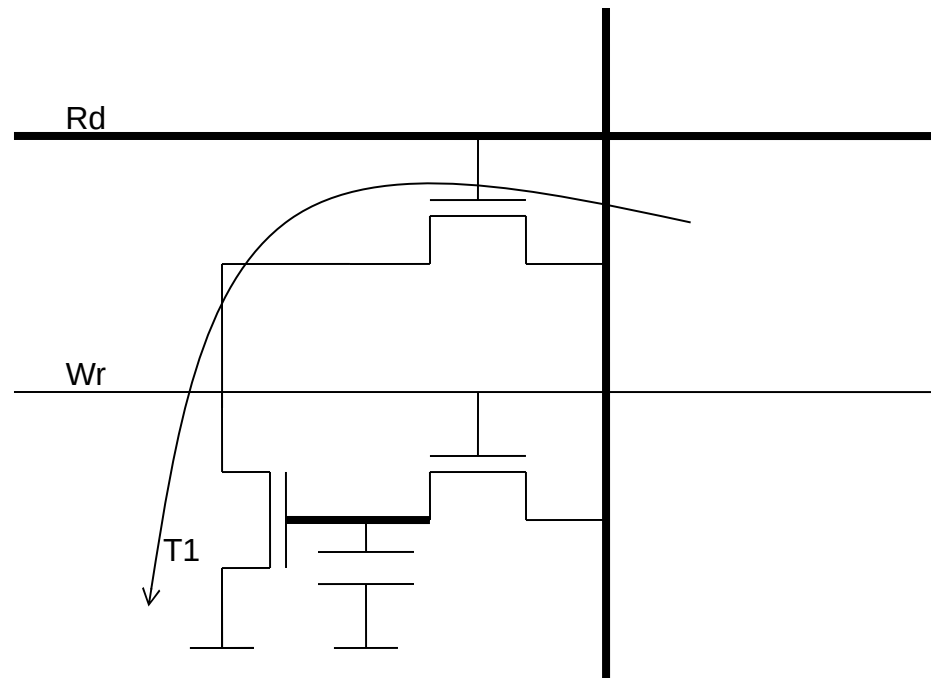
- DRAM



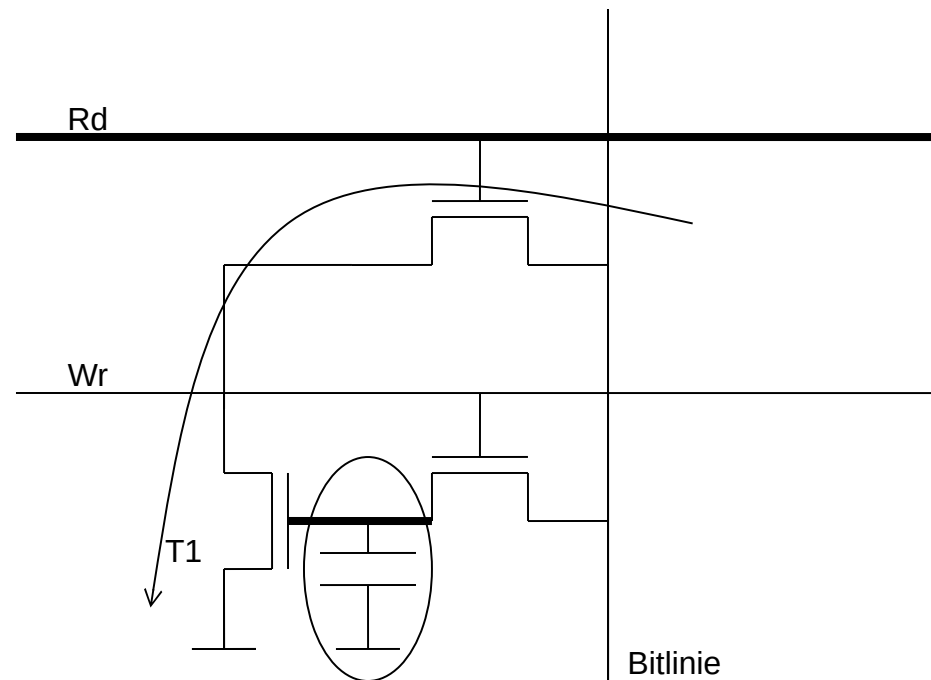
- DRAM



- DRAM

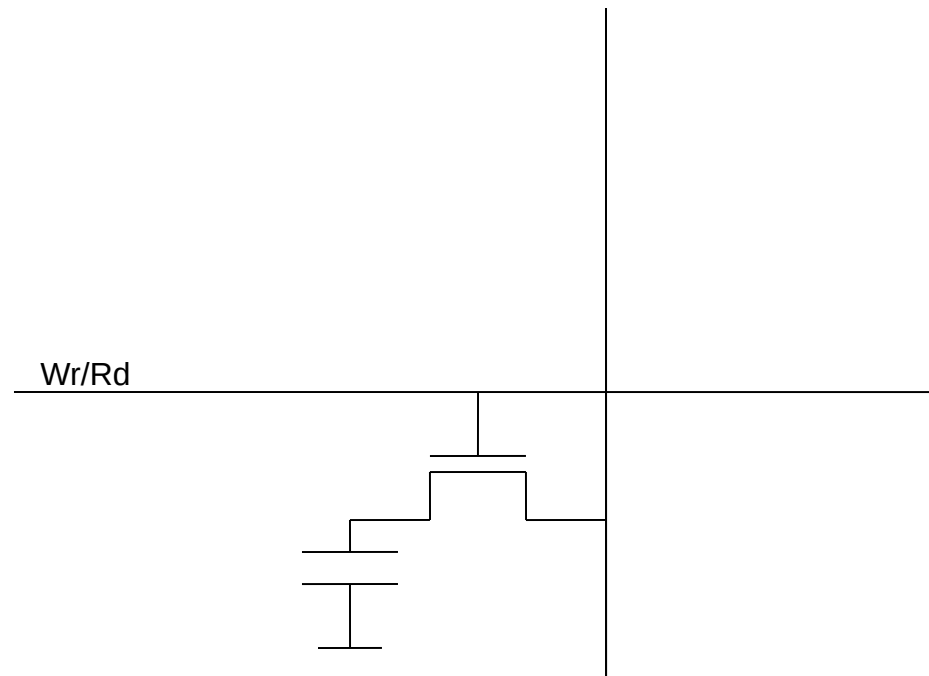


- DRAM

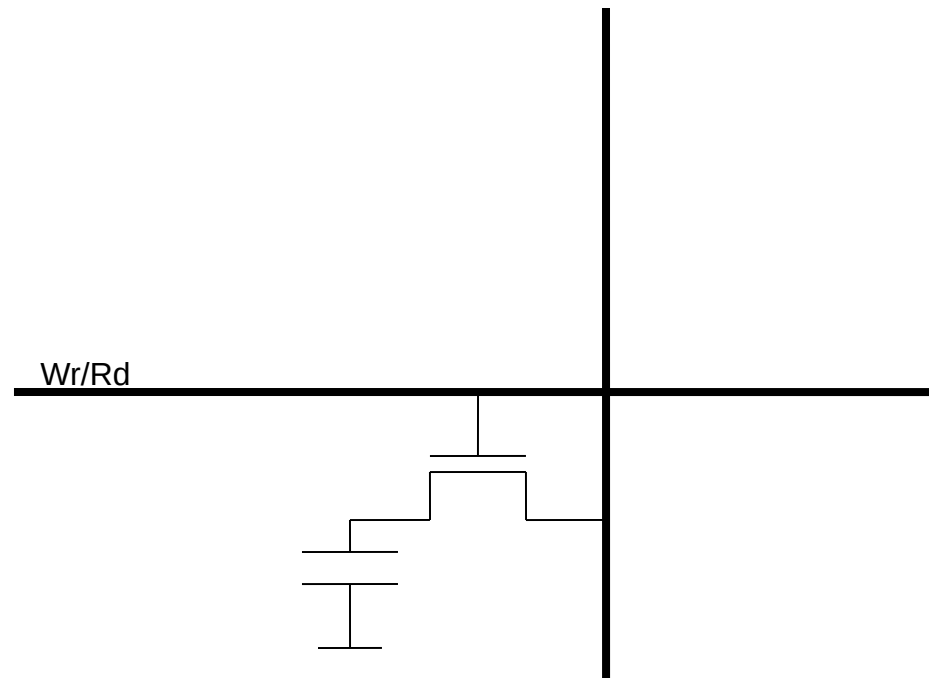


Ladung bleibt erhalten

- Realisierung 2
- 1-transistor DRAM

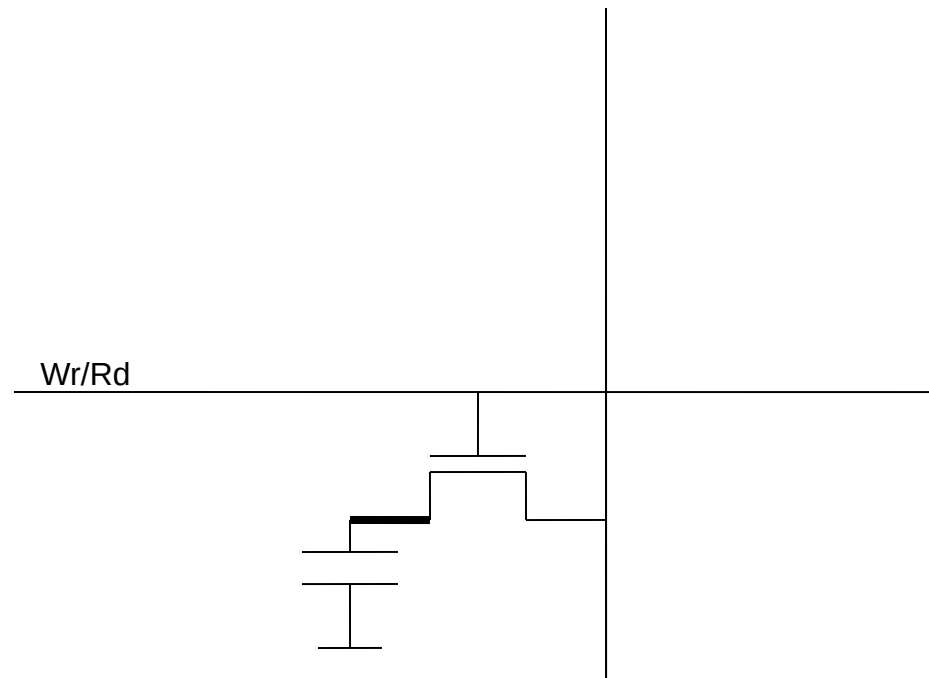


- Write ist einfach

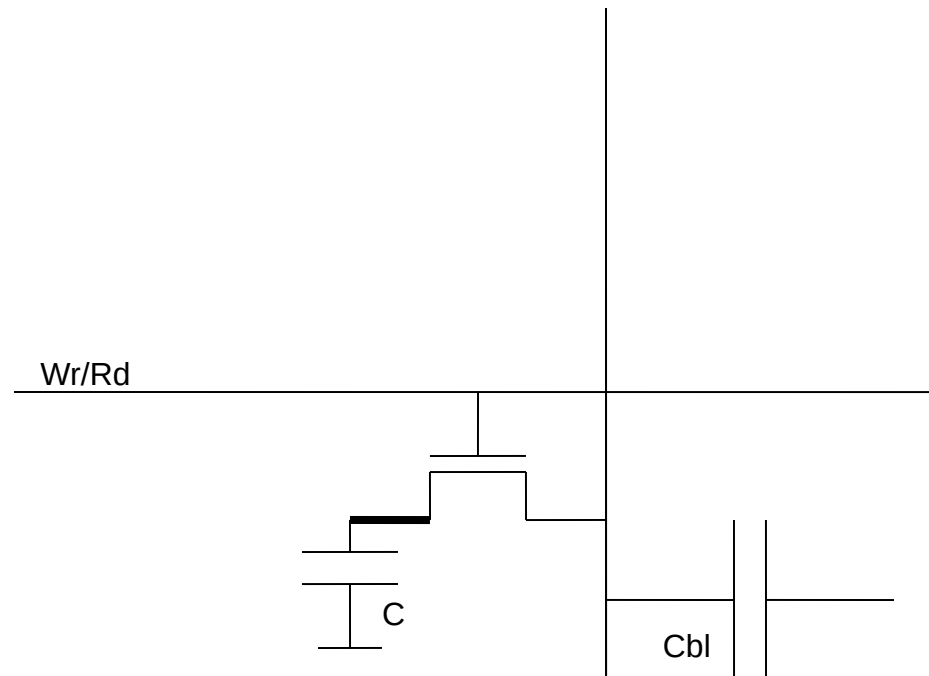


-

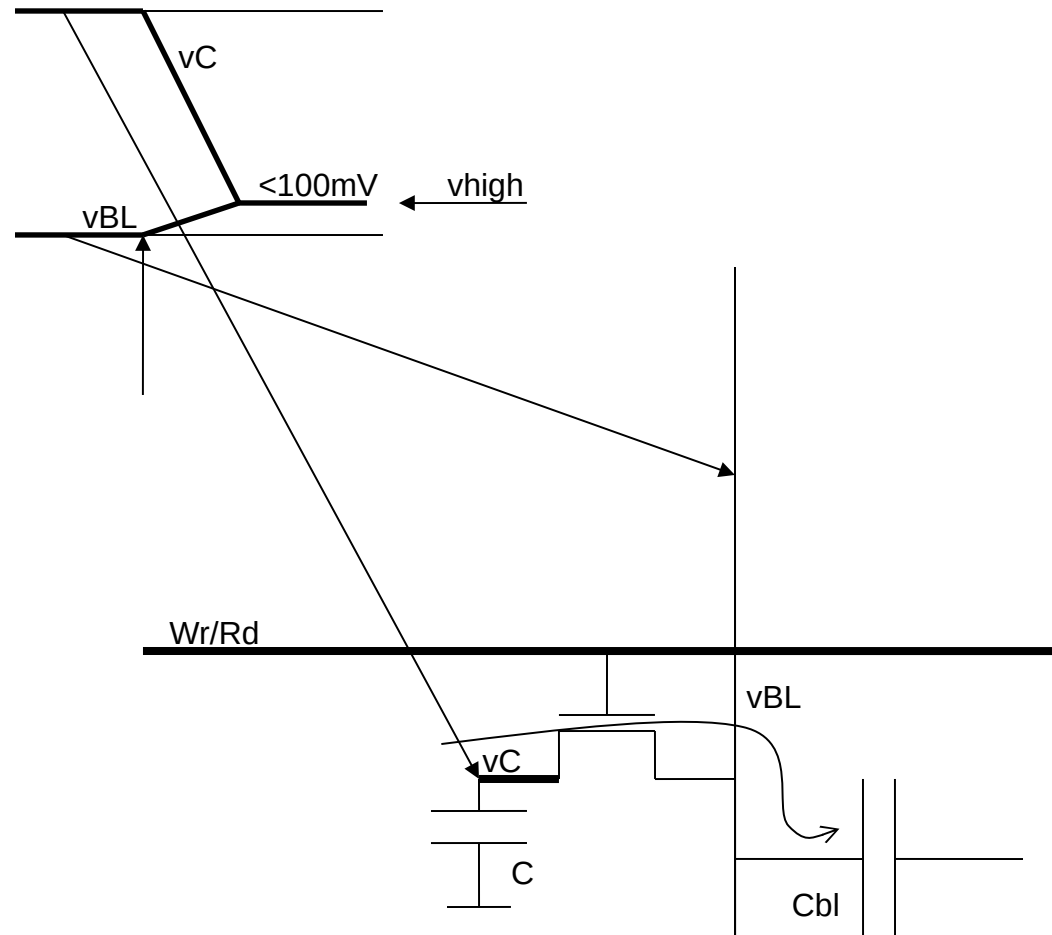
- Write ist einfach



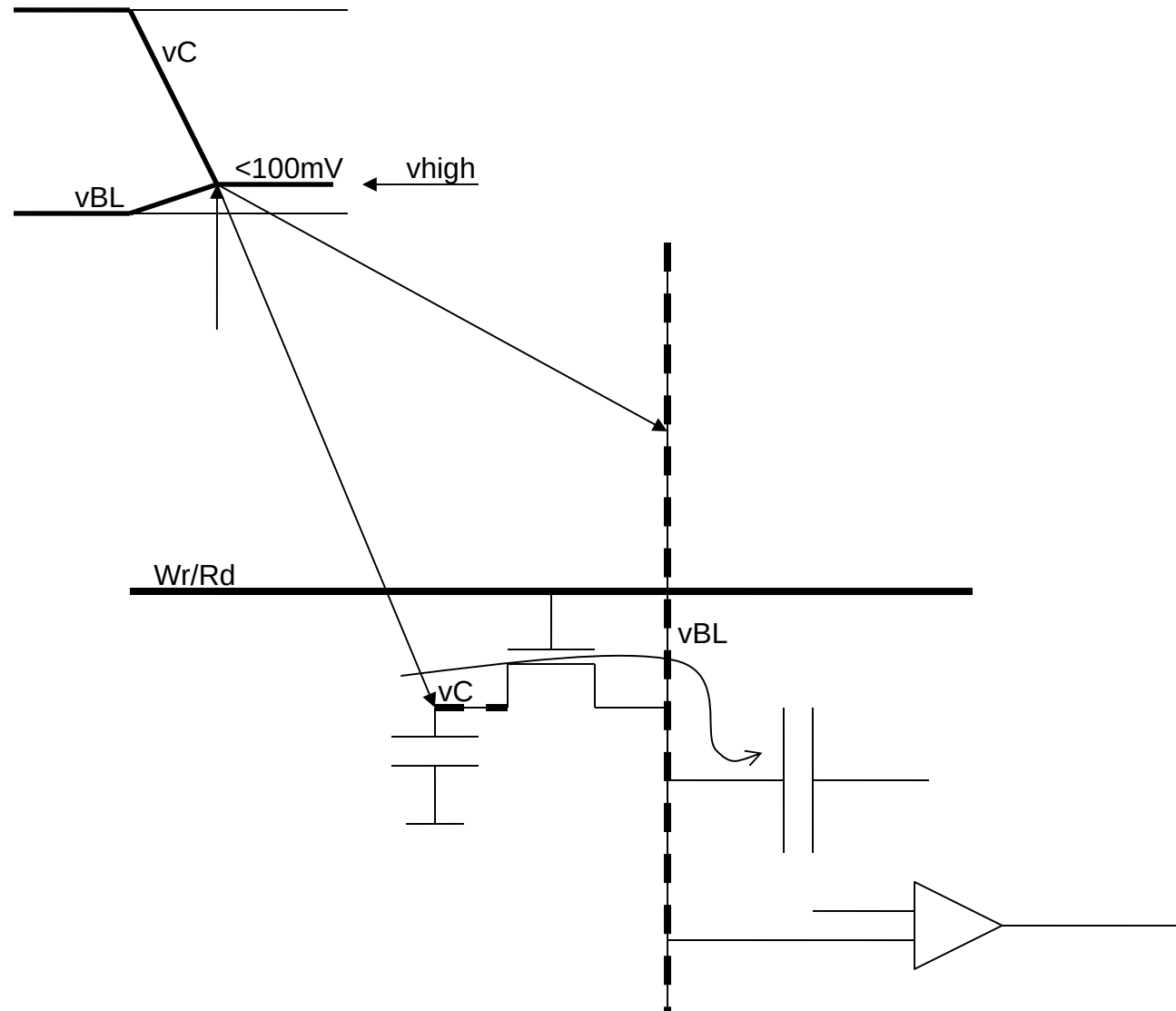
- Lesezyklus
- Bit-line Kapazitäten C_{bl} führen zum Entladen von RAM Kapazitäten C



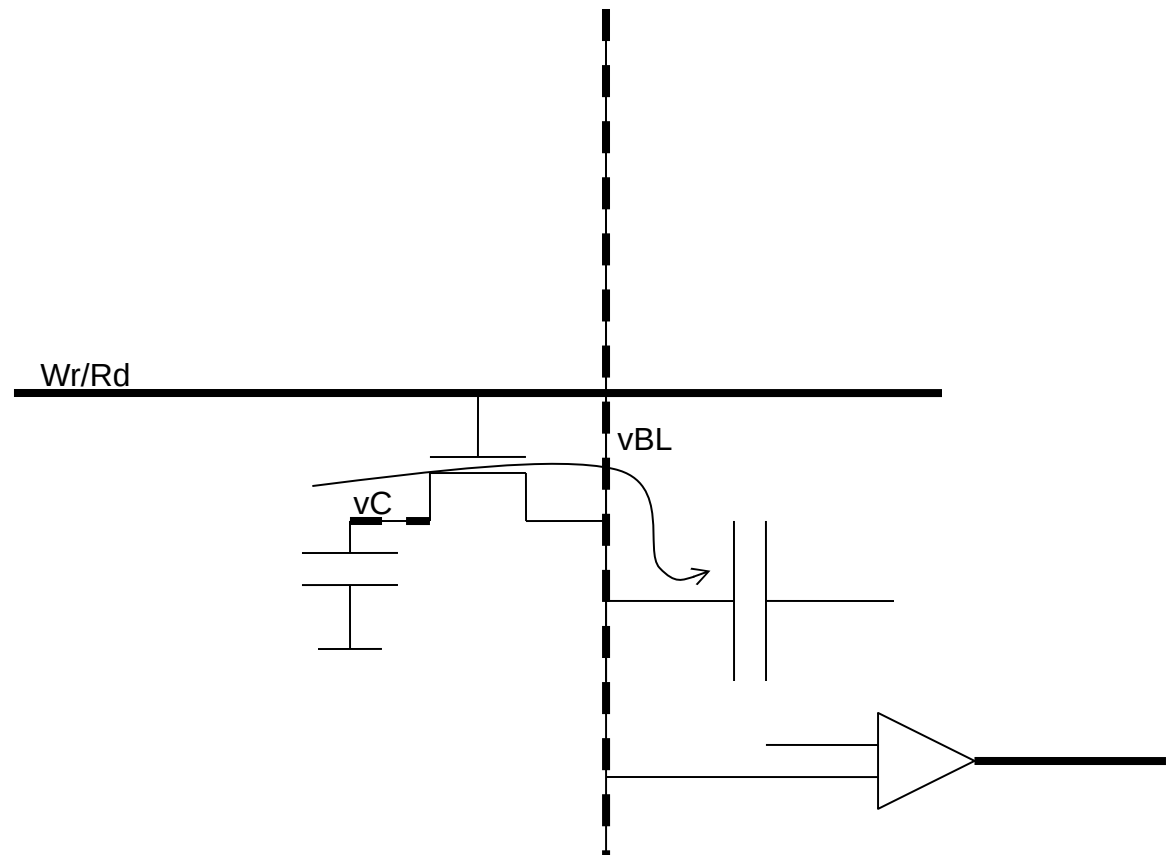
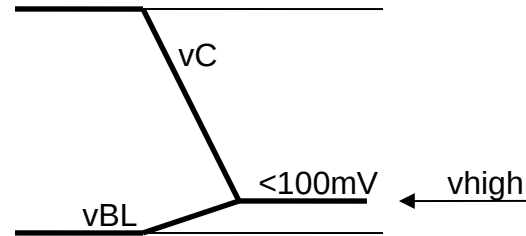
- Bit-line Kapazitäten C_{bl} führen zum Entladen von RAM Kapazitäten C



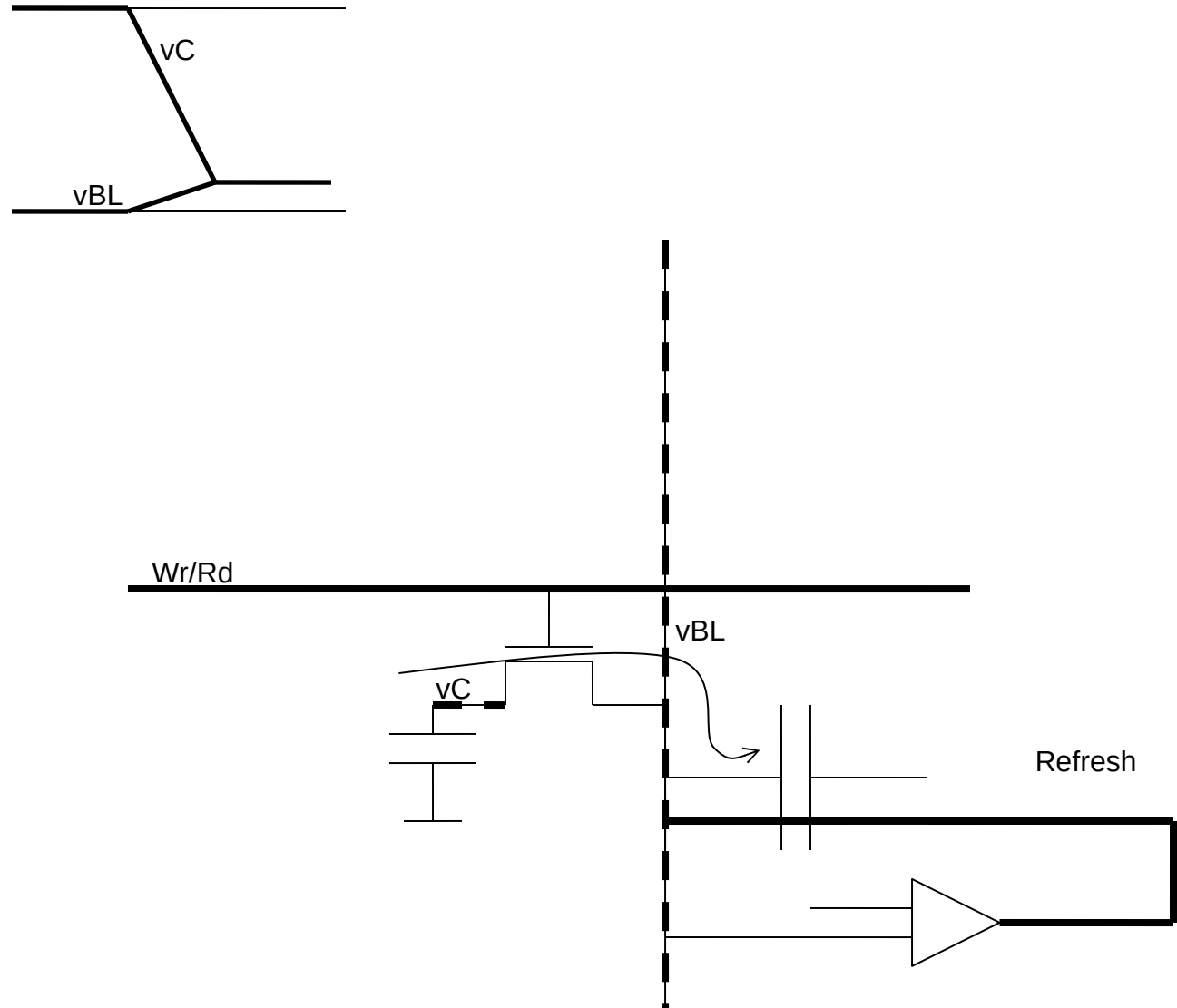
- Bit-line Kapazitäten C_{bl} führen zum Entladen von RAM Kapazitäten C



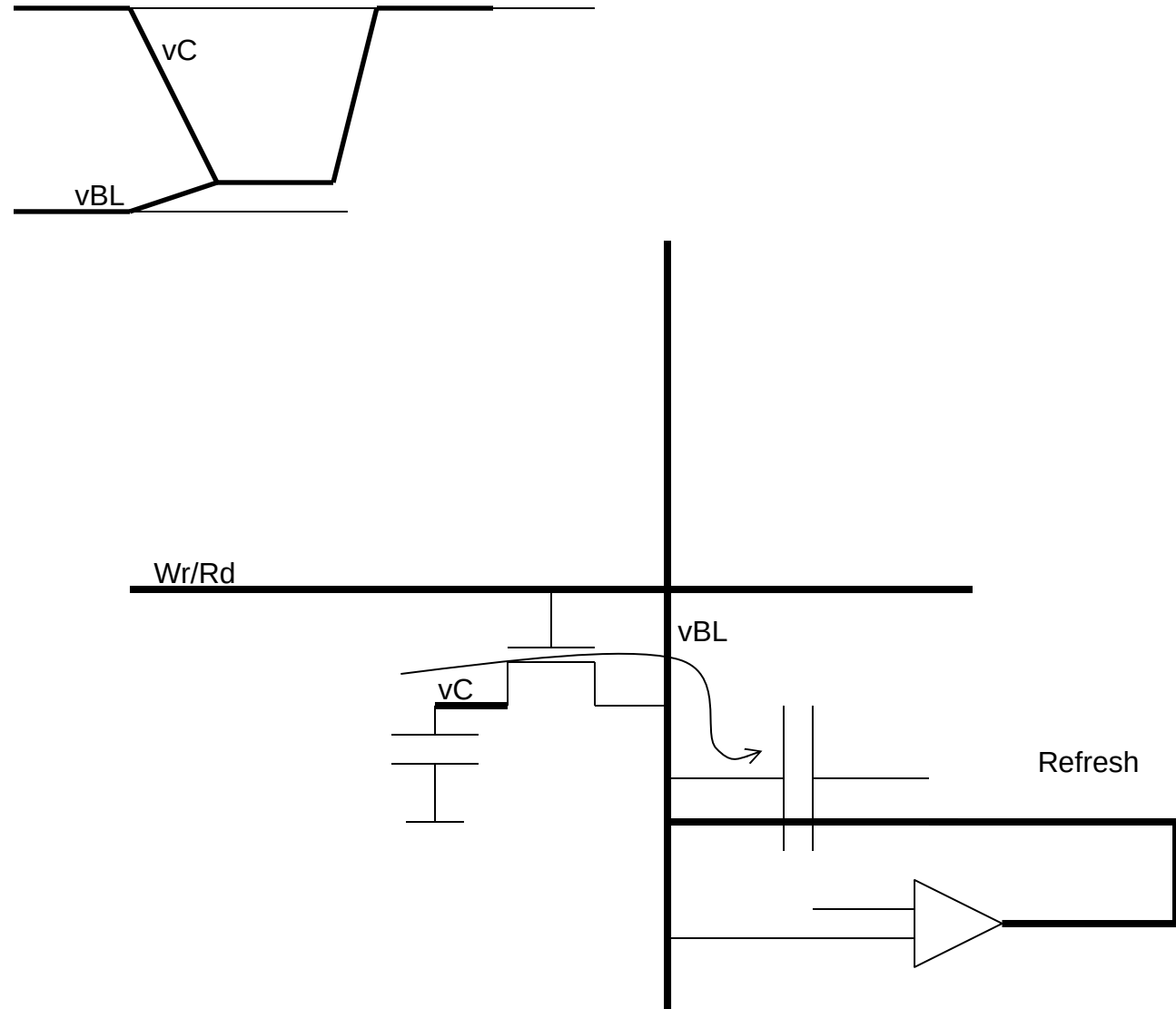
- Ein Verstärker oder analoger Komparator wird benutzt um V_{high} als logische 1 zu erkennen



- Refresh



- Refresh



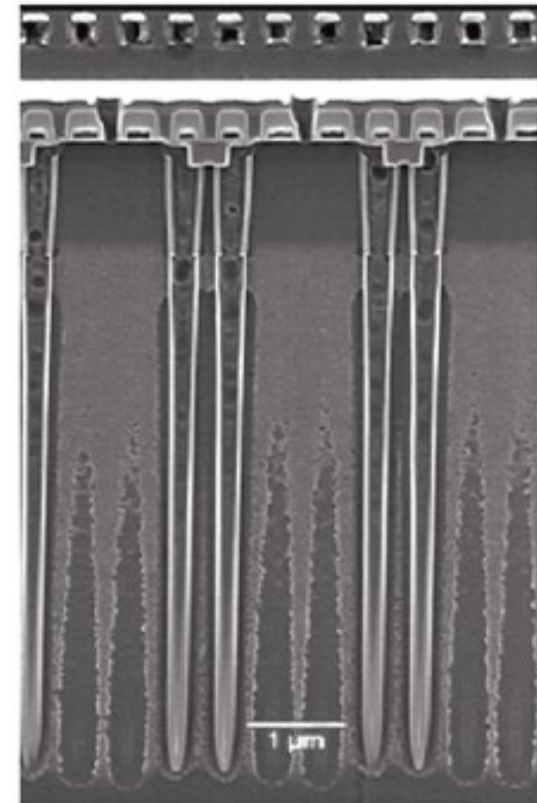
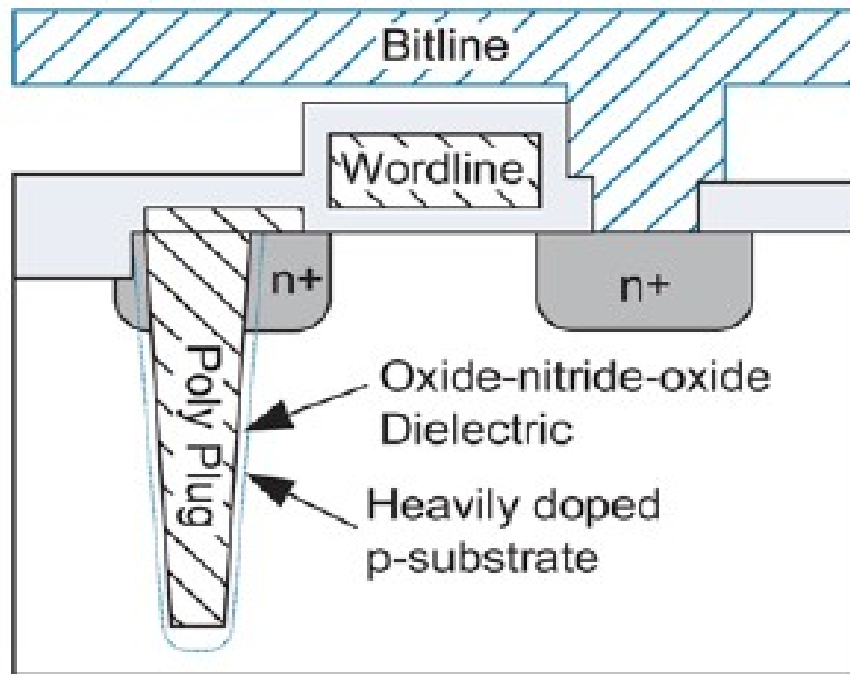
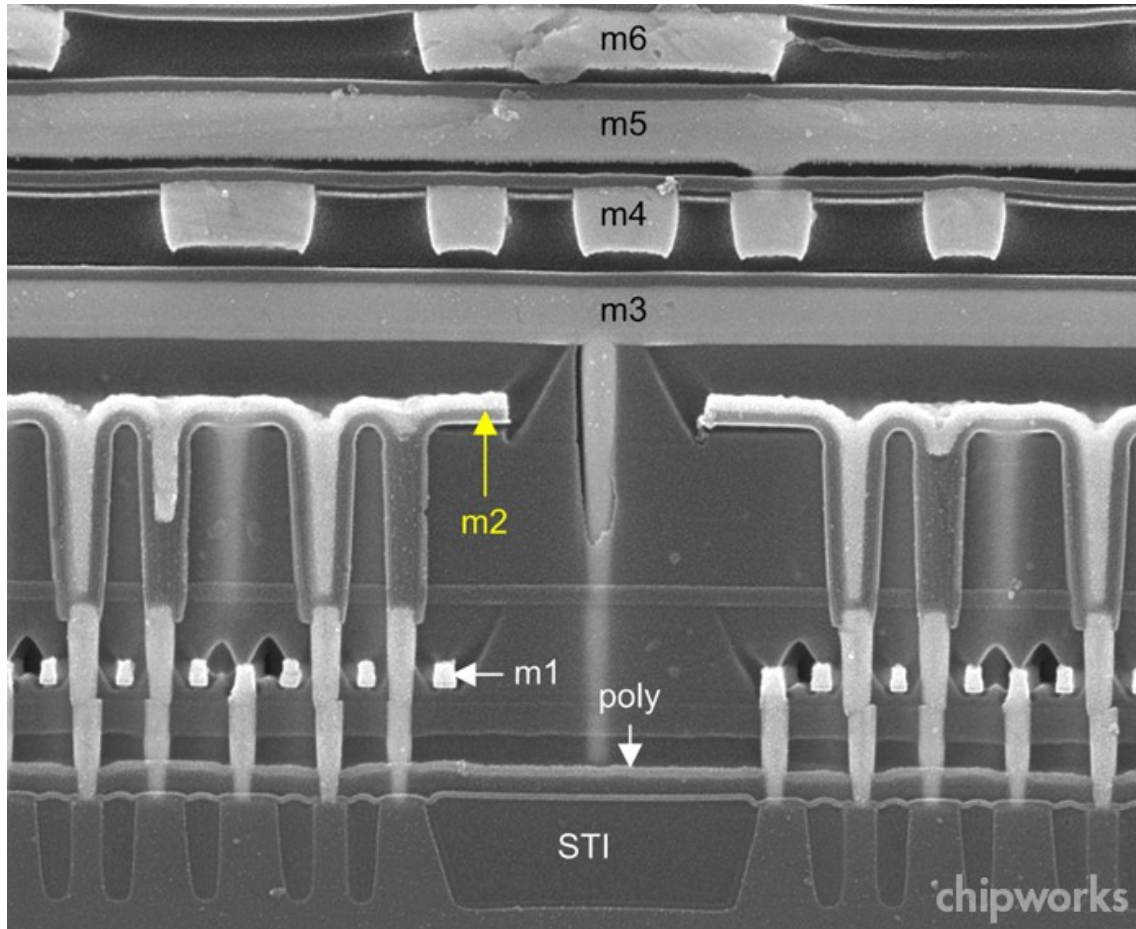
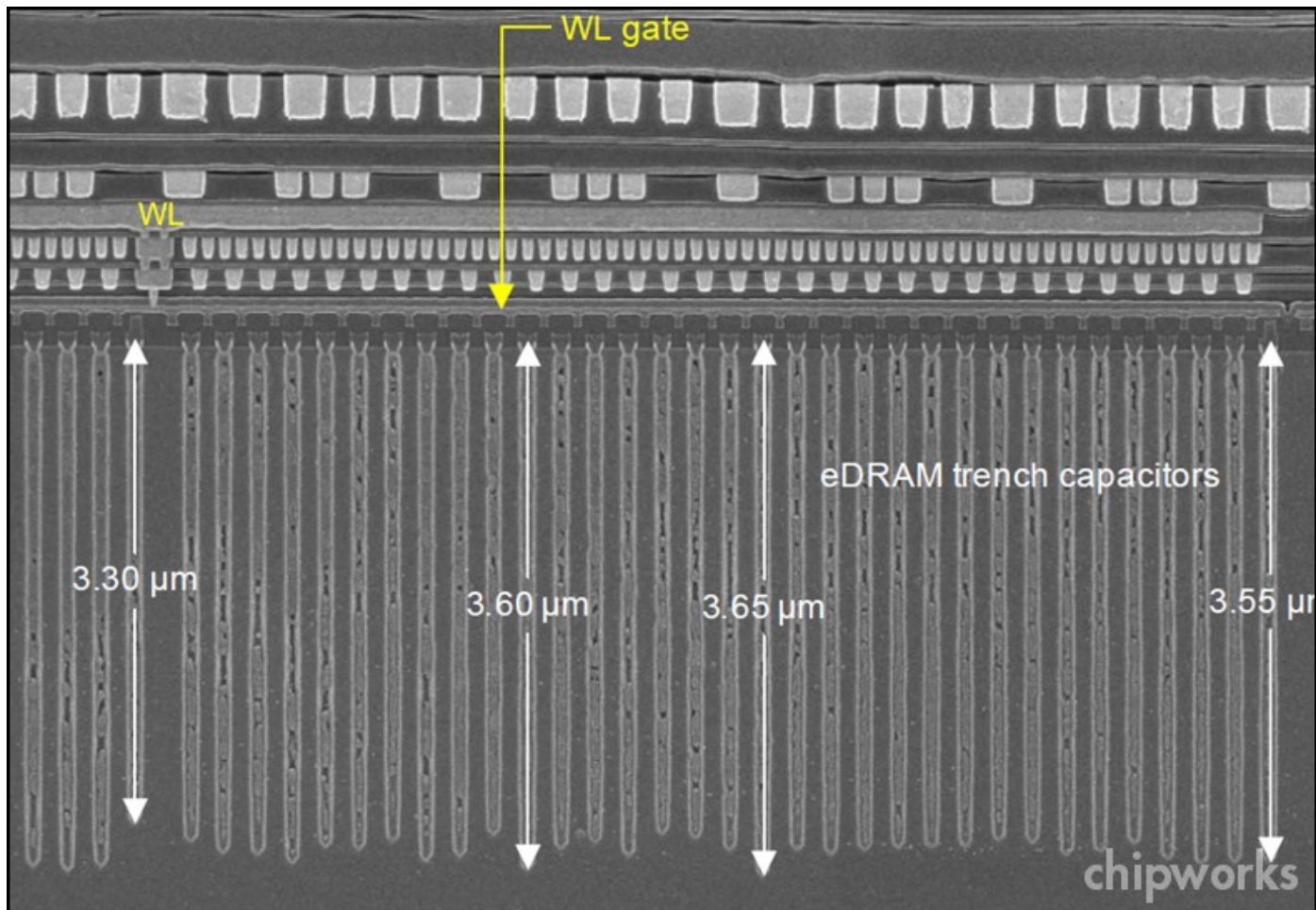


FIG 11.27 Trench capacitor

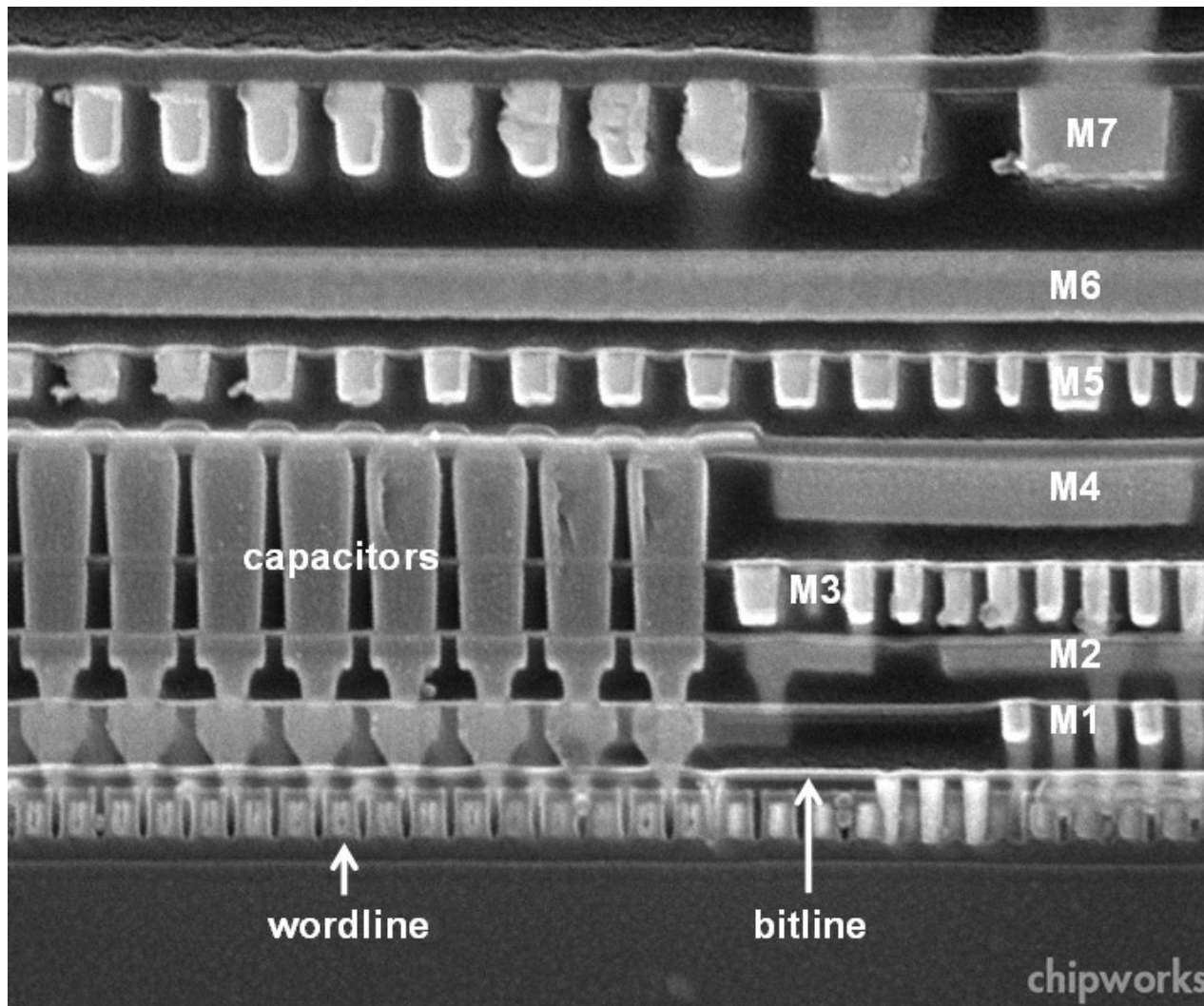


Embedded DRAM in Nintendo Wii U GPU fabbed by Renesas (45-nm)

<http://chipworksrealchips.blogspot.de/2014/02/intels-e-dram-shows-up-in-wild.html>



Embedded DRAM in IBM Power 7+ microprocessor (32-nm)

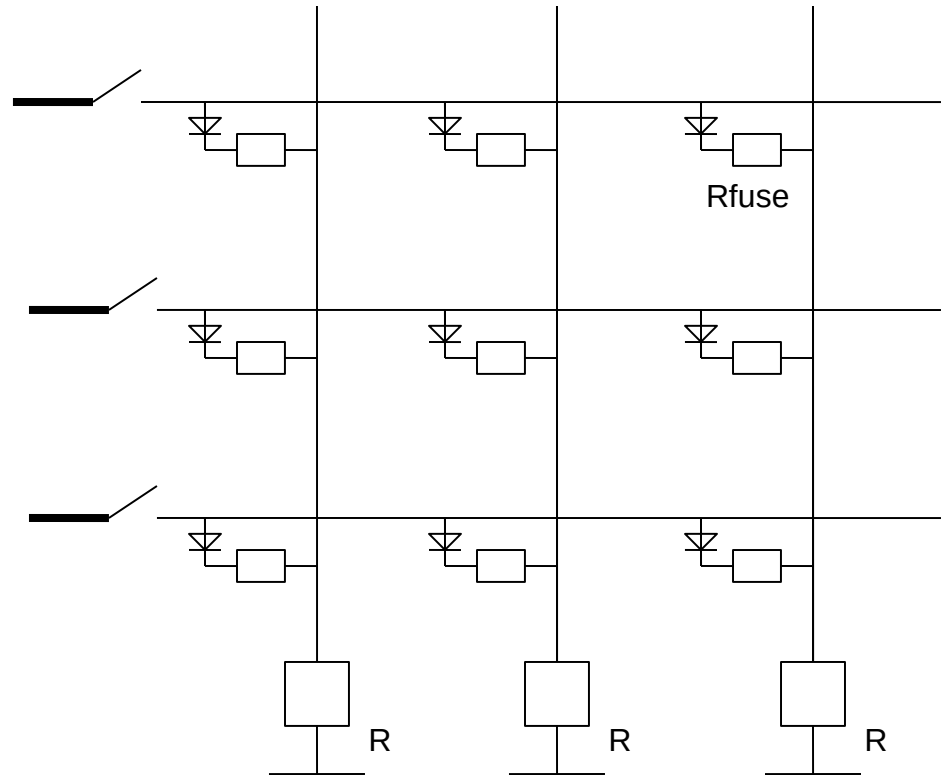
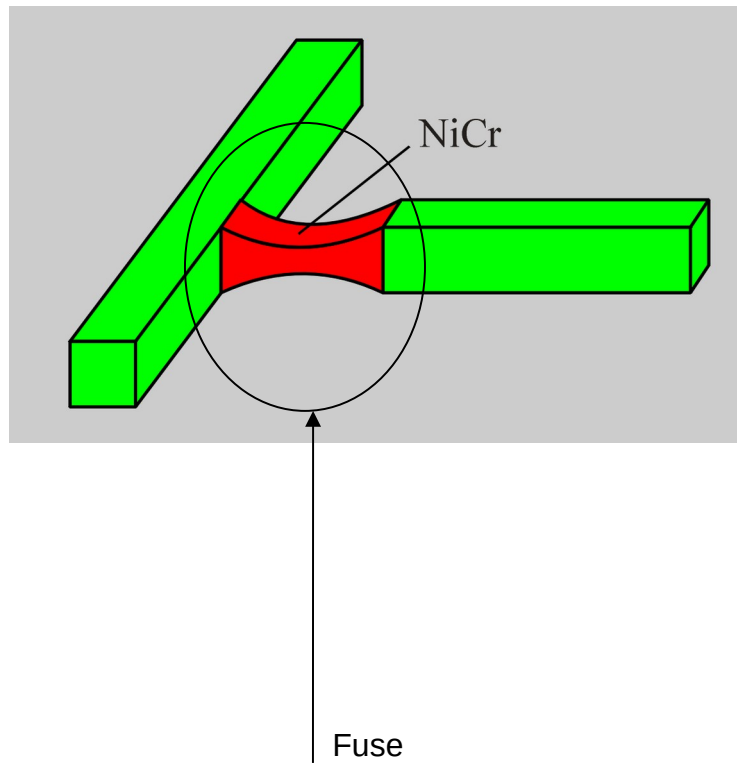


Intel's 22-nm embedded DRAM stack

Permanentspeicher (non-volatile)

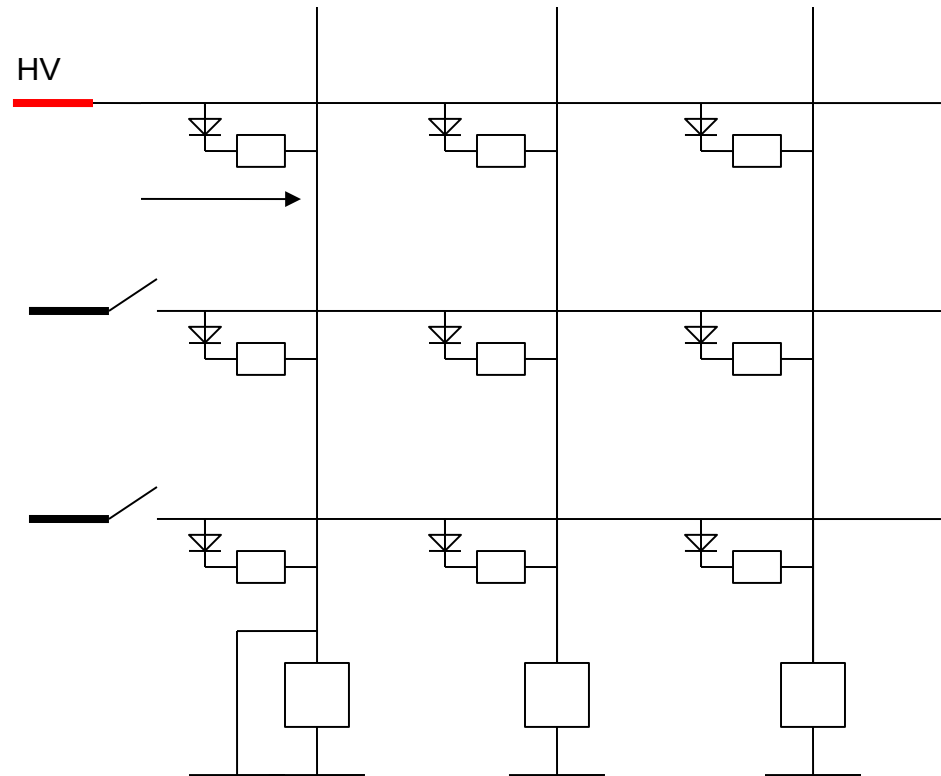
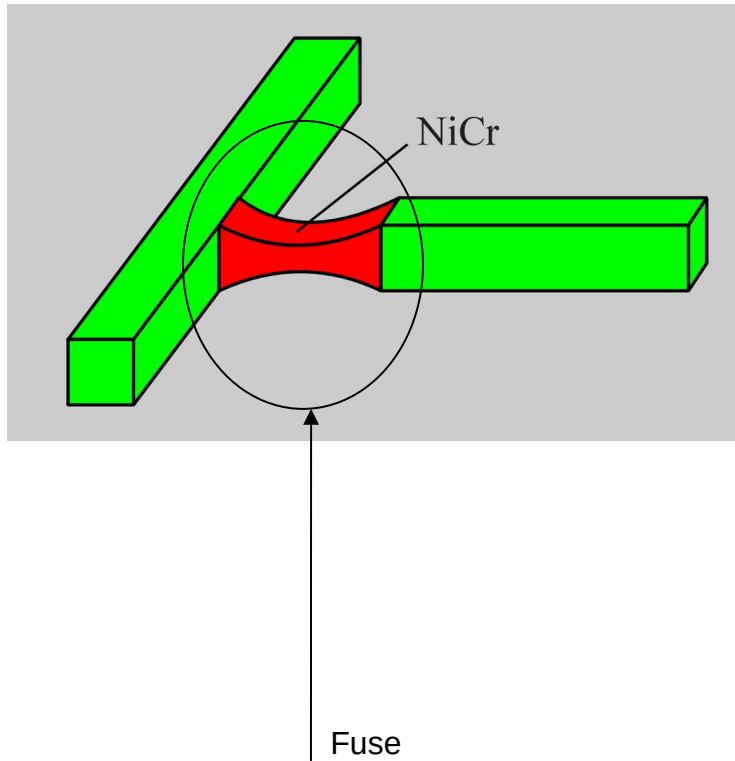
Programmiert vor Verwendung

PROM



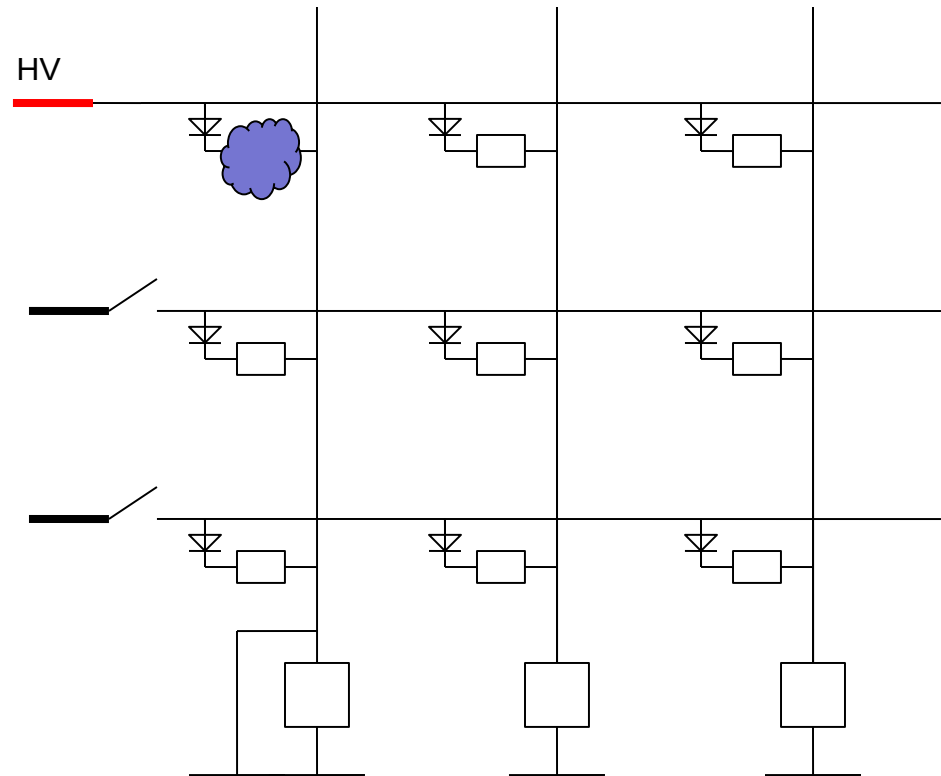
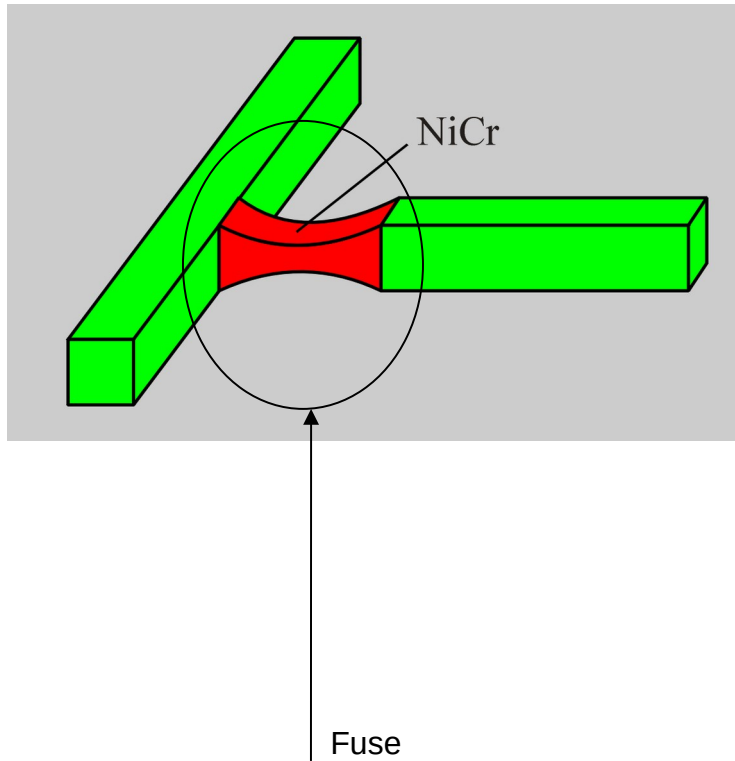
Programmiert vor Verwendung

PROM



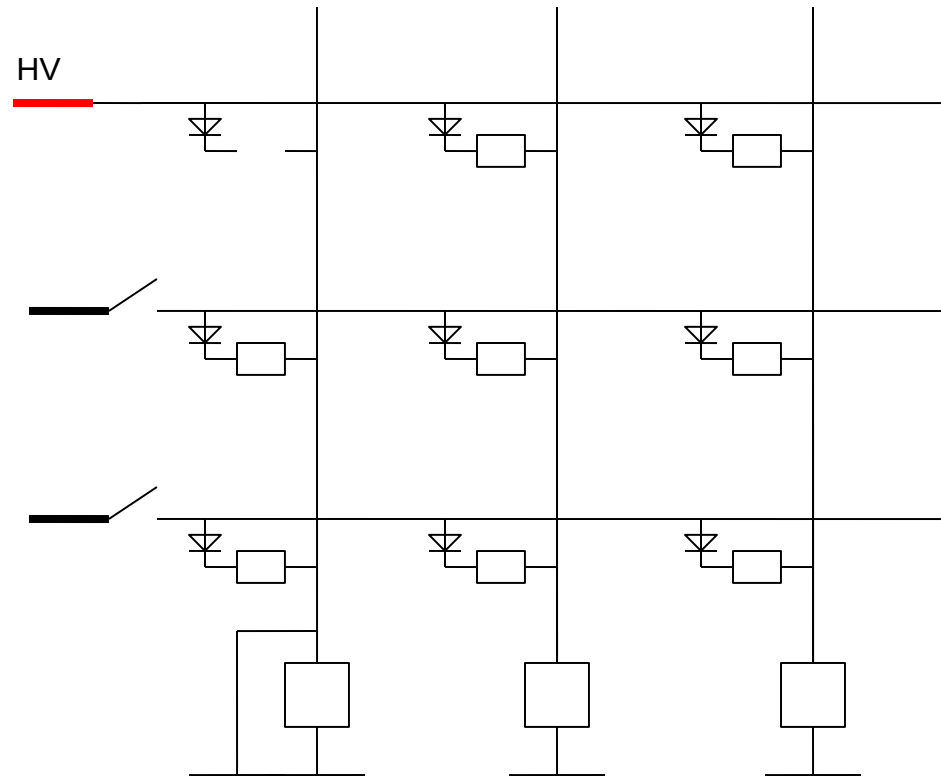
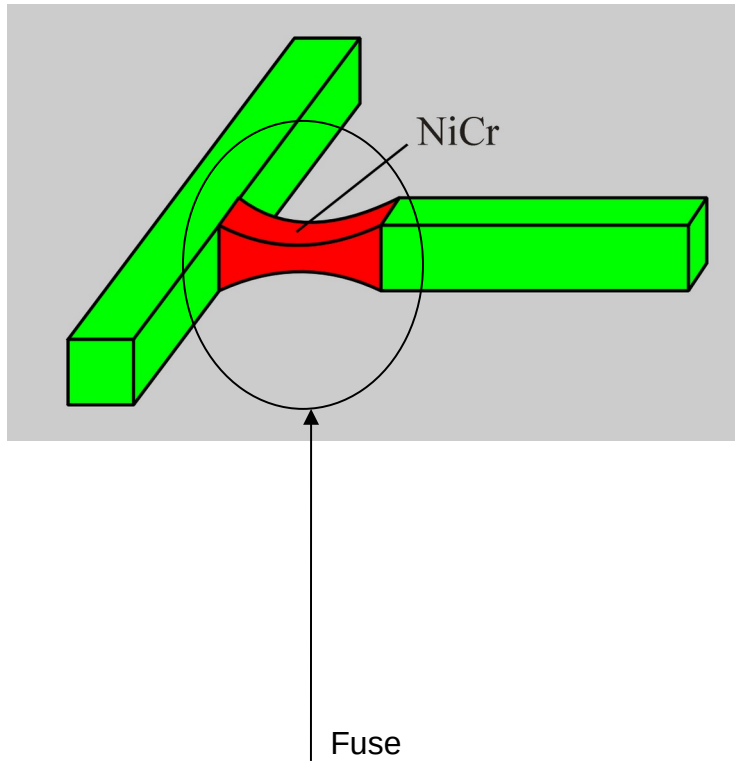
Programmiert vor Verwendung

PROM



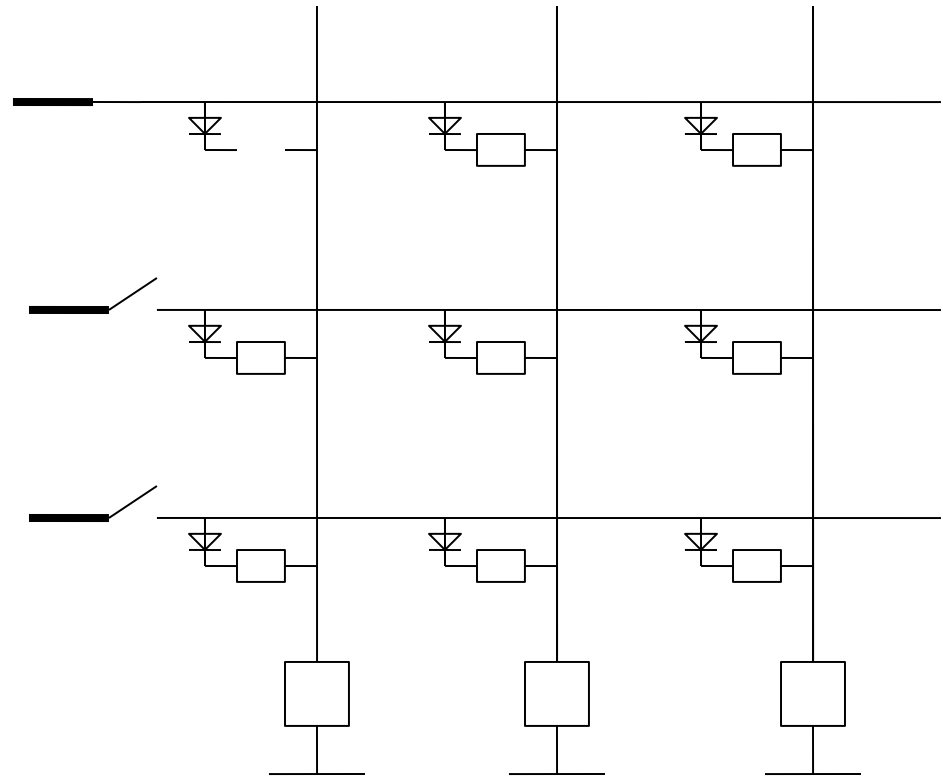
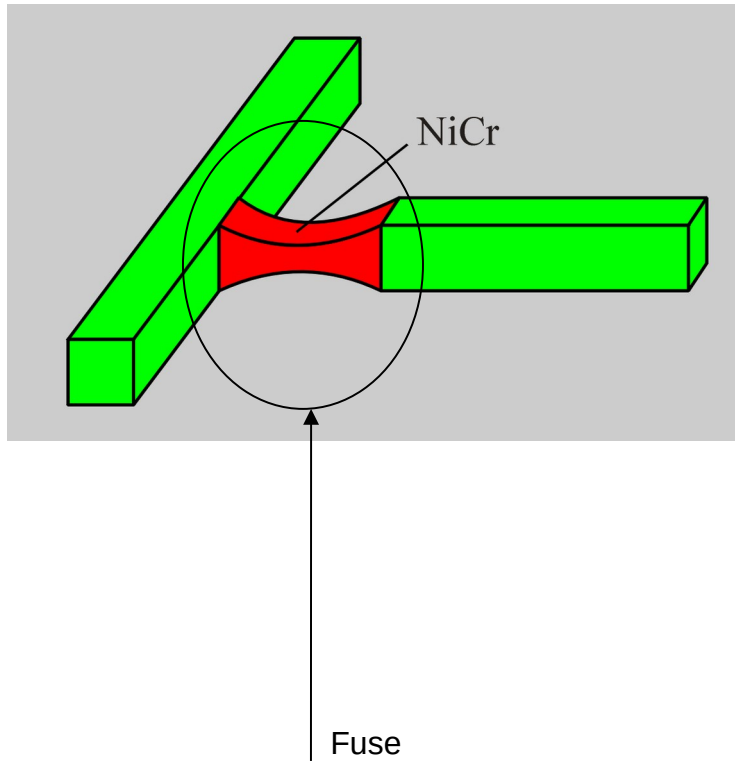
Programmiert vor Verwendung

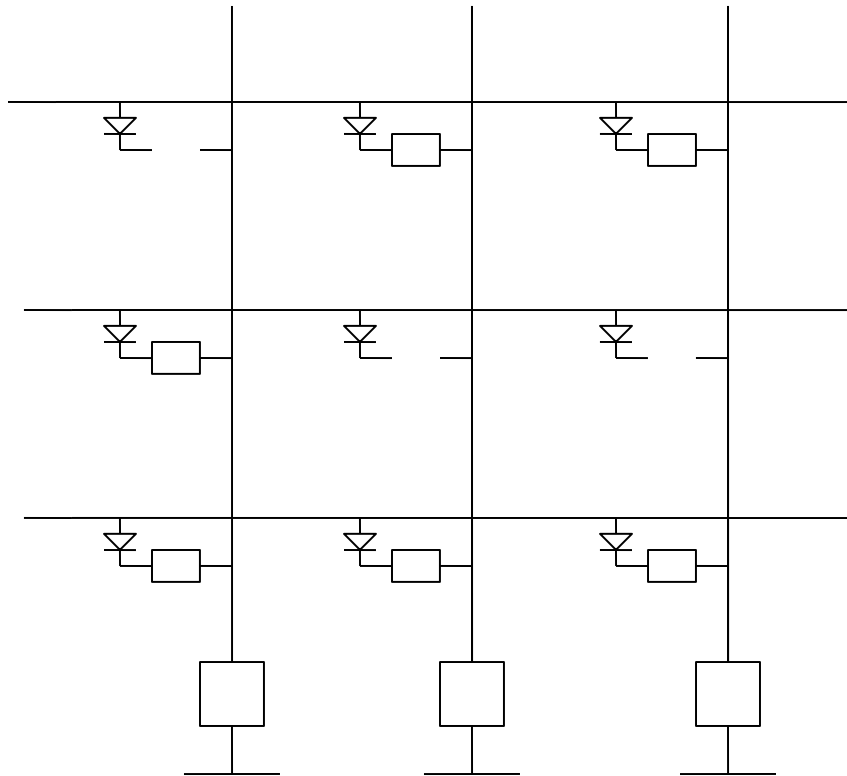
PROM

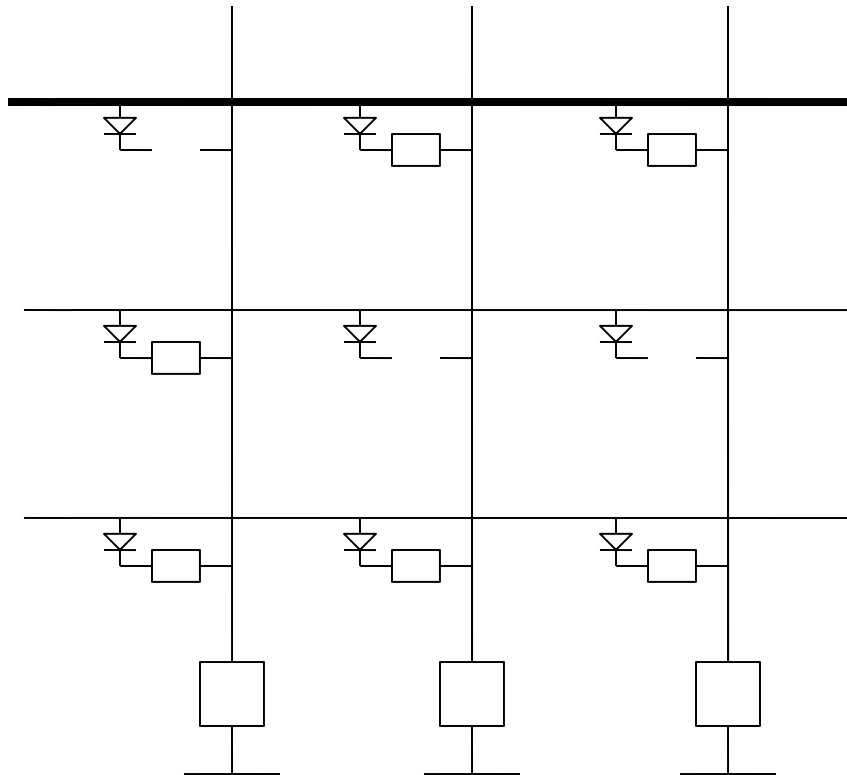


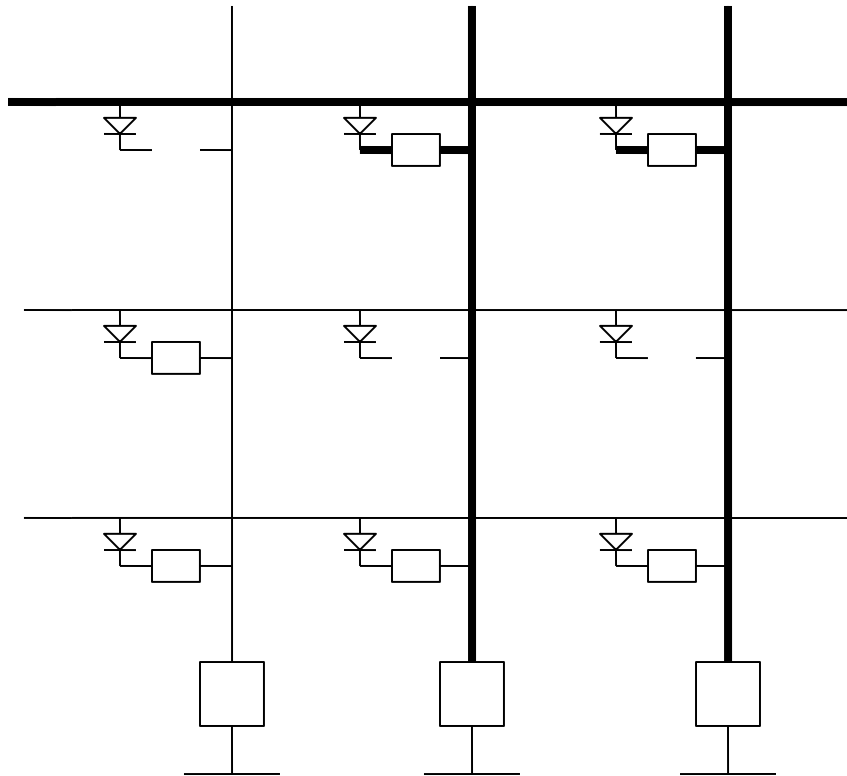
Programmiert vor Verwendung

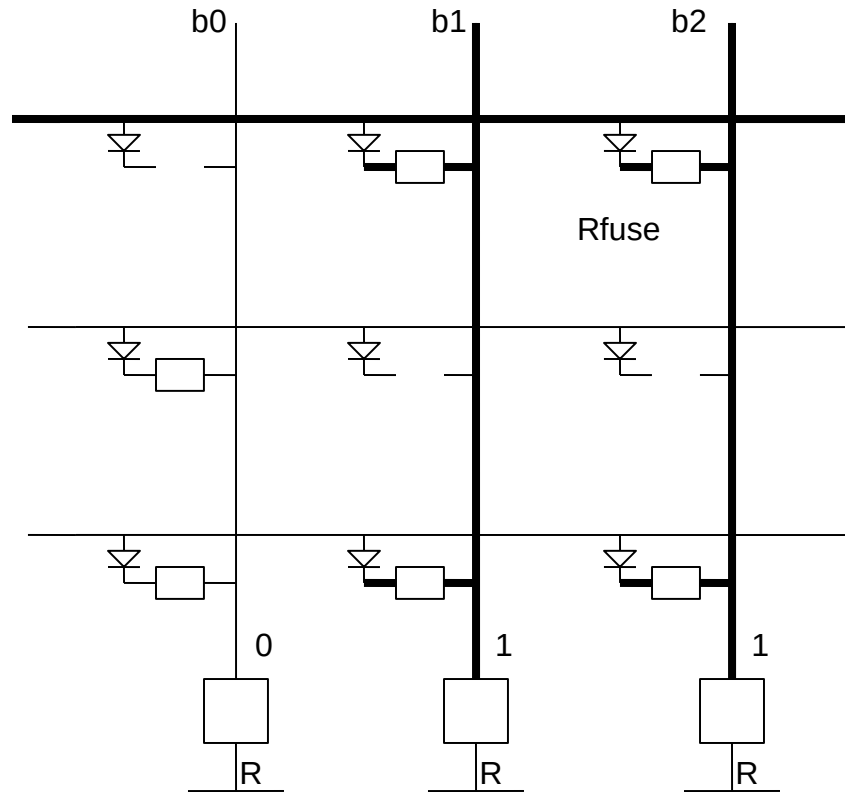
PROM





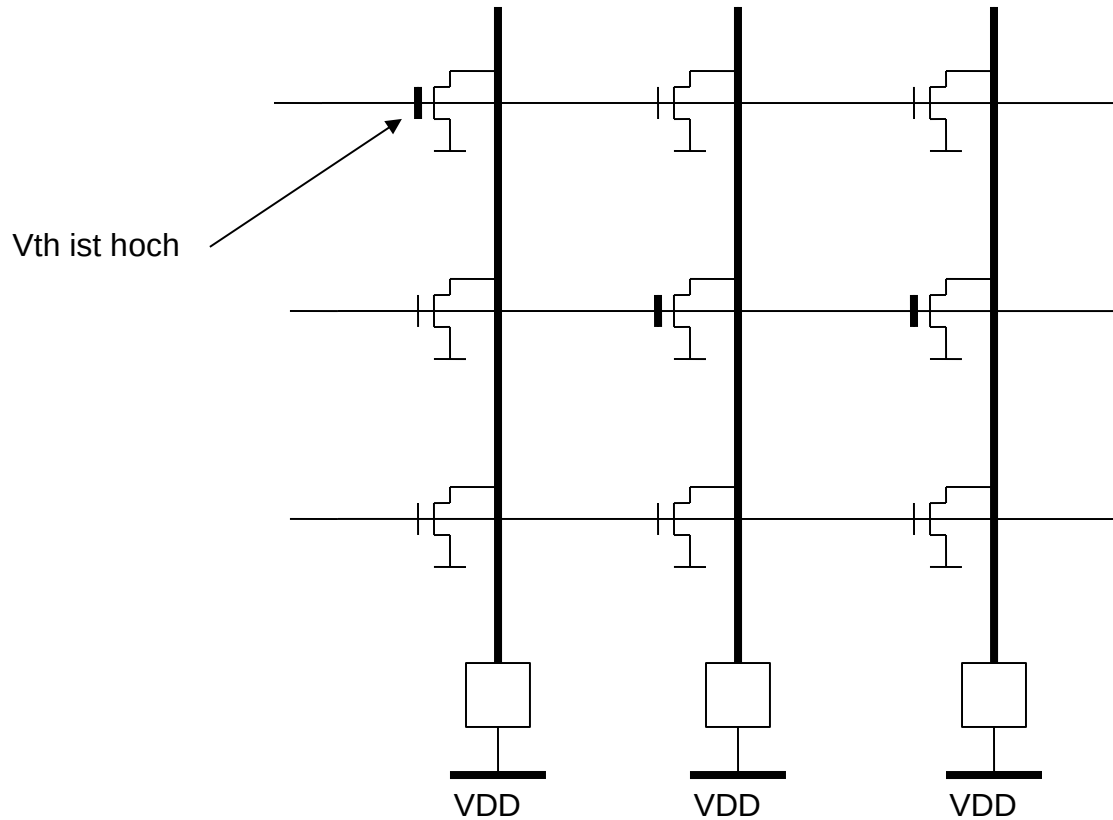




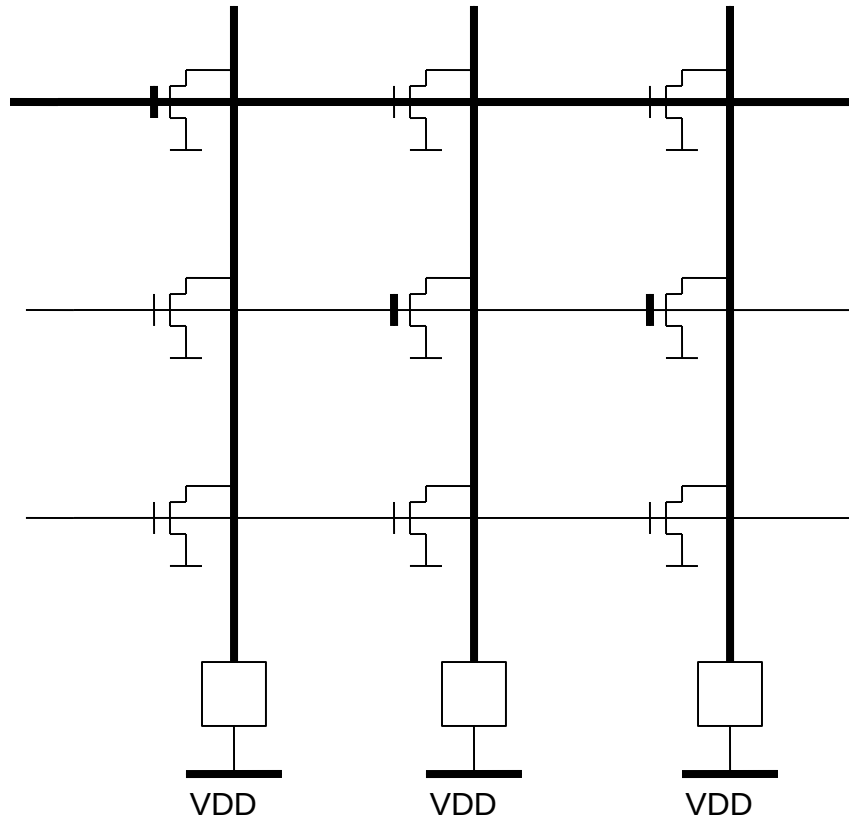


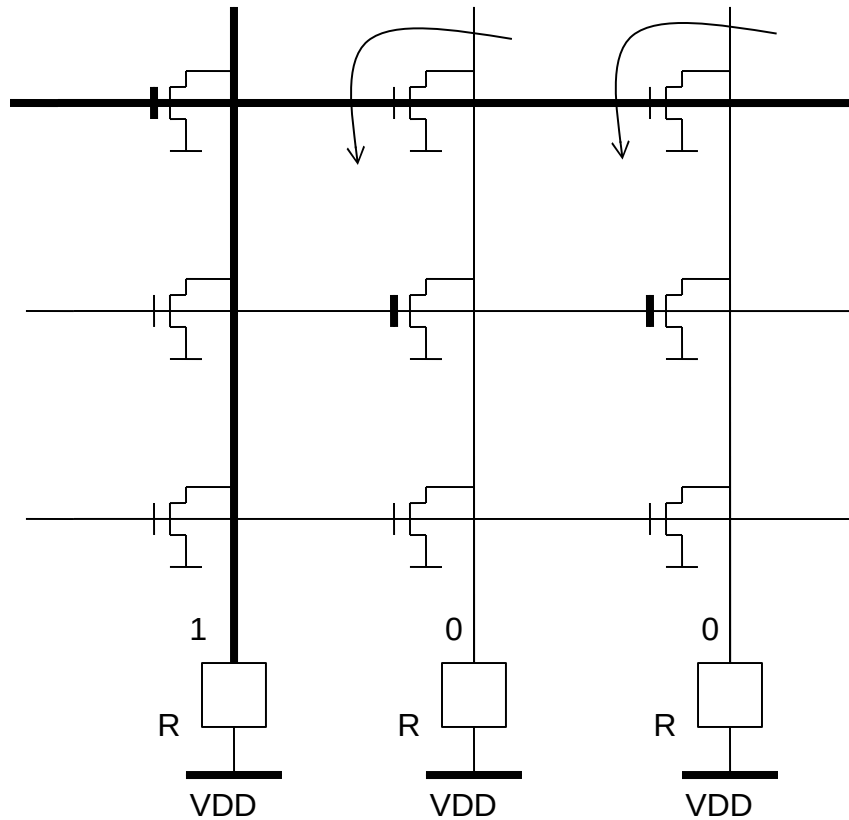
EPROM, EEPROM und FLASH

- Transistor (ODER-Schaltung)

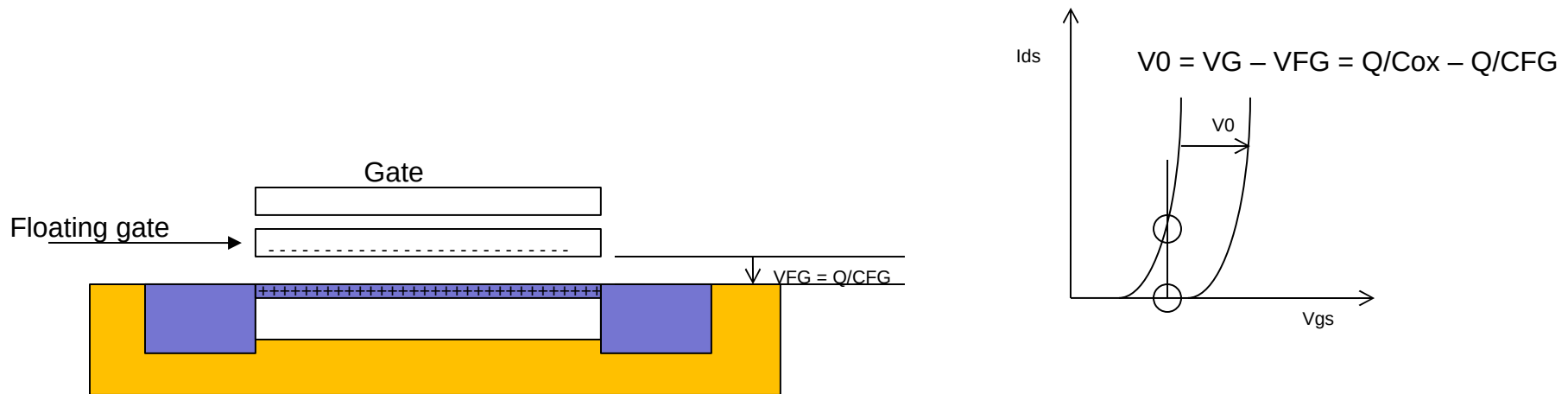


- Transistor (ODER-Schaltung)

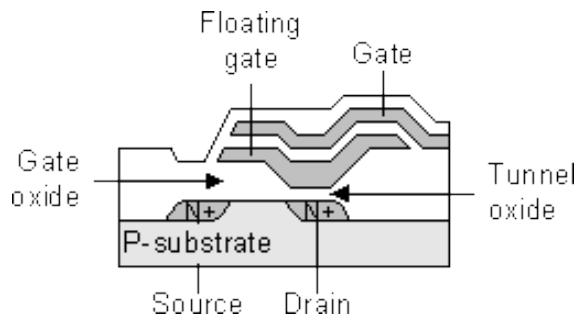




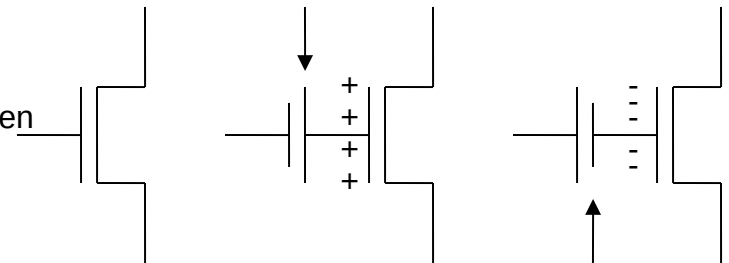
- Durch die gespeicherte Ladung wird die Schwellspannung des Transistors zu höheren Werten verschoben. Das Auslesen erfolgt bei niedrigen Spannungen. Ist U_{th} verschoben, schaltet der Transistor nicht ein.



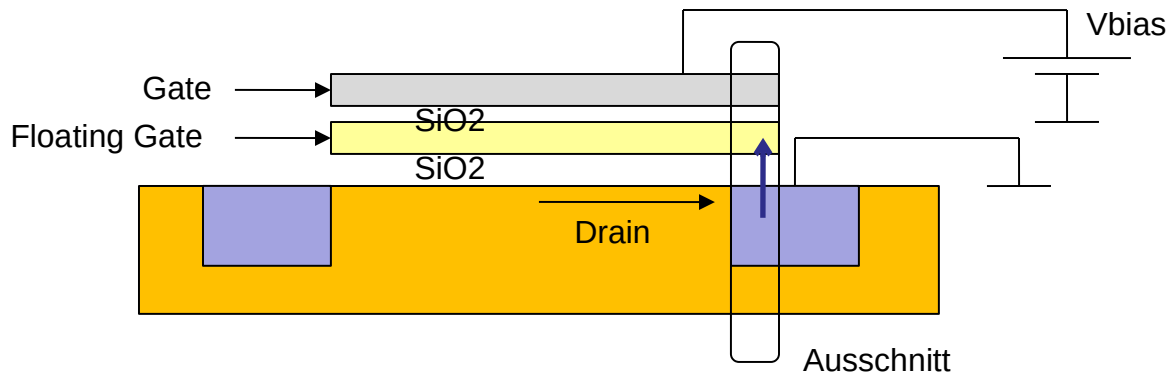
Floating gate negativ aufgeladen



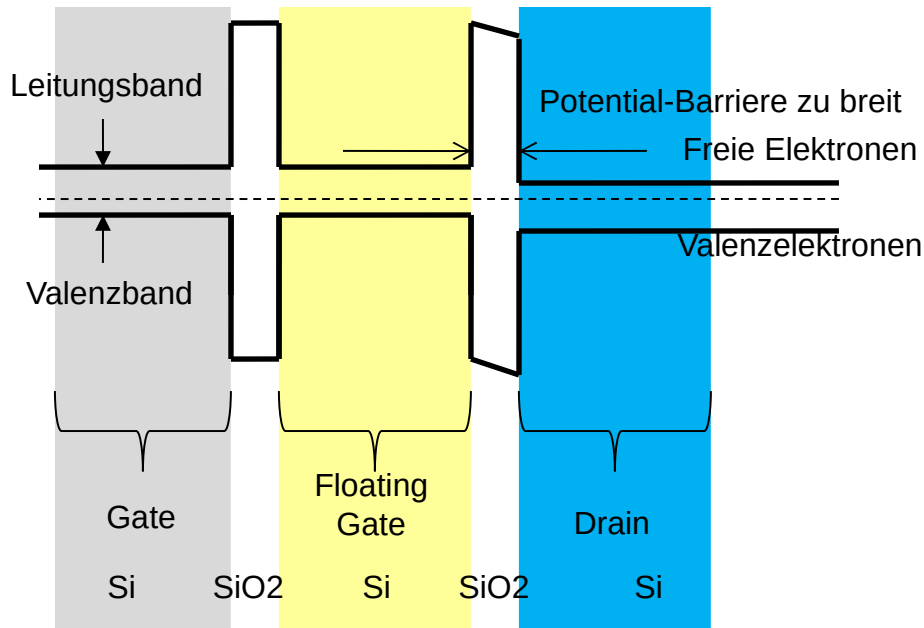
Floating gate nicht aufgeladen



Floating Gate positiv aufgeladen

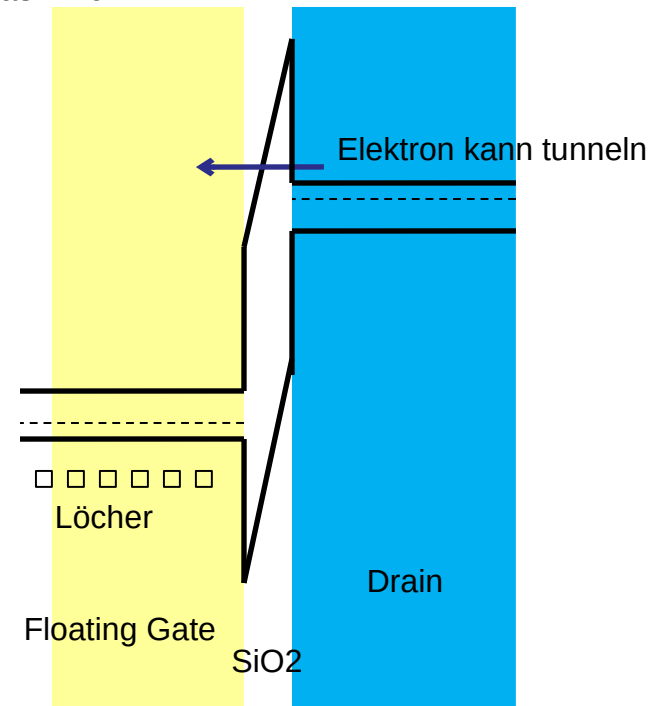


Energiediagramm: $V_{bias} = 0$

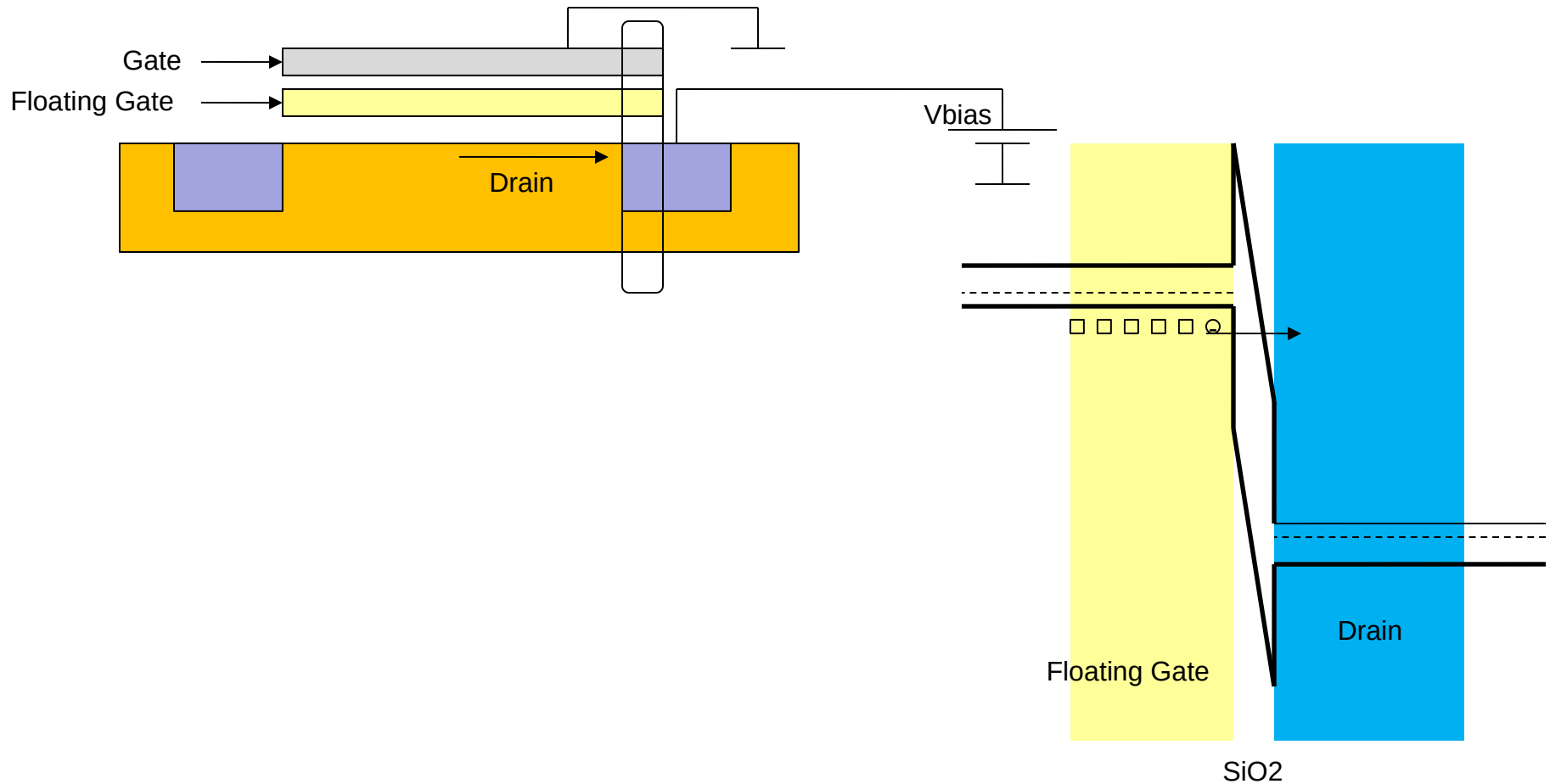


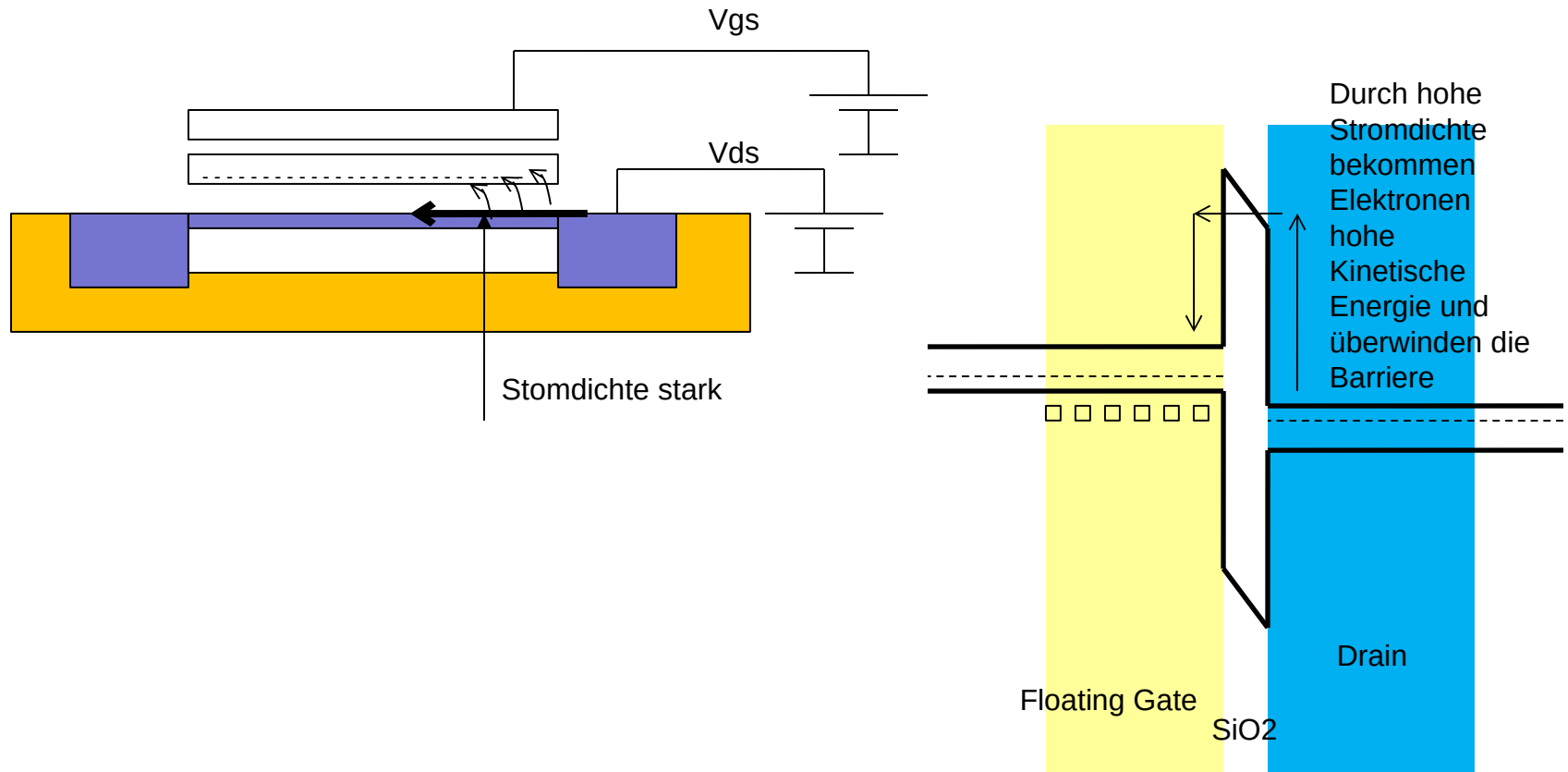
Wegen hoher Spannung wird die Barriere schmaler

$V_{bias} \sim 10V$

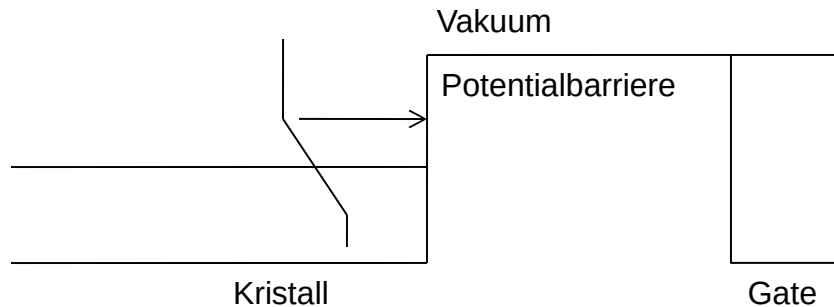


- EEPROM erase, Fowler-Nordheim tunnelling

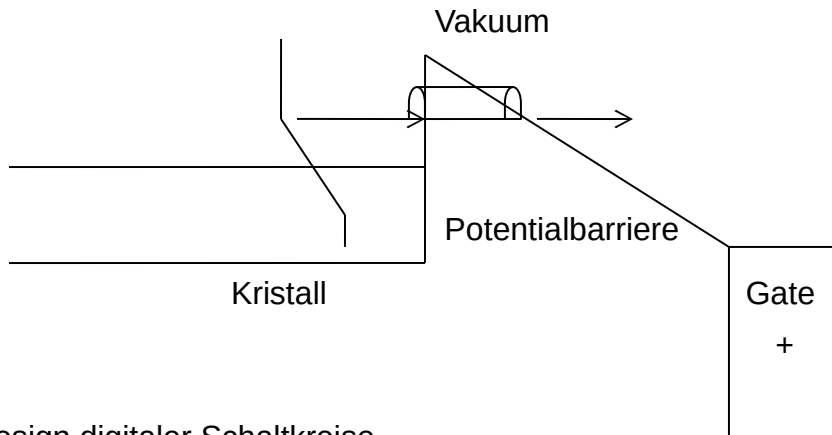




- Klassisch betrachtet ist es für ein Teilchen mit einer bestimmten mittleren thermischen Energie, die kleiner ist als die Höhe der [Austrittsarbeit](#), unmöglich, das Kathodenmaterial zu verlassen. [Quantenmechanisch](#) betrachtet gibt es jedoch eine bestimmte Wahrscheinlichkeit, dass einzelne Elektronen aus dem [Festkörper](#) austreten.
- Diesen Effekt nennt man allgemein auch [Tunneleffekt](#). Das Elektron tunnelt durch den Potentialwall, der durch das äußere elektrische Feld verkippt wurde – diese spezielle Art von Tunneln nennt man auch „**Fowler-Nordheim-Tunneln**“ (benannt nach [Ralph Howard Fowler](#) und [Lothar Nordheim](#)).



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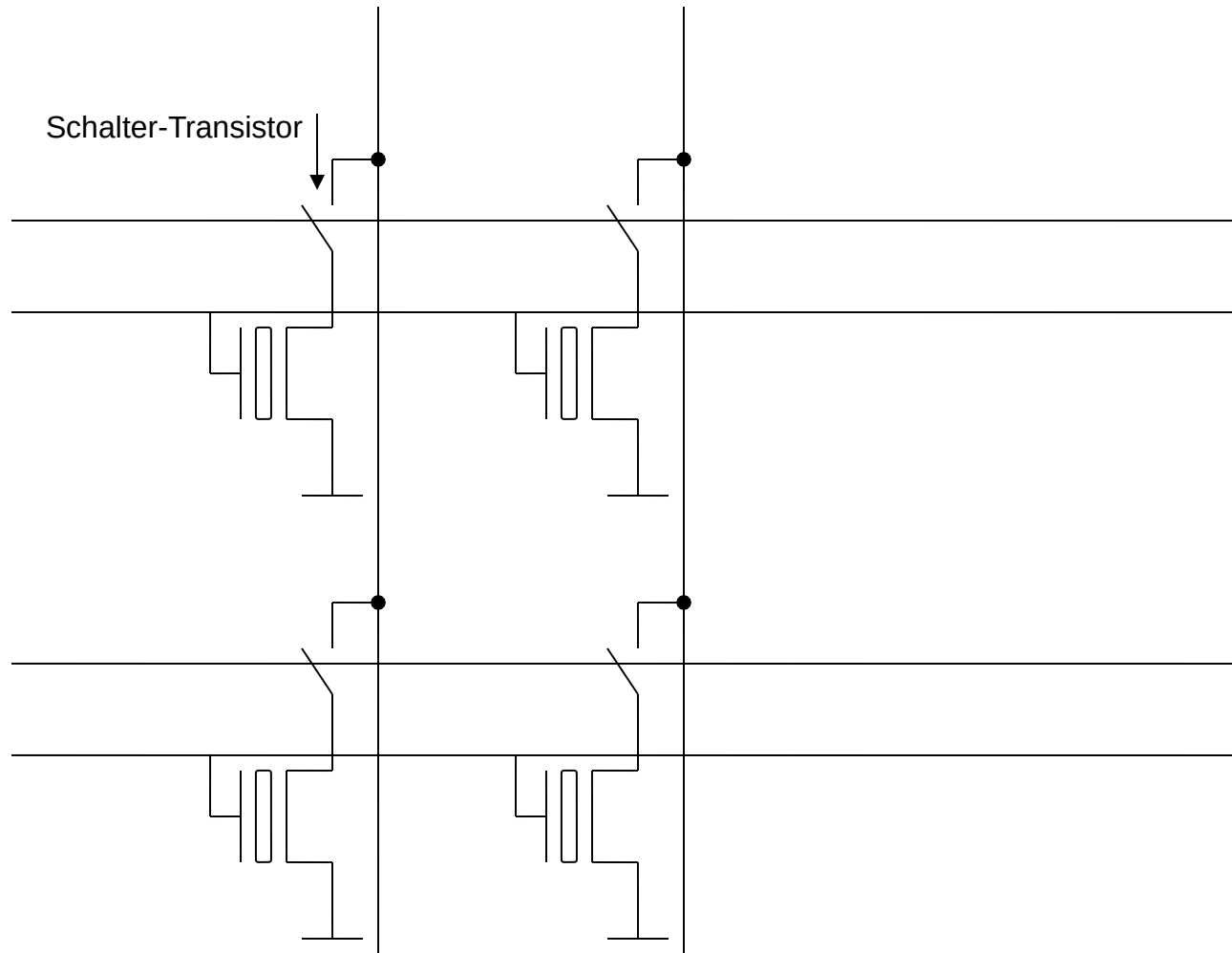


EEPROM – verschiedene Möglichkeiten

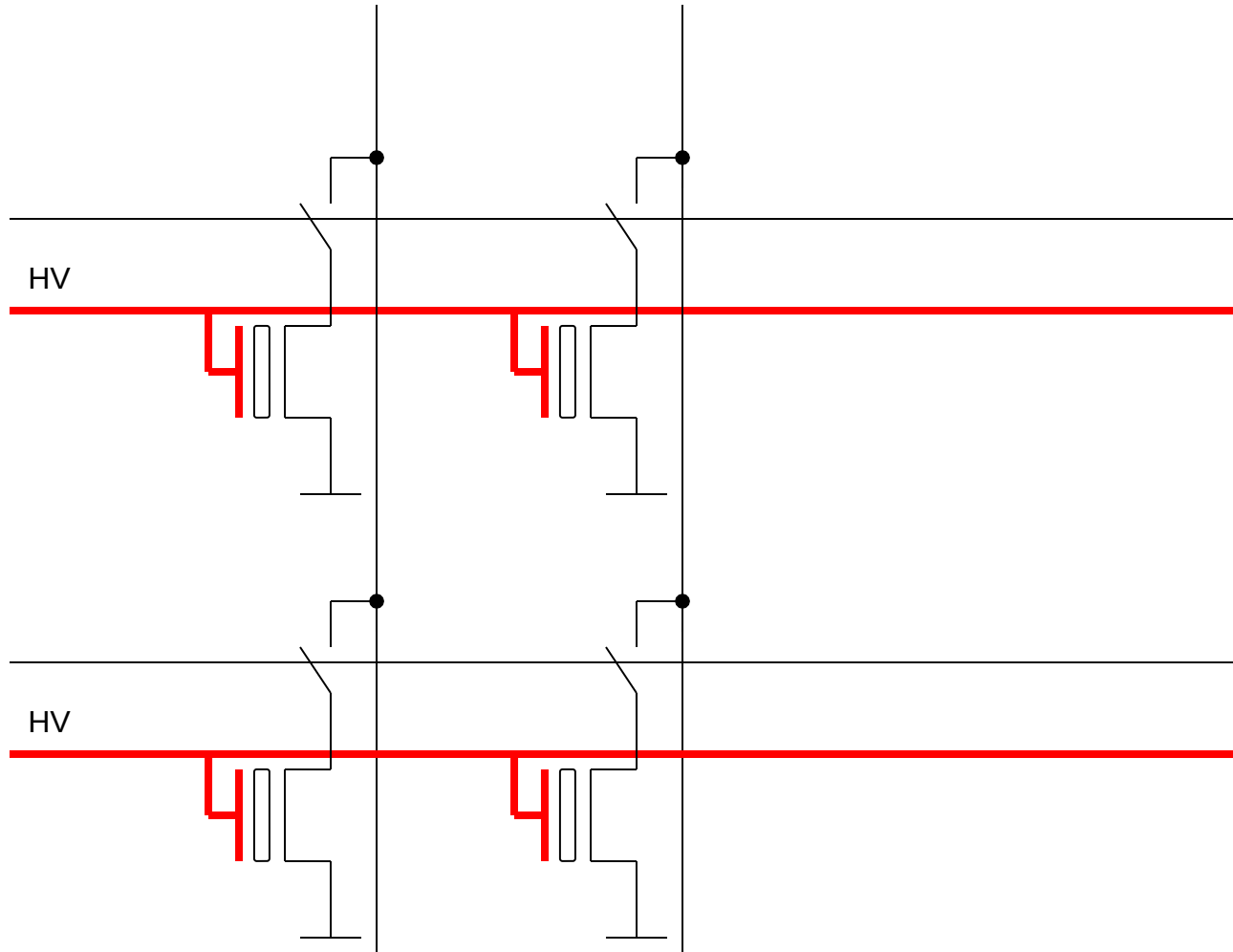
Variante 1

Erase and program based on tunnel effect

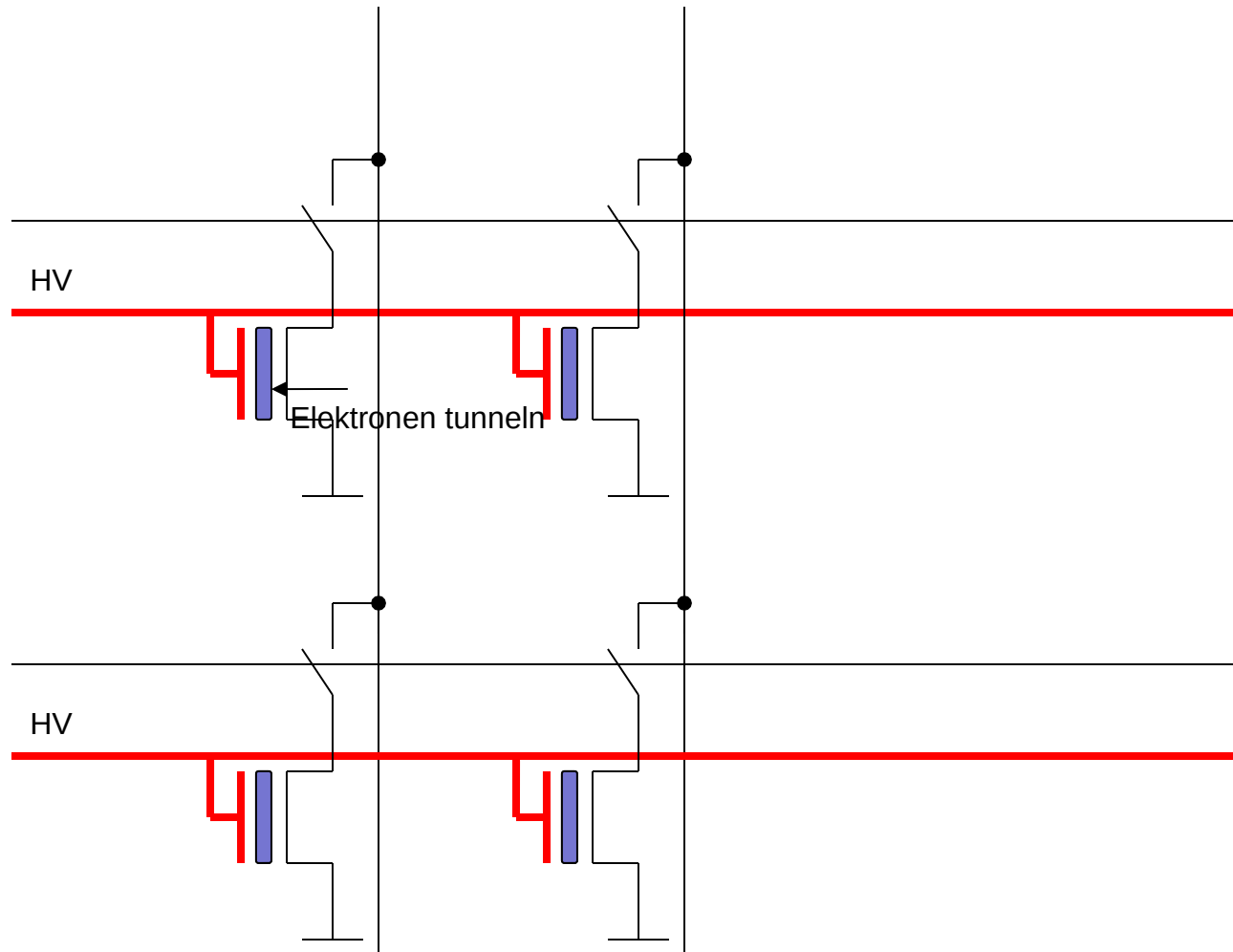
- EEPROM (erase and program based on tunnel effect)



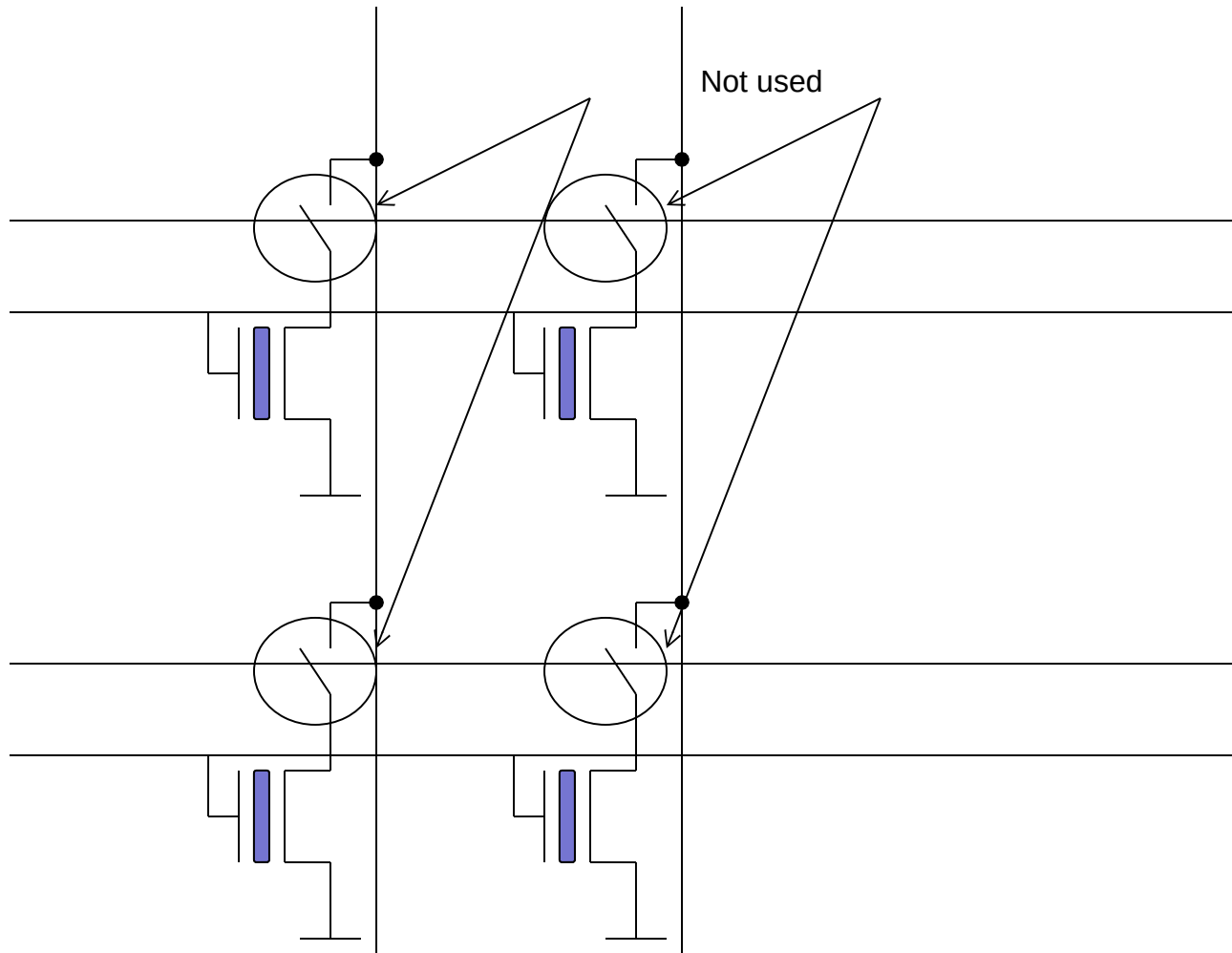
- EEPROM (erase and program based on tunnel effect)



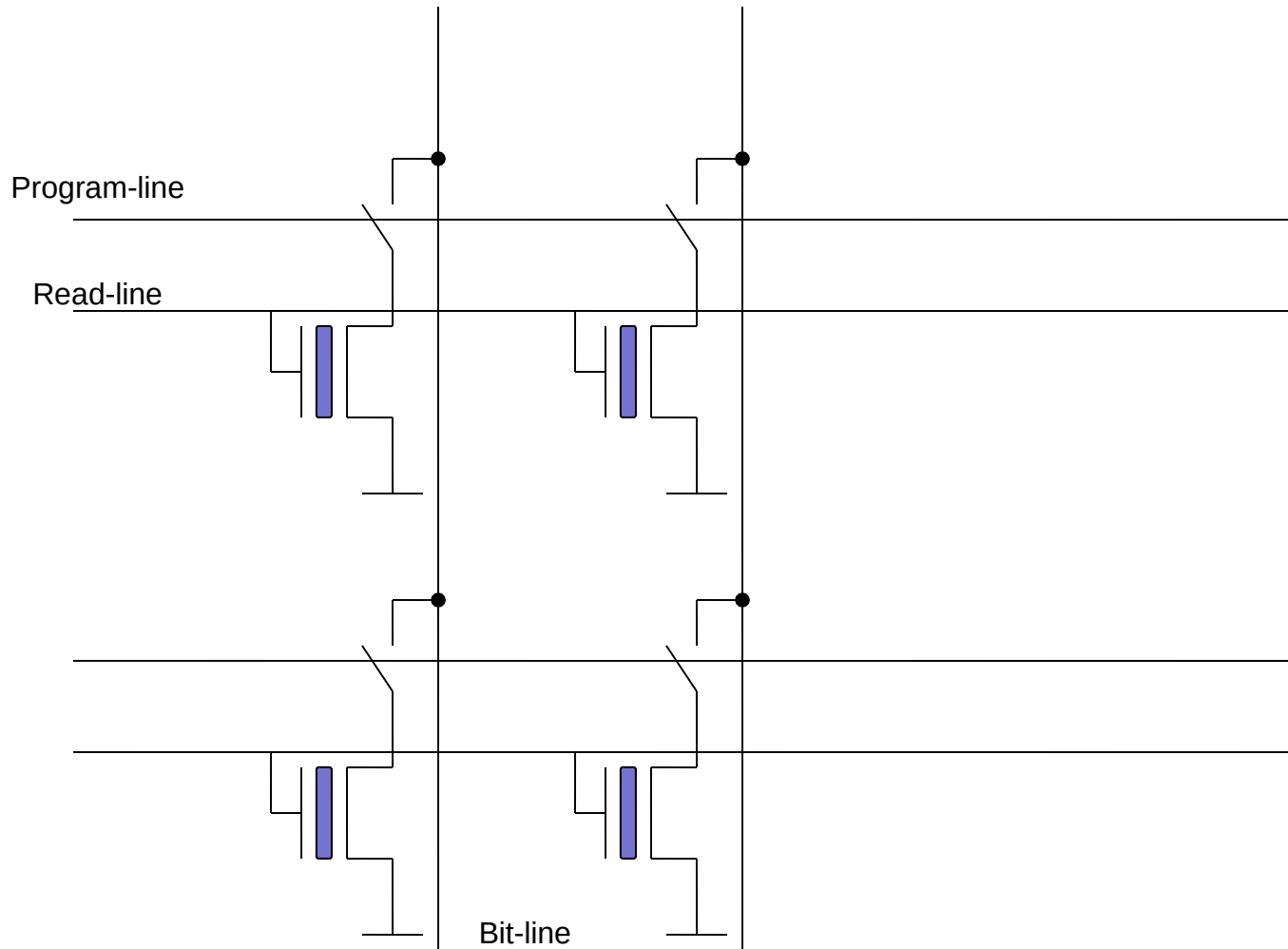
- EEPROM (erase and program based on tunnel effect)



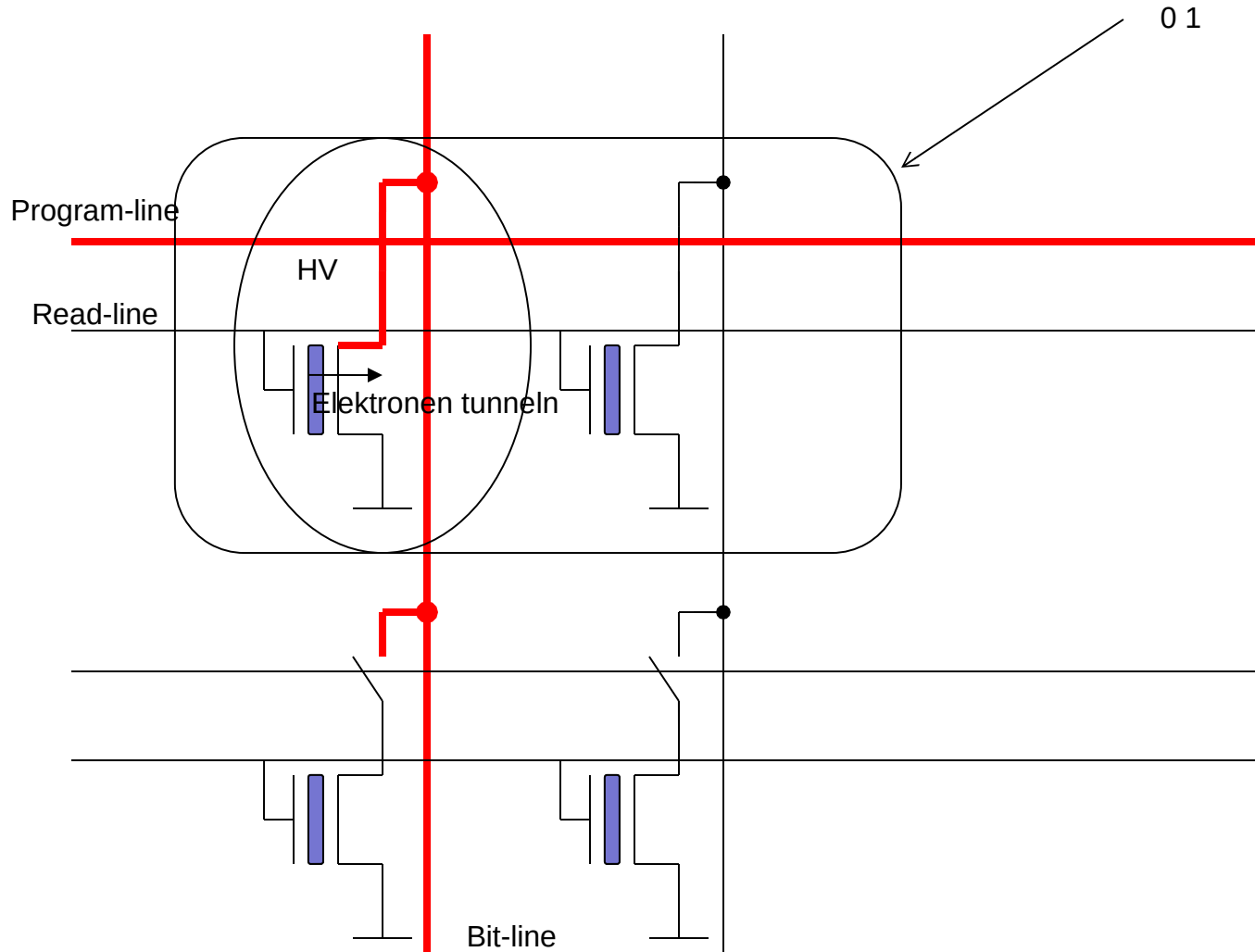
- EEPROM (erase and program based on tunnel effect)



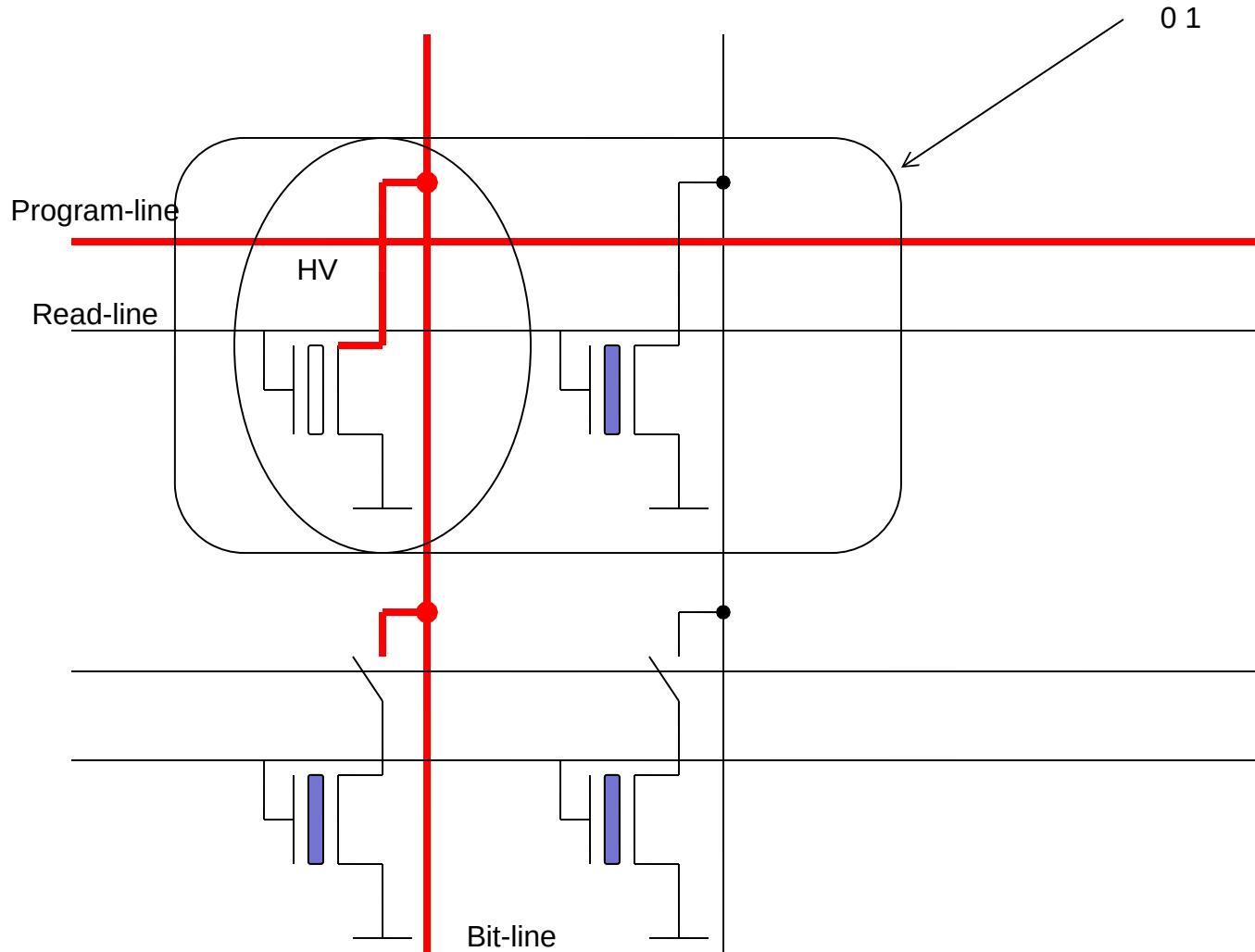
- EEPROM (erase and program based on tunnel effect)



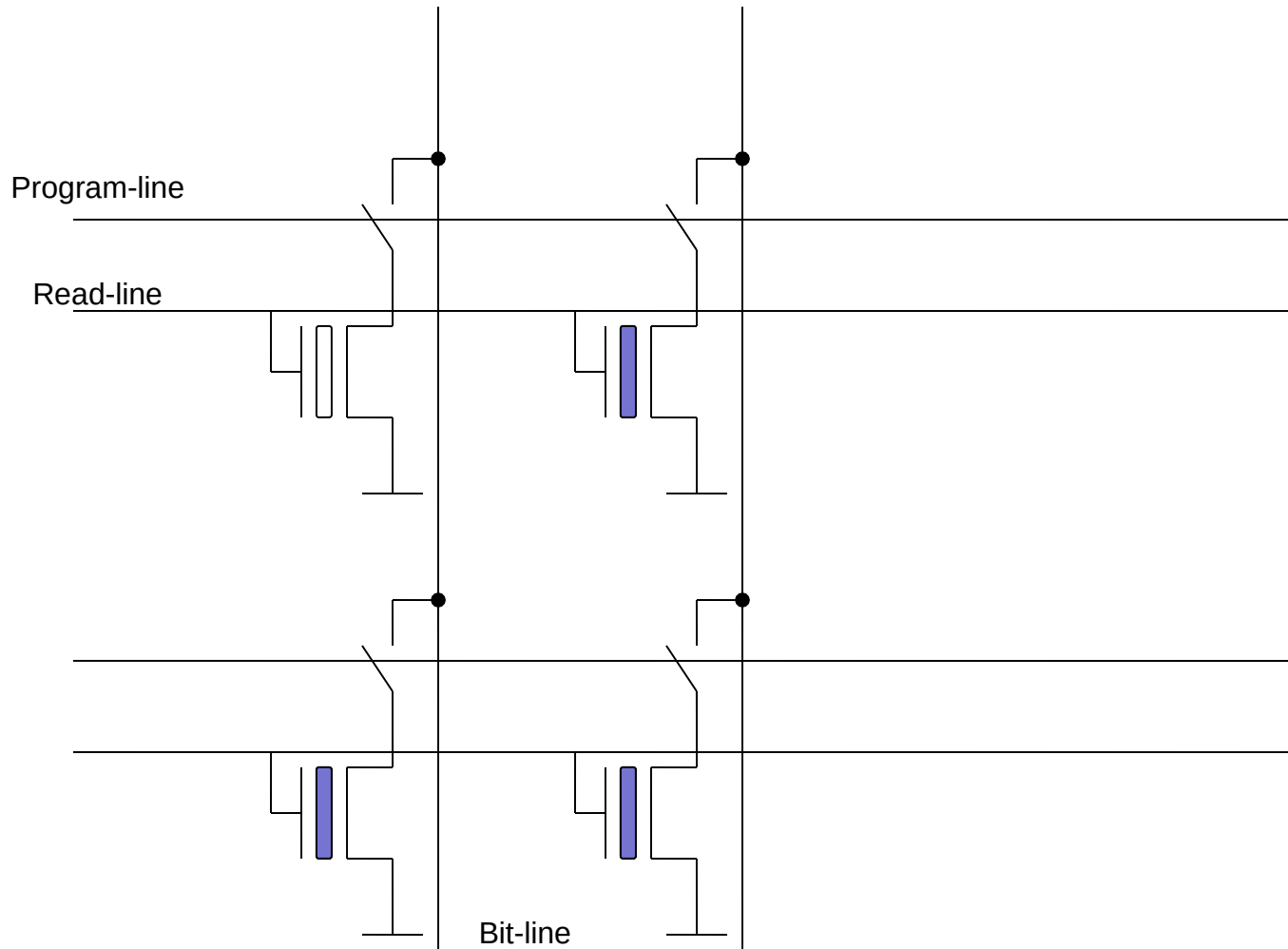
- EEPROM (erase and program based on tunnel effect)



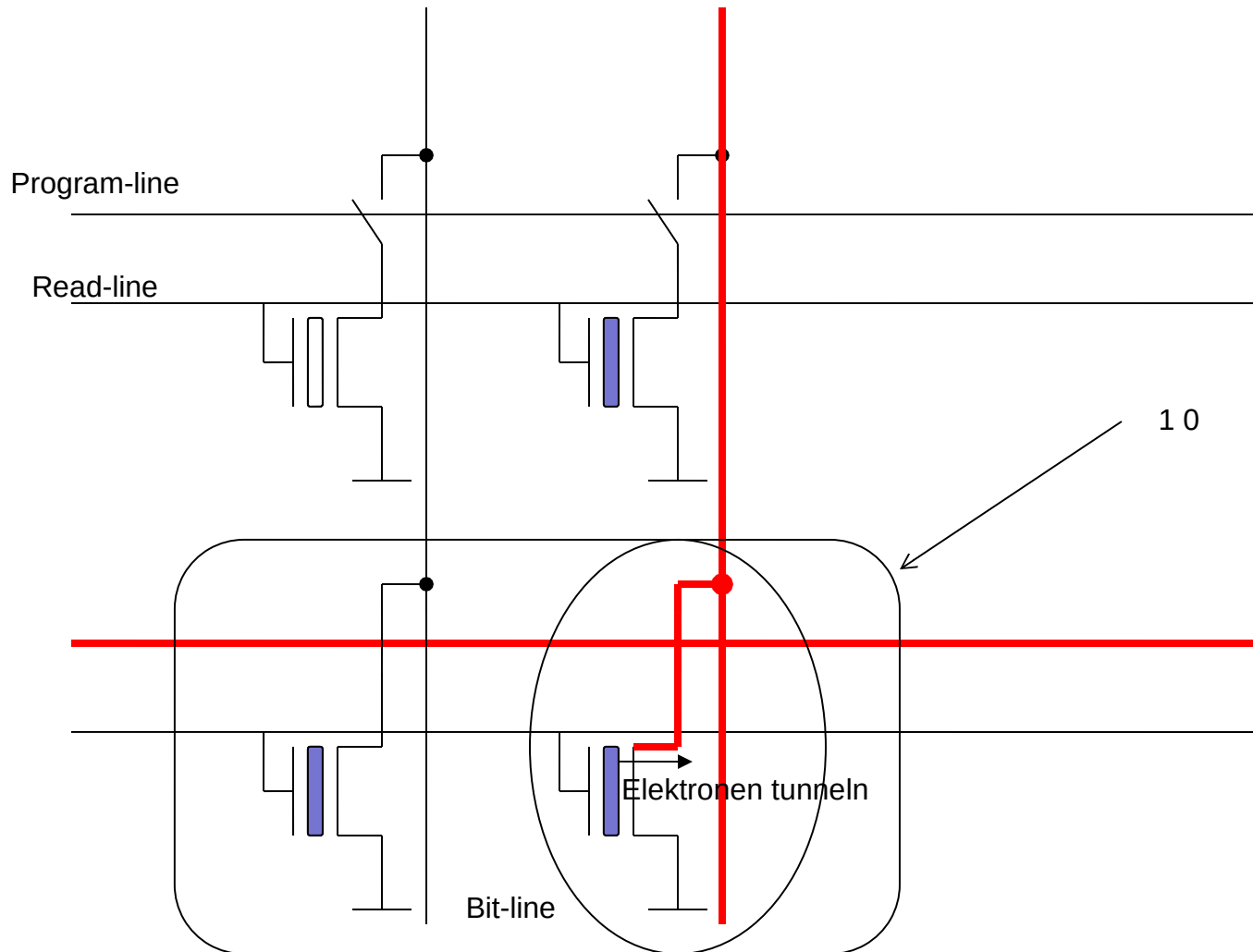
- EEPROM (erase and program based on tunnel effect)



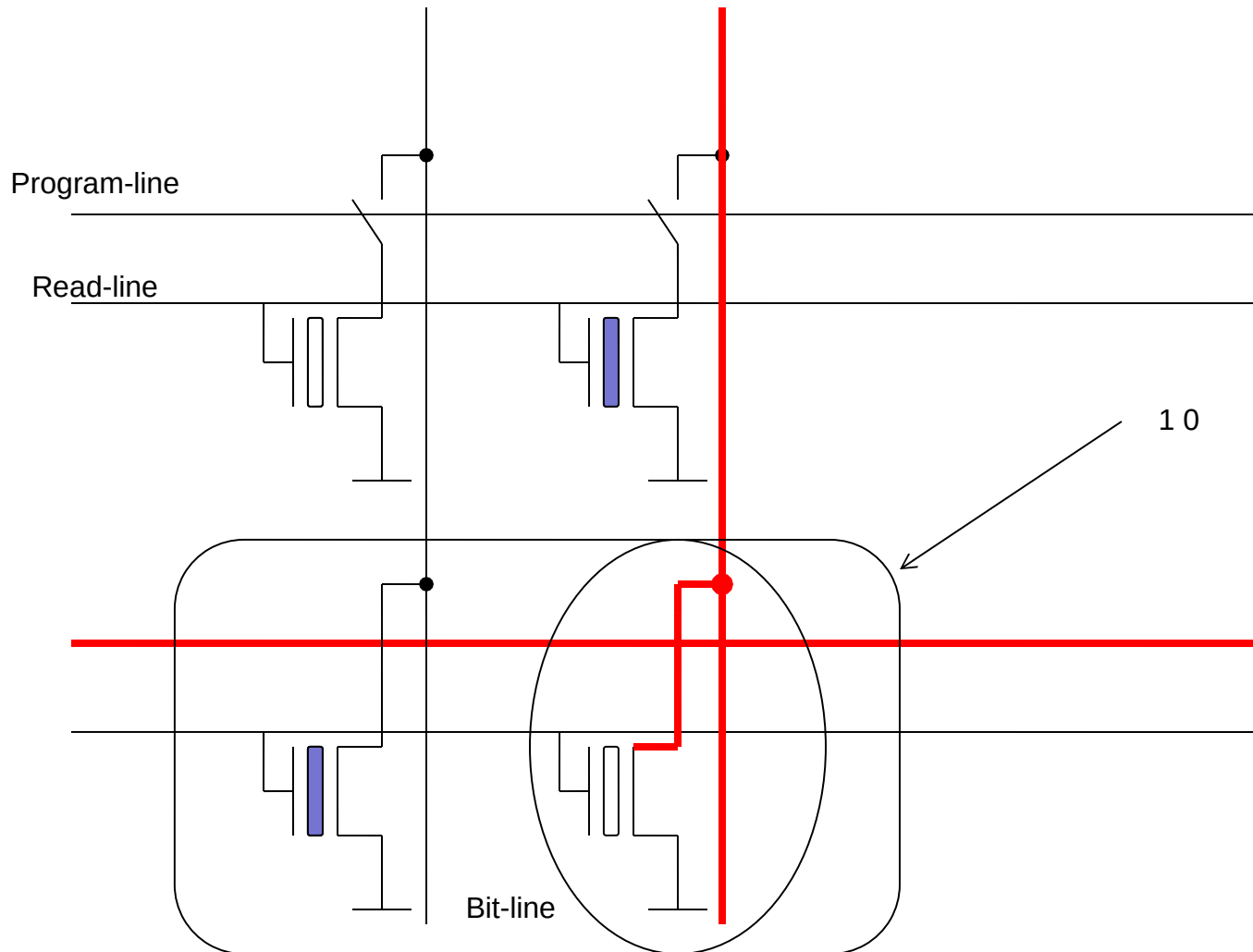
- EEPROM (erase and program based on tunnel effect)



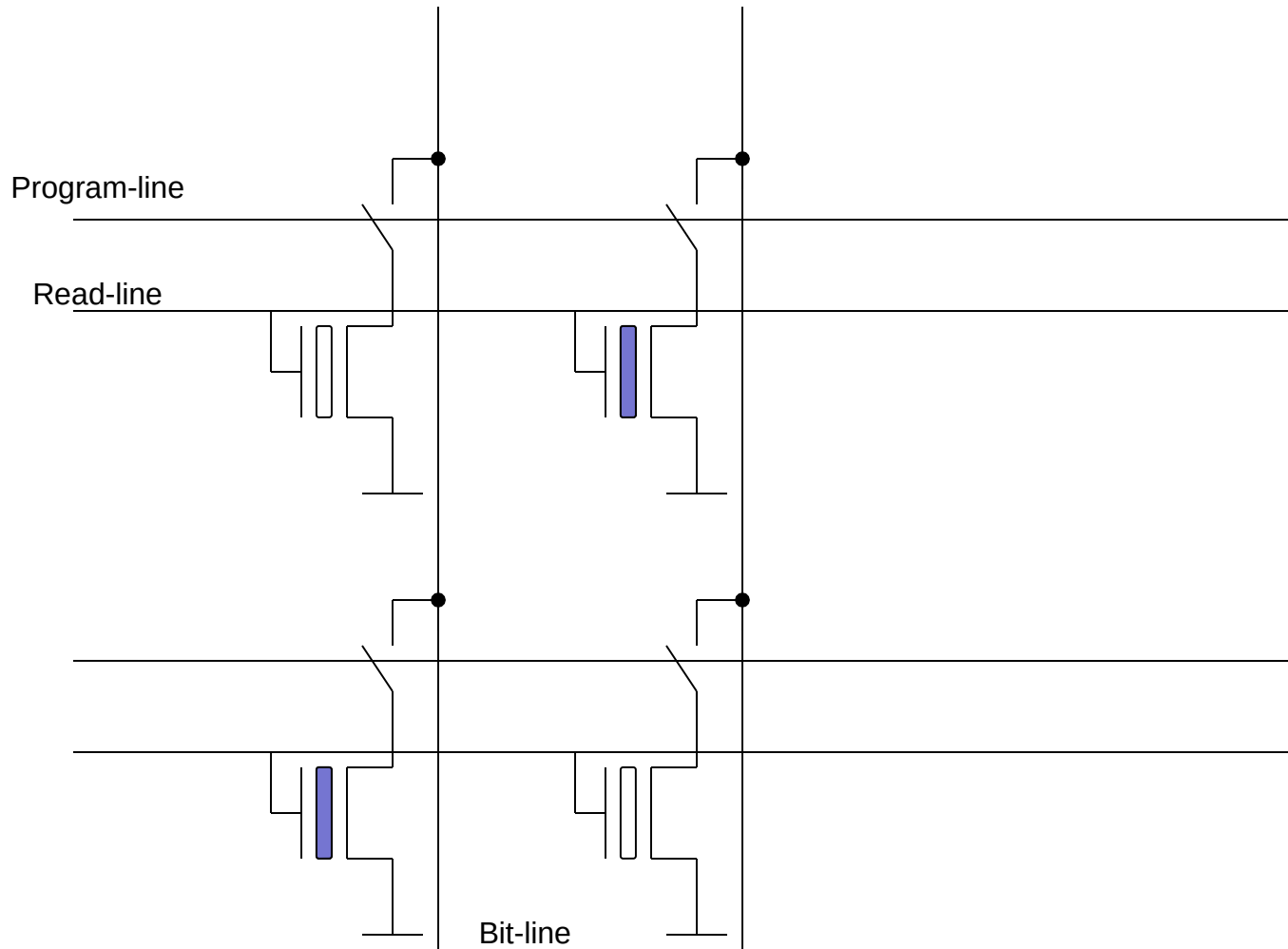
- EEPROM (erase and program based on tunnel effect)



- EEPROM (erase and program based on tunnel effect)



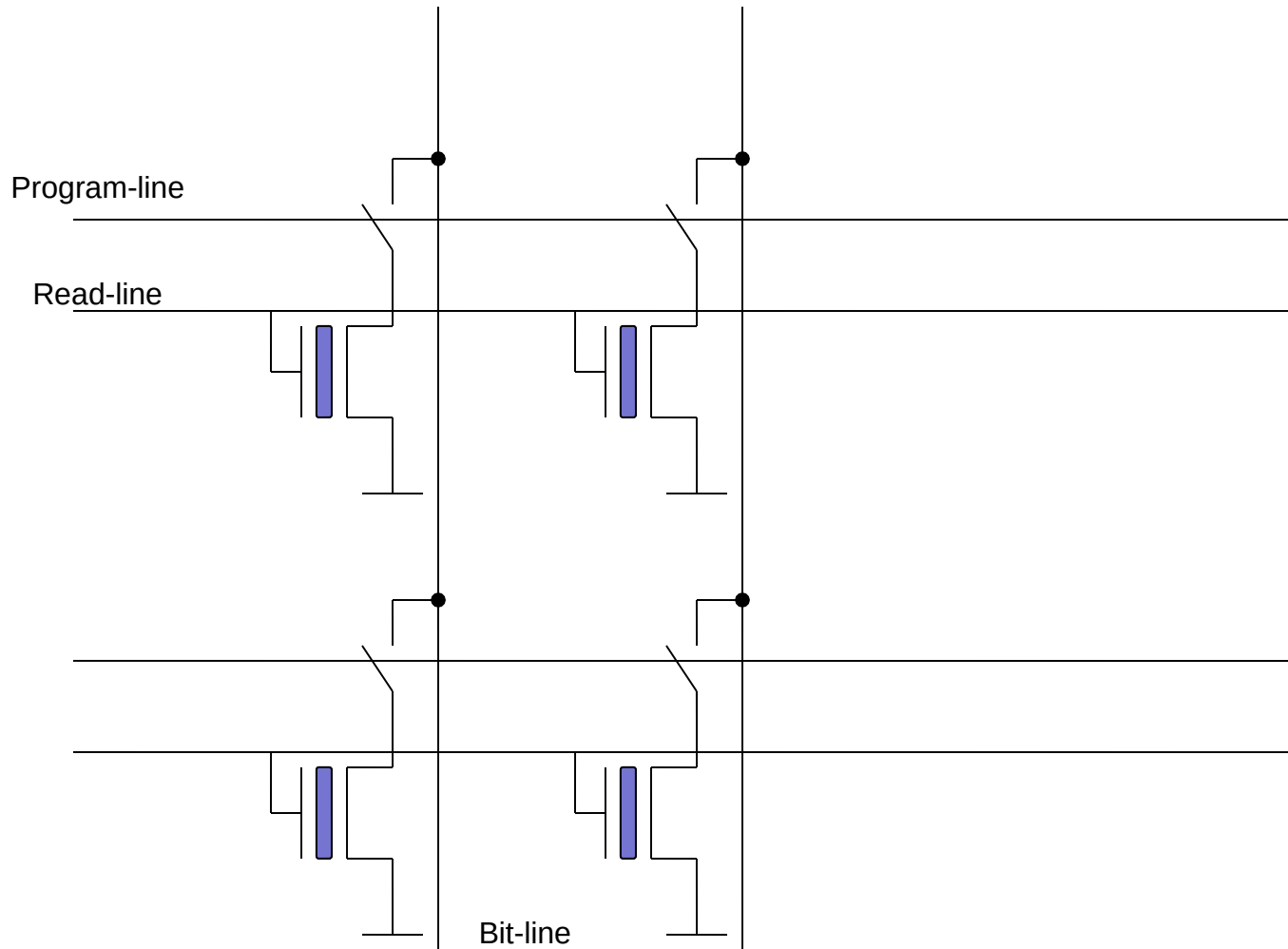
- EEPROM (erase and program based on tunnel effect)



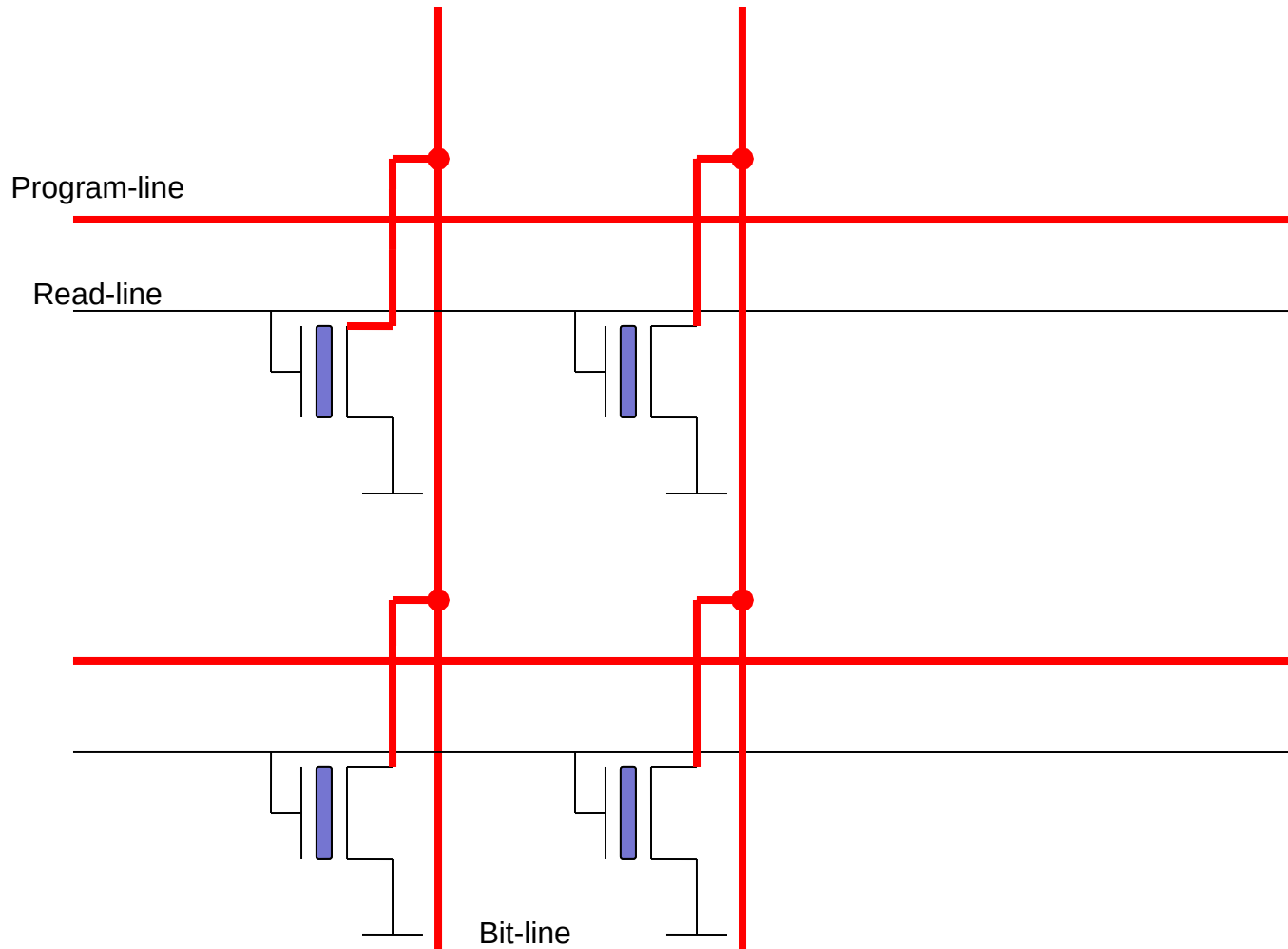
Variante 2

Erase based on tunnel effect, program based on hot carriers injection

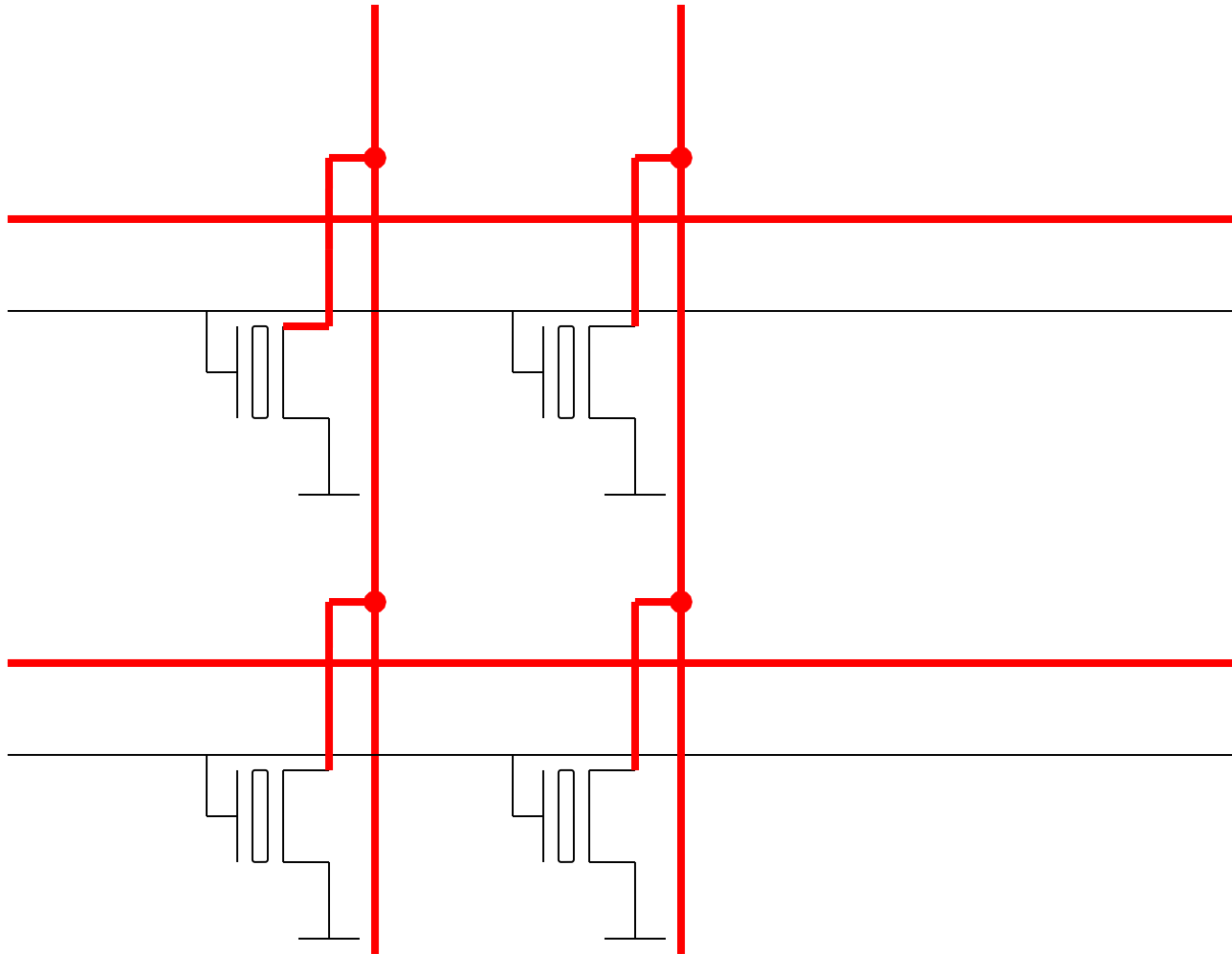
- EEPROM (erase based on tunnel effect, program based on hot carriers injection)



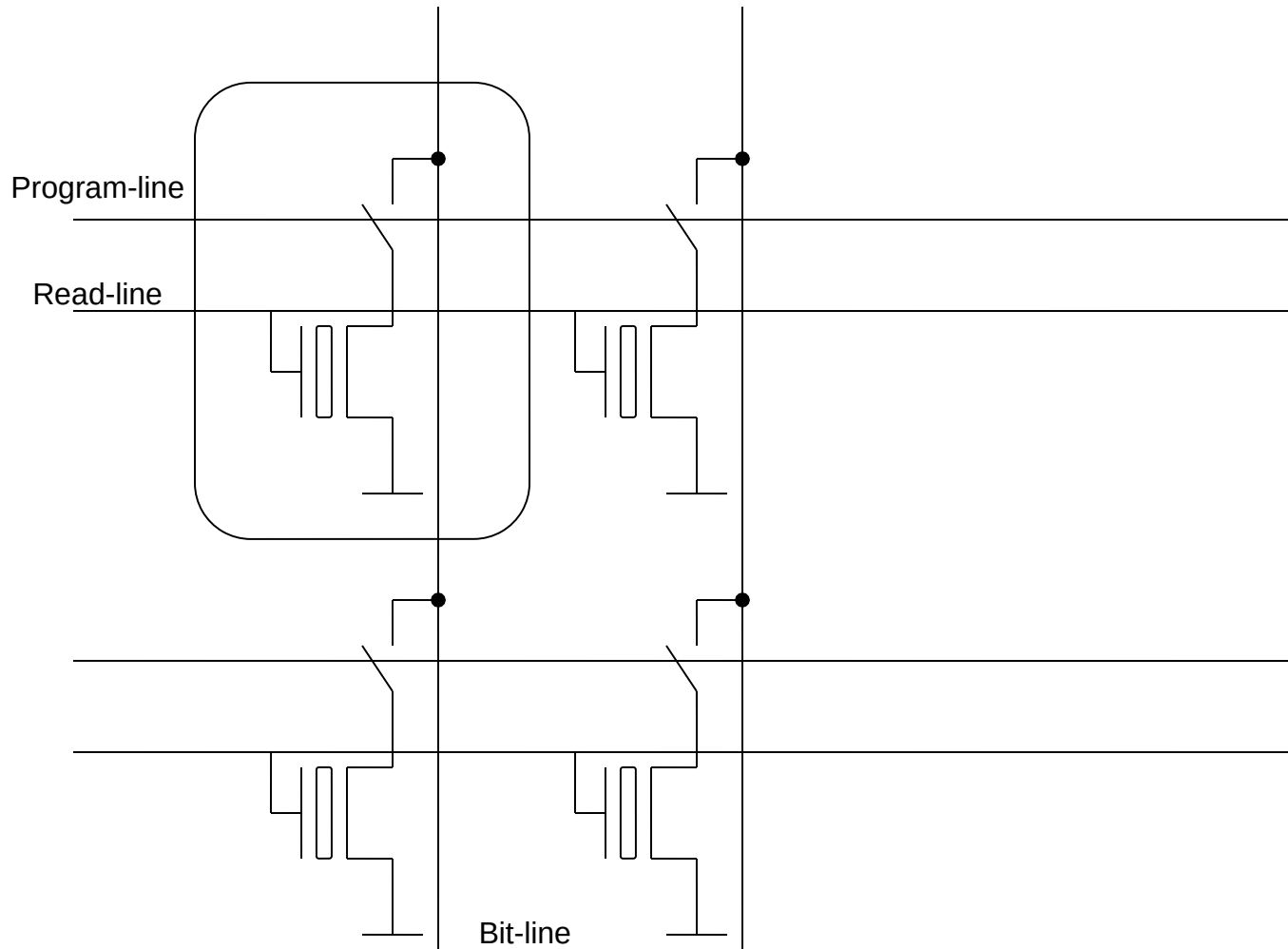
- EEPROM (erase based on tunnel effect, program based on hot carriers injection)



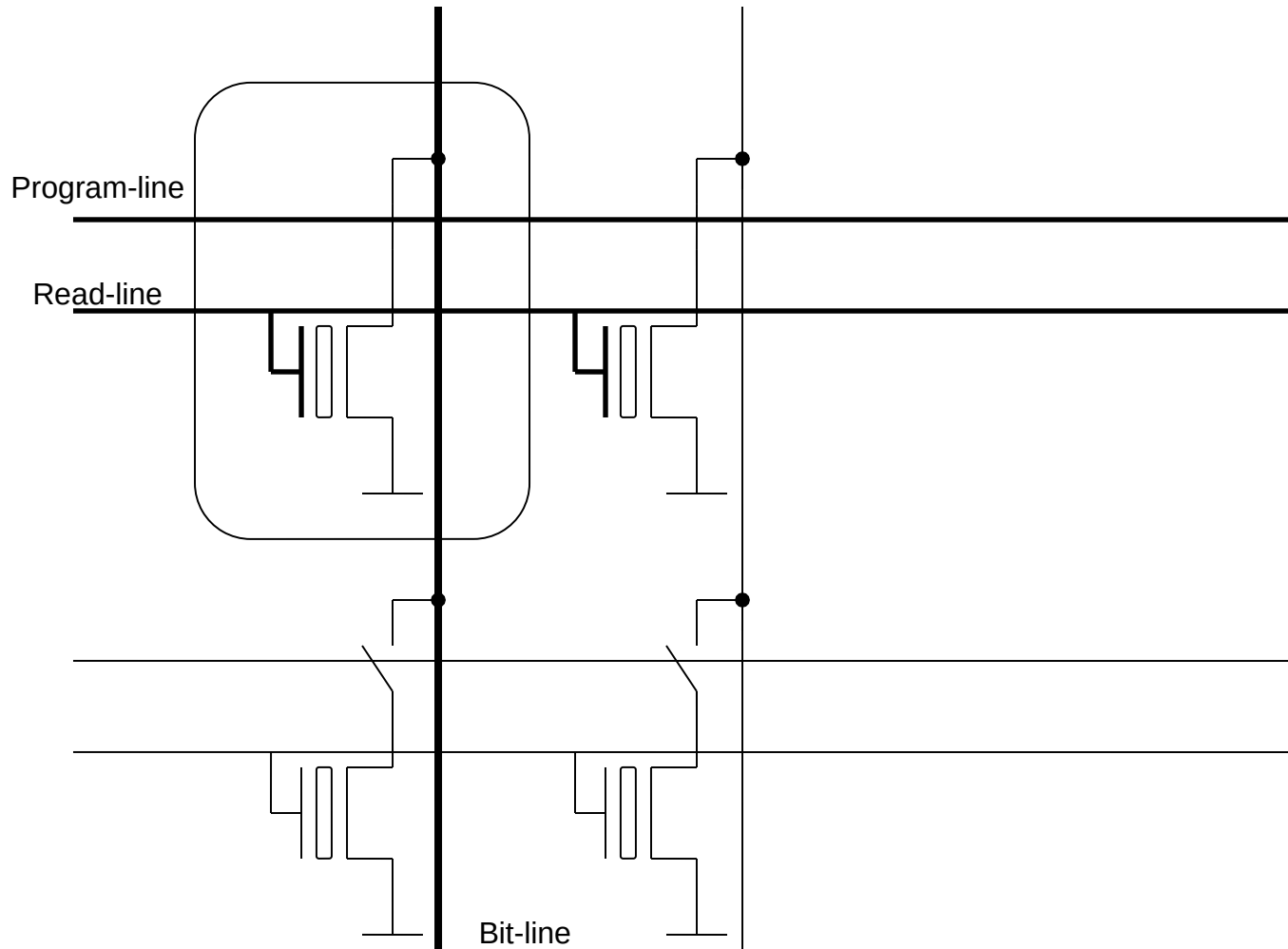
- EEPROM (erase based on tunnel effect, program based on hot carriers injection)



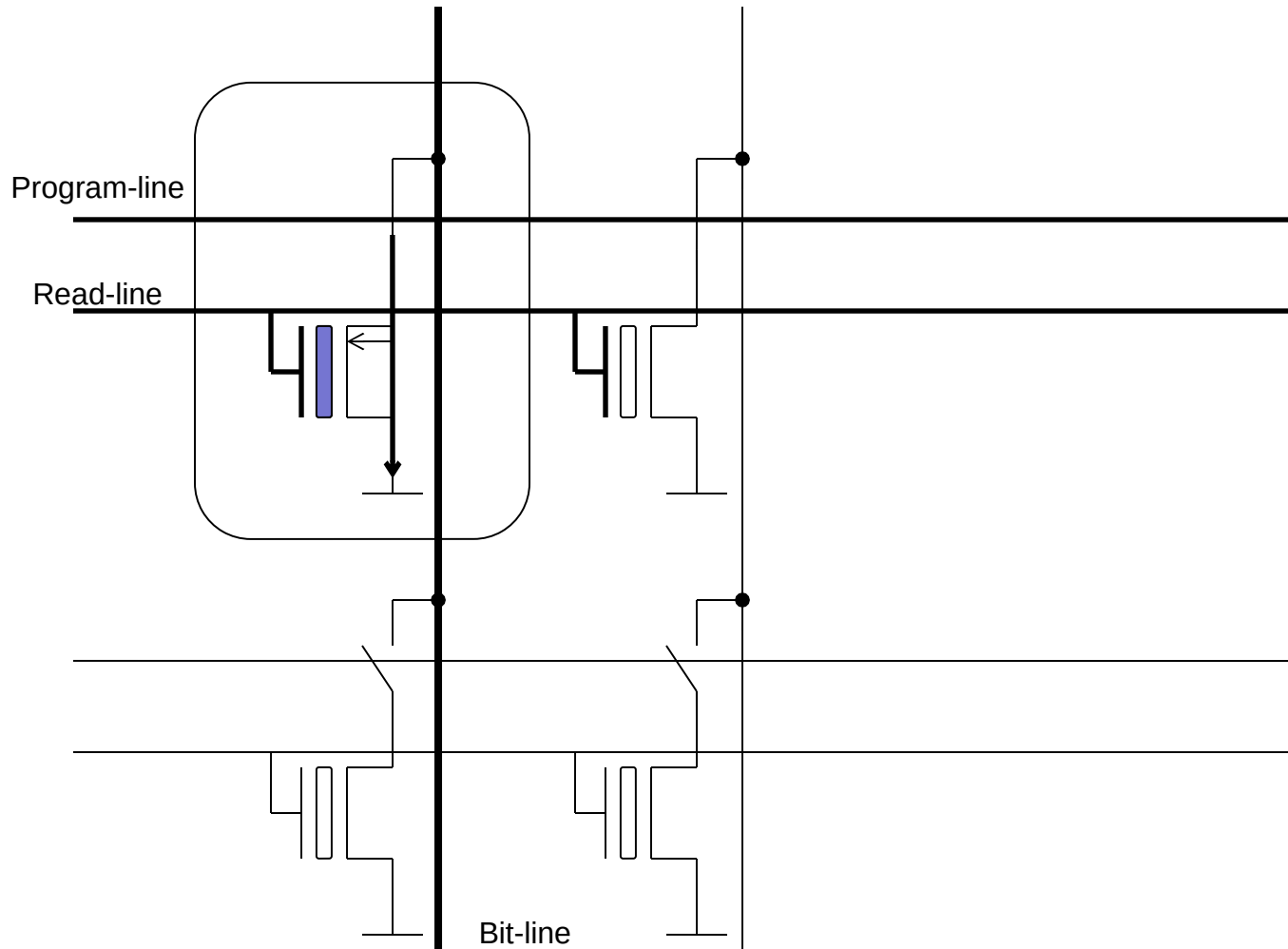
- EEPROM (erase based on tunnel effect, program based on hot carriers injection)



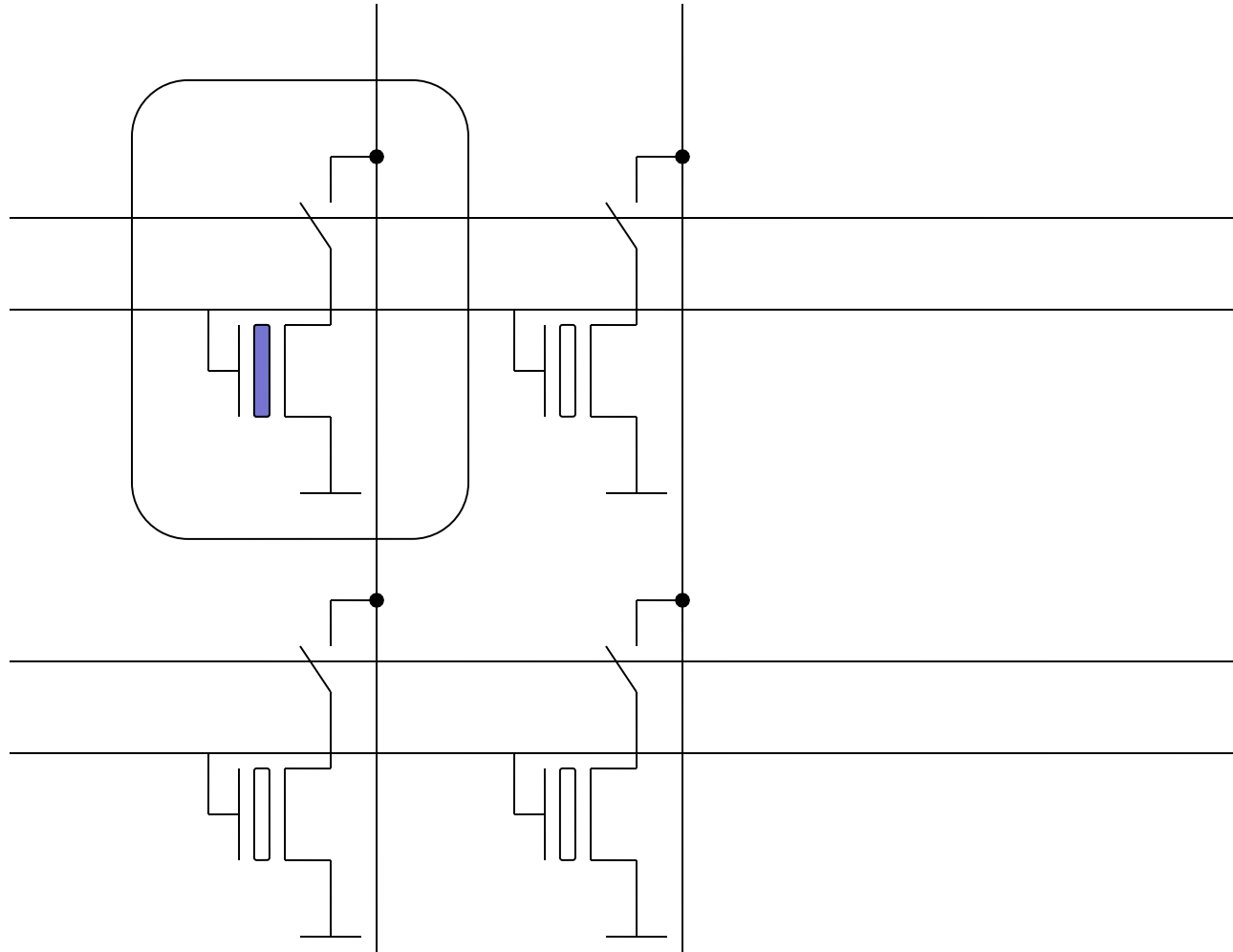
- EEPROM (erase based on tunnel effect, program based on hot carriers injection)



- EEPROM (erase based on tunnel effect, program based on hot carriers injection)



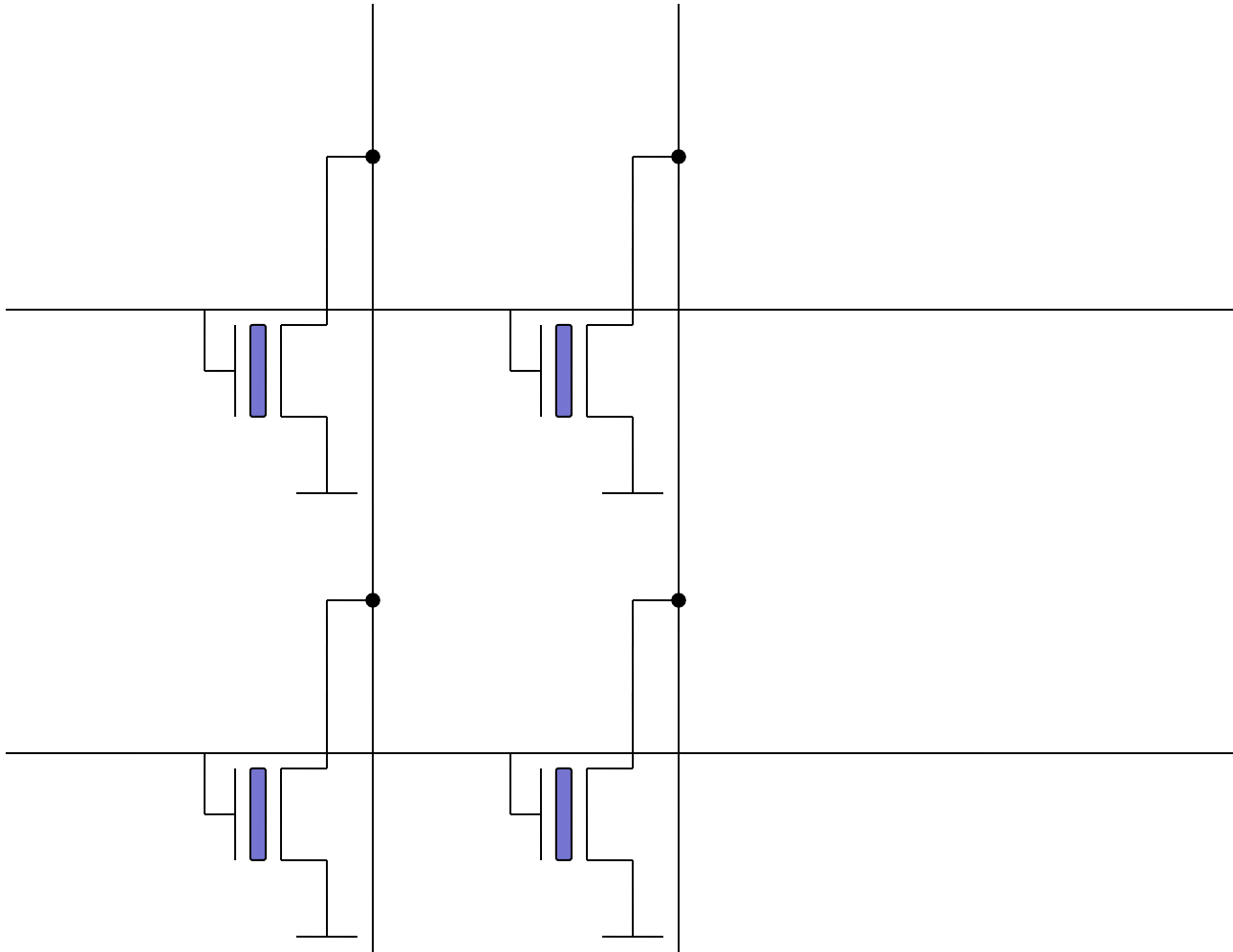
- EEPROM (erase based on tunnel effect, program based on hot carriers injection)



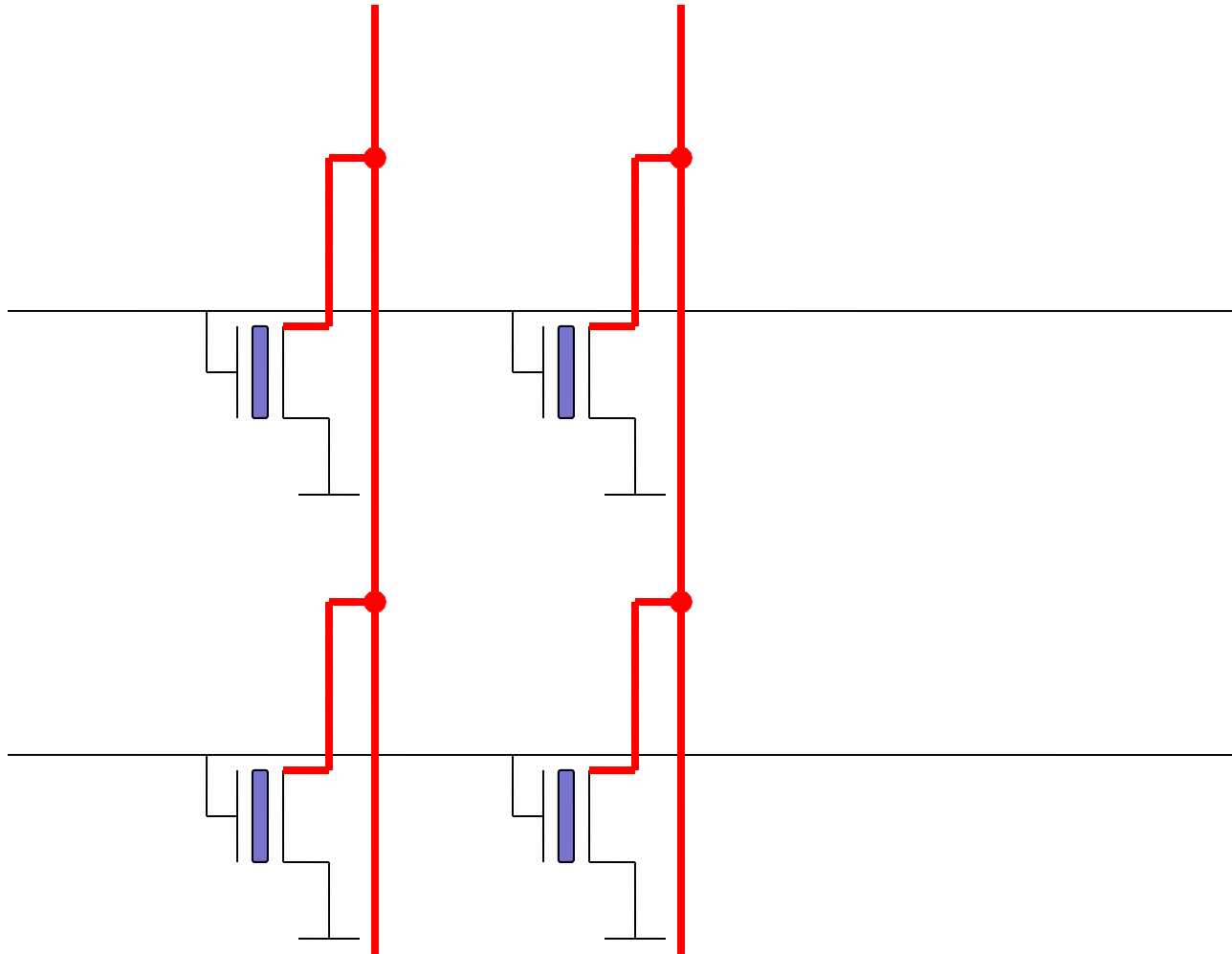
Variante 3

1 Transistor EEPROM (erase based on tunnel effect,
program based on hot carriers injection)

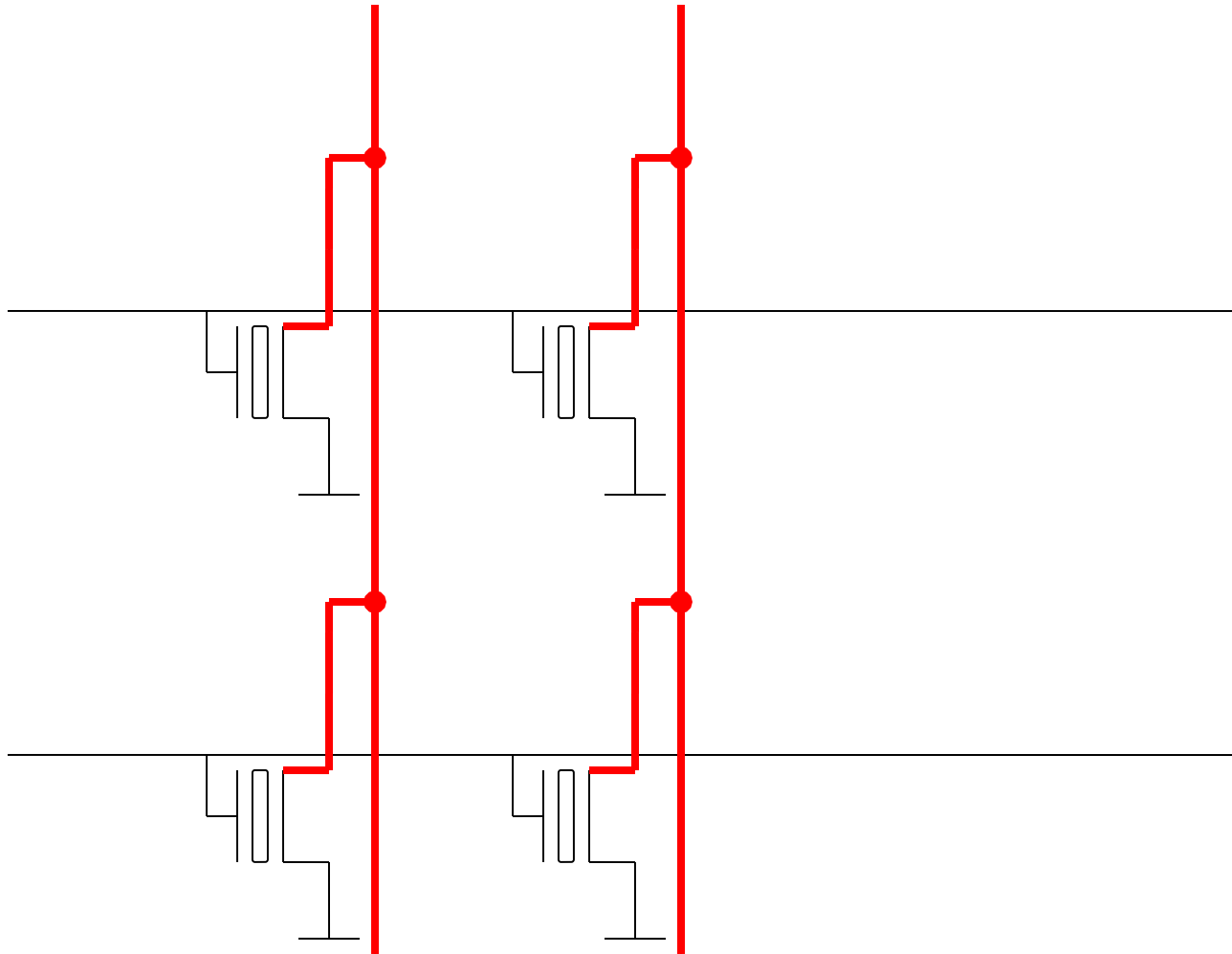
- 1 Transistor EEPROM (erase based on tunnel effect, program based on hot carriers injection)



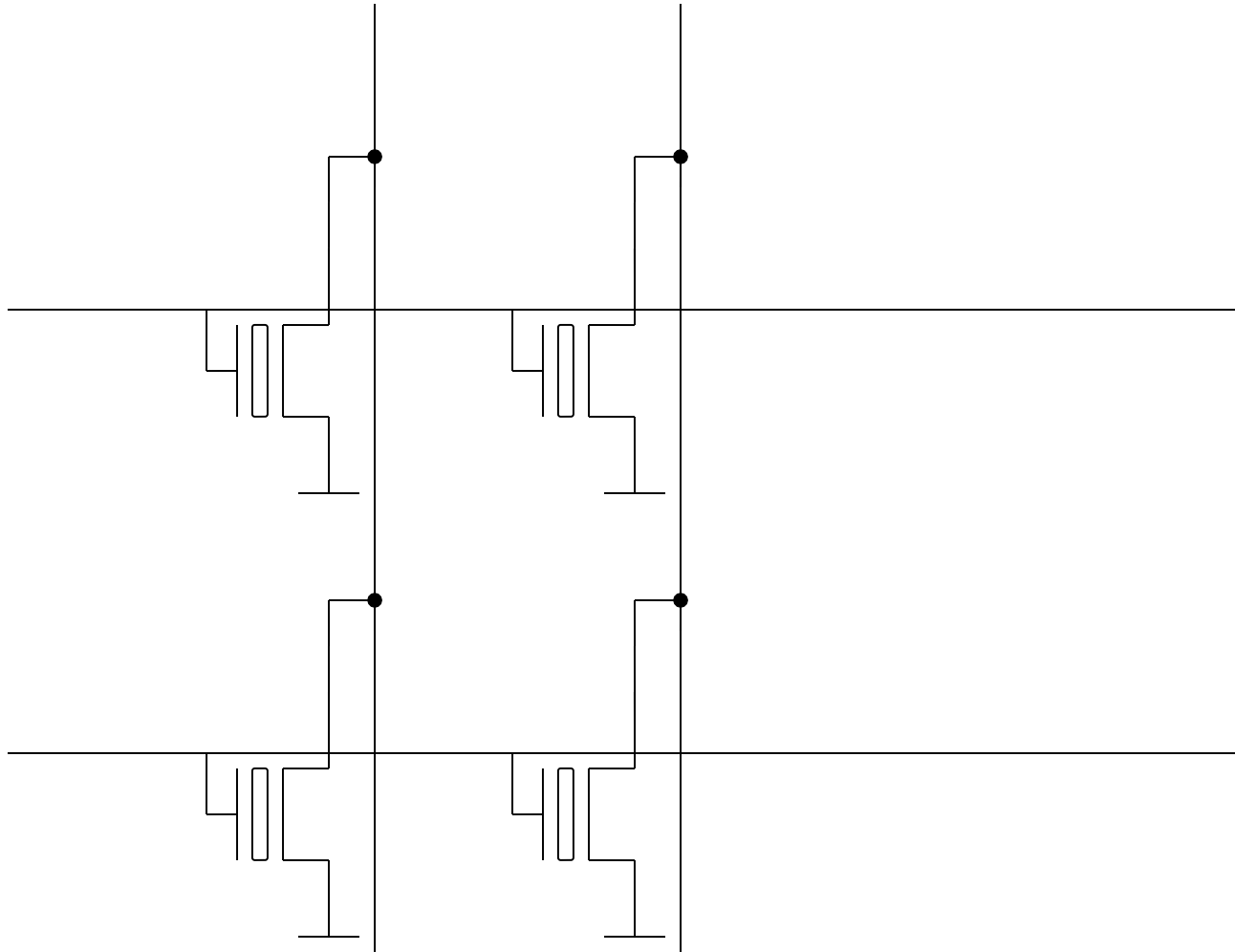
- 1 Transistor EEPROM (erase based on tunnel effect, program based on hot carriers injection)



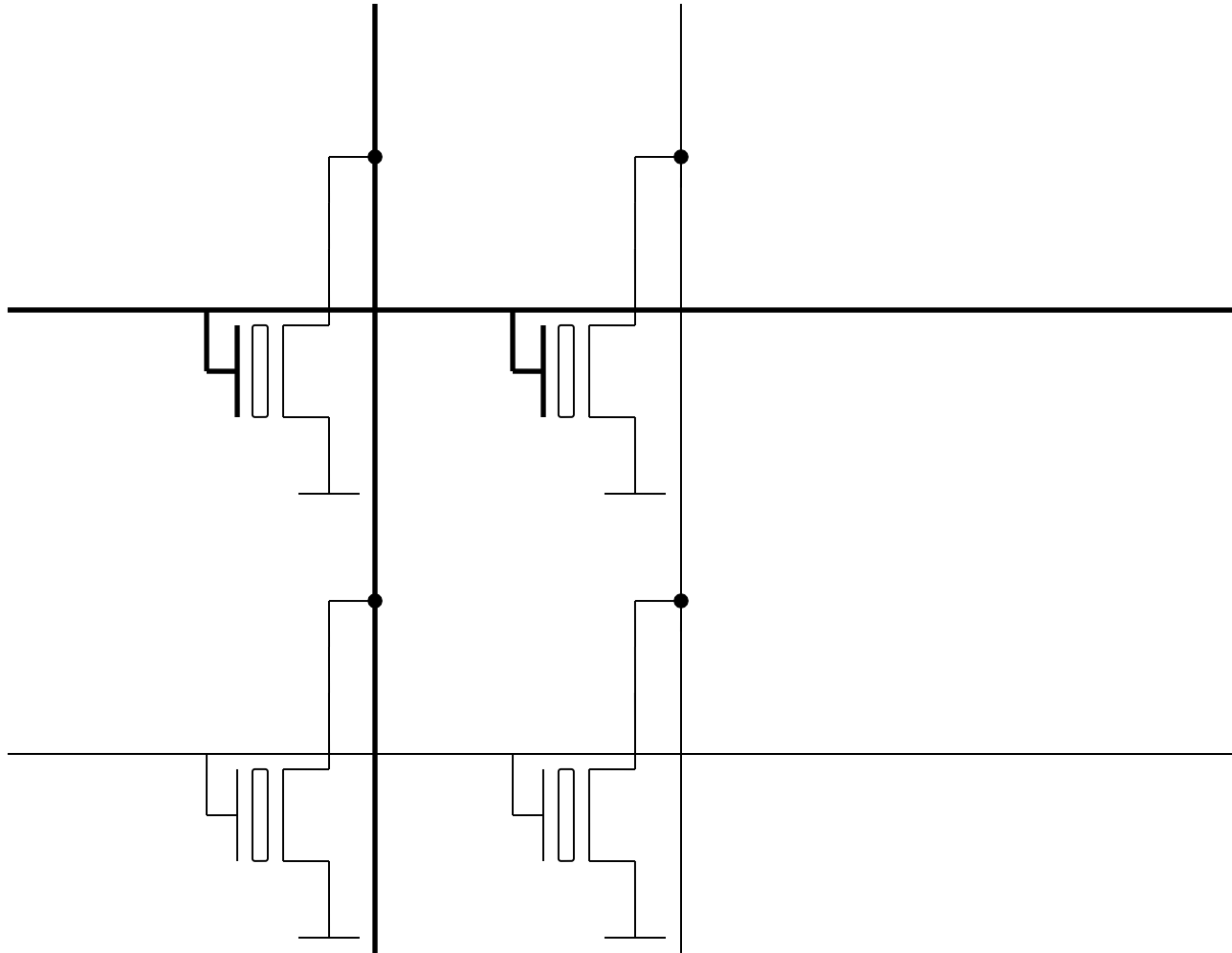
- 1 Transistor EEPROM (erase based on tunnel effect, program based on hot carriers injection)



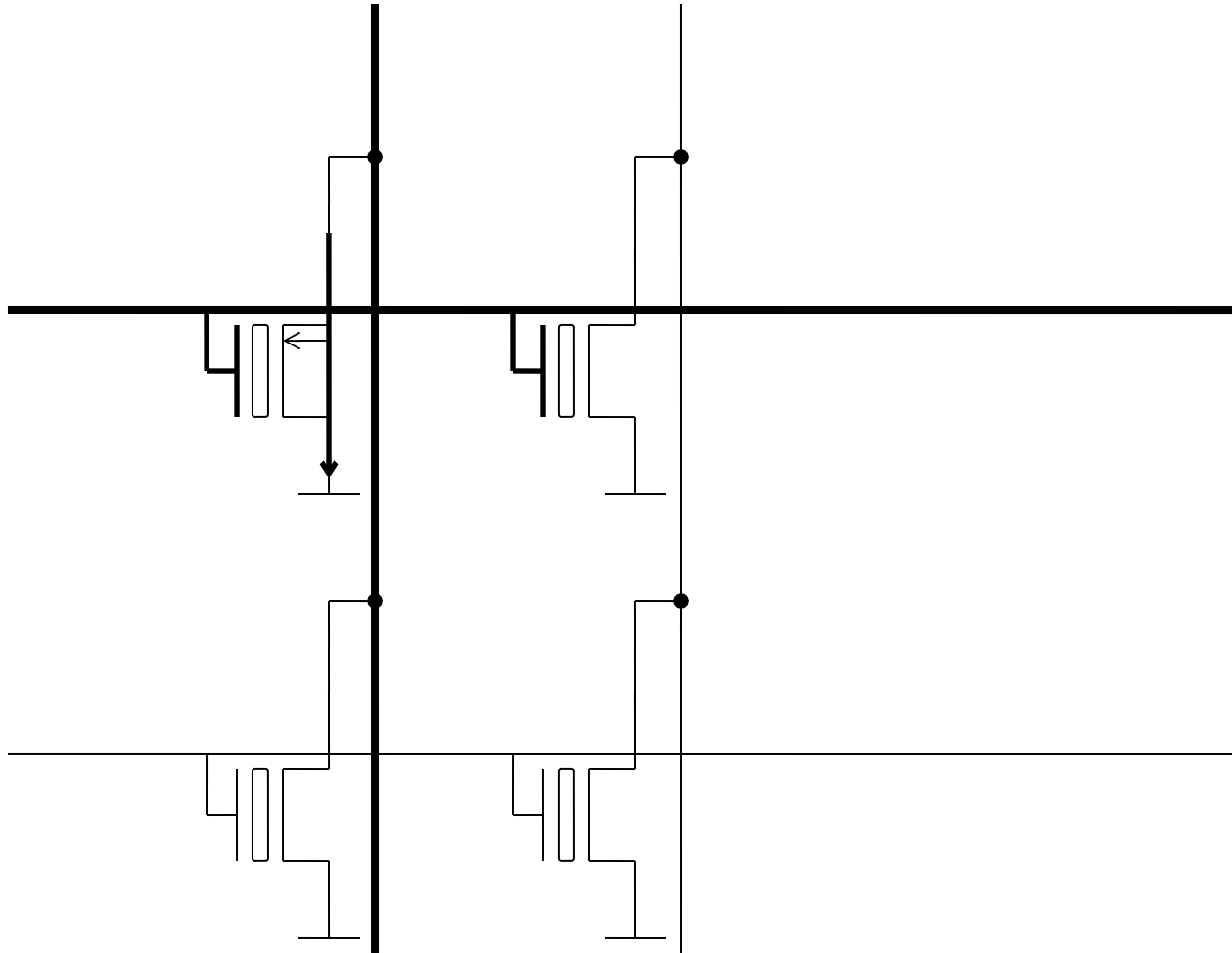
- 1 Transistor EEPROM (erase based on tunnel effect, program based on hot carriers injection)



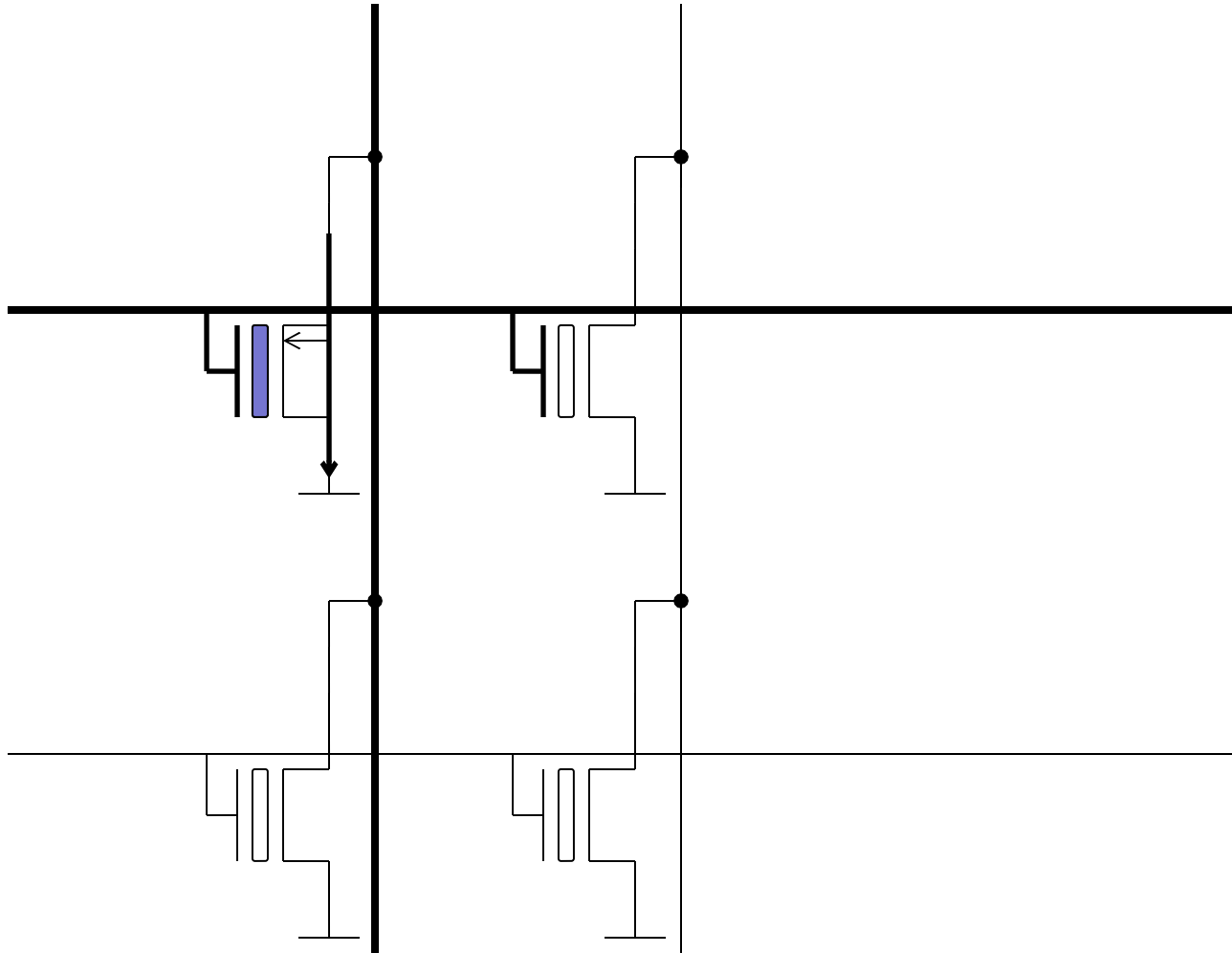
- 1 Transistor EEPROM (erase based on tunnel effect, program based on hot carriers injection)



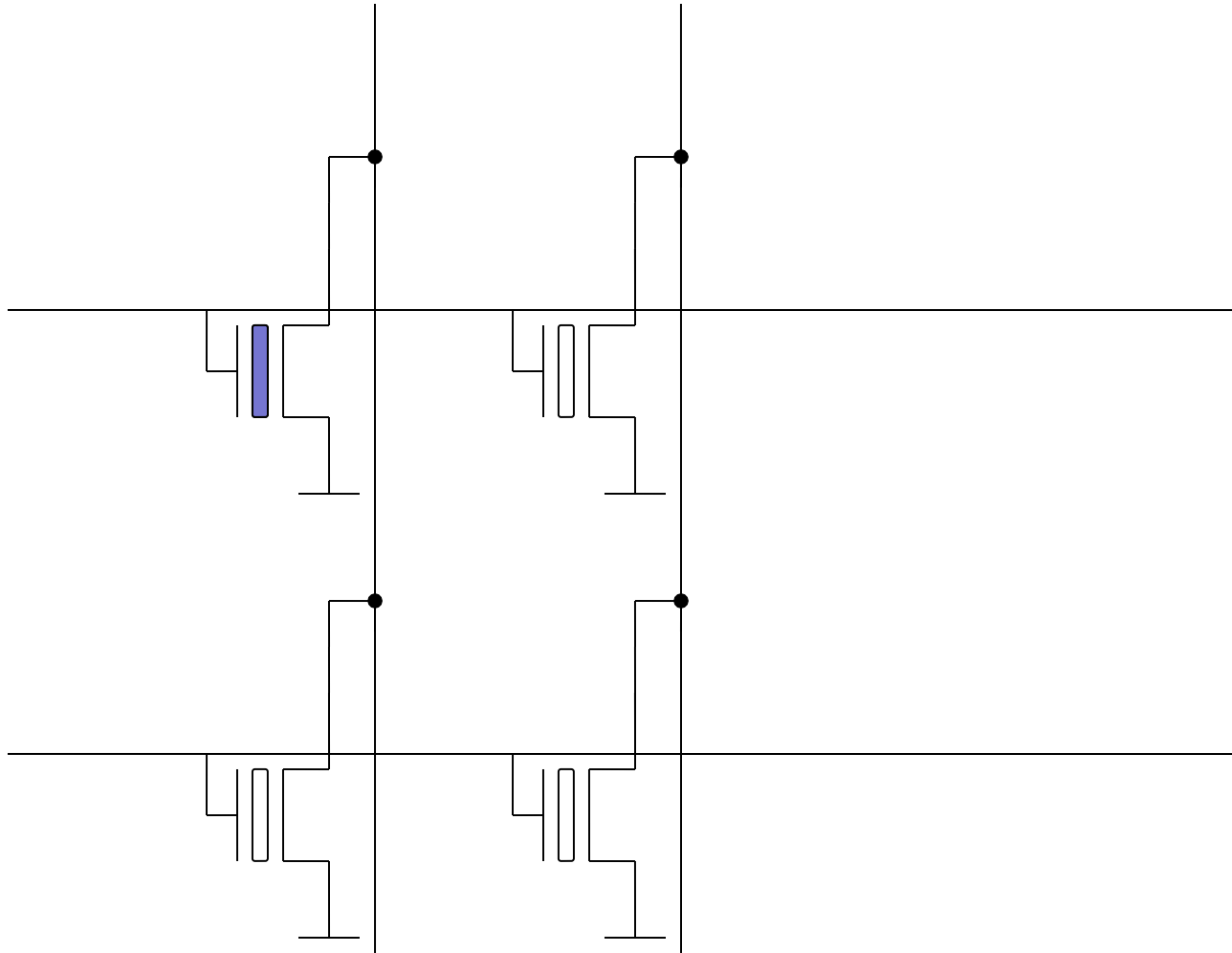
- 1 Transistor EEPROM (erase based on tunnel effect, program based on hot carriers injection)



- 1 Transistor EEPROM (erase based on tunnel effect, program based on hot carriers injection)

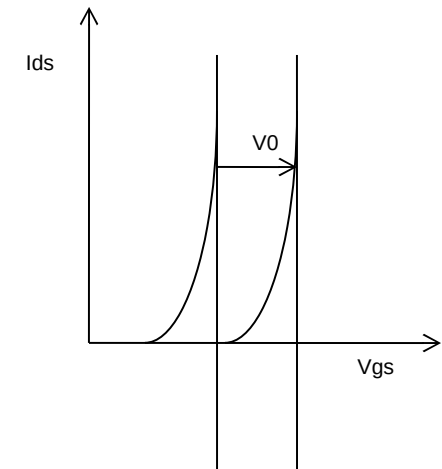
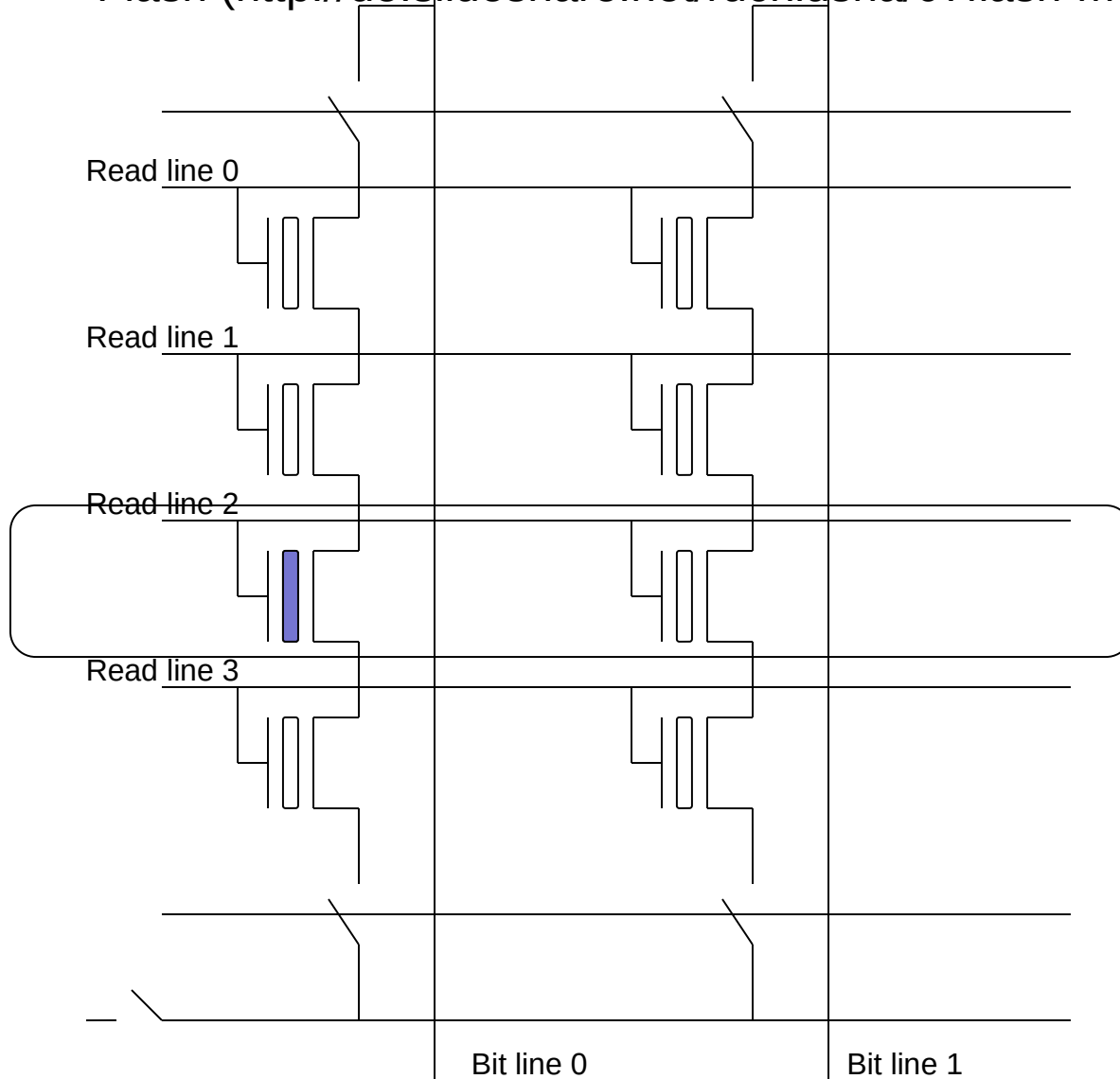


- 1 Transistor EEPROM (erase based on tunnel effect, program based on hot carriers injection)

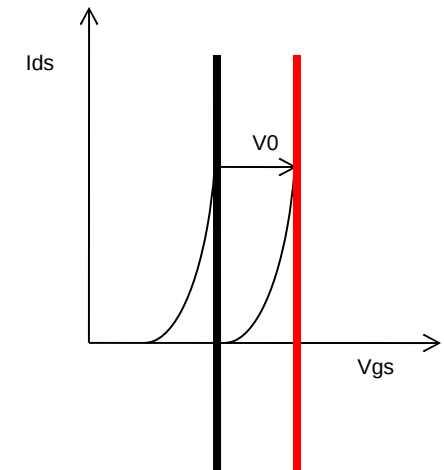
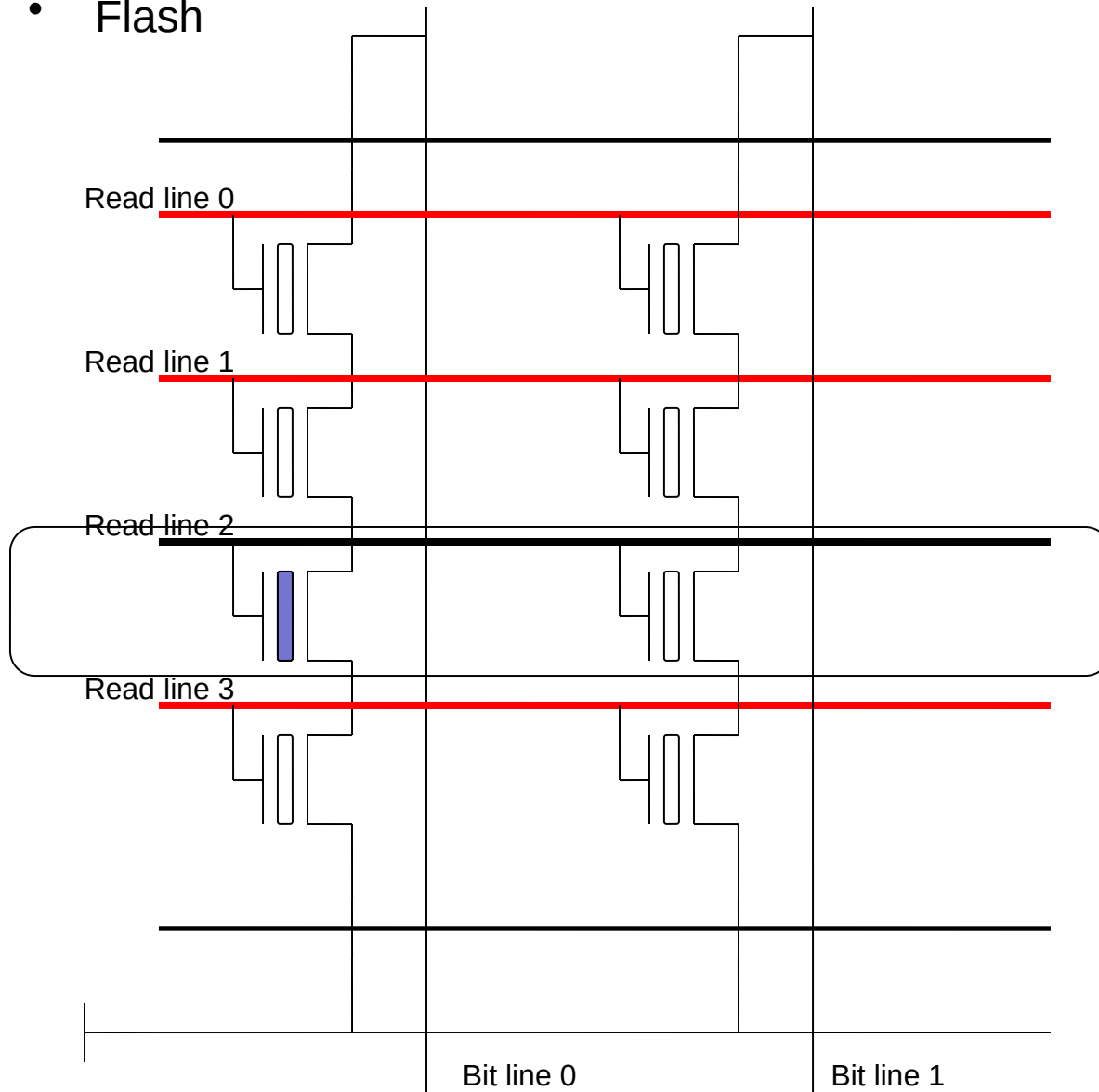


FLASH Speicher

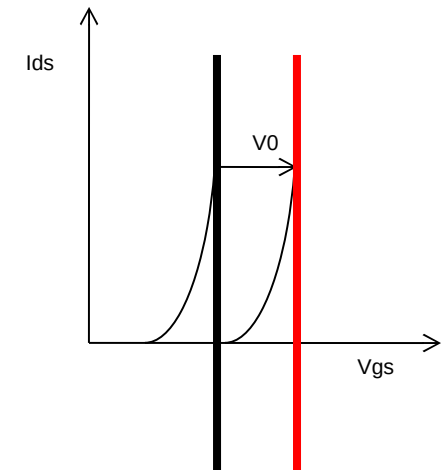
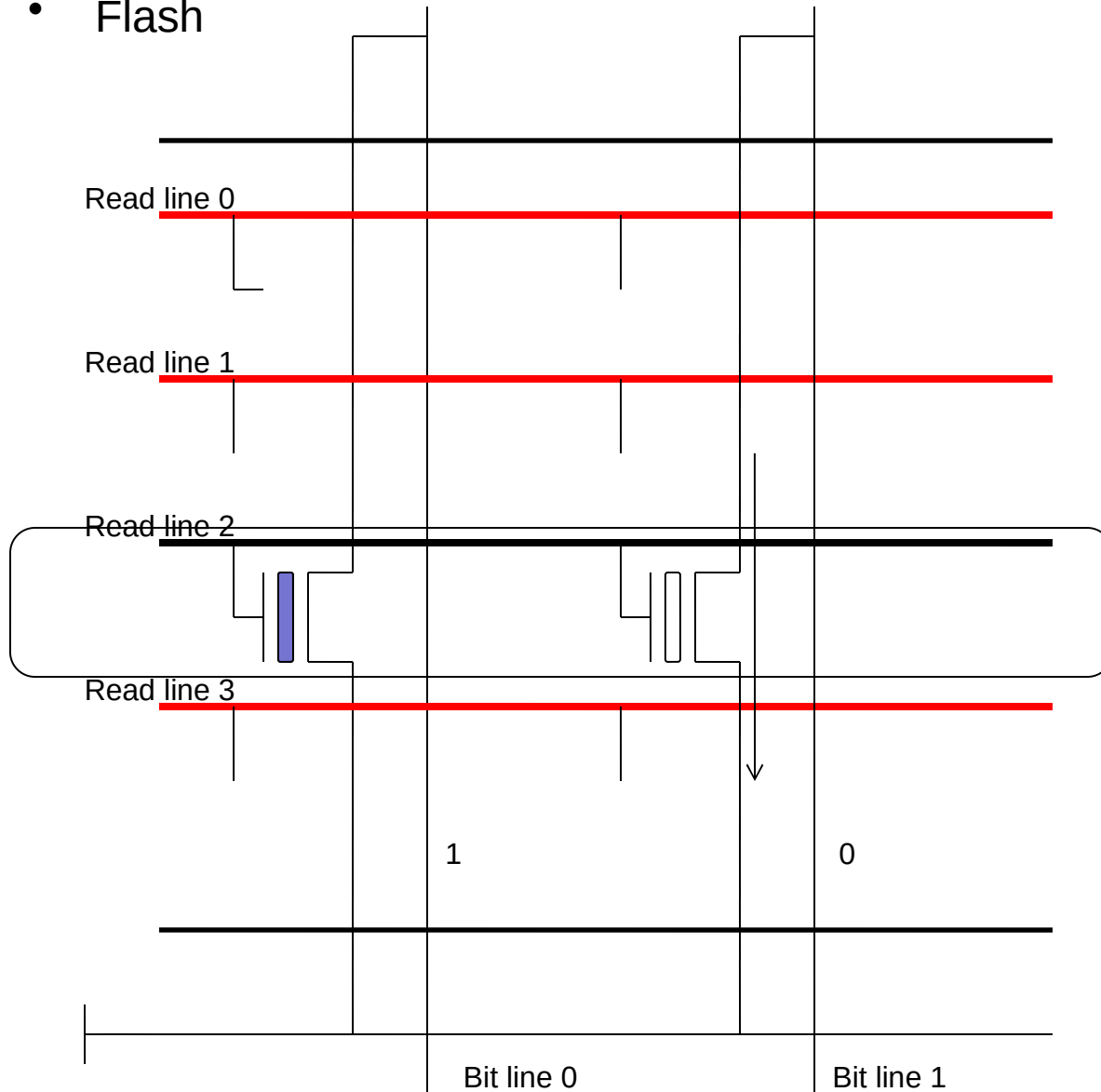
- Flash (<http://de.slideshare.net/ruchiusha/07flash-memory-technology>)



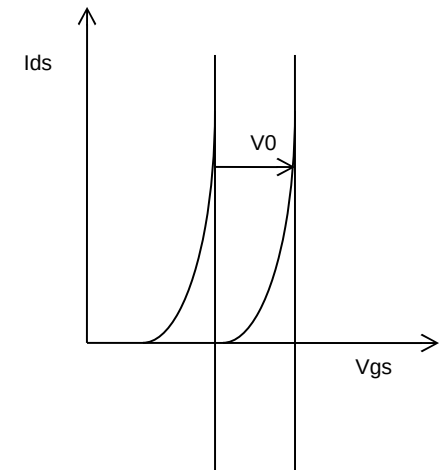
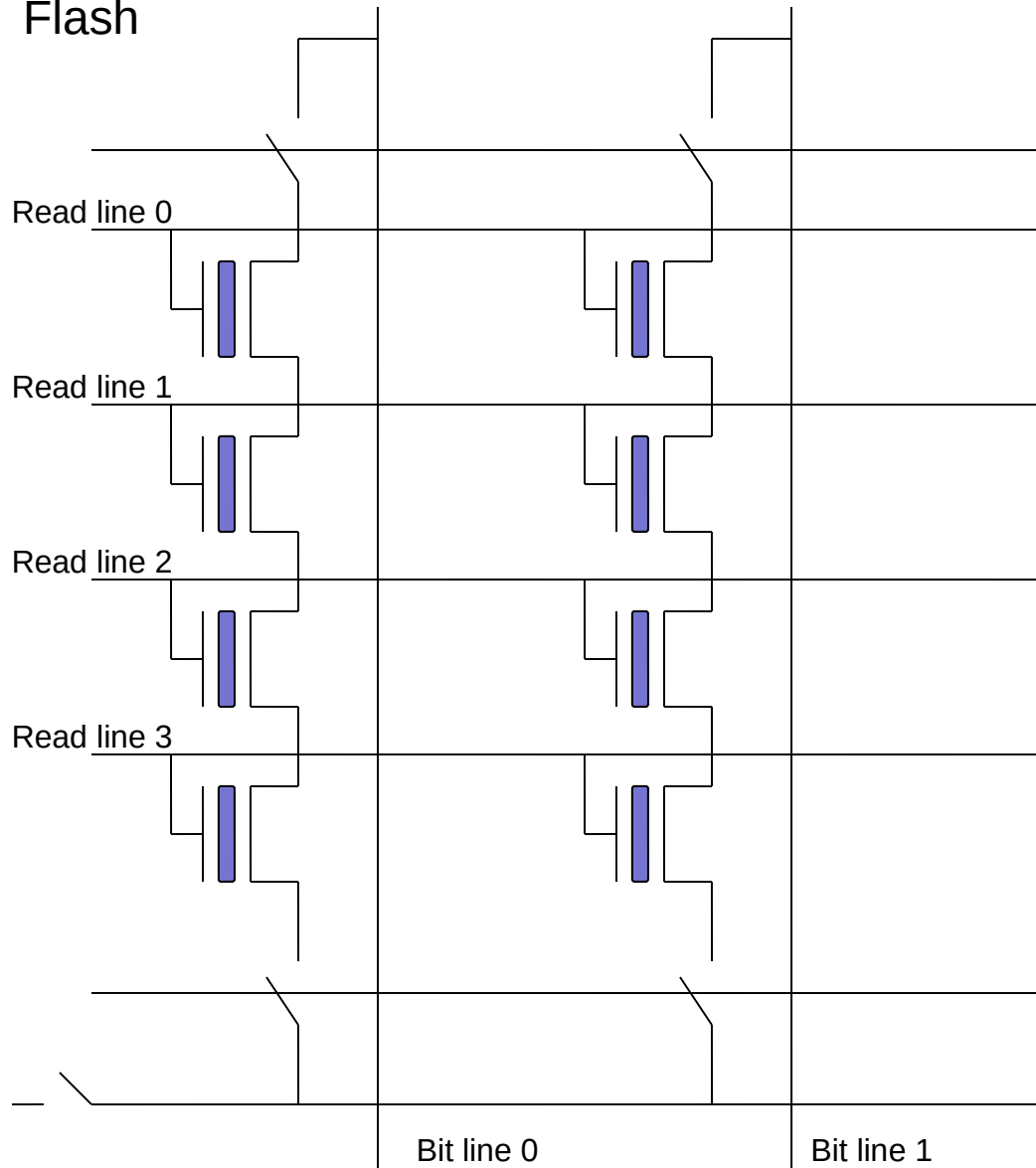
- Flash



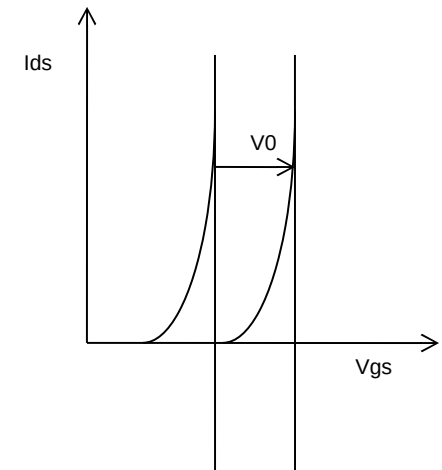
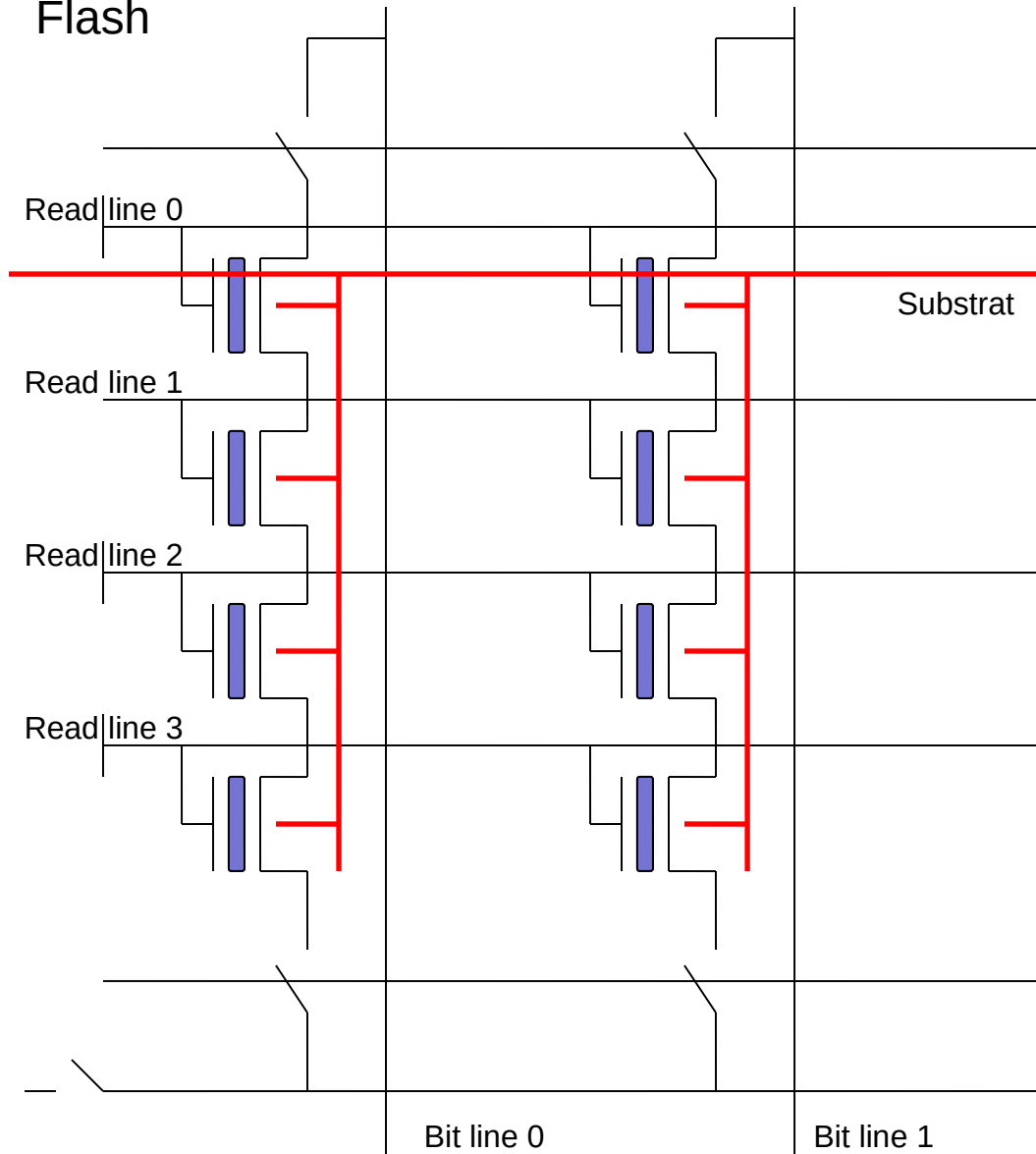
- Flash



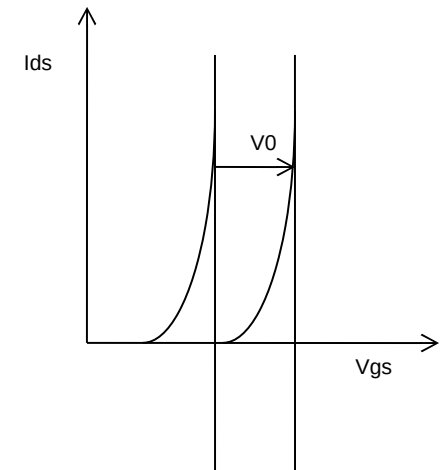
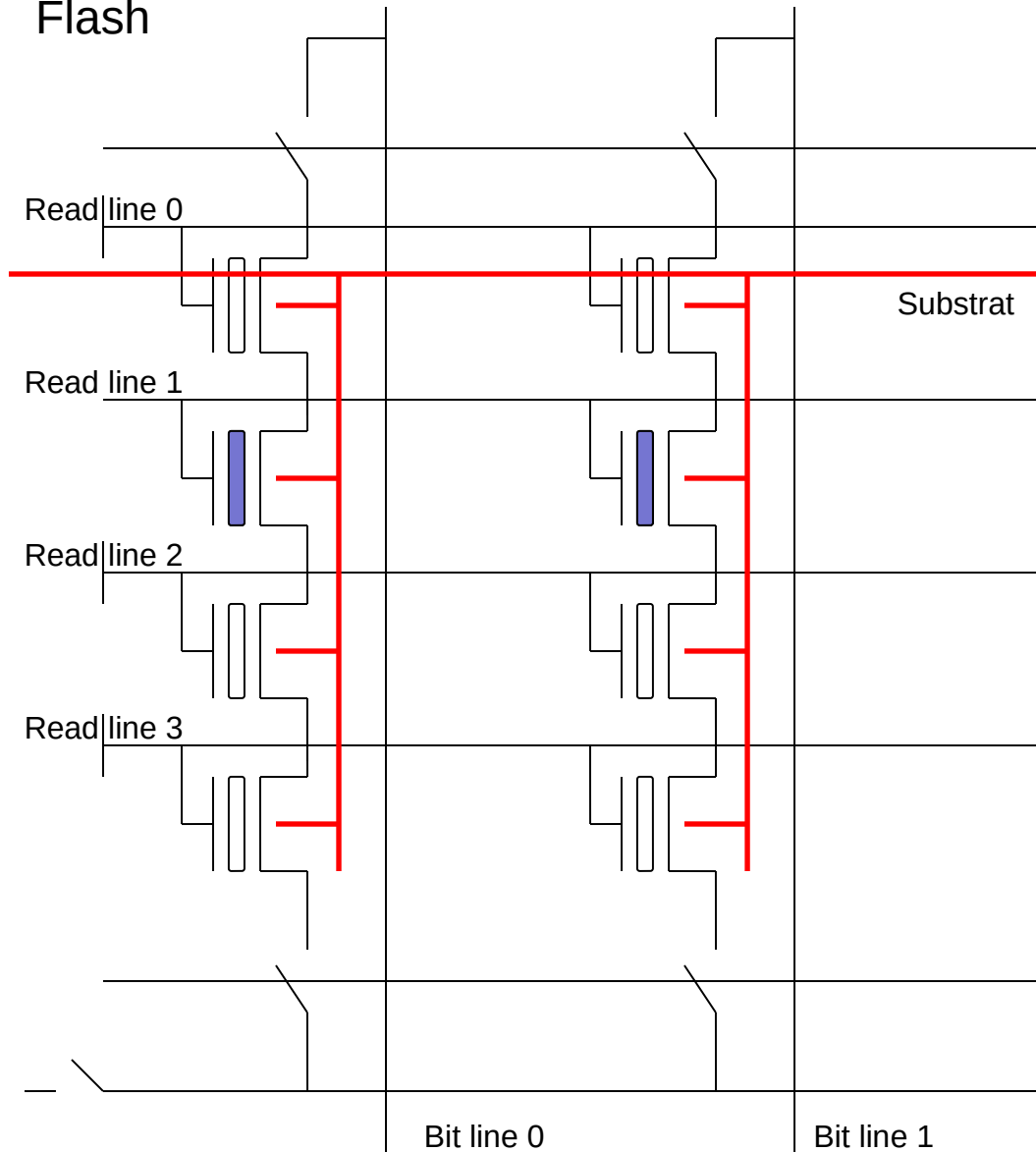
- Flash



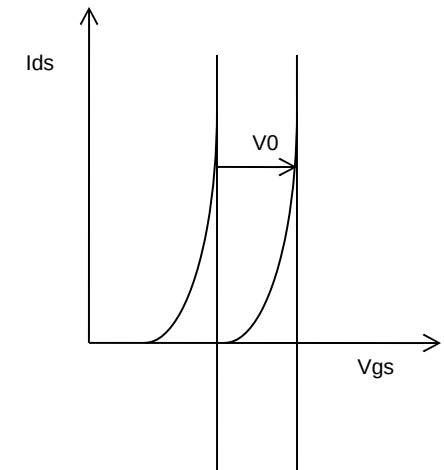
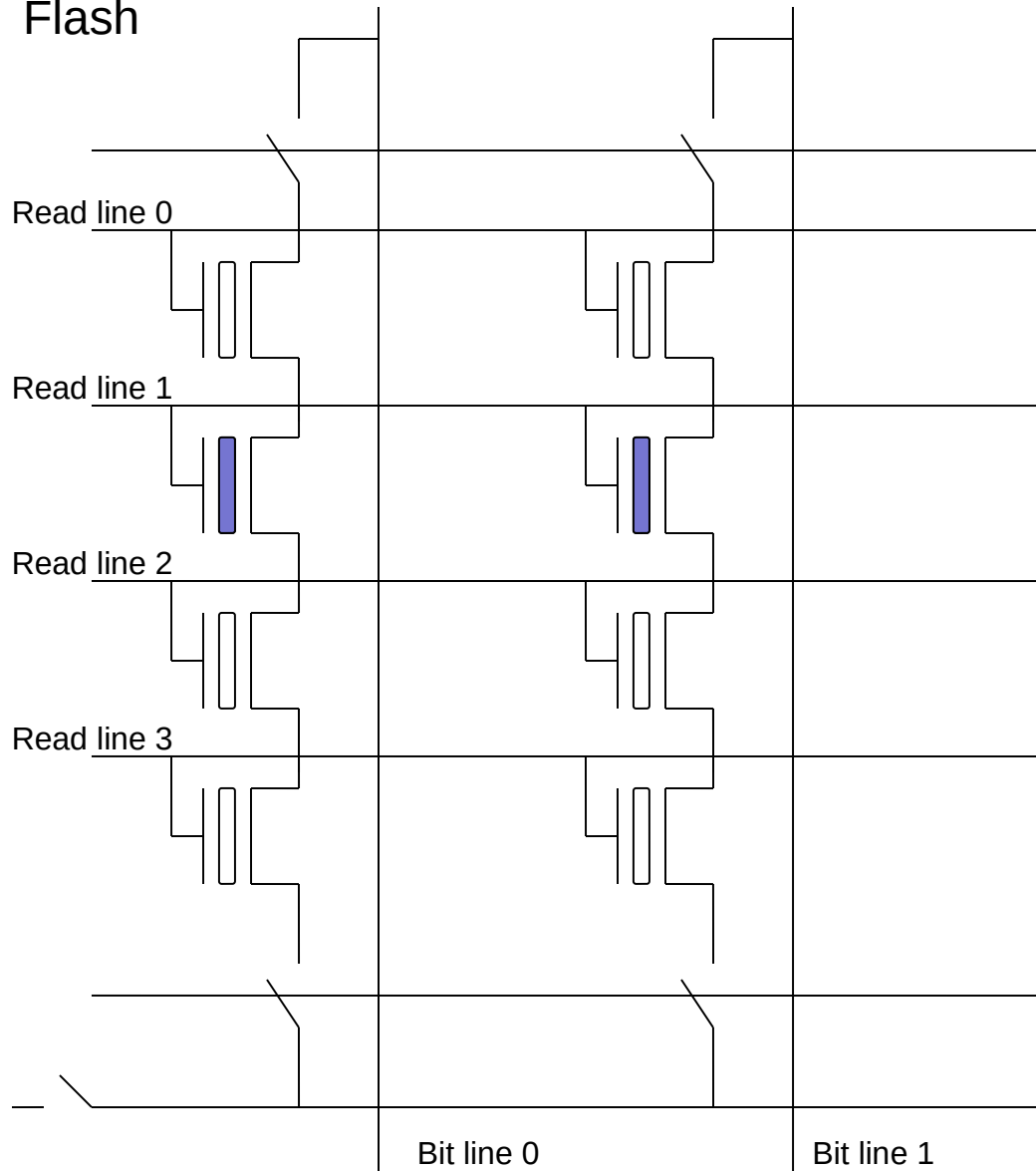
- Flash



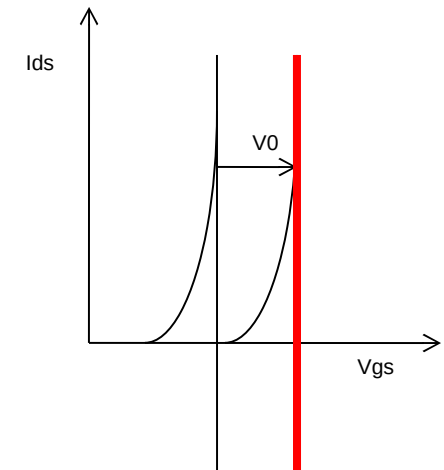
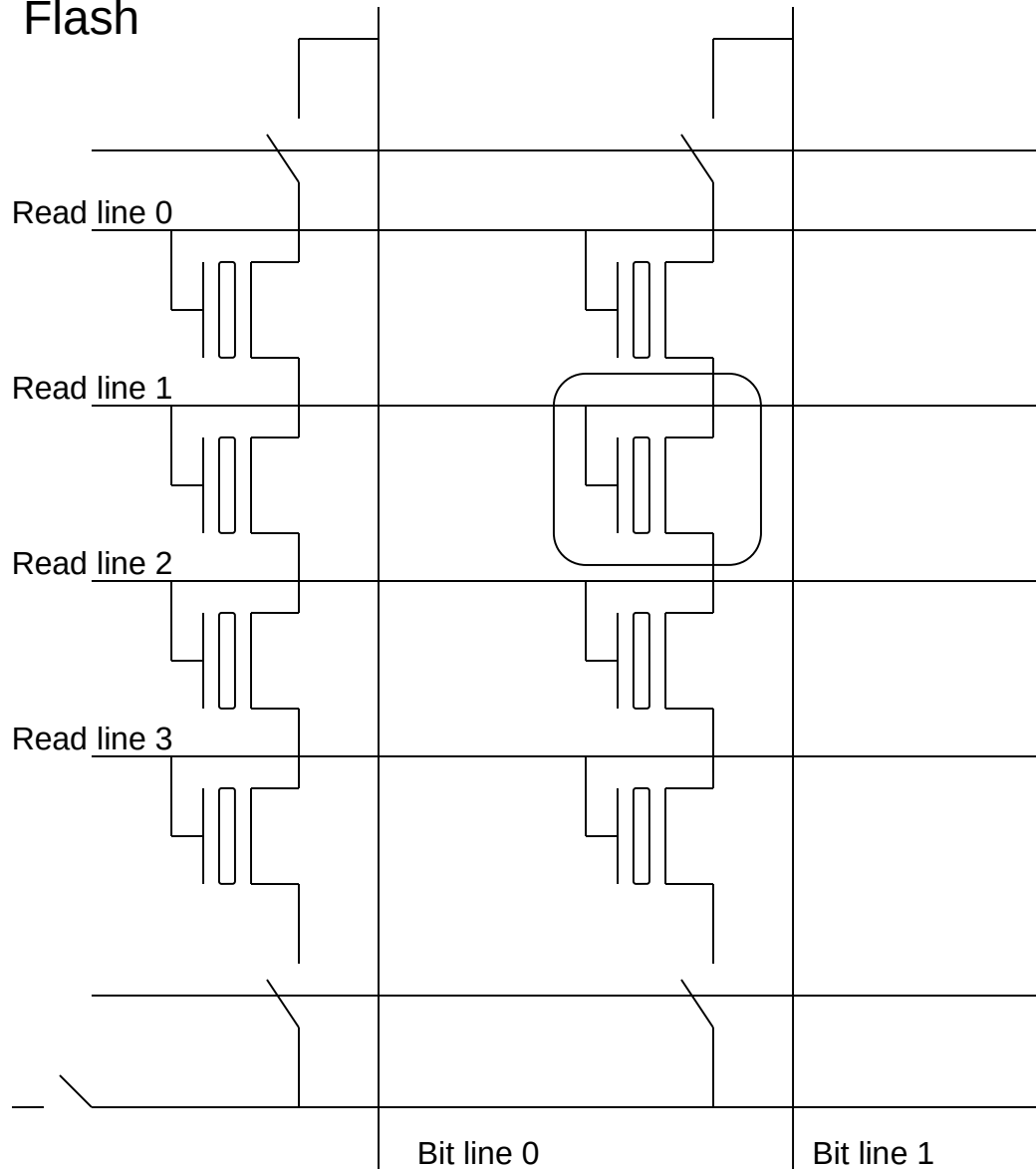
- Flash



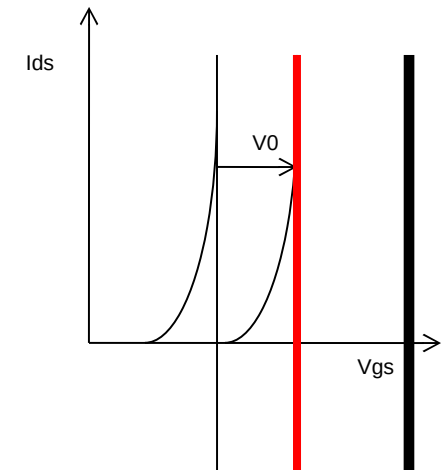
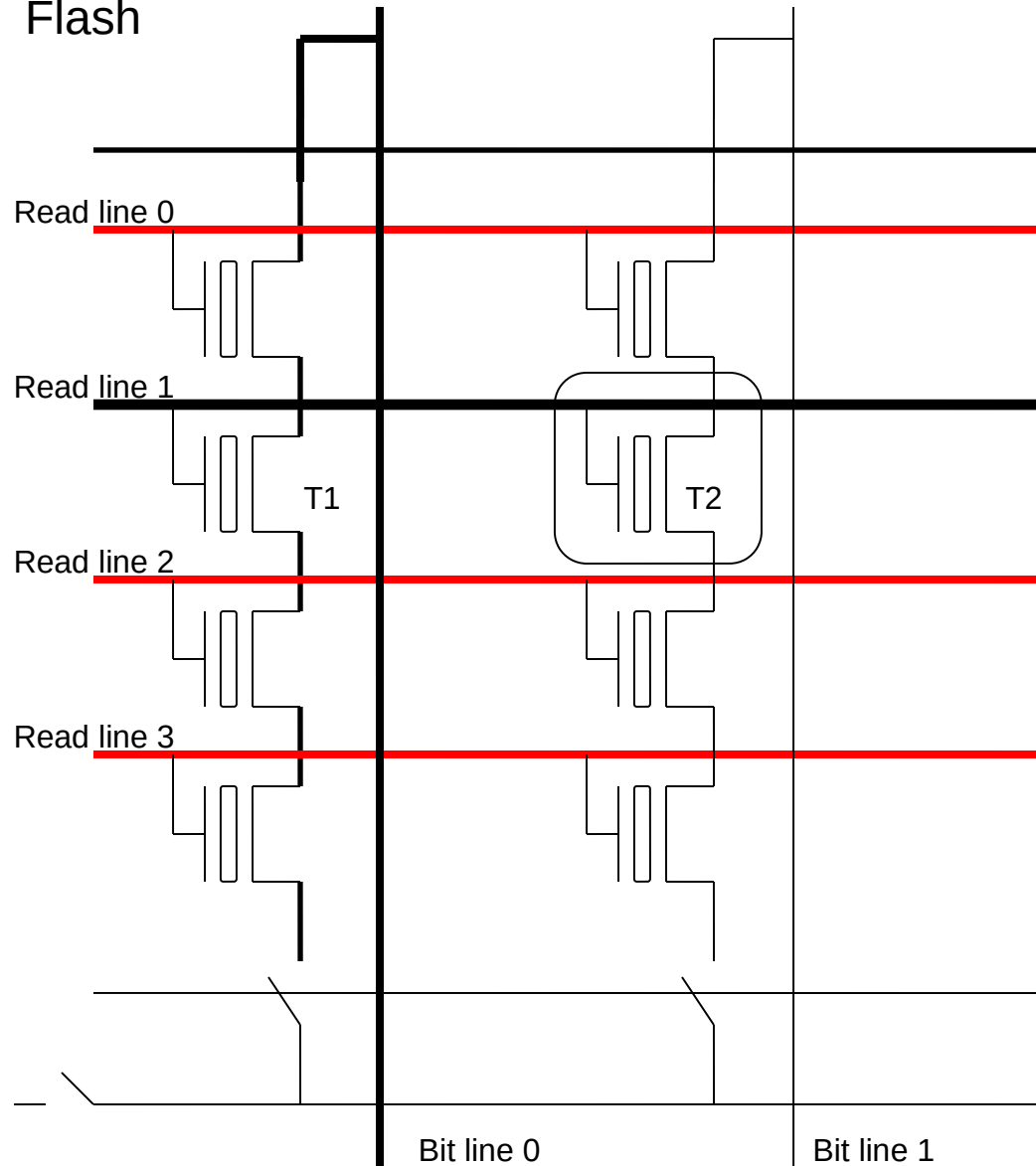
- Flash



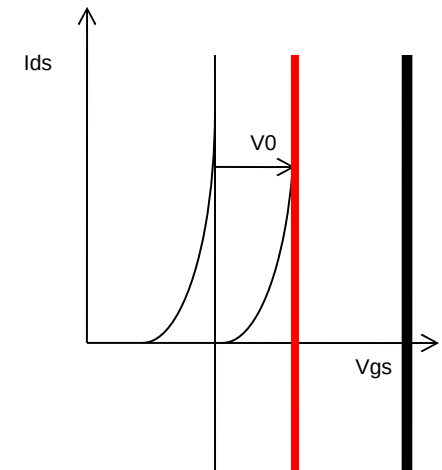
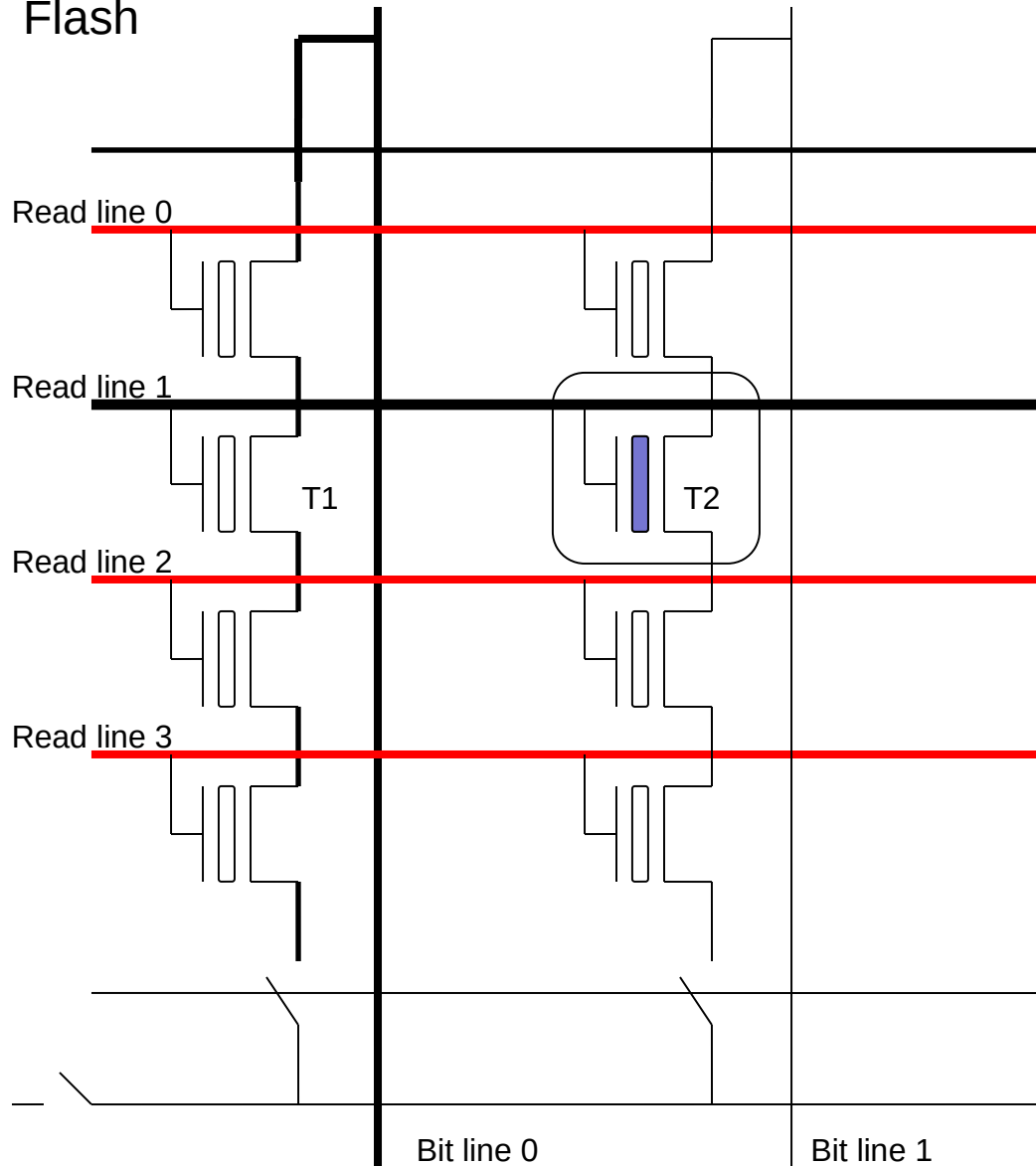
- Flash



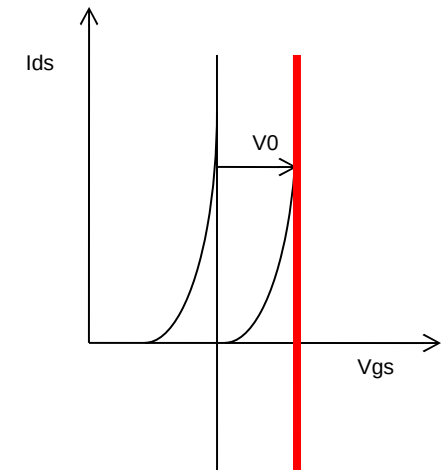
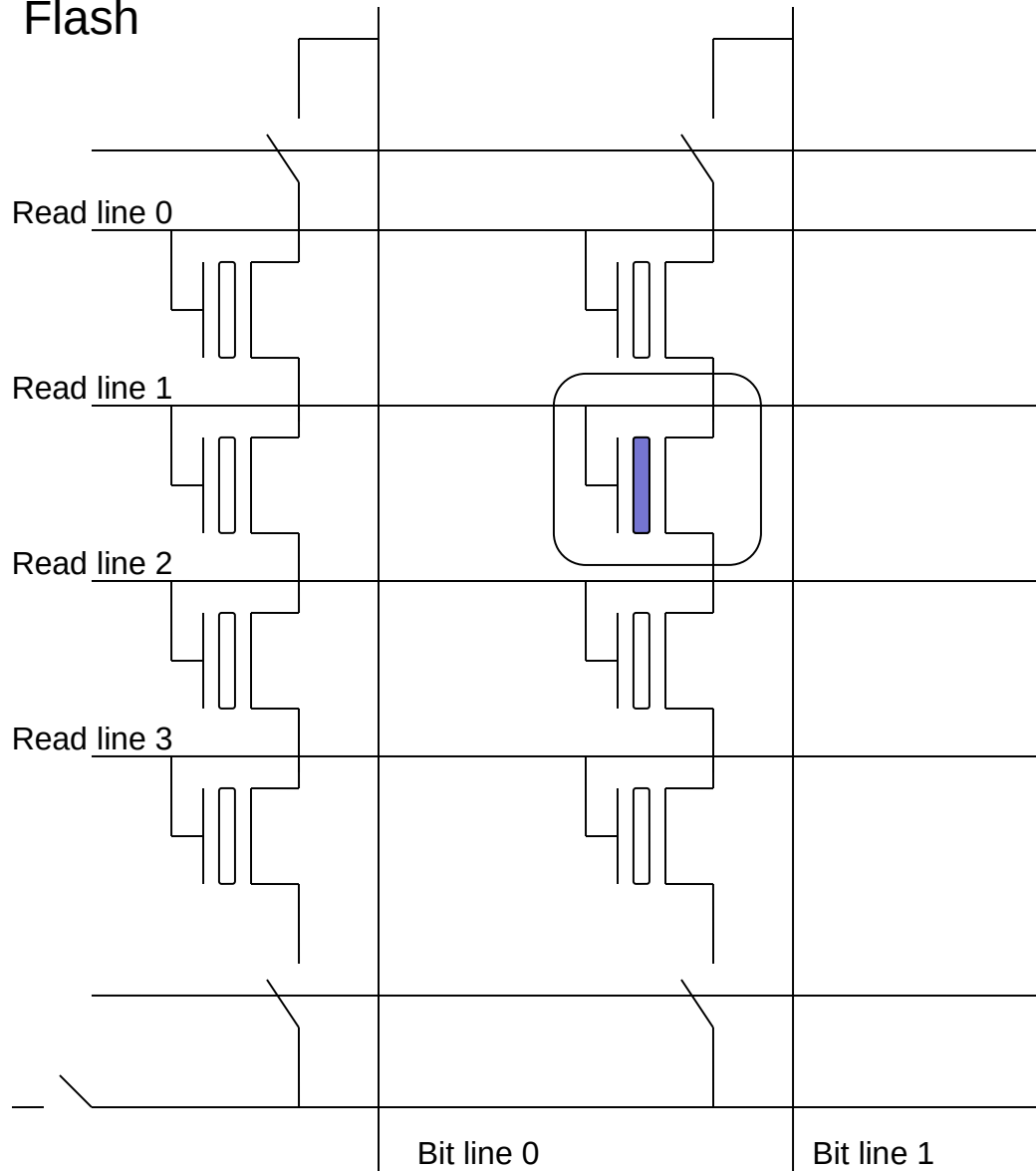
- Flash



- Flash

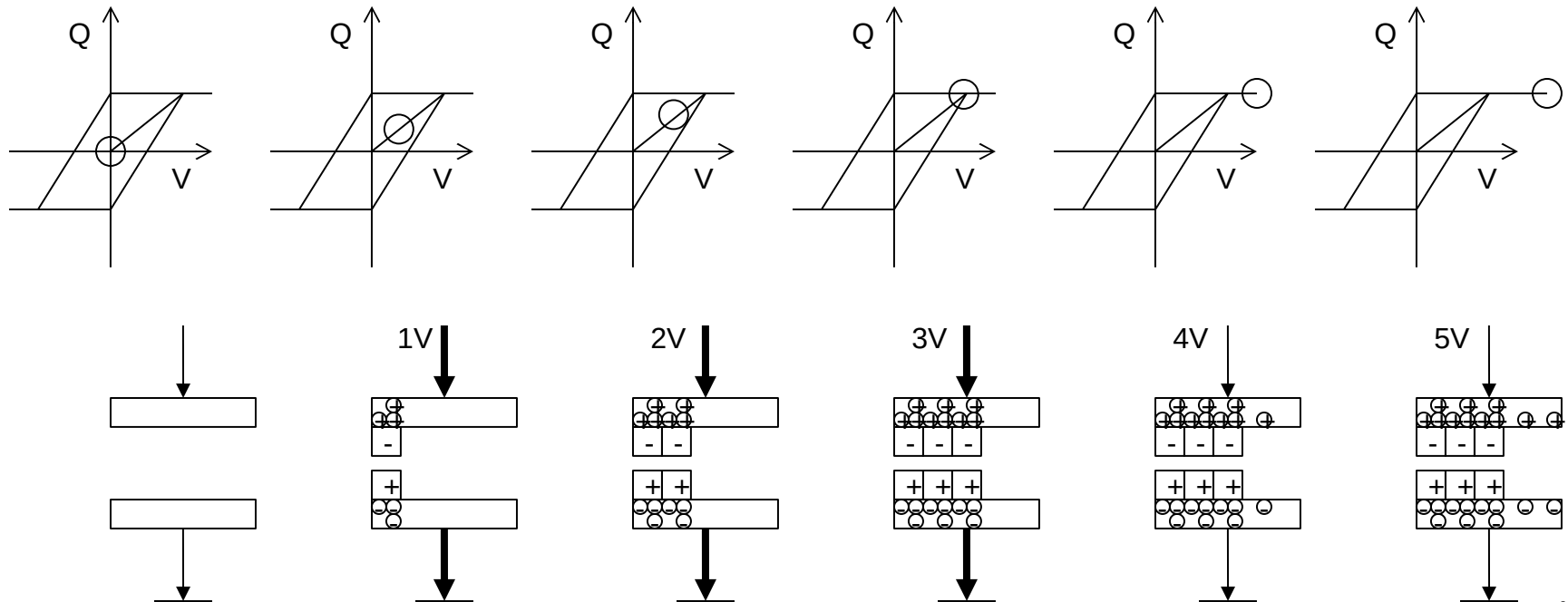


- Flash

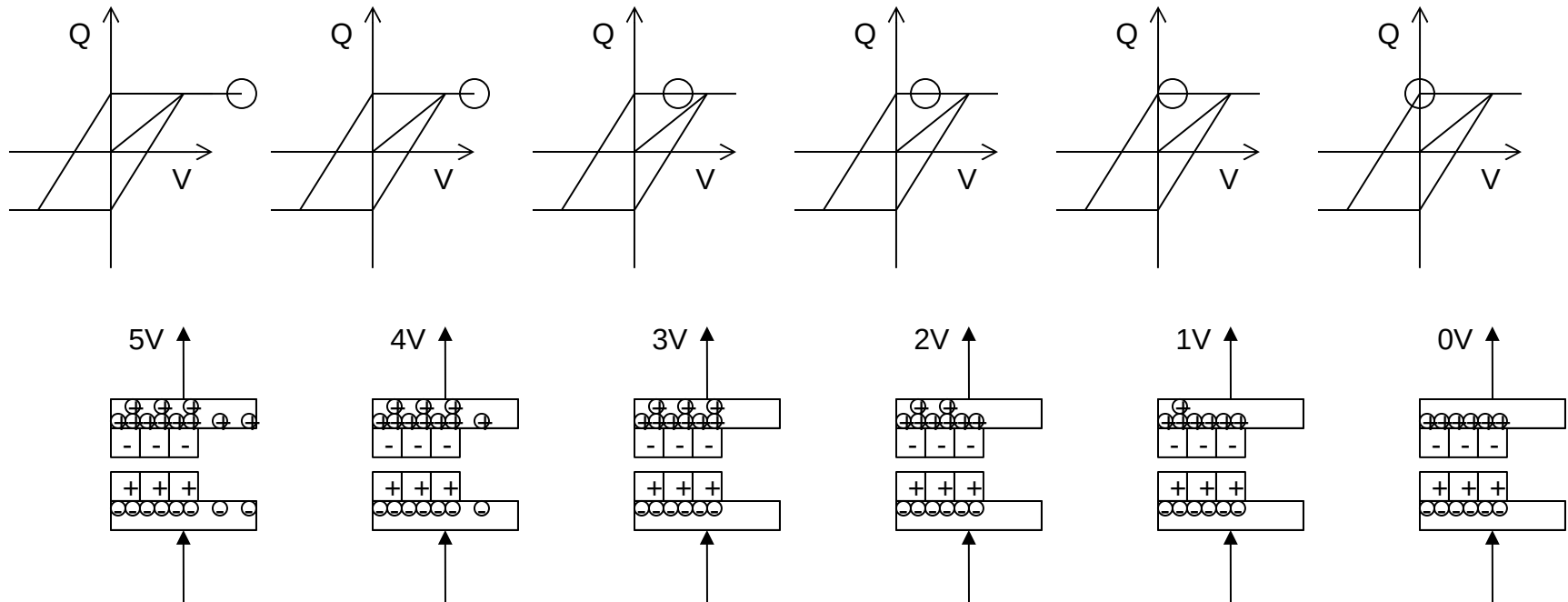


Ferroelectric RAM

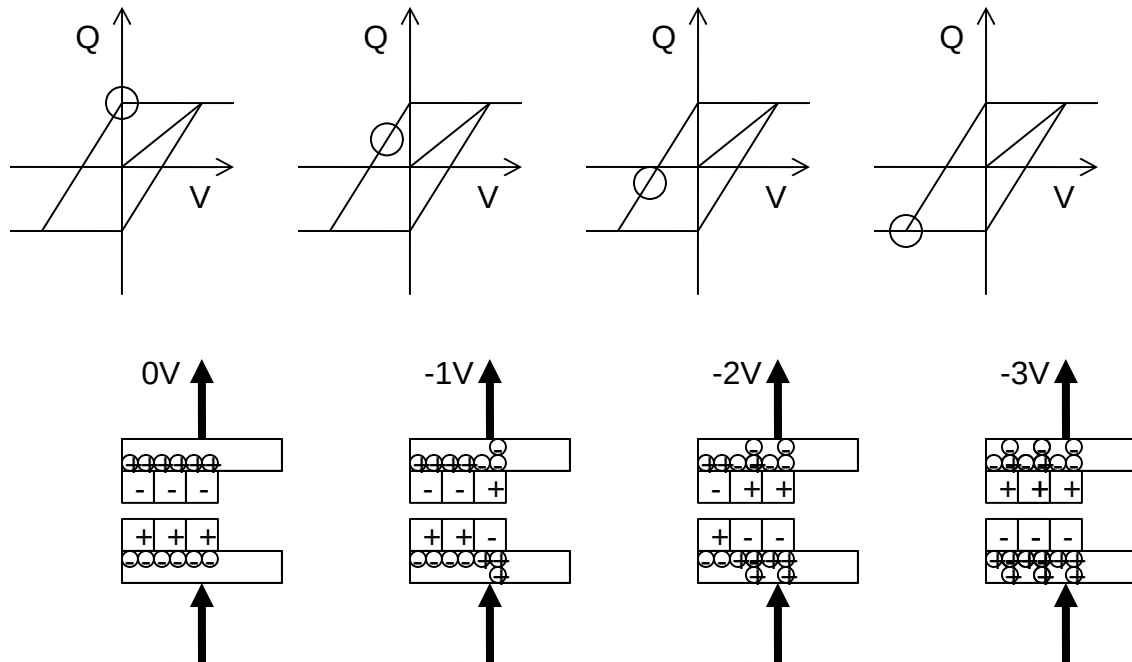
- Polarisation -> high current



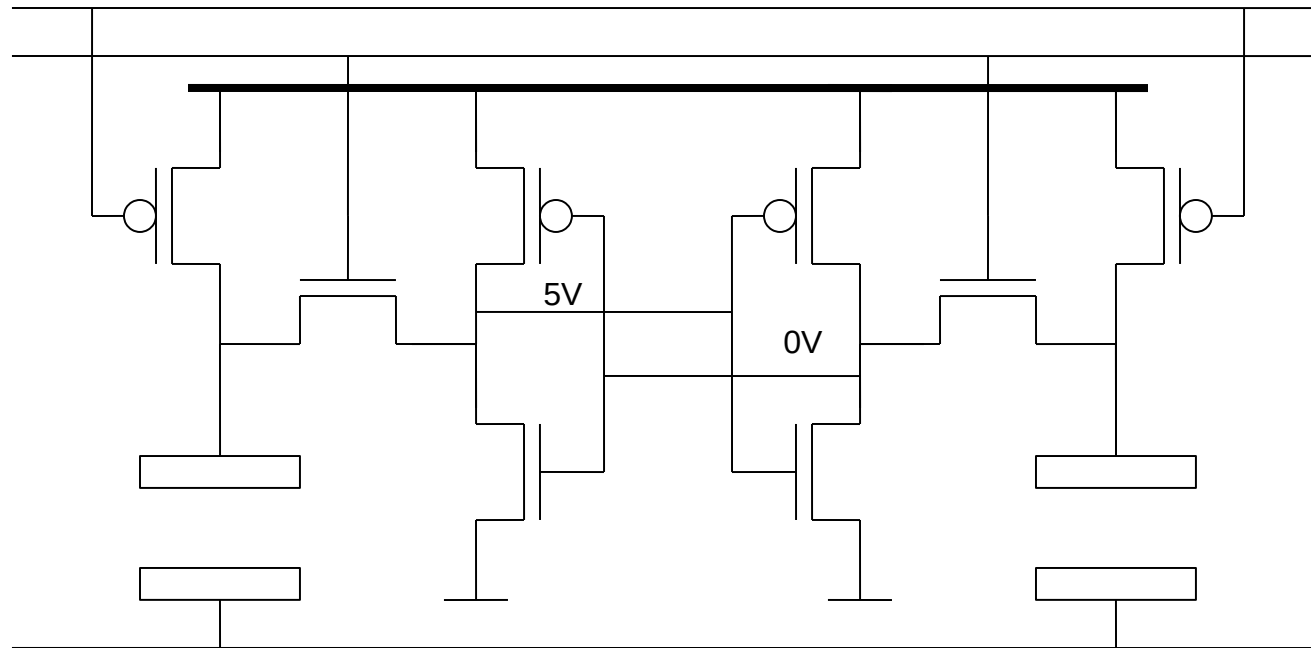
- Maintaining of polarity -> low current



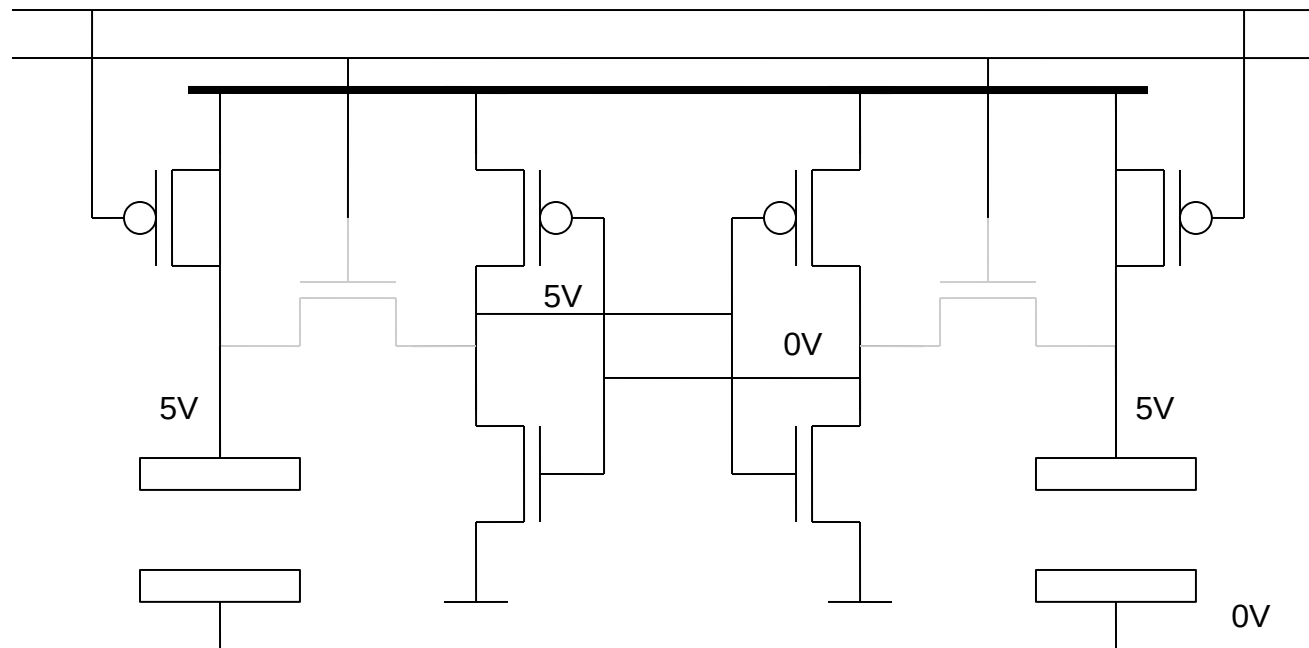
- Reversal of polarity -> high current



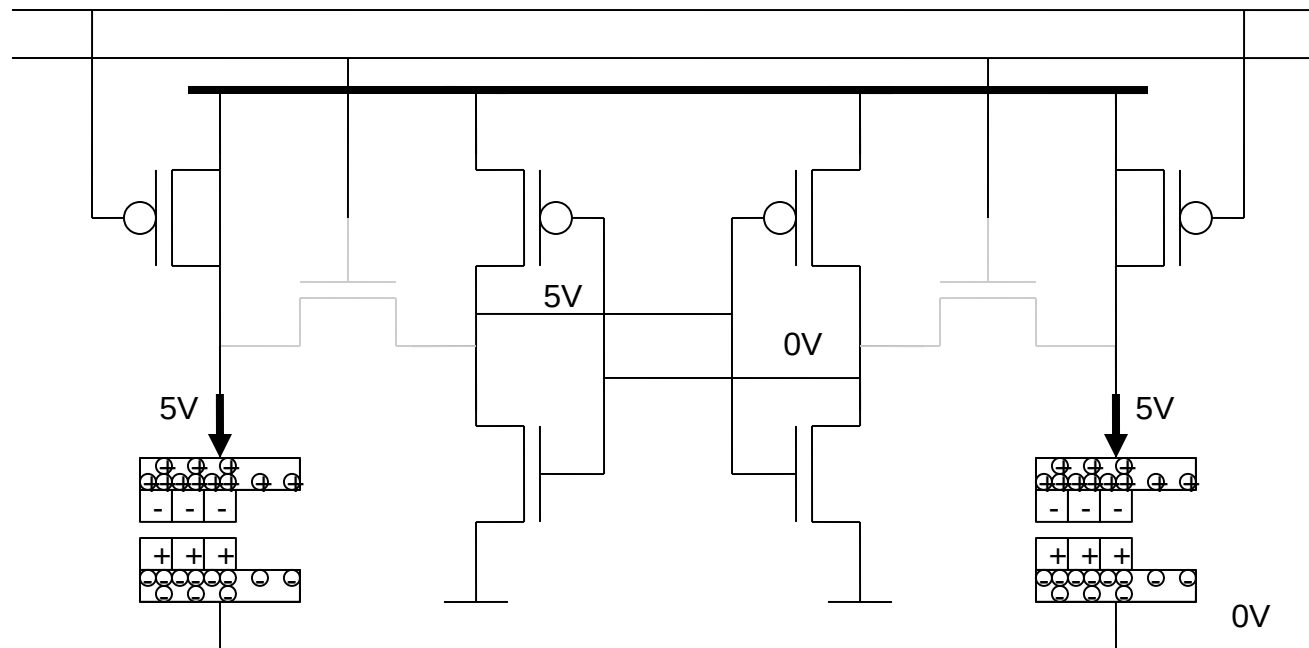
- Precharge



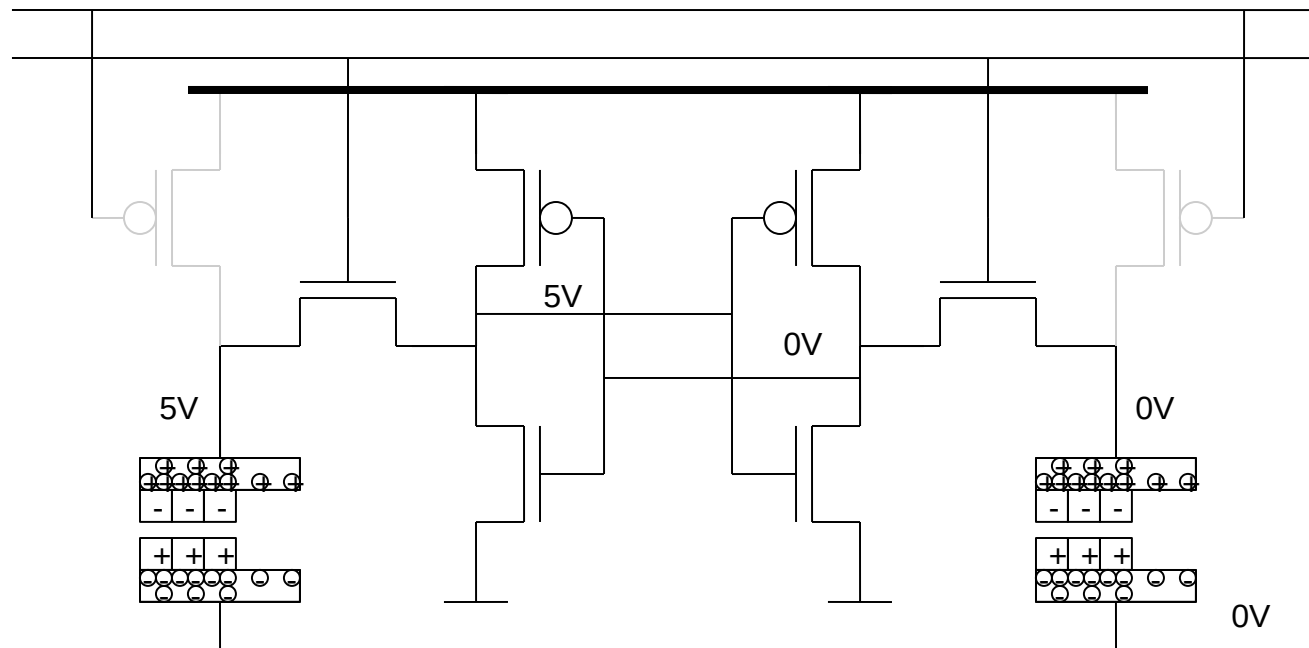
- Precharge



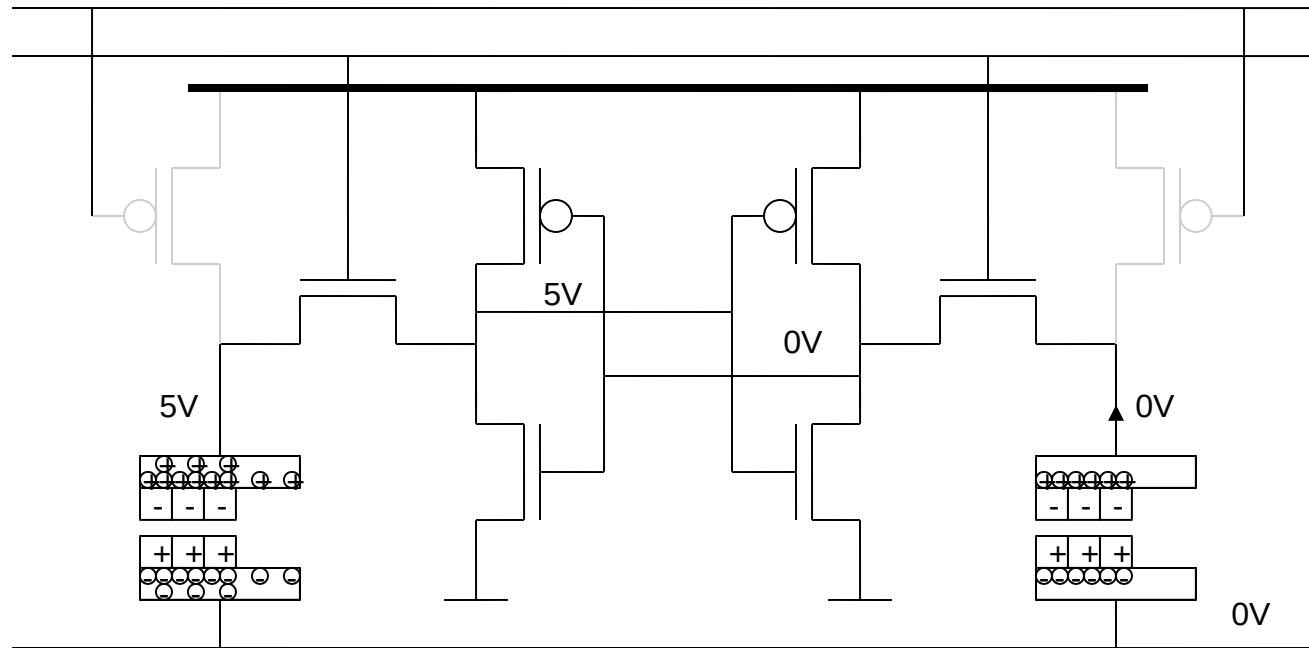
- Precharge



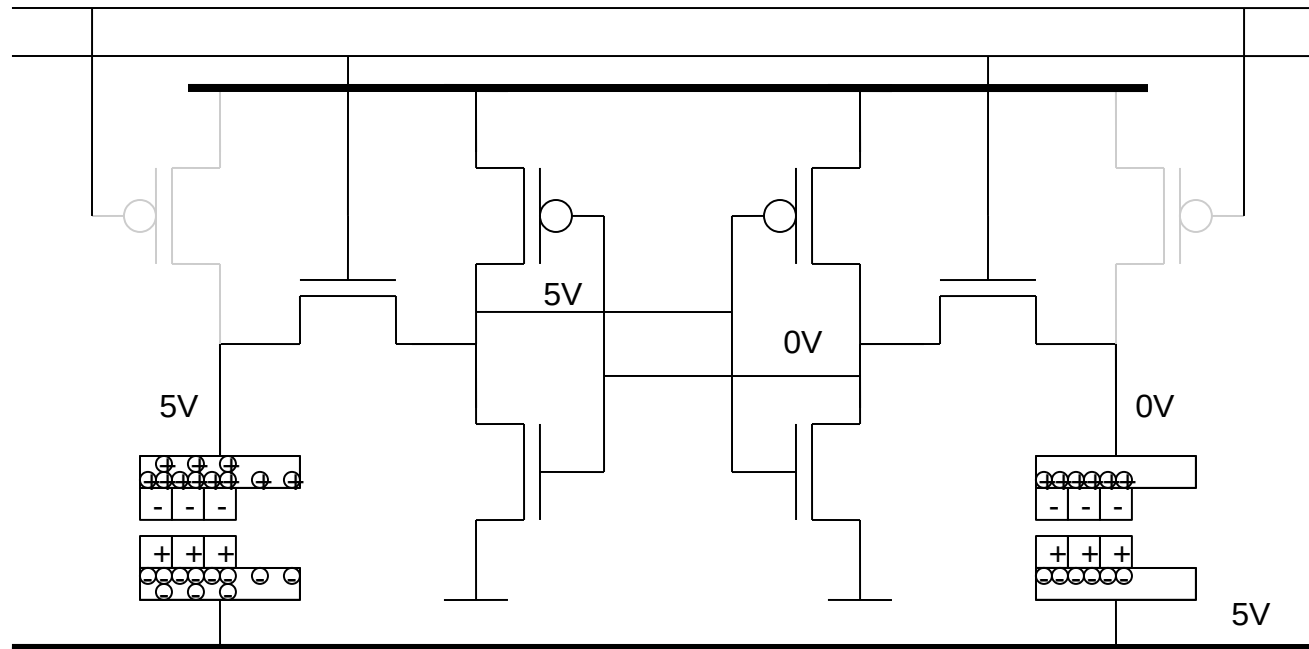
- Write FERAM



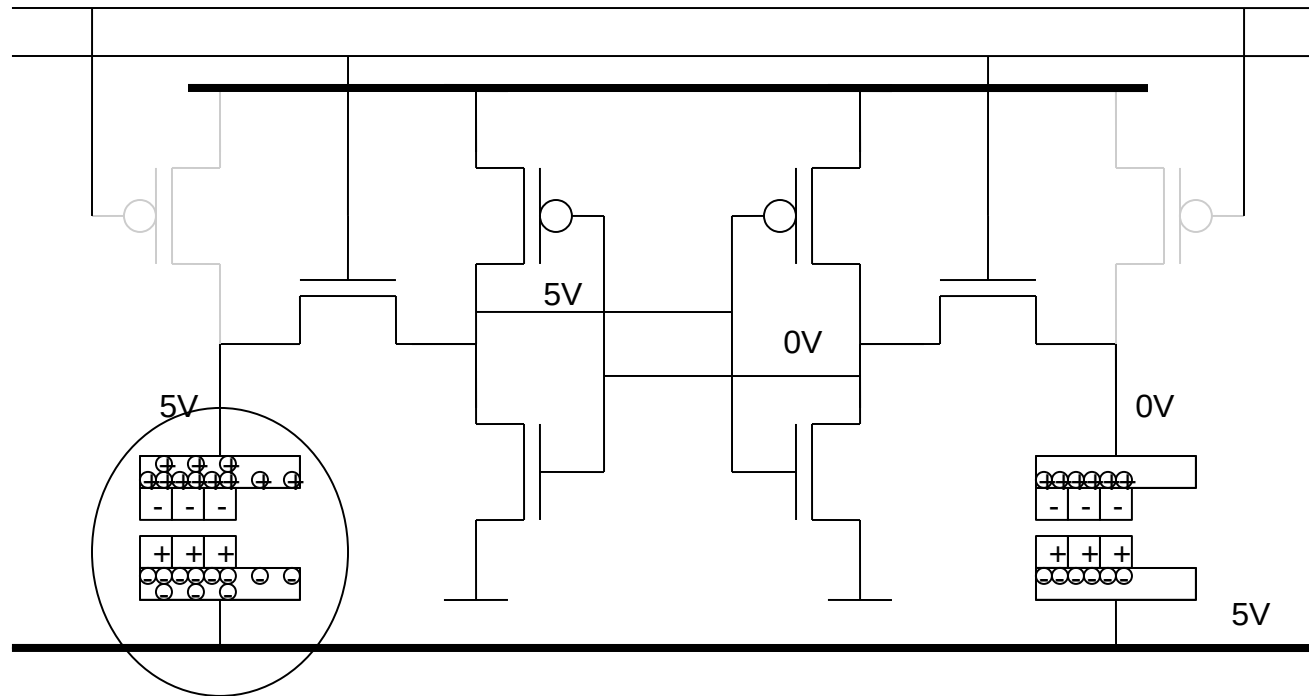
- Write FERAM



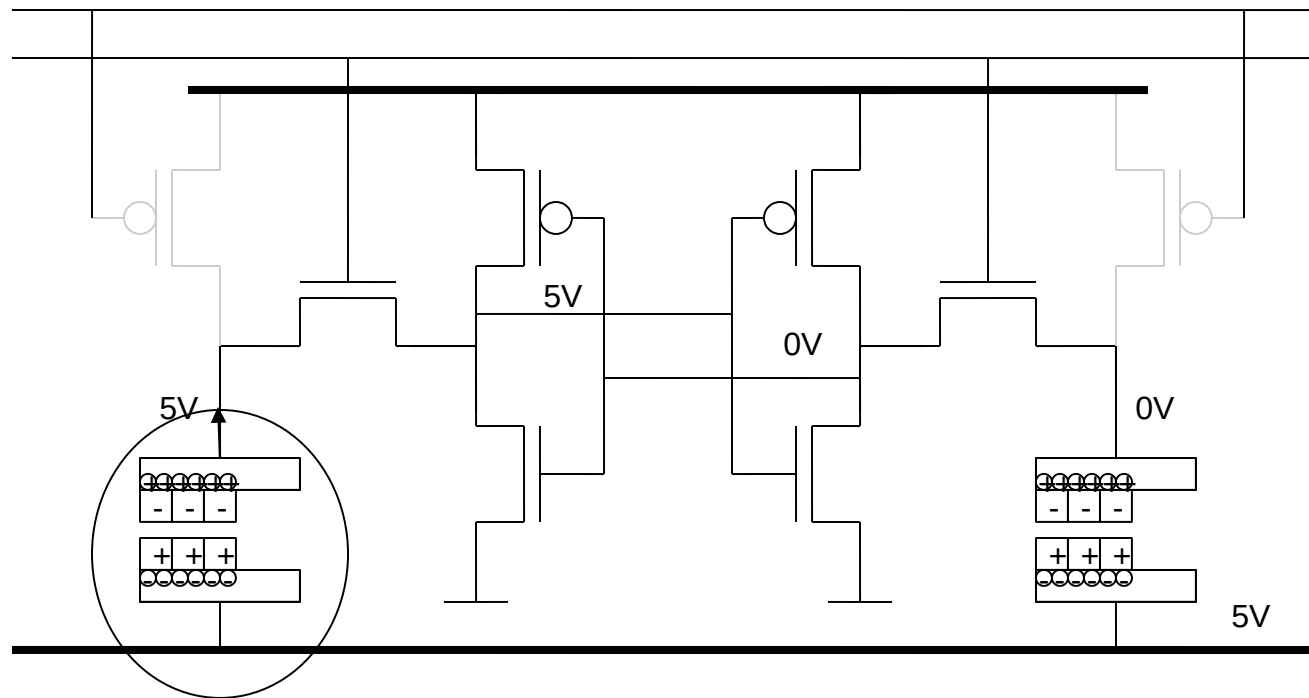
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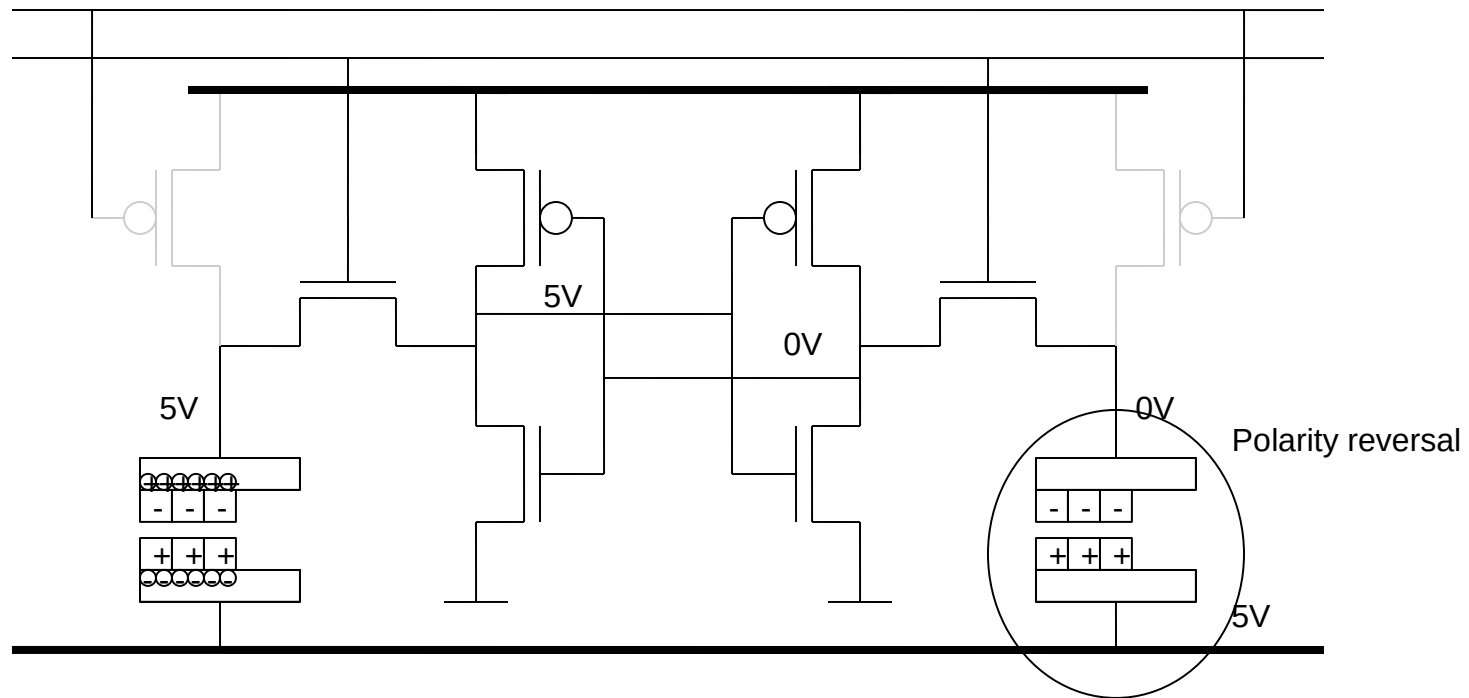
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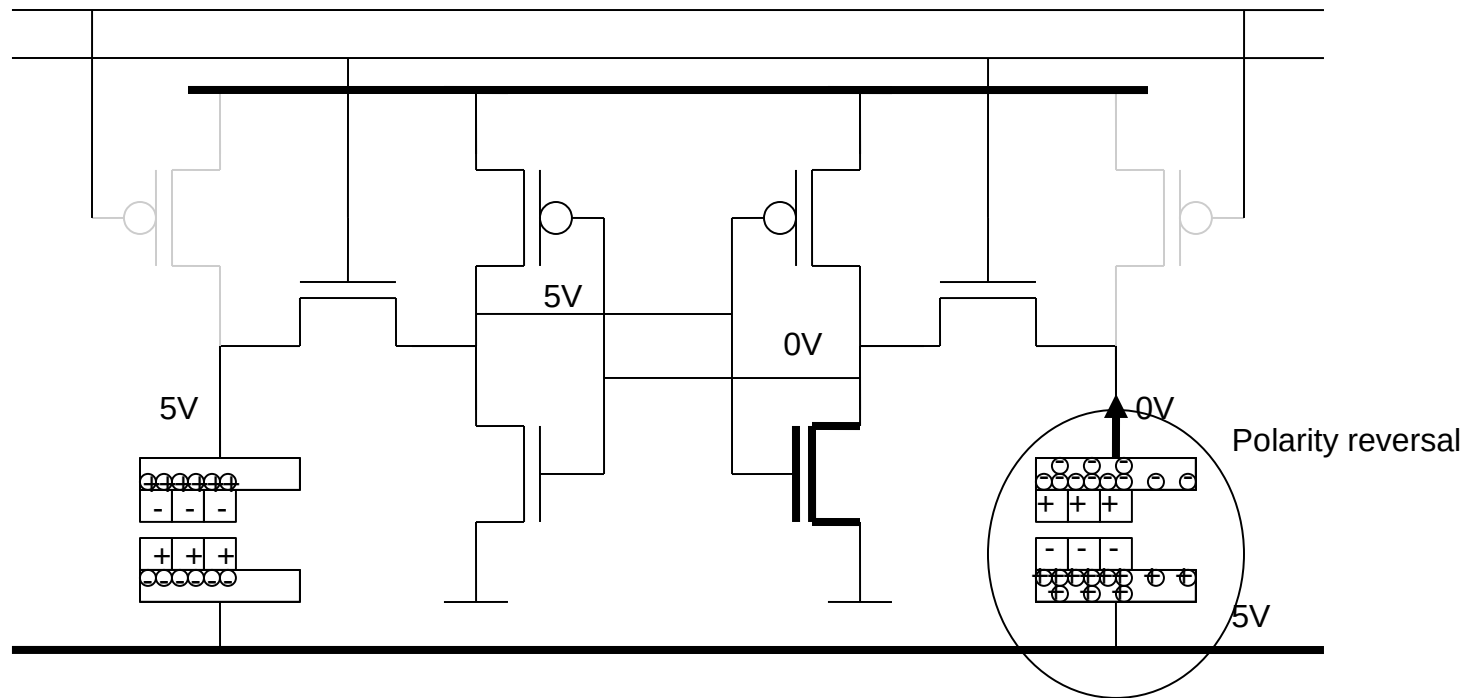
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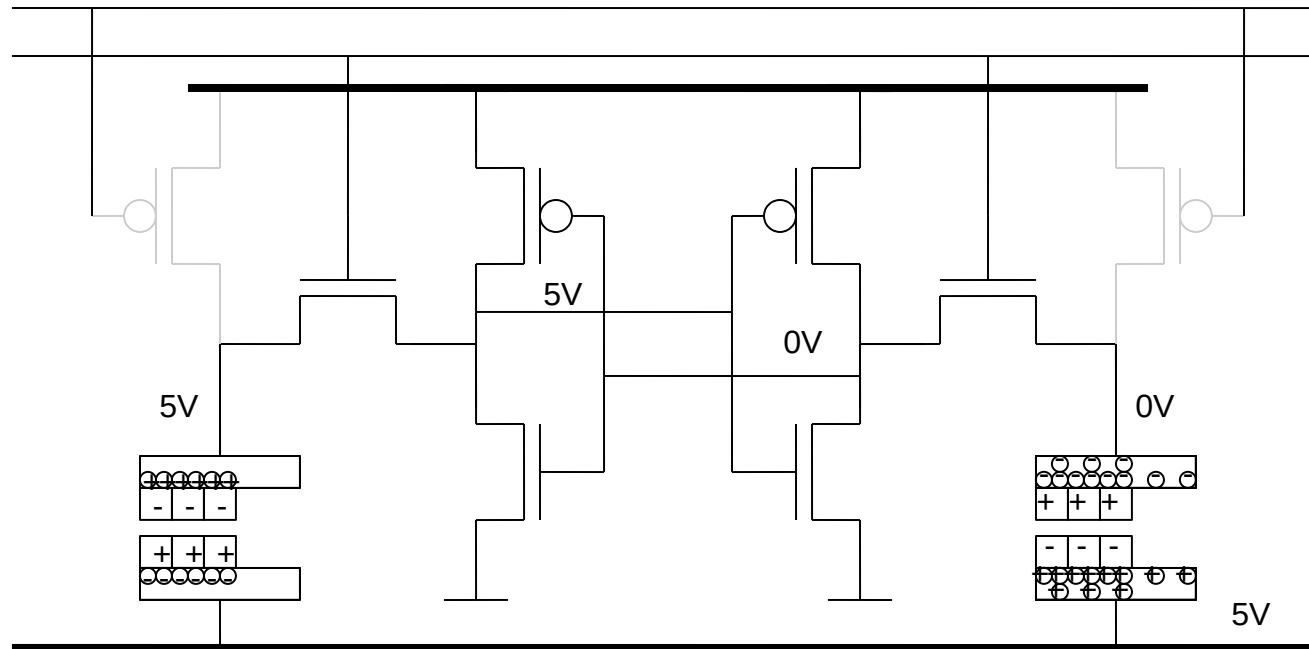
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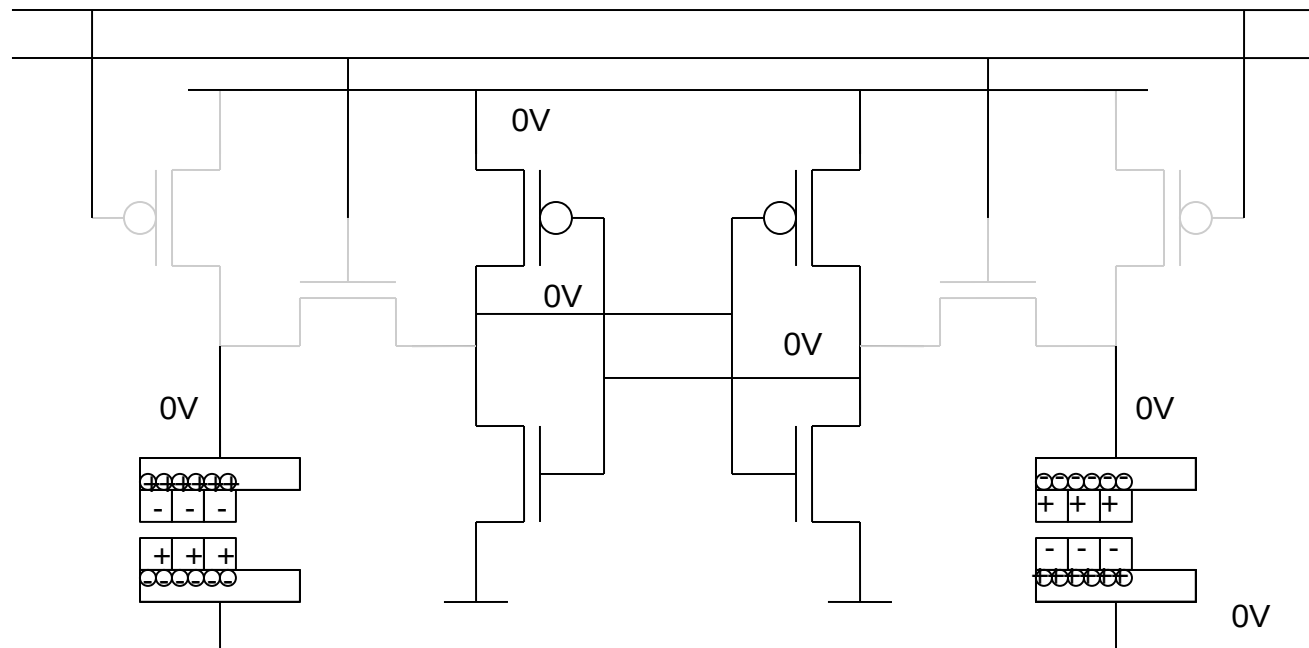
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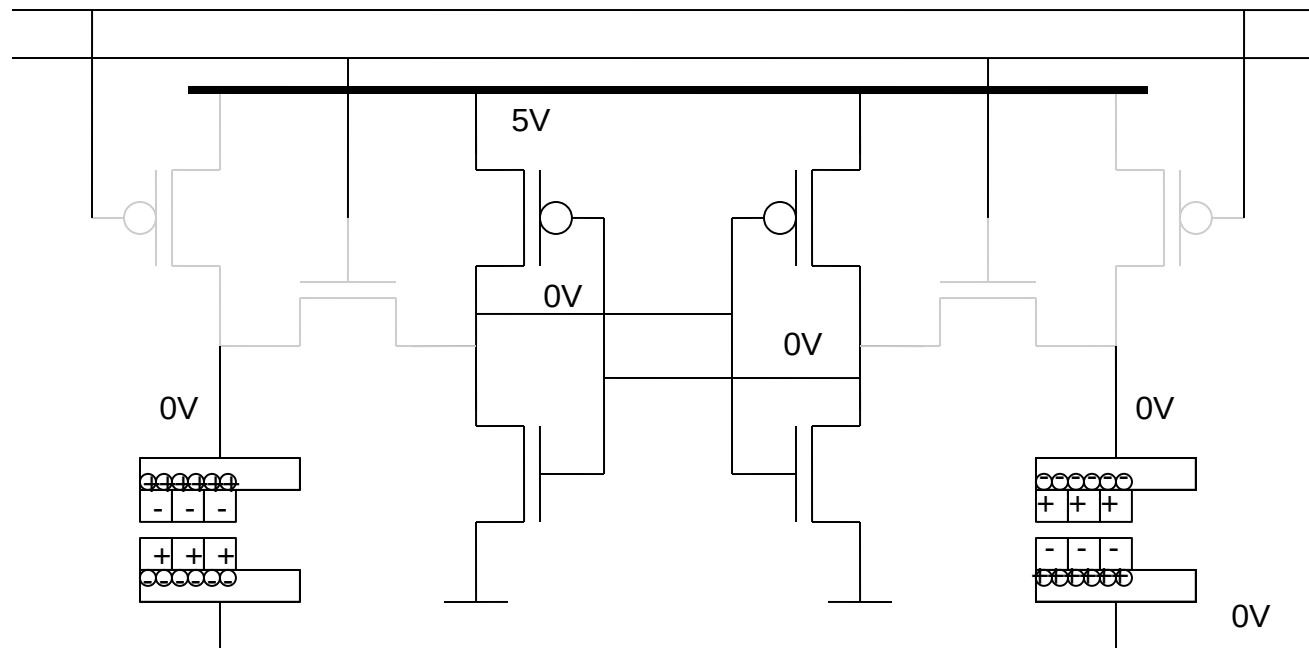
- Write FERAM



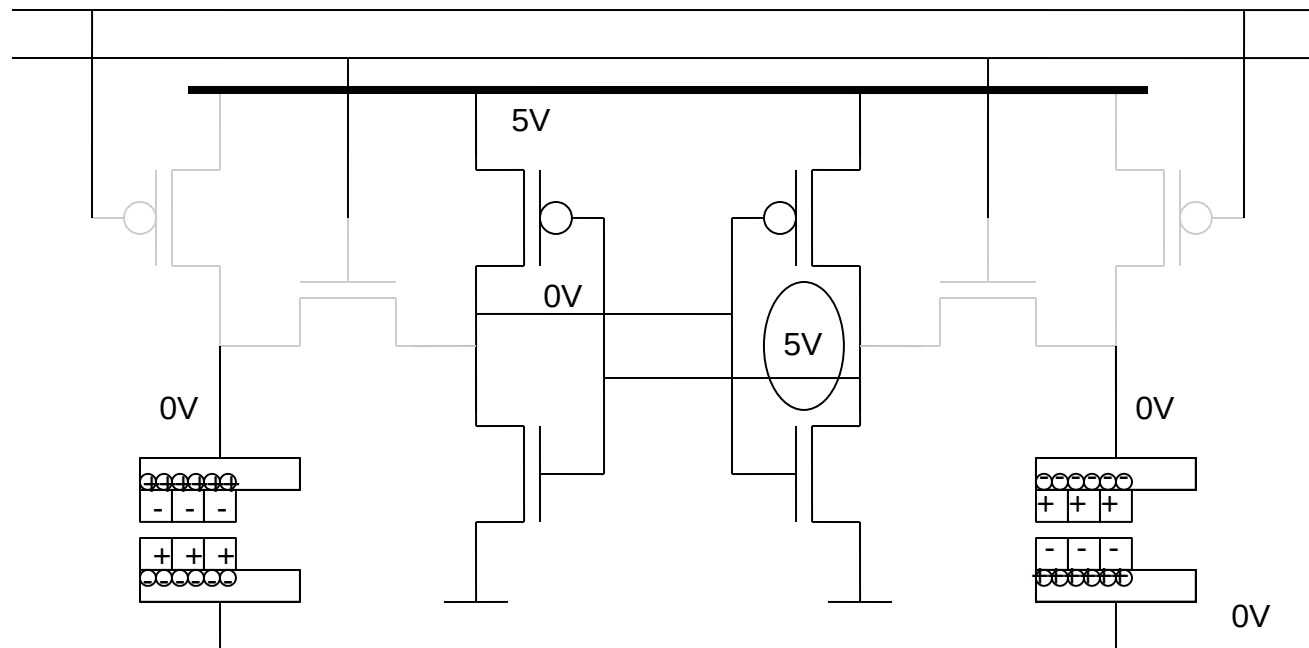
- Power off



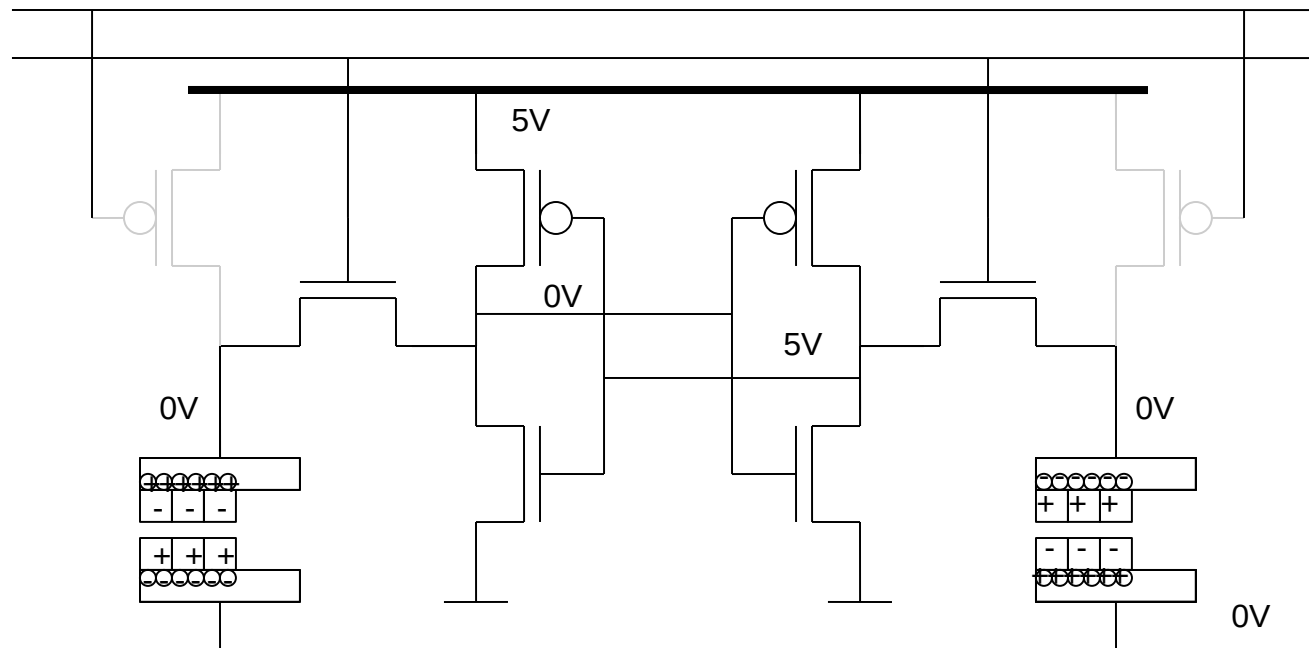
- Power on



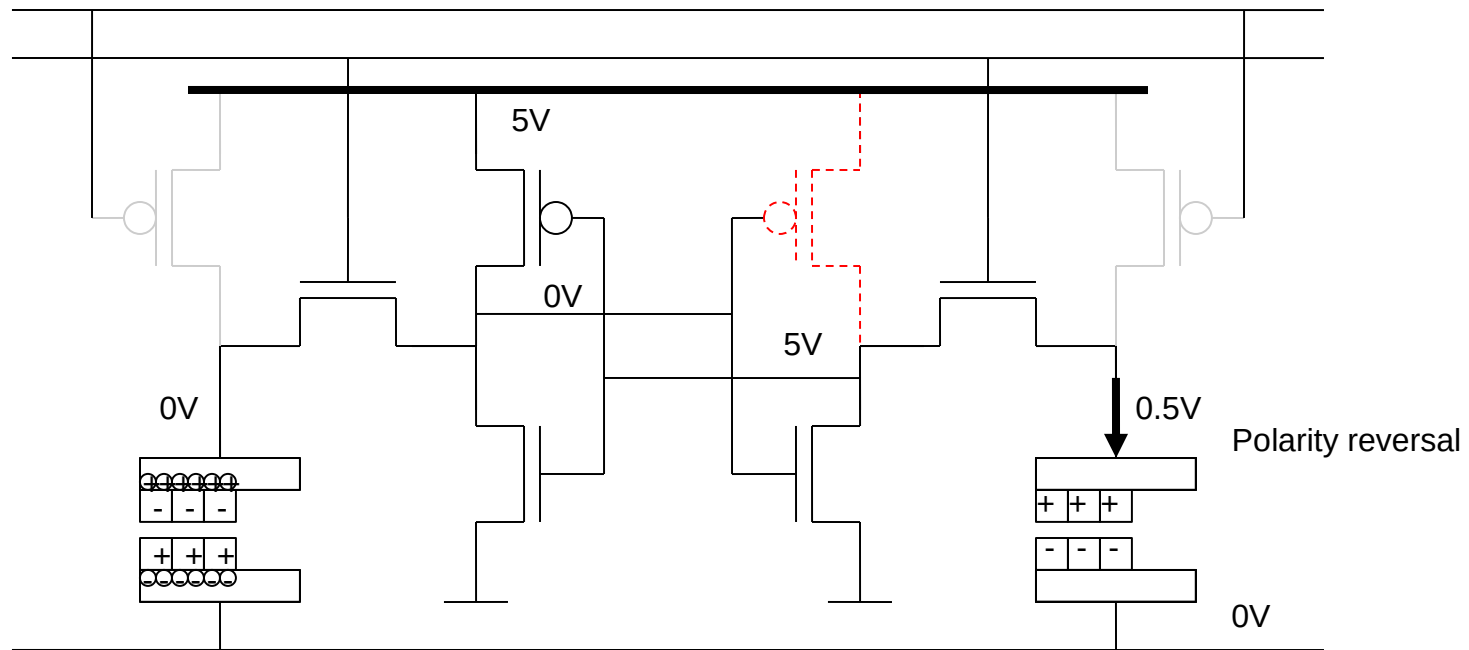
- Power on



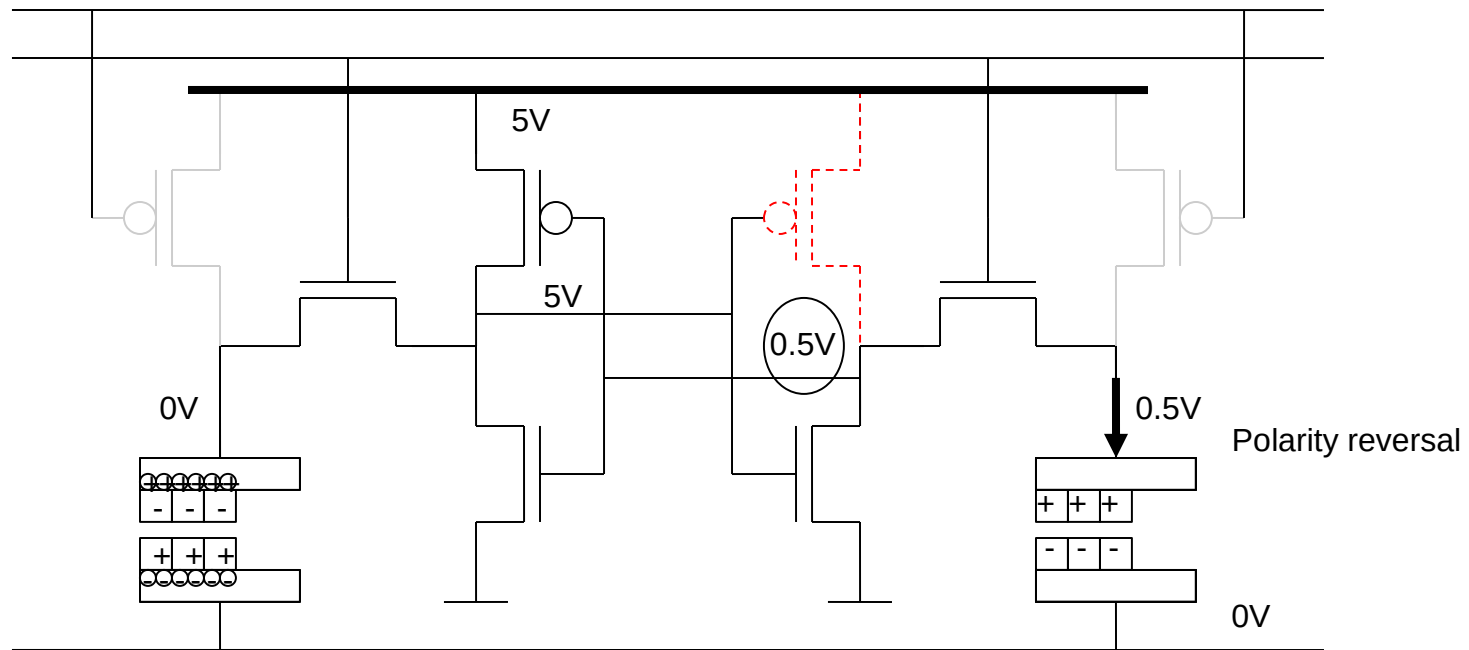
- Write SRAM



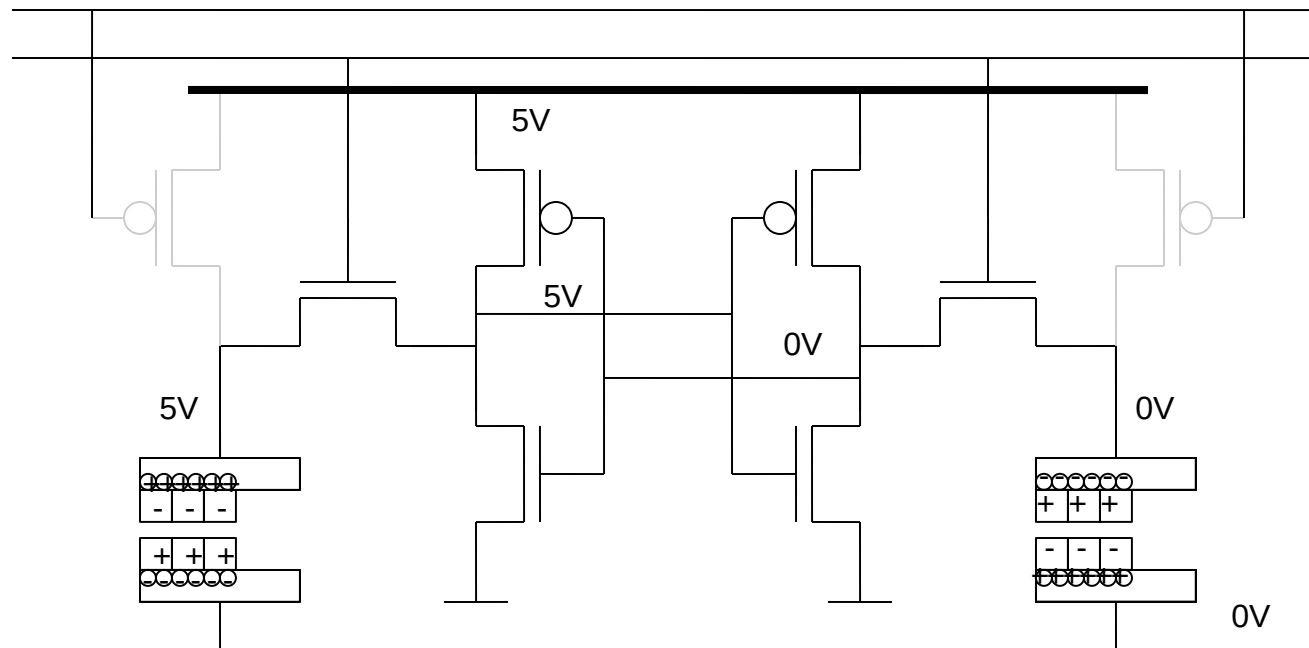
- Write SRAM



- Write SRAM



- Write SRAM



- Write SRAM

